

Power and Sensing

Selection Guide 2019

EN







Connectivity and linking the real to the digital world is no longer a dream – it is a lived reality. Future is something we create together to make life easier, safer, and greener.

连接真实世界和数字世界不再是一个梦想, 而是活生生的现实。未来由我们共同创造, 让生活更轻松、更安全、更环保。

Andreas Urschitz, Division President of Power Management & Multimarket 电力管理和多市场部门总裁

Dear Customer,

Today we communicate to everyone and everything. Interaction is no longer limited to human-to-human, but has been extended to human-to-machine and, with the latest innovations, even further to machineto-machine communication.

As a leader in the semiconductor industry, Infineon is offering a wide product range of world-class power, sensor, and security technologies. Ultraprecise sensing solutions, such as advanced 3D ToF imagers, MEMS microphones or radar sensors, substitute human senses in IoT devices, enabling them to react to their surroundings. The next generations of GaN-based products open up a new paradigm of ultimate efficiency and reliability in power solutions that actuate sensing and computing functions at the very core of intelligent devices. Infineon's portfolio also integrates cooler, smaller and lighter audio amplifiers which enable customers to create better sounding products and enjoy exceptional audio performance of HMI-enabled speakers and other audio products.

These technologies together enable energy-efficient, secure, and seamless human-to-machine and machineto-machine interaction and bridge the link between the real and the digital world. They also facilitate data storage in smart cities, industries, buildings, and homes, supporting the Internet of Intelligent Things. The 2019 edition of the Power and Sensing Selection Guide offers great solutions for your future success; together, we will make life easier, safer, and greener.

尊敬的客户:

今天我们已步入互联时代,人与人、人与事的交互成为了现实。 科技发展日新月异,本来仅局限于人与人之间的交互,已经扩展 到人与机器之间,未来机器与机器的通信,也在最新技术的推 动下成形。

作为半导体行业的领导者,英飞凌旗下备有一系列的世界级电 源、传感器和安全技术。超精密的传感解决方案,如先进的3D ToF成像仪、MEMS麦克风或雷达传感器,在物联网设备中发挥 人类感官的功能,对周围环境作出反应。下一代基于GaN的产 品,是智能设备核心传感和计算功能的动力,为极高效而可靠的 电源解决方案树立新标杆。英飞凌的产品组合还集成了更酷、更 小、更轻的音频放大器,使客户能够创造更好的音响产品,并享受 配备HMI的扬声器和其他音频产品的卓越音响表现。 上述技术结合应用,实现高效、安全、无缝的人机交互和机器对机 器的交互,给现实世界和数字世界之间架起了桥梁。它们还支持 智能物联网,促成智能城市、工业、建筑和家居的数据存储。 2019版的电力和传感选择指南的出色解决方案,为您指出未来 成功之道;让我们共同努力,使生活变得更轻松、更安全、更环保。

Andreas Urschitz, Division President of Power Management & Multimarket 电力管理和多市场部门总裁

Contents

pplications	6
Battery powered applications	6
E-mobility	8
Audio solutions	12
DC-DC enterprise power solution for data processing	16
Industrial welding	20
LED lighting	22
Major home appliances	24
Air conditioning	24
Induction cooking	25
Multicopter	26
Smart home	28
Enabling secured communication for IoT	30
Robotics	31
SMPS	34
Laptop adapter	34
Mobile charger	36
PC power supply	37
TV power supply	38
Embedded power supply	41
Server power supply	42
Telecom power supply	44
DC EV charging	46
Uninterruptible power supply	50
Solar	55
Wireless charging	60

20-300 V MOSFETs	66
500-950 V MOSFETs	96
Wide bandgap semiconductors	122
Discrete IGBTs	144
Power ICs	160
Gate driver ICs	224
Motor control ICs	252
Microcontrollers	254
Sensors	272
Packages	302



From product thinking to system understanding

Infineon enables efficient generation, transmission and conversion of electrical energy

We make life easier, safer and greener – with technology that achieves more, consumes less and is accessible to everyone.



www.infineon.com/power

Motor control ICs

Microcontrollers

XENSIVTM sensors



Battery powered applications Highest performance in motor control

We live in a mobile world filled with electrical devices - consumer-grade robots, light electric vehicles, multicopters and other end products driven by highly efficient electric motors. As these products evolve and improve, there is an increasing need for designers and engineers to find solutions that are more efficient, smaller, and less costly than ever before.

Based on the industry-leading technology, the highest quality, and manufacturing expertise, Infineon provides a variety of innovative power semiconductors addressing a broad range of battery powered motor control applications, such as power tools, forklifts, all kinds of light electric vehicles including e-skateboards, e-scooters, pedelecs, low speed cars, and many others. Through an excellent selection of devices for power management, consumption and voltage regulation – such as power MOSFETs (e.g. CoolMOS™, OptiMOS™, and HEXFET™/StrongIRFET™), XMC™ microcontrollers, EiceDRIVER™ gate drivers and more, Infineon offers all components that are needed for the compact, cost-effective designs of today, and for the innovative designs of tomorrow.



Consumer multicopters, vacuum robots, RC toys, service household, and other consumer robots

Power tools, gardening tools, commercial multicopters, cordless home appliance, cordless vacuum cleaners, and healthcare equipment

eScooter, eBike, electric wheelchair, electric forklift, low speed electric vehicles (LSEV), electric motorcycle, and other battery vehicles

Key enabling products for battery powered applications

	Consumer robotics	Home and professional applications	Light electric vehicles	
		HEXFET™/StrongIRFET™ 20-300 V		
MOSFETs	OptiMOS	™ 25-100 V	OptiMOS™ 80-300 V	
	CoolMOS™ P7 superjunction (SJ) MOSFET*			
Gate driver ICs		EiceDRIVER™		
Gate driver its	200 V and 600 V gate driver ICs			
IPM	CIPOS [™] Nano			
	XMC1100 XMC1300/XMC1400		/XMC1400	
Microcontrollers	XMC1000/XMC4000	XMC4500	/XMC4400	
	iMOTION [™] and embedded power ICs			
Microcontroller and driver supply	Linear voltage and DC-DC switching regulators			
CAN transceivers	IFX1050, IFX1051			
Magnetic sensors	Hall and xMR sensors			
Authentication	OPTIGA [™] Trust B/X, OPTIGA [™] TPM OPTIGA [™] Trust B			

To shorten customer development time and cost, we offer a complete portfolio of low voltage motor control application kits:



www.infineon.com/motorcontrol

6

* If the necessary package/R_{DSton} combination is not available in the new CoolMOS[™] P7 series yet, the previous CoolMOS[™] CE and P6 series are the preferred series

Packages



Typical battery powered three-phase system - a one-stop-shop for battery powered drives

A complete set of components that ensure system-cost competitiveness and high performance solution

Infineon product offering		Consumer robotics	Home and professional applications	Light electric vehicles
Supply voltage		12-48 V	10.8-56 V	24-144 V
OptiMOS [™] and	Voltage	25-200 V	20-100 V	60-300 V
HEXFET™/StrongIRFET™ power MOSFETs	Package	SuperS08, PQFN 3x3, DirectFET™ S/M/L- Can, TOLL, TO-220, DPAK, D ² PAK	SuperSO8, PQFN 3x3, DirectFET™ S/M/L- Can, TOLL, TO-220, TO-247, DPAK, D ² PAK, D ² PAK 7-pin	SuperS08, PQFN 3x3, TO-220, DPAK, D ² PAK, D ² PAK 7-pin, D ² PAK 7-pin+, TOLL, DirectFET™ L-Can
CoolMOS™ P7 SJ MOSFET*	Voltage	600-800 V	600-700 V	600 V
Gate driver ICs		1EDN, 2EDN, 1EDN7550, 2EDL811x, 6ED003L02-F2, 6ED003L06-F2, 6EDL04N- 02PR, 6EDL04N06PT, 2EDL05N06PF, IRS2005S, IRS2005M, IRS2007S, IRS2008S, IRS2011S Integrated gate driver ICs: IFX9201/2, NovalithIC™ BTN8982, Trilith IC BTM7752	1EDN/2EDN/6EDL04N02PR, 6ED003L02- F2, 2EDL05N06PF, 2ED2304S06F, IRS2005S/M, IRS2007S, IRS2008S, IRS2301, IRS21867, IRS2304 Integrated: IFX9201SG/ BTN8982	1EDN/2EDN/2EDL/ 6EDL04N02PR, 6ED003L02-F2, 2EDL05N06PF, 2ED2304506F, IRS2005S/M, IRS2007S, IRS2008S, IRS2301, IRS21867, IRS2304
IPM – CIPOS [™] Nano		IRSM836-0x4MA (x=2,4,8), IRSM808-204MH	IRSM005-800MH, IRSM005-301MH	
Authentication IC, security		OPTIGA [™] Trust B/X, OPTIGA [™] TPM OPTIGA [™] Trust B OPTIG		OPTIGA™ Trust B
XMC™ microcontrollers iMotion™ ePower		XMC1100 XMC1000/XMC4000 iMOTION™: IRMCK099M ePower: TLE987X (BLDC), TLE986X (BDC)	XMC1300 XMC4400/XMC4500 iMOTION™ IRMCK099M ePower: TLE987X (BLDC)	XMC1300 XMC 4400/XMC4500
Microcontroller and driver sup linear voltage and DCDC switc regulators		IFX1763/IFX54441/IFX54211/IFX30081/IFX90121/IFX91041		
CAN transceivers		IFX1050, IFX1051		
Sensors		Hall switches (TLE 496X), Angle sensor (TLI5012B, TLE5501), 3D magnetic sensor (TLV493D), Current sensor (TLI4970)	Hall switches (TLE496X), Angle sensor (TLI5012B), 3D magnetic sensor (TLV493D)	Hall switches (TLE496X), Angle sensor (TLI5012B), 3D magnetic sensor (TLV493D)

Why to choose Infineon as your partner for innovation in battery powered applications

Infineon product offering	Customer benefits
Complete solutions – broad portfolio	Whatever design specification, Infineon has the answer in the comprehensive portfolio of products and solutions which you can easily tailor to your needs
	Infineon offers solutions for power supplies, chargers, motor drives and sensors
Extended battery lifetime and	> BiC MOSFETs e.g. OptiMOS™ and HEXFET™/StrongIRFET™ extend battery lifetime and reduce chances for control failure
product life spans	High reliability of Infineon components results in prolonged product lifespans
Productive capability	Offering LV FETs with SMD packaging improves the productive capability by automatic production, improves reliability and reduces assembly cost
Overall system size and cost reduction	With Infineon's components you can reduce of overall system size and cost due to components occupying smallest area and featuring compact design, both of which are required for highest power density and BOM savings thanks to lowest R _{DS(m)}
Security, quality and safety	Trustworthy hardware-based security
	> As a security market leader with a proven track record and outstanding partner network for embedded security, Infineon provides highest quality standards and a safety certified development process
Authentication	> OPTIGA [™] Trust enables authentication of components connected to the system (e.g., battery pack recognition to avoid second party batteries etc.)
Fast time-to-market	Faster time-to-market is enabled by providing evaluation and demo boards for fast prototyping, and simulations, documentation, and system support that reduce development time and cost

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* If the necessary package/R_{oSton} combination is not available in the new CoolMOS™ P7 series yet, the previous CoolMOS™ CE and P6 series are the preferred series

Packages

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*For off-board chargers only



efficiency is an important design criterion.

AC-DC battery chargers: functional blocks

E-mobility

possible to stay cool at the lowest possible weight.

Onboard chargers

Off-board chargers

Best solutions for battery chargers, wireless charging and battery management

To recharge the battery of an electric or hybrid car, a charger is needed. Chargers can be implemented onboard or

In cars with onboard chargers the batteries can be recharged from any standard AC power outlet, which provides maximum power of 6.6 kW best case (single-phase 230 V/32 A). This standard charging at low power takes several hours (overnight). Battery charging via the power grid requires a flexible power converter topology to handle different voltage and power ratings wherever the car may go to, and onboard chargers need to be as efficient and small as

In off-board chargers, the power conversion from AC grid voltage to DC battery voltage is done outside the car and the resulting DC power is transmitted by wire to the DC-charging socket in an electric vehicle. Ultrafast chargers with power

be a market for off-board chargers in the power range up to 10 kW, for example to charge small and economic electric vehicles (LEVs). Also in case of the off-board chargers, selecting the right topology to enable maximum conversion

ratings at 50 kW and more have been designed in this way. As the power converter is off-board, automotive grade qualification is not required for the respective electronic components. Apart from fast and ultrafast chargers, there may

off-board the vehicle. Electric energy is transferred to the vehicle by wire or by wireless methods like resonant inductive power transfer. Power units onboard the vehicle require automotive-grade components, while the wider

product selection of industrial-grade components can be used for off-board units.







Product portfolio for onboard and off-board charger applications

Infineon's comprehensive portfolio of semiconductors (sensors, microcontrollers, power semiconductors, etc.) lends itself perfectly to designs of compact units for onboard, off-board, and wireless charging. Our products in this sector support high switching frequencies at lowest possible on-state resistance (R_{DS(on)}) to enable compact and efficient designs: MOSFETs such as CoolMOS[™], IGBTs such as TRENCHSTOP[™] 5 and SiC Schottky diodes, such as 650 V CoolSiC[™] diode. In addition, integrated MOSFET and IGBT drivers, controller ICs for active CCM PFC high-performance microcontroller solutions and highly accurate current sensors complete our product portfolio. For more information about off-board chargers, refer to **page 46** DC EV charging.

Automotive products for onboard units

Typical part number	Product family	Description
1ED020I12FA2	Automotive EiceDRIVER™	Single-channel isolated driver for 650 V/1200 V IGBTs and MOSFETs
1ED020I12FTA	Automotive EiceDRIVER™	Single-channel isolated driver, two-level turn-off for 650 V/1200 V IGBTs
2ED020I12FA	Automotive EiceDRIVER™	Dual-channel isolated driver for 650 V/1200 V IGBTs and MOSFETs
IPx65RxxxCFDA	CoolMOS™	650 V MOSFET with integrated fast body diode
TC23xL, TC26xD	AURIX™	32-bit lockstep microcontroller
TLF35584 ¹⁾	System supply	New ISO26262 – system-supply optimized for AURIX™
TLE7250G	Transceiver	High-speed automotive CAN transceiver
TLE6251D	Transceiver	High-speed automotive CAN transceiver, with wake-up

Industrial products for off-board units

Typical part number	Product family	Description
IKWxxN65F5/H5/EH5, IKZxxN65EH5/NH5	TRENCHSTOP [™] 5 IGBTs	650 V ultrafast/fast IGBT with Rapid 1 diode
IGWxxN65F5/H5, IGZxxN65H5	TRENCHSTOP [™] 5 IGBTs	650 V ultrafast/fast IGBT
IDWxxG65/120C5(B3)	CoolSiC [™] diodes	650 V/1200 V SiC Schottky diode generation 5
IDWDxxG120C5	CoolSiC [™] diodes	1200 V SiC Schottky diode generation 5 TO-247 2-pin
IMW/Z120RxxxM1	CoolSiC [™] MOSFETs	1200 V SIC MOSFETs
IPW65RxxxC7	CoolMOS [™] SJ MOSFETs	650 V MOSFET, CoolMOS™ C7 series for hard switching topologies
IPW60RxxxP7	CoolMOS [™] SJ MOSFETs	600 V MOSFET, CoolMOS™ P7 series for hard switching topologies
IPW65RxxxCFD	CoolMOS [™] SJ MOSFETs	650 V MOSFET, CoolMOS™ CFD2 series for soft switching topologies
IPW60RxxxCFD7	CoolMOS [™] SJ MOSFETs	600 V MOSFET, CoolMOS™ CFD7 series for soft switching topologies
HYBRIDPACKTM 1	Power module	1200 V/200 A for fast and ultrafast charging (>10 kW/phase)
XMC1000 ²⁾ , XMC4000 ²⁾	XMC [™] microcontrollers	32-bit ARM® Cortex® M0/M4F microcontrollers, up to 125°C ambient temperature (XMC4000)
IFX1763, IFX54441, IFX54211	Linear voltage regulators	Linear voltage regulator family with output current capability of 500 mA/300 mA/150 mA respectively
IFX1050, IFX1021	Transceivers	High-speed CAN transceiver/LIN transceiver
TLI4970	Current sensor	600 V functional isolation, ± 50 A
2EDNxxxxF/R	EiceDRIVER™ 2EDN gate driver ICs	Dual-channel, low-side, non-isolated
1EDIxxN12AF	EiceDRIVER™ 1EDL Compact gate driver ICs	Single-channel, high-side isolated

Wireless charging

Wireless methods for power transfer to charge the batteries of electric vehicles are gaining attention. Several concepts for wireless power transfer systems have been proposed, which in general seek to compensate the significant stray inductances on primary and secondary sides of the magnetic couplers by adaptive resonant methods. At the end of 2013, SAE announced a new standard for inductive charging which defined three power levels at 85 kHz. Infineon's TRENCHSTOP™ 5 IGBTs and CoolSiC™ diodes are perfectly suited for driving inductive power transfer systems on the road side which operate inside the 80 to 90 kHz band.



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in development
 for external chargers
 R^e in product pame refers to com

Automotive products for the car side*

Typical part number	Product family	Description
1ED020I12FA2	Automotive EiceDRIVER™	Single-channel isolated driver for 650 V/1200 V IGBTs and MOSFETs
1ED020I12FTA	Automotive EiceDRIVER™	Single-channel isolated driver, two-level turn-off for 650 V/1200 V IGBTs
2ED020I12FA	Automotive EiceDRIVER™	Dual-channel isolated driver for 650 V/1200 V IGBTs and MOSFETs
IPx65RxxxCFDA	CoolMOS™	650 V MOSFET with integrated fast body diode
TC23xL, TC26xD	AURIX™	32-bit lockstep microcontroller
TLF35584 ¹⁾	System supply	New ISO26262-system-supply optimized for AURIX™

Industrial products for the road side*

Typical part number	Product family	Description
IKW40N65F5	TRENCHSTOP [™] 5 IGBTs	Fast IGBT with Rapid 1 diode, 40 A, TO-247
IGW40N65F5	TRENCHSTOP [™] 5 IGBTs	Fast IGBT, single, 40 A, TO-247
IDW40G65C5	CoolSiC™ diode	650 V SiC Schottky diode generation 5, 40 A, TO-247 ²⁾
XMC4000	XMC [™] microcontroller	32-bit ARM® Cortex® -M4F microcontrollers, up to 125 °C ambient temperature
IFX1763, IFX54441	Linear voltage regulators	Linear voltage regulator family with output current capability of 500 mA or 300 mA respectively
TLI4970	Current sensor	600 V functional isolation, ± 50 A

*Available in different current ratings

Charger concepts without galvanic isolation of the power stages

Transformerless designs, without galvanic isolation inside the power stages, are economic and efficient. But enhanced safety measures may be required to operate such designs from standard AC-grid power outlets. Type-B RCD (GFCI) safety switches are needed on the grid side to immediately break the circuit in case an unintended feedback of DC-voltage from the HV-battery into the AC-grid occurs under worst-case failure conditions, but type-B safety switches on the grid side are not standard by today. The main reason why non-isolated designs are currently not accepted for onboard chargers is because the level of safety measures on the grid side of the charging spot is uncertain. However, inside an off-board charger installation with an integrated type-B safety switch, the use of non-isolated concepts may be indicated. To highlight their opportunities, Infineon has investigated non-isolated concepts, built and evaluated laboratory demonstrators of single-phase 3 kW chargers without galvanic isolation inside the power stages.

Concept demonstrator³⁾ of lean and efficient off-board DC-charger without galvanic isolation

- > Input 230 V/50 Hz single-phase AC
- Output 220 V-390 V_{DC}, max. power
 3.3 kW at 350 V with 96.2 percent efficiency



Industrial products for the road side

Typical part number	Product family	Description
ICE3PCS01G	Integrated controller	For active CCM PFC, DSO 14-pin
IPW65R019C7	CoolMOS™ C7 SJ MOSFET	650 V MOSFET, 19 mΩ, TO-247
IDW30G65C5	CoolSiC™ diode	650 V SiC Schottky diode generation 5, 30 A, TO-247
TLI4970	Current sensor	600 V functional isolation, ± 50 A

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1) In development

2) Automotive version under consideration

3) More detailed information about this demonstrator is available upon request

XENSIVTM sensors

Best solution for battery management

An intelligent battery management system (BMS) is necessary to sustain battery performance throughout its entire lifetime – the challenge there is to tune the utilization of each battery cell individually. Passive cell balancing is the default approach where the weakest of the cells sets the limits for battery lifetime and cruising range. Infineon's microcontrollers and sensors, in combination with our power devices, enable active cell balancing while charging and discharging. An active cell balancing system helps to increase the effective cruising range and the battery lifetime by 5 to 10 percent, compared to passive balancing. In this context, highlights are our 8-bit XC886CM microcontroller family for the slave blocks and the new 32-bit AURIX[™] microcontroller family for the master block, OptiMOS[™] low voltage MOSFETs, automotive CAN transceivers TLE7250G, TLE6251D, as well as step-down DC-DC controllers TLE6389-2GV and brand-new TLF35584.

Main switch

Typical part number	Product family	Description
IPx65RxxxCFDA	CoolMOS [™] CFDA	650 V SJ MOSFET with integrated fast body diode

Battery master

Typical part number	Description
TC23xL, TC26xD	32-bit AURIX™ lockstep microcontrollers
TLF35584 ¹⁾	ISO26262-system-supply optimized for AURIX™
TLE7250G	High-speed automotive CAN transceiver
TLE6251D	High-speed automotive CAN transceiver, with wake-up

Battery master

Typical part number	Description
XC886CM	8051-compatible 8-bit automotive microcontroller
TLE6389-2GV	Step-down DC-DC controller
TLE7250G	High-speed automotive CAN transceiver
IPG20N04S4L	OptiMOS™-T2 power transistor, logic level, dual, 40 V/8.2 mW
IPD70N03S4L	OptiMOS™-T2 power transistor, logic level, 30 V/4.3 mW
IPD70N10S3L	OptiMOS™-T2 power transistor, logic level, 100 V/11.5 mW



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1) In development

11

Packages



Audio amplifier

Class D audio solutions

Cooler, smaller and lighter amplifiers for great sounding audio products

Infineon's audio solutions enable audio designers to improve the performance of their products, while increasing efficiency and reducing solution size. Advances in semiconductor processes in combination with new innovative architectures are behind a portfolio of class D technologies that allow professional, commercial/home and portable audio applications to benefit from unparalleled performance, power density and reliability.



Infineon's advantage

Infineon offers a unique design platform with high-performance class D amplifier solutions for all power ranges and applications between 20 W and 2000 W per channel - from the smallest fully integrated single-chip solutions to highly scalable driver and discrete MOSFET combinations.

Integrated audio solutions

MERUS[™] integrated multilevel audio amplifier ICs for class D audio solutions

With the revolutionary multilevel class D audio amplifier ICs, Infineon is leading in efficiency and power density. Monolithic multilevel class D amplifier ICs give designers full flexibility to optimize audio systems for size, performance, and cost to meet critical design objectives in today's and tomorrow's audio applications. These applications include battery operated speakers, voice controlled active speakers, television sets, stereo HiFi, soundbars, monitors, power-over-ethernet (PoE) and multichannel systems.



Filterless topology with "flying capacitor" of an integrated class D IC

www.infineon.com/audiosolutions



MERUS[™] integrated audio amplifier multi-chip modules (MCM)

The integrated class D audio module family of devices integrates PWM controller and digital audio power MOSFETs in a single package to offer a highly efficient, compact solution that reduces component count, shrinks PCB size up to 70 percent and simplifies class D amplifier design.



Multi-chip audio amplifier module

Discrete audio solutions

MERUS[™] discrete audio amplifier driver ICs

Infineon's family of ICs developed specifically for class D audio applications enable audio system manufacturers to more efficiently design audio product with superior audio performance and higher reliability.

Recommended audio MOSFETs

Audio MOSFETs are specifically designed for class D audio amplifier applications. Key parameters, such as on-state resistance ($R_{DS(on)}$), gate charge (Q_G), and reverse recovery charge (Q_{rr}), are optimized for maximizing efficiency, THD and EMI amplifier performance.

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Integrated class D audio solution portfolio

MERUS[™] integrated multilevel audio amplifier IC portfolio

		MA12040	MA12040P	MA12070	MA12070P
Specifications	Number of audio channels	2xBTL/2xSE/1xPBTL	2xBTL/2xSE/1xPBTL	2xBTL/2xSE/1xPBTL	2xBTL/2xSE/1xPBTL
	Max. peak power @ 4 Ω 10% THD	2x40 W	2x40 W	2x80 W	2x80 W
	Supply voltage	4-18 V	4-18 V	4-26 V	4-26 V
	3-level and 5-level modulation	\checkmark	\checkmark	\checkmark	\checkmark
	Max. PWM frequency		726	kHz	
	Audio input	Analog	Digital	Analog	Digital
	Hi-Res audio compliant		\checkmark		\checkmark
	Volume and dynamic range control		\checkmark		\checkmark
	Idle power dissipation Max output and all channels switching	<100 mW	<110 mW	<160 mW	<160 mW
	Audio performance (PMP2)	>107 dB DNR 55 µV output noise 0.003% THD+N	>98 dB DNR 135 µV output noise 0.006% THD+N	>110 dB SNR 45 µV output integrated 0.004%THD+N	101 dB SNR 140 μV output noise 0.007% THD+N
Features	Comprehensive protection scheme*	\checkmark	\checkmark	\checkmark	\checkmark
	Configurable for SE or PBTL operation	\checkmark	\checkmark	\checkmark	\checkmark
	I ² C communication	\checkmark	\checkmark	\checkmark	\checkmark
	Filterless implementation	\checkmark	\checkmark	\checkmark	\checkmark
	Package type	64-pin QFN package with exposed thermal pad	64-pin QFN package with exposed thermal pad	64-pin QFN package with exposed thermal pad	64-pin QFN package with exposed thermal pad
	Evaluation boards	EVAL_AUDIO_MA12040	EVAL_AUDIO_MA12040P	EVAL_AUDIO_MA12070	EVAL_AUDIO_MA12070P

*All ICs carry a full protection scheme comprising undervoltage-lockout, overtemperature warning/error, short-circuit/overload protection, power stage pin-to-pin short-circuit, error-reporting through serial interface (I²C), DC protection.

MERUS[™] integrated audio amplifier multi-chip module (MCM) portfolio

		IR4301M	IR4321M	IR4311M	IR4302M	IR4322M	IR4312M
Specifications	Number of audio channels	1	1	1	2	2	2
	Max. power per channel	160 W	90 W	45 W	130 W	100 W	40 W
	Supply voltage	$\sim\pm31$ V or 62 V	~ ±25 V or 50 V	~ ±15 V or 30 V	~ ± 31 V or 62 V	~ ±25 V or 50 V	~ ±16 V or 32 V
	Max. PWM frequency	500 kHz	500 kHz	500 kHz	500 kHz	500 kHz	500 kHz
Features	Differential audio input	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	✓
	Over-current protection	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
	Integrated power MOSFET	(80 V)	(60 V)	(40 V)	(80 V)	(60 V)	(40 V)
	PWM controller	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	✓
	Thermal shutdown	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	✓
	Click noise reduction	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	✓
	Clip detection				\checkmark	√	✓
	Fault output				\checkmark	\checkmark	✓
	Package type	5 x 6 mm QFN	5 x 6 mm QFN	5 x 6 mm QFN	7 x 7 mm QFN	7 x 7 mm QFN	7 x 7 mm QFN
	Evaluation boards	IRAUDAMP12, IRAUDAMP19	IRAUDAMP21	IRAUDAMP15	IRAUDAMP16, IRAUDAMP17	IRAUDAMP22	IRAUDAMP18

Packages

Discrete class D audio solution portfolio

MERUS[™] discrete audio amplifier driver IC product portfolio

		IRS20965S	IRS20957S	IRS2092S	IRS2052M	IRS2093M	IRS2452AM
Specifications	Number of audio channels	1	1	1	2	4	2
	Max. power per channel	500 W	500 W	500 W	300 W	300 W	500 W
	Supply voltage	±100 V	±100 V	±100 V	±100 V	±100 V	±200 V
	Gate sink/source current	2.0/2.0 A	1.2/1.0 A	1.2/1.0 A	0.6/0.5 A	0.6/0.5 A	0.6/0.5 A
Features	Over-current protection	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
	Over-current flag	√					
	PWM input	\checkmark	\checkmark				
	Floating input	√	\checkmark	\checkmark	\checkmark	\checkmark	√
	Dead time		\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
	Protection control logic	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
	PWM controller			\checkmark	\checkmark	\checkmark	\checkmark
	Clip detection				\checkmark		
	Click noise reduction			\checkmark	\checkmark	\checkmark	\checkmark
	Temperature sensor input				\checkmark		\checkmark
	Thermal shutdown				\checkmark		
	Clock input				\checkmark		\checkmark
	Package type	16-pin SOIC narrow	16-pin SOIC narrow	16-pin SOIC narrow	MLPQ48	MLPQ48	MLPQ32
	Evaluation boards	-	IRAUDAMP4A, IRAUDAMP6	IRAUDAMP5, IRAUDAMP7S, IRAUDAMP7D, IRAUDAMP9	IRAUDAMP10	IRAUDAMP8	EVAL_IRAUDAMP23

Recommended audio MOSFET (through-hole) portfolio

Output power [W]	Recommended driver IC	Speaker resistance				
Output power [w]		2 Ω	4 Ω	8 Ω		
150	IRS2093S*	IRFB4019	IRFB4019	IRFI4020H		
200	IRS2052M*	IRFB5615	IRFB4019	IRFI4020H		
300	IRS2092S**	IRFB4228	IRFB4227	IRFB4229		
500	IRS20957S**	IRFB4228	IRFB4227	IRFB4229		
750		IRFB4227	IRFB4229			
1000		IRFP4668	IRFB4229 x 2			

Recommended audio MOSFET (DirectFET™) portfolio

	Recommended driver IC	Speaker resistance				
Output power [W]	Recommended unver iC	2 Ω	4 Ω	8 Ω		
150	IRS2093S*	IRF6645	IRF6665	IRF6775		
200	IRS2052M*	IRF6646	IRF6775	IRF6775		
300	IRS2092S**	IRF6644	IRF6775	IRF6785		
500	IRS20957S**	IRF6643	IRF6641			

Recommended CoolGaN[™] e-mode HEMTs portfolio

	CoolGaN 400 V	Recommended audio driver IC	
Package	PG-DSO-20-87 (top-side cooling)	HSOF-8-3 (TO-leadless)	
P _{max}	Up to 500 W Up to 200 W		IRS20957S
R _{DS(on) max.}	70 mΩ	70 mΩ	183209375
Part number	IGOT40R070D1	IGT40R070D1	

www.infineon.com/audiosolutions www.infineon.com/gan

www.innieon.com/gun

*IRS2093S works up to 150 W and IRS2052M works up to 300 W. ** IRS2092S and IRS20957S work with all power levels listed above. Applications



DC-DC enterprise power solution for data processing applications

Multiphase and point-of-load DC-DC solution

An industry leader in digital power management, Infineon delivers solutions for the next generation server, communication, storage and client computing applications. Infineon offers a complete portfolio, including digital PWM controllers, integrated power stages, integrated point-of-load (POL), MOSFET drivers, power blocks and discrete MOSFETs. These proven technologies offer full flexibility to our customers to optimize a complete system solution for space, performance, ease of design and cost to meet critical design goal objectives. In addition, our latest software tools help simplify design, shorten design cycles and improve time-to-market.



Benefit	Advantage
Best-in-class efficiency	Digital controller and power stage provide industry's best efficiency of more than 95 percent
Support all major VID interface and control schemes	Intel SVID, AMD SVI2, NVIDIA PWM VID, Parallel VID (up to 8-bit) , PMBus™ Rev1.3, AVS Bus (PMBus™ Rev1.3)
Complete system solution	A broad portfolio of fully integrated point-of-load, integrated power stage and digital controller solutions in addition to discrete drivers and MOSFETs offers full flexibility to optimize complete system solutions requiring 1 A to 300 A+, single output/single-phase to multiple output/multi-phase
Digital controller flexibility	The industry's benchmark full featured 8-phase, multiple output, flexible configuration digital controllers
Ease of design	GUI-based optimization and configuration significantly reduces design cycle time
Smallest solution size	High density packaging and unique control schemes enable reduced external component count and overall board space

20-300 V MOSFETs

Motor control ICs

Packages



Multiphase DC-DC system solution

Server	Server/storage		Powered ICs	Voltage		
Storage	Server-Intel/IBM/AMD/ARM		Constanting	VCCIO	V _{core}	
			Server chip set	VMCP	V _{mem}	
Consumer	High-end consumer			V _{core}		
U	High-end desktop Notebook Gaming	Graphic Industrial PC	PC chip set		Graphics	
Datacom	<u> </u>	nms		FPGAs (~0.5–3.3 V)	Networking SoCs and ASICs, FPGAs	
Telecom	Datacom Comms core	Telecom Base station	ASIC ASSP	ASICs (~1.0 V)	Multi-core processors	
···	SOHO SAN Edge access (macro + distributed) FPGA		ASSPs (~1.0 V)	Ethernet switch ICs		
				10-30 A single-phase (multi-rail)	>30 A multi-phase/rail	

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIV[™] sensors

DC-DC	

DC-DC enterprise power solution for data processing applications

Integrated point-of-load converters

Infineon's point-of-load converters integrate a PWM controller, driver and MOSFETs into a small PQFN package for ease of use. The patented PWM modulation scheme allows greater than 1 MHz switching frequencies to deliver ultracompact layouts and and the smallest bill of materials. A PMBus[™] interface is available for monitoring and control in systems that use advanced CPUs, ASICs and FPGAs.

Block diagram



Key features

- Input voltage range
 4.5-21 V
- Output current 1-35 A
- Operating temperature range of -40 to 125°C

Key benefits

- Integrated controller, driver, MOSFETs for small footprint
- High efficiency MOSFETs and thermally enhanced packages for operation without heat sinks



DC-DC IPOL portfolio

Digital interface IPOL

	I ² C PMBus™, telemetry, margin, faults, SVID PVID Digital control/configuration, telemetry and diagnostic						
Part number	Max. current [A]	Package size [mm]	Max. V _{in}	Max. f _{sw}	Distinctive features		
IR38064	35	5 x 7	21 V	1500 KHz	PMBus™		
IR38063	25	5 x 7	21 V	1500 KHz			
IR38062	15	5 x 7	21 V	1500 KHz			
IR38060	6	5 x 6	16 V	1500 KHz			
IR38163	30	5 x 7	16 V	1500 KHz	OptiMOS [™] 5, SVID + PMBus [™]		
IR38165	30	5 x 7	16 V	1500 KHz	OptiMOS™ 5, SVID		
IR38363	15	5 x 7	16 V	1500 KHz	OptiMOS [™] 5, SVID + PMBus [™]		
IR38365	15	5 x 7	16 V	1500 KHz	OptiMOS™ 5, SVID		
IR38263	30	5 x 7	16 V	1500 KHz	OptiMOS [™] 5, PVID + PMBus [™]		
IR38265	30	5 x 7	16 V	1500 KHz	OptiMOS™ 5, PVID		
IR38164	30	5 x 7	16 V	1500 KHz	OptiMOS [™] 5, SVID + PMBus [™] , enhanced Imon		
IRPS5401	4+4+2+2+0.5	7 x 7	14 V	1500 KHz	5 output PMIC, PMBus™		

Analog interface IPOL

	"Performace" voltage mode PWM Ultralow jitter and noise, high accuracy and low ripple						
Part number	Max. current [A]	Package size [mm]	Max. V _{in}	Max. f _{sw}	Distinctive features		
IR3883	3	3 x 3	14 V	800 KHz	Constant-on-time		
IR3823	3	3.5 x 3.5	21 V	1500 KHz	3 soft start		
IR3897	4	4 x 5	21 V	1500 KHz	DDR tracking and		
IR3898	6	4 x 5	21 V	1500 KHz	analog voltage margin/AVSO		
IR3899	9	4 x 5	21 V	1500 KHz	margini/A050		
IR3894	12	5 x 6	21 V	1500 KHz			
IR3895	16	5 x 6	21 V	1500 KHz			
IR3826	23	5 x 6	17 V	1500 KHz	OptiMOS™ 5, 3-level OCP		
IR3826A	16	5 x 6	17 V	1500 KHz	OptiMOS™ 5, 3-level OCP		
IR3448	16	5 x 6	21 V	1500 KHz	True differential		
IR3847	25	5 x 6	21 V	1500 KHz	remote sensing for accuracy and ther-		
IR3846	35	5 x 7	21 V	1500 KHz	mally enhanced Cu clip package		
IR3891	4+4	5 x 6	21 V	1500 KHz	Dual output for		
IR3892	6+6	5 x 6	21 V	1500 KHz	density and out-of-phase for less input capacitor		

Applications

20-300 V MOSFETs

Discrete IGBTs

www.infineon.com/dataprocessing



Packages

Industrial welding* High efficiency, easy design and cost competitive solutions

Discrete IGBTs are used in small inverterized single-phase handheld welders with current output from 120 to 200 A and three-phase industrial welding machines with current output up to 280 A. Infineon offers a wide product range to address key industry trends.

Price competitive 650 V TRENCHSTOP[™] 5 WR5 series has been specifically developed for the low power single-phase welding machine market. The TRENCHSTOP[™] 5 WR5 offers low switching losses coupled with low conduction losses to provide efficiency to customers and outstanding thermal performance.

For the best-in-class performance, where customers strive for differentiation, the 650 V TRENCHSTOP[™] 5 H5 series offers outstanding efficiency for optimized, low inductance designs.

The new high speed, soft switching 650 V TRENCHSTOP[™] 5 S5 series have soft and smooth switching behavior with no tail current, while keeping very competitive switching performance. The TRENCHSTOP[™] 5 S5 series can be used as plug-and-play replacement of previous generations of Infineon's IGBTs. The low V_{CE(sat)} 650 V TRENCHSTOP[™] 5 L5 series is an excellent solution for secondary inverter AC output welding machines used for aluminum (Al) or magnesium (Mg) welding.

For three-phase welding inverters, the 1200 V HighSpeed 3 family keeps leading market position in >20 kHz designs with best performance/cost trade-off and highest reliability. For medium switching frequency designs, 1200 V TRENCHSTOP[™] IGBT6 provides the best efficiency performance with a unique combination of low conduction losses of 1.85 V V_{CE(sat)} and the lowest switching losses.



Typical topologies for inverter welding machine < 280 A

*(MMA/TIG < 280 A)





Infineon's product recommendation for industrial welding

Stage		Topology	Voltage class	Technology/product family	Selection/benefit
PFC AC-DC		Boost converter/switch	650 V	TRENCHSTOP [™] 5 WR5	Cost/performace
		Boost converter/switch	650 V	TRENCHSTOP [™] 5 S5	Efficiency and ease of use
		Boost converter/switch	650 V	TRENCHSTOP [™] 5 H5	Best efficiency
		Boost converter/switch	1200 V	TRENCHSTOP™ IGBT6	Efficiency
		Low-side gate driver	25 V	Single low-side driver 1ED44176N01F	OCP, fault and enable function in DSO-8
		Low-side gate driver	25 V	Dual low-side driver IRS4427S	Rugged and reliable in DSO-8
		Low-side gate driver	25 V	Single low-side driver IRS44273L	Rugged and reliable in SOT23-5
Inverter	DC-DC	Two transistor forward	650 V	TRENCHSTOP [™] 5 WR5	Cost/performace
		Two transistor forward	650 V	Rapid 1 diode	Efficiency
		Full-bridge/half-bridge	650 V	TRENCHSTOP [™] 5 WR5	Cost/performace
		Full-bridge/half-bridge	650 V	TRENCHSTOP [™] 5 S5	Efficiency and ease of use
		Full-bridge/half-bridge	650 V	TRENCHSTOP [™] 5 H5	Best efficiency
		Full-bridge	1200 V	TRENCHSTOP™ IGBT6	Efficiency
	DC-AC	Al/Mg welding secondary inverter	650 V	TRENCHSTOP [™] 5 L5 Low V _{CE(sat)}	Efficiency
	DC-DC / DC-AC	Single high-side gate driver	1200 V	EiceDRIVER™ galvanic isolated 1EDI05I12AF	1 A output current, separate sink/source outputs
		Single high-side gate driver	1200 V	EiceDRIVER™ galvanic isolated 1EDI60N12AF	10 A output current, separate sink/source outputs
Secondary side	DC-DC	Output rectifier	650 V	Rapid 1 diode	Efficiency
rectification		Output rectifier	650 V	Rapid 1 diode – common cathode	Efficiency
Controller	Auxiliary	Flyback control	800 V	CoolSET™ F5	Recommendation
	power control	Boost converter	-	XMC1000	Flexibility
	Microcontroller supply	Linear voltage regulator	up to 20 V	IFX54211	Efficiency

www.infineon.com/welding

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

 \bigcap

20-300 V MOSFETs

500-950 V MOSFETs

LED lighting

Solutions for cost sensitive applications as well as for smart lighting

At Infineon, we focus on supplying tailored products for LED drivers, LED strips, horticultural, and smart lighting. Our broad portfolio of tailored products and solutions for LED lighting comprises LED driver ICs, MOSFETs, and microcontrollers suited for LED drivers as well sensors and dedicated ICs for secure communication. In addition to offering products of proven quality, a competent global lighting team supports our lighting customers in designing LED lighting products and systems in collaboration with our channel partners.

Key trends and challenges in LED lighting and our offering:

- Light quality and human-centric light
 - No current ripple by using two stage topologies (i.e. ICL5102, XDPL8221, XDPL8218, BCR601)
 - Easy implementation of tunable white with a lighting dedicated peripheral brightness and color control unit-BCCU (i.e. XMC1300)
- > Designing smaller and flatter LED drivers
 - Integrating up to 25 discrete components in one 0-10 V dimming interface IC (i.e. CDM10V)
 - High voltage SJ MOSFETs in small and cost-effective SOT-223 package
- > Smart lighting enabled by radar sensors
 - Reliable presence detection and large area coverage up to 300 m²
 - Integrated XENSIV™ 24 GHz radar transceiver eliminates the need on trimming and handling component tolerances
 - Ready-to-use module solutions with our radar partners (i.e. K -LD 2 from RF beam and INS-Serie from InnoSent), based on our XENSIV[™] radar sensor IC (BGT24LTR11)



LED drivers



Recommended LED driver products

Functional block	Product type	IC product family	MOSFET technology	Voltage class
PFC stage	PFC	IRS2505	CoolMOS™ P7	600/700/800/950 V ¹⁾
Main stage	PFC + LCC (constant current)	ICL5102 ²⁾	CoolMOS™ P7 (up to 600 mΩ)	600 V/650 V
	PFC + LLC (constant current)		CoolMOS [™] CE (above to 600 mΩ)	600 V
	PFC + flyback (dual stage)	XDPL8220 ³⁾ /XDPL8221 ²⁾	CoolMOS™ P7	800 V/950 V
	PFC/flyback (single-stage constant voltage)	XDPL8105	CoolMOS™ P7	800 V/950 V
	PFC/flyback (single-stage constant voltage)	XDPL8218	CoolMOS™ P7	800 V/950 V
Buck / linear solutions	Secondary buck (single-channel)	ILD6150 / ILD8150	Integrated	60 V/80 V
	Secondary buck (multichannel)	XMC1300 / XMC1400 1)	OptiMOS™	100 V/150 V/ 200 V/250 V/ 300 V
	Secondary linear	BCR601	OptiMOS™	75 V/100 V
Synchronous rectification	Synchronous rectification controller	IR1161 / IR11688	OptiMOS™	100 V/150 V/200 V
Dimming	0-10 V dimming interface IC	CDM10V	-	-
		CDM10VD	-	-
Hardware based security	OPTIGA™	OPTIGA [™] Trust	-	-
MCU	XMC [™] microcontroller	XMC1100	-	-
Sensors	XENSIV™ radar sensor IC	BGT24LTR11	-	-

LED driver with constant voltage output and linear/switch mode LED driver ICs



Linear/switch mode LED driver IC product portfolio

Functional block	Topology	IC product family	MOSFET technology	Voltage class
Linear LED driver IC	Linear	BCR400 series	Integrated (extra transistor for BCR450)	-
		BCR602	External N-channel MOSFET	75 V / 100 V
Switch mode LED driver IC	Buck	ILD6000 series	Integrated	-
		XMC1300/XMC1400*	OptiMOS™	100 V/150 V/200 V/250 V/ 300 V
	Buck/boost	ILD1151	OptiMOS™	60 V/100 V

* Including communication

Applications

Packages

1) 700 V, 800 V and 950 V CoolMOS[™] P7 are optimized for PFC and flyback topologies. 600 V CoolMOS[™] P7 is suitable for hard as well as soft switching topologies (flyback, PFC and LLC) 2) PFC and resonant combo controllers 3) PFC and flyback combo controllers

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs



Major home appliances

Product designers are facing the daunting challenge of delivering smaller, smarter, more powerful and more energy-efficient appliances. Based on industry-leading technology and manufacturing expertise, Infineon's line of innovative components for household appliances meets and exceeds even the most rigorous requirements for reliability and quality. The following block diagram example of an air conditioning system, together with the product selection table, provides effective recommendation for engineers selecting the right component for each power management stage inside major home appliances.



IGBT - PFC CCM (low frequency - SC) GOV TRENCHSTOP™ Performance Recommendation IGBT - PFC CCM (low losses - SC) GSU V TRENCHSTOP™ GBTG Recommendation IGBT - PFC CCM (low losses - SC) GSU V TRENCHSTOP™ GBTG Recommendation IGBT - PFC CCM (low losses - SC) GSU V TRENCHSTOP™ GBTG Recommendation IGBT - PFC CCM (cost competitive - no SC) GSU V TRENCHSTOP™ SWRS Recommendation IGBT - PFC CCM GSU V TRENCHSTOP™ SWRS Recommendation IGBT - PFC CCM GSU V TRENCHSTOP™ SWRS Recommendation IGBT - PFC CCM GSU V Rapid 1 and Rapid 2 diodes Recommendation Controller - PFC CCM 6SU V Rapid 1 and Rapid 2 diodes Recommendation IPM - PFC CCM 6SU V CIPOS™ Min IPFC interleaved IPM series Recommendation IDM - PFC CCM 2SV Single low-side driver IRS44273 Rugged and reliable in S02-8 IDM - PFC CCM 6SU V TRENCHSTOP™ IGBT6 Efficiency IDM - PFC CCM 6SU V TRENCHSTOP™ IGBT6 Efficiency IDW - Sic VSI	Functional block	Topology	Voltage class	Technology/product family	Selection/benefit
IGBT - PFC CCM (cost competitive - no SC) 650 V TRENCHSTOP™ 5-H5 Recommendation IGBT - PFC CCM (low losses - SC) 650 V TRENCHSTOP™ (GBT6 Recommendation IGBT - PFC CCM (low losses - SC) 650 V TRENCHSTOP™ dvanced Isolation Recommendation IGBT - PFC CCM (cost competitive - no SC) 650 V TRENCHSTOP™ 5 WR5 Recommendation IGBT - PFC CCM 600 V CoMOS™ PT Reference Diode - PFC CCM 650 V Rapid 1 and Rapid 2 diodes Recommendation IDM - PFC CCM - ICEPSCNS, ICESPCSNG Recommendation IDM - PFC CCM 25 V Single low-side driver IED44176N01F @SS OCP, fault and enable function IDM - BFC CCM 600 V RCDrives Fast	PFC AC-DC	IGBT – PFC CCM (high frequency – SC)	600 V	HighSpeed 3	Recommendation
IGBT - PFC CCM (low losses - SC) 650 V TRENCHSTOP" IGBT6 Recommendation IGBT - PFC 600 V TRENCHSTOP" Advanced Isolation Recommendation IGBT - PFC (cost competitive - no SC) 650 V TRENCHSTOP" SWR5 Recommendation IGBT - PFC (CCM 600 V Colloss" PT Reference Dide - PFC CCM 650 V Rapid 1 and Rapid 2 dides Recommendation Controller - PFC CCM 650 V Rapid 1 and Rapid 2 dides Recommendation Controller - PFC CCM - ICE2PCS0x6, ICE3PCS0x6 Recommendation Controller - PFC CCM - ICE2PCS0x6, ICE3PCS0x6 Recommendation IBM - PFC CCM 650 V CIPOS" Mini PFC integrated IPM series. Recommendation Low-side gate driver IC-PFC 25 V Single low-side driver IRS44275 Rugged and reliable in S073.5 BC-AC IBBT - B6-VSI 650 V TRENCHSTOP" IGBT6 Efficiency IGBT - B6-VSI 600 V RecDrives Fast Recommendation MOSFET - 86-VSI 600 V ColNOS" CE Cost/performance IPM - B6-VSI 600 V		IGBT – PFC CCM (low frequency – SC)	600 V	TRENCHSTOP [™] Performance	Recommendation
IGBT - PFC 600 V TRENCHSTOP [™] Advanced Isolation Recommendation IGBT - PFC (cost competitive - no SC) 650 V TRENCHSTOP [™] 5 WR5 Recommendation MOSFET - PFC (CCM 600 V CoolMOS [™] P7 Reference Diode - PFC CCM 650 V Rapid 1 and Rapid 2 diodes Recommendation Controller - PFC CCM - ICE2PC50KG, ICE3PC50KG Recommendation IPM - PFC CCM - ICE2PC50KG, ICE3PC50KG Recommendation IPM - PFC CCM 650 V CIPOS [™] Mini PFC interleaved IPM series, CIPOS [™] PFC integrated IPM series OCP, fault and enable function in DSO-8 Low-side gate driver IC-PFC 25 V Single low-side driver IRS44275 Rugged and reliable in DSO-8 DC-AC IGBT - B6-VSI 650 V RecOrrives Fast Recommendation MOSFET - B6-VSI 600 V ReCOrives Fast Recommendation MOSFET - B6-VSI 600 V ColMOS [™] CE Cost/performance IPM - B6-VSI 600 V CIPOS [™] Mini Recommendation MOSFET - B6-VSI 600 V ColMOS [™] CE Cost/performance IPM - B6-VSI		IGBT – PFC CCM (cost competitive – no SC)	650 V	TRENCHSTOP [™] 5-H5	Recommendation
IGBT - PFC (cost competitive - no SC) 650 V TRENCHSTOP"'S WR5 Recommendation MOSFET - PFC (CCM 600 V CoolMOS" P7 Reference Diode - PFC CCM 650 V Rapid 1 and Rapid 2 diodes Recommendation Controller - PFC CCM - ICE2PCS0KG, ICE3PCS0KG Recommendation IPM - PFC CCM - ICE2PCS0KG, ICE3PCS0KG Recommendation IDMOSET - Single low-side driver IPM series ClPOS" MINI PFC integrated IPM series Recommendation IDMOSET - Single low-side driver IRS4427S Rugged and reliable in DSO-8 Single low-side driver IRS4427S Rugged and reliable in SO-28 IDET - B6-VSI 600 V RCDrives Fast Recommendation Sol Vifoou V ColMONS" CE ColMOSTerper Control SO ColMorter ret Sod Sol Vifoou V Coo		IGBT – PFC CCM (low losses - SC)	650 V	TRENCHSTOP™ IGBT6	Recommendation
MOSFET - PFC CCM 600 V CoolMOS [™] P7 Reference Diode - PFC CCM 650 V Rapid 1 and Rapid 2 diodes Recommendation Controller - PFC CCM - ICE2PCSxG, ICE3PCS0xG Recommendation IPM - PFC CCM 550 V ICPOS [™] Mini PFC interleaved IPM series, CIPOS [™] Mini PFC interleaved IPM series Recommendation Low-side gate driver IC-PFC 25 V Single low-side driver IE041176N01F ITM OCP, fault and enable function in DSO-8 DC-AC IGBT - B6-VSI 650 V TRENCHSTOP™ IRS4427S Rugged and reliable in DSO-8 IGBT - B6-VSI 650 V RENOTINGEMENT Recommendation IGBT - B6-VSI 650 V RENCHSTOP™ IGBT6 Efficiency IGBT - B6-VSI 600 V RENOTINGEMENT Recommendation IGBT - B6-VSI 600 V ColNOS [™] CE Cost/performance IPM - B6-VSI 600 V CONVS [™] NINI Recommendation Half-bridge gate driver ICs 600 V 2ED2304S06F Instal Sol with integrated bootstrap diode/FI Half-bridge gate driver ICs 600 V 2ED105106FF, 2EDL23106PJ, IRS2890DS Integrated bootstrap diode/		IGBT – PFC	600 V	TRENCHSTOP [™] Advanced Isolation	Recommendation
Didde-PFC CCM 550 V Rapid 1 and Rapid 2 diodes Recommendation Controller - PFC CCM - ICE2PCS0x6, ICE3PCS0xG Recommendation IPM - PFC CCM 550 V CIPOS" Mini PFC interleaved IPM series, CIPOS" PFC integrated IPM series Recommendation Low-side gate driver IC-PFC 25 V Single low-side driver IE041176N01F Imm OCP, fault and enable function in DSO-8 Datal Constraint of the PFC CCM 25 V Single low-side driver IR544273 Rugged and reliable in DSO-8 Datal Constraint of the PFC PFC CFC 25 V Single low-side driver IR544273 Rugged and reliable in DSO-8 Data Constraint of the PFC PFC PFC 25 V Rugged and reliable in DSO-8 Rugged and reliable in DSO-8 Data Constraint of the PFC PFC PFC 25 V Single Constraint RS44273 Rugged and reliable in DSO-8 DFC PFC PFC PFC PFC PFC PFC 16BT - B6-VSI 650 V Recommendation Recommendation MOSPET - B6-VSI 500 V/600 V COMOST CE Cost/performance Sol with integrated bootstrap diode/FET IPM - B6-VSI 600 V 2EDI25106PF, ZEDI23106PJ, IRS2890DS Integrated bootstrap diode/FET IPM - B6-VSI 600 V<		IGBT – PFC (cost competitive - no SC)	650 V	TRENCHSTOP [™] 5 WR5	Recommendation
Controller - PFC CCM - ICE2PCS0x6, ICE3PCS0x6 Recommendation IPM - PFC CCM 650 V CIPOS [™] Mini PFC interleaved IPM series, CIPOS [™] PFC intergrated IPM series Recommendation Low-side gate driver IC-PFC 25 V Single low-side driver ID44176N01F item in D50-8 OCP, fault and enable function in D50-8 DCAC IGBT - B6-VSI 650 V TRENCHSTOP [™] IGBT6 Efficiency IGBT - B6-VSI 650 V ReCOTIVE FACTOR Recommendation MOSFET - B6-VSI 600 V R-Drives Fast Recommendation MOSFET - B6-VSI 600 V CIPOS [™] Mini Recommendation MOSFET - B6-VSI 600 V CIPOS [™] Mini Recommendation MOSFET - B6-VSI 600 V CIPOS [™] Mini Recommendation MoSFET - B6-VSI 600 V CIPOS [™] Mini Recommendation MoSFET - B6-VSI 600 V 2ED2304S06F Item Sol with integrated bootstrap diode/FET Micro ontroller Half-bridge gate driver ICS 600 V 6EDL04106PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V ColSET		MOSFET – PFC CCM	600 V	CoolMOS™ P7	Reference
IPM - PFC CCM 650 V CIPOS [™] Mini PFC interleaved IPM series, CIPOS [™] PFC interleaved IPM series, Recommendation Low-side gate driver IC-PFC 25 V Single low-side driver 1ED44176N01F ITSM OCP, fault and enable function in DSO-8 Dall low-side driver IRS44275 Rugged and reliable in DSO-8 Single low-side driver IRS44273 Rugged and reliable in SOT23-5 DC-AC IGBT - B6-VS1 650 V TRENCHSTOP [™] IGBT6 Efficiency IGBT - B6-VS1 600 V RC-Drives Fast Recommendation MOSFET - B6-VS1 500 V/600 V CoolMOS [™] CE Cost/performance IPM - B6-VS1 600 V RC-Drives Fast Recommendation MOSFET - B6-VS1 600 V ColMOS [™] CE Cost/performance IPM - B6-VS1 600 V 2ED2304S0F IEW SOI with integrated bootstrap diode/FET Half-bridge gate driver ICS 600 V 2ED123106PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICS 600 V CoolSIT [™] F5 Recommendation AUX Flyback fixed frequency 700 V CoolSIT [™] F5 Recommendation Microcontroller/motor control IC		Diode – PFC CCM	650 V	Rapid 1 and Rapid 2 diodes	Recommendation
Instrume Instrume CIPOS™ PFC integrated IPM series COPOS™ PFC integrated IPM series Low-side gate driver IC-PFC 25 V Single low-side driver IED4176N01F IEOD OCP, fault and enable function in DSO-8 DC-AC IGBT - 86-VSI 650 V TRENCHSTOP* IGBT6 Rugged and reliable in DSO-8 DC-AC IGBT - 86-VSI 650 V TRENCHSTOP* IGBT6 Efficiency MOSFET - 86-VSI 600 V RC-Drives Fast Recommendation IDM - 86-VSI 600 V CIPOS™ Mini Recommendation IPM - 86-VSI 600 V CIPOS™ Mini Recommendation IPM - 86-VSI 600 V 2ED105106FF, 2ED123106PJ, IRS2890DS Integrated bootstrap diode/FET IPM - 86-VSI 600 V 2EDL05106FF, 2ED123106PJ, IRS2890DS Integrated bootstrap diode/FET AUX Half-bridge gate driver ICs 600 V ColsET** F5 Recommendation Microcontroller/motor control IC More Phase gate driver ICs 600 V ColsET** F5 Recommendation Microcontroller/motor control IC Microcontrol IC Recommendation Recommendation Microcontrol IC		Controller – PFC CCM	-	ICE2PCS0xG, ICE3PCS0xG	Recommendation
Index of the original oriserecercerecerecercercercerecercerecercer		IPM – PFC CCM	650 V		Recommendation
Bote Bote <th< td=""><td></td><td>Low-side gate driver IC-PFC</td><td>25 V</td><td>Single low-side driver 1ED44176N01F</td><td>· · ·</td></th<>		Low-side gate driver IC-PFC	25 V	Single low-side driver 1ED44176N01F	· · ·
DC-AC IGBT - B6-VSI G50 V TRENCHSTOP™ IGBT6 Efficiency IGBT - B6-VSI 600 V RC-Drives Fast Recommendation MOSFET - B6-VSI 500 V/600 V CoolMOS™ CE Cost/performance IPM - B6-VSI 600 V CIPOS™ Mini Recommendation Half-bridge gate driver IC 600 V CIPOS™ Mini Recommendation Half-bridge gate driver ICs 600 V 2EDL05060FF, 2EDL23106PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICs 600 V 6EDL04106PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX1763, IFX54441, IFX54211, IFX3008 Efficiency Microcontroller supply Linear voltage regulator - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - IFX1050, IFX1051, IFX1040 Robustness				Dual low-side driver IRS4427S	Rugged and reliable in DSO-8
IGBT - B6-VSI 600 V RC-Drives Fast Recommendation MOSFET - B6-VSI 500 V/600 V CoolMOS™ CE Cost/performance IPM - B6-VSI 600 V CIPOS™ Mini Recommendation Half-bridge gate driver IC 600 V 2ED2304S06F NeW SOI with integrated bootstrap diode/FET Half-bridge gate driver ICs 600 V 2EDL05106PF, 2EDL23106PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICs 600 V 6EDL04106PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC MOTION™ 100 TOION™ IRMCxx motor control IC Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX1763, IFX54441, IFX54211, IFX3008 Efficiency Position sensing Angle sensor - IFX1050, IFX1051, IFX1040 Robustness				Single low-side driver IRS44273L	Rugged and reliable in SOT23-5
MOSFET - B6-VSI 500 V/600 V CoolMOS TM CE Cost/performance IPM - B6-VSI 600 V CIPOS TM Mini Recommendation Half-bridge gate driver IC 650 V 2ED2304S06F NEW SOI with integrated bootstrap diode Half-bridge gate driver ICs 600 V 2EDL05I06PF, 2EDL23I06PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICs 600 V 6EDL04I06PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET TM F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX163, IFX54441, IFX54211, IFX3008 Efficiency Microcontroller supply Linear voltage regulator - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - IFX1050, IFX10512B Recommendation	DC-AC	IGBT – B6-VSI	650 V	TRENCHSTOP™ IGBT6	Efficiency
IPM - B6-VSI 600 V CIPOS™ Mini Recommendation Half-bridge gate driver IC 500 V 2ED2304S06F KEWI SOI with integrated bootstrap diode Half-bridge gate driver ICs 600 V 2EDL05I06PF, 2EDL23I06PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICs 600 V 6EDL04I06PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-IM4 - XMC4100/XMC4200 Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX163, IFX54441, IFX54211, IFX3008 Efficiency Microcontroller supply Angle sensor - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - TLE5009, TLI5012B Recommendation		IGBT – B6-VSI	600 V	RC-Drives Fast	Recommendation
Half-bridge gate driver IC 650 V 2ED2304S06F INEX SOI with integrated bootstrap diode Half-bridge gate driver ICs 600 V 2EDL05106PF, 2EDL23106PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICs 600 V 6EDL04106PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IRMCxx motor control IC (incl. motion control algorithm) Efficiency Microcontroller supply Linear voltage regulator - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - IFX1050, IEX10512B Recommendation		MOSFET - B6-VSI	500 V/600 V	CoolMOS™ CE	Cost/performance
Interview Interview bootstrap diode Half-bridge gate driver ICs 600 V 2EDL05I06PF, 2EDL23I06PJ, IRS2890DS Integrated bootstrap diode/FET Three-phase gate driver ICs 600 V 6EDL04106PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX163, IFX54441, IFX54211, IFX3008 Efficiency Communication CAN transceiver - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - TLE5009, TLI5012B Recommendation		IPM – B6-VSI	600 V	CIPOS™ Mini	Recommendation
Three-phase gate driver ICs 600 V 6EDL04I06PT, IR2136S, 6ED003L06-F2 OCP, fault and enable function AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IRMCxx motor control IC (incl. motion control algorithm) Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX163, IFX54441, IFX54211, IFX3008 Efficiency Communication CAN transceiver - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - TLE5009, TLI5012B Recommendation		Half-bridge gate driver IC	650 V	2ED2304S06F NEW!	
AUX Flyback fixed frequency 700 V CoolSET™ F5 Recommendation Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation MiCrocontroller supply imOTION™ - RMCxx motor control IC (incl. motion control algorithm) Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX163, IFX54441, IFX54211, IFX3008 Efficiency Communication CAN transceiver - IFX1050, IFX1040 Robustness Position sensing Angle sensor - TLE5009, TLI5012B Recommendation		Half-bridge gate driver ICs	600 V	2EDL05I06PF, 2EDL23I06PJ, IRS2890DS	Integrated bootstrap diode/FET
Microcontroller/motor control IC 32-bit ARM® Cortex®-M4 - XMC4100/XMC4200 Recommendation Microcontroller supply iMOTION™ - IRMCxx motor control IC (incl. motion control algorithm) Recommendation Microcontroller supply Linear voltage regulator Up to 20 V IFX1763, IFX54441, IFX54211, IFX3008 Efficiency Communication CAN transceiver - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - TLE5009, TLI5012B Recommendation		Three-phase gate driver ICs	600 V	6EDL04I06PT, IR2136S, 6ED003L06-F2	OCP, fault and enable function
iMOTION™-IRMCxx motor control IC (incl. motion control algorithm)RecommendationMicrocontroller supplyLinear voltage regulatorUp to 20 VIFX1763, IFX54441, IFX54211, IFX3008EfficiencyCommunicationCAN transceiver-IFX1050, IFX1051, IFX1040RobustnessPosition sensingAngle sensor-TLE5009, TLI5012BRecommendation	AUX	Flyback fixed frequency	700 V	CoolSET™ F5	Recommendation
Image: supply Image: s	Microcontroller/motor control IC	32-bit ARM [®] Cortex [®] -M4	-	XMC4100/XMC4200	Recommendation
Communication CAN transceiver - IFX1050, IFX1051, IFX1040 Robustness Position sensing Angle sensor - TLE5009, TLI5012B Recommendation		iMOTION™	-		Recommendation
Position sensing Angle sensor - TLE5009, TLI5012B Recommendation	Microcontroller supply	Linear voltage regulator	Up to 20 V	IFX1763, IFX54441, IFX54211, IFX3008	Efficiency
	Communication	CAN transceiver	-	IFX1050, IFX1051, IFX1040	Robustness
Hall switch - TLI496x Recommendation	Position sensing	Angle sensor	-	TLE5009, TLI5012B	Recommendation
		Hall switch	-	TLI496x	Recommendation

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Motor control ICs

XENSIVTM sensors

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



Major home appliance

Highest performance and efficiency for induction cooking

Resonant-switching applications such as induction cooktops and inverterized microwave ovens have unique system requirements. The consumer marketplace demands them to be cost-effective, energy efficient and reliable. To achieve these goals, designers need solutions that are developed specifically for these applications.

Infineon's RC discrete IGBTs were developed for resonant switching with a monolithically integrated reverse conducting diode. With this technology leadership and a broad portfolio of devices from 650 to 1600 V, Infineon is the market leader and provides the industry benchmark performance in terms of switching and conduction losses.

The latest RC-H5 family, previously offered with blocking voltage of 1200 V and 1350 V in a wide current range from 20 to 40 A, is now completed with the addition of a new 30 A 1600 V IGBT.

The TRENCHSTOP[™] Feature IGBT protected series (protected IGBT) is a new device in the IGBT portfolio for induction heating application, which adds new functionality to standard discrete IGBTs. The innovative protected IGBT combines a 20 A 1350 V IGBT in RC-H5 technology with a unique protecting gate driver IC in a TO-247 6-pin package.

The RC-E family is cost- and feature-optimized specifically for low- to mid-range induction cookers and other resonant applications. This new family offers Infineon's proven quality in RC IGBTs with the best price-performance ratio and ease of use. Infineon also offers a range of complementary products, such as low-side gate drivers and high voltage level-shift gate drivers which can be used with the IGBTs, as well as in the central control and power supply subsystems of induction cooking appliances.

Induction heating inverter (current resonance) Half-bridge



Induction heating inverter (voltage resonance) Single switch



Induction heating	Topology	Voltage class	Technology/product family	Selection/benefit
DC-AC	Series-resonant half-bridge	650 V	RC-H5	Recommendation
	Quasi-resonant single switch	1100 V	RC-H3	Recommendation
	Quasi-resonant single switch	1200 V	RC-H5, RC-E	Recommendation
	Quasi-resonant single switch	1350 V	RC-H5	Recommendation
	Quasi-resonant single switch	1600 V	RC-H2	Recommendation
	Quasi-resonant single switch and protective driver	1350 V	RC-H5/protected IGBT	Recommendation
Gate driver ICs	Single low-side gate driver	25 V	1ED44176N01F, IRS44273L	1ED integrated with OPC, fault and enable functions
	Half-bridge gate driver	650 V	2ED2304S06F	SOI with integrated bootstrap diode
	Single high-side gate driver	1200 V	1EDI40I12AF, 1EDI30I12MF	Galvanic isolation, separate sink/source output
Microcontroller	32-bit ARM [®] Cortex [®] -M0	-	XMC1302	Recommendation
Microcontroller supply	Linear voltage regulator	Up to 20 V	IFX54211	Efficiency
AUX	Fixed-frequency flyback	700 V	CoolSET™ F5	Recommendation

www.infineon.com/homeappliance



Multicopter

Multicopter

Reliable and cost-effective solutions to support future design trends

Initially regarded as toys, multicopters are now serious business. From FPV drone racing to the observation of remote places or even future delivery solutions, entire businesses are emerging around the design, supply, and the use of multicopters. The major differentiator between toy drones and professional multicopters is the complexity of the control system. In professional applications, multicopters must provide a useful function on top of mere flying. Most often, this is a vision system that requires video processing, gimbal control, and other functionalities which are integrated into the control system. With great development progress in the field of data processing, navigation and control, the overall system performance is determined from reliable and efficient power management.

Multicopter solutions from Infineon

Infineon's comprehensive portfolio of high quality products allows designers to rapidly design, develop, and deploy systems that address the ever more demanding needs of today's customers. We offer a near system solution – everything from XMC[™] microcontrollers, to iMOTION[™] motor control ICs, to magnetic sensors and many other cutting-edge technologies – with the exception of one commodity, an IMU (inertial measurement unit) for existing solutions. In the very fast growing multicopter market, energy efficiency and reliability are becoming more important. Camera applications, autonomous flying and sophisticated onboard equipment are pushing the limits of power management and reliability. With increased adoption comes increased regulation and the multicopter itself needs to be capable of being piloted in a safe and well-controlled manner. Being a recognized leader in automotive and industrial power electronic systems, Infineon offers high quality system solutions for the next generation of multicopters and enables customers to achieve a higher degree of innovation and differentiation.



Overview of the main electronic subsystems of a typical multicopter design

www.infineon.com/multicopter

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Benefits	Offer
Development effort and cost reduction	> With no or little experience in motor control, customers can implement the iMOTION™ motor control IC and take flight
	> Project development can be reduced up to 30 percent by using reference designs and the DAVE [™] platform for microcontroller programming
Authentication	Infineon's solutions enable authentication of components connected to the system
	Guaranteed safety and protection of the product, avoiding liability
Ease-of-precision control for	> Through the benefits of multifunction sensors, the user can experience an easy, stable, smooth and accurate control of the multicopter
flight and data	Closed loop control of gimbal motor, sensors enhanced camera stability and data transmission when recording video
Longer flight times	> The highly efficient components and effective flight control can make the multicopter lighter, which results in longer flight time
Collision avoidance	XENSIV [™] 24 GHz radar sensors have the capability of detecting the proximity of objects such as trees, buildings, etc.
Altitude stabilization	> The miniaturized digital barometric air pressure sensors based on capacitive technology guarantee high precision during temperature changes
Broader portfolio	> Infineon can provide all the necessary critical semiconductor components for multicopters
Fast time-to-market	> A complete eco-system of simulations, documentation and demoboard solutions enables a faster time-to-market

Infineon offers a comprehensive portfolio to address a broad range of multicopters.

Find more information at www.infineon.com/multicopter

Solution tree for multicopters

	Flight control						ESC	
	Microcontroller	Sensor	DC-DC module	LDO	Low noise amplifer(LNA)	Microcontroller	Sensor	Intelligent power module
>	XMC4000 family XMC1000 family AURIX™	 > XENSIV[™] pressure sensor: DPS310 > XENSIV[™] 24 GHz radar sensor: BGT24MR > Current sensor: TLI4970 	 > IFX90121ELV50 > IFX91041EJV33 > IFX91041EJV50 	 > IFX1117ME > IFX54441EJV > IFX1763XEJV33 	 LTE: BGA7H, BGA7M, BGA7L GPS: BGA524N6, BGA824N6 Wi-Fi: BFP842ESD, BFR840L3RHESD, BFR843L3, etc. 	 > XMC1300 family > iMOTION[™] IRMCK099 > ePOWER: TLE987x 	 Hall sensor: TLI4961, TLV4961 Angle sensor: TLI5012B, TLE5009 	 IRSM005-800MH IRSM836-084MA

Security	Accessory authentication	Joystick	Interface protection diode	LED driver	MOSFET gate driver	Dual n-channel power MOSFETs	Low voltage MOSFETs
 > OPTIGA™ Trust E SLS 32AIA > OPTIGA™ Trust P SLJ 52ACA > OPTIGA™ TPM SLB 96XX 	 > OPTIGA™ Trust > SLS 10ERE > OPTIGA™ Trust B SLE 95250 > OPTIGA™ Trust X SLS 32AIA 	 3D magnetic sensor: TLV493D 	> ESD102 series	 > BCR450 > BCR321U > BCR421U 	 IRS2301S 6EDL04N02P IRS23365 PX3517 	 IR3742, etc. BSC0925ND, etc. 	 > OptiMOS[™] 5 series > StrongIRFET[™] series

Charger			Battery management		
High voltage MOSFETs	Low voltage MOSFETs	Stand alone PWM controller	Authentication ICs	Cell balancing	Low voltage MOSFETs
> 600 V CoolMOS™ P7*	 > 40-80 V OptiMOS[™] 5 in TO-220, SuperSO8 > 40-75 V StrongIRFET[™] 	> ICE2QS03G	> OPTIGA™ Trust B SLE95250	 > 30 V OptiMOS[™] in SSO8, S308, DirectFET[™] > 30 V StrongIRFET[™] 	 > OptiMOS[™] 5 in SuperSO8, S3O8, DirectFET[™] > 40-80 V StrongIRFET[™]

			Gimbal control			
Microcontrollers	Angle sensor	LDO	CAN transceiver	Low voltage MOSFETs	Dual n-channel power MOSFETs	MOSFET gate driver
> XMC1400 family	> TLI5012B > TLE5009	 > IFX1117ME > IFX54441EJV > IFX1763XEJV33 	> HS CAN IFX1050G> IFX1050GVIO	 25-30 V OptiMOS[™] 5 25-30 V StrongIRFET[™] 	> IRFHM8363TRPBF, etc.	> IR2101STRPBF, etc.

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* If the necessary package/R_{DSIon} combination is not available in the new CoolMOS[™] P7 series yet, the previous CoolMOS[™] CE and P6 series are the preferred series

Packages

Smart Home

Smart home Smartifying homes the secured way

How does a smart home differ from a regular home? A smart home is equipped with technologies that make our lives more convenient and energy efficient. Today, the growing range of technologies encompasses smart home appliances, mobile devices and home automation systems, many of which are interconnected. But being 'smart' in this sense requires appliances and systems fitted with the right semiconductor solutions. They empower smart appliances, devices and systems to make sense of their environment and current situation. Working together, sensors, controllers and actuators enable members of a smart home to properly collect, interpret and process real-time data, then trigger the appropriate action or response. In an age of mounting security threats, security solutions keep all activities and system secured and out of harm's way.

From intelligent lighting control to optimized energy consumption, each smart home function depends on intelligent semiconductors. As this rapidly changing field continues to evolve and mature, having a reputable and reliable partner in smart home semiconductor technologies such as Infineon makes all the difference.



Benefit from our smart home expertise

Unparalleled system knowledge	Our in-depth system know-how coupled with our market expertice means you get application specific solutions that are best in class
Lasting reliability	With a proven track record, our high-quality products help keep our customers' business uncertainty at a minimum.
Easy-to-integrate solutions	We enable you to reduce your time-to-market thanks to easy-to-integrate products and a strong global support team for your designs.

www.infineon.com/smarthome



Infineon's leading portfolio of best-fit, ready-to-use semiconductor solutions empowers you to create innovative smart home applications that meet both current and future demands. You can count on our components to be smart, secured and energy efficient. In our one-stop shop, you will find all components and solutions required for your project. Furthermore, our products are easy to integrate into your designs.

As you forge new, unexplored territory in the smart home realm, our in-depth know-how of our components and their potential in smart homes and home automation systems enable us to support you through and through. At the cutting-edge of key smart home technologies, we are in the position to guide you through this exciting new market while you explore new opportunities and business models. Especially those new to smart homes will appreciate our easy-to-use smart home demo and our basic offering of solutions.

How Infineon's offering enhances your project

Advanced $(((\bullet))$ sensing

Contextual sensitivity with market-leading accuracy and reliability. For more natural, seamless interaction between humans, machines and the surroundings.



The right, easy to implement security solutions for smart, always secured homes. We meet your design's evolving security needs without compromising on convenience.



Ensure optimized system performance thanks to our deep system understanding and strong processing and steering know-how. The result: an excellent user experience.

Efficient power management

Our innovative power electronics technologies allow users to save energy and run applications at a market-leading low energy level. It's the basis for real green smart homes.

29

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



Enabling secured communication for IoT OPTIGATM Trust product family

An increasingly connected world enables new services and features leading to new business models. For these services, high system reliability and data integrity are key necessities. The Internet of Things generates an increased amount of data due to the proliferation of sensors and actuators that have become available at an attractive cost.

Intelligent lighting systems represent one of the leading applications that enable collection of information that goes beyond pure lighting functionality. Lighting systems manufacturers are looking into implementing new functions to their customers such as:

- > advanced presence detection including people counting
- > sound detection
- > pressure and environmental sensing

Collection and processing of that data targets to increase customer value in smart buildings and smart cities. Proliferation of interconnected nodes poses serious challenge in terms of ensuring that the IoT does not offer backdoors to cybercrimes. Infineon offers several products that build an "anchor of trust" in order to ensure secure data communication with the OPTIGA™ Trust product family. In a connected world, the performance and security of the smart IoT systems can be continuously improved by firmware updates. As an example, a radar system that fulfills a presence detection function in office meeting rooms might be enhanced by software update to count people in meeting rooms in order to optimize the usage of assets, in this case meeting rooms. The implementation of this firmware update in a secure manner is fundamental. The update may need to be authenticated to verify its source and the authenticity of the file or may be sent encrypted to protect the know how included in the update. To do so and prevent unauthorized firmware updates, these can be sent with a cryptographic signature as encrypted files allowing the receiving system to verify and decrypt the update before installing it. With Infineon's OPTIGA™ Trust product family, the keys used for the signature and encryption are stored in the hardware-based OPTIGA™ security solution, and therefore cannot be easily read out or altered.

Application flow for secure software update



Key benefits of OPTIGA[™] security

Combining state-of-the-art hardware security controllers with software

- > Reliable turnkey products with a proven track record
- > Strong security based on the latest cryptography
- Offering a variety of interfaces to match your system architecture
- Easy to integrate based on evaluation kits, host code and reference applets
- > Developed and manufactured in certified environment

www.infineon.com/optiga

Applications

Industrial robotics

Robotics

Superior solutions for industrial and service robotics

Disruptive technologies have significantly changed our lifestyle in the past few decades. Now a new era is on the horizon – the age of robots. Robots are joining the ranks of innovative and disruptive technologies by revolutionizing traditional habits and processes. Today's robots are able to identify and navigate their surroundings, work alongside and even interact with humans and they teach themselves the skills required to complete a new task.

All this would not be possible without semiconductor solutions. Whether in an industrial robot, a cobot, an automated guided vehicle (AGV) or a service robot, intelligent semiconductors are the key enabler for all major robotic functions. Drawing on our insight into all facets of the robotics field, and with a comprehensive portfolio of power products and sensors on offer, we are able to provide reliable system solutions that address the latest trends in robotics like artificial intelligence, the Internet of Things, smart home, cloud based services, human machine interface etc., and add value to nearly every robot design.

Industrial robots - achieve greater productivity and optimize costs



Structural system overview: industrial robot

In the era of Industry 4.0 and smart factories, the latest generation of industrial robots is revolutionizing traditional manufacturing processes, thus creating the benefits for manufactures worldwide, such as increased productivity and enhanced cost optimization. Regardless of the robot's size, number of axes and payload, Infineon's wide product portfolio has the right solution for nearly any industrial robot design.

Cobots – advance through collaboration

Cobots, or collaborative robots, work outside the limitation of a safety cell, in a direct interaction with real people. This setup requires a precise set of design features, especially for the sake of workplace safety. With Infineon's semiconductors for cobot systems, you benefit from the expertise of an experienced and reliable partner. Our radar and sensor solutions, for example, provide the tools to uphold even the highest safety standards and allow the robots to leave their formerly fenced working environment.

www.infineon.com/robotics www.infineon.com/industrial-robotics

Automated guided vehicles – driving production and logistics forward

Structural system overview: battery-powered AGV



Automated guided vehicles (AGVs) are a self-driving force behind automated manufacturing processes. Battery-powered systems offer the highest degree of flexibility within working environment. Covering the entire product portfolio of robotics applications – from the power supply to motor drives and sensors for navigation and environment scanning – Infineon is equipped to ensure AGVs can find their way through nearly all production environments.

Service robots - simplifying everyday life and work

Structural system overview: service robot



The latest generation of service robots is ushering in a new level of assistance and simplicity in homes and professional environments. They directly interact with humans, which introduces unique challenges from a design perspective, especially in domestic environments. Energy efficiency and long battery life as well as security aspects and sensing capabilities are key to user-friendly and safe designs. By choosing Infineon, you get a one-stop semiconductor shop for all

your service robot design needs.

How our offering enhances your project

At Infineon you will find ready-to-use semiconductor solutions out of one hand. Our well-thought-out products, combined with our deep know-how and proven experience, enable you to take your robotics project to the next level. By providing everything from reliable chargers and efficient power plus battery management, to compact motor control and indispensable sensors, to unrivalled hardware-based security solutions, our portfolio of leading semiconductor solutions covers everything you need to leverage the full potential of any robotic system.

www.infineon.com/robotics www.infineon.com/service-robotics

500-950 V MOSFETs 20-300 V MOSFETs

Discrete IGBTs

Motor control ICs

Infineon's key enabling products for robotics

Functional block	Purpose	Characteristics	Component Type or Family
Power:	Power switches	25-150 V	OptiMOS™
Power supply	(0.4-6 kW output power)	20-75 V	StrongIRFET™
Power factor correction (PFC) Charger		P-/N-channel -60 to 20 V	Small signal MOSFETs
Battery management		600-800 V	CoolMOS™ P7
succes y management		600 V	CoolMOS™ C7
		600 V	CoolMOS™ CFD7
		600 V	CoolGaN™
		600 V	IGBT HighSpeed 5
	PFC power diodes	650 V Schottky diode	CoolSiC™
	Integrated power stage	800 V	CoolSET™
	Gate driver ICs	12-100 V	IRS2000x
		12-1200 V, non-isolated	EiceDRIVER [™] 1EDN/2EDN
		12-1200 V, functional/safe isolation	EiceDRIVER [™] 1EDI/2ED/2EDF/2EDS
		12-1200 V, three-phase	EiceDRIVER™ 6ED, 6EDL
	Microcontroller	ARM [®] Cortex [®] -M0 microcontroller	XMC1100/XMC1300
		ARM [®] Cortex [®] -M4 microcontroller	XMC4200
	Voltage regulators	LDO and DCDC switching regulators	e.g. IFX1763, IFX90121
	Battery authentication	Hardware-based, embedded security	OPTIGA™ Trust B
otor control	Motor inverter power switches	<12 V, <400 W	PROFET TM
	Motor inverter power switches	20-60 V	
			StrongIRFET™
		60 V	SIPMOS™
		25-100 V, <1kW	OptiMOS™
		P-/N-channel MOSFETs ranging from -60 V to 20 V	Small signal MOSFETs
		600 V, <500 W	CoolMOS™ CFD7
		650 V, <500 W	CoolMOS [™] CFD2
		600/1200 V, <10 kW	TRENCHSTOP™
		1200 V, 10-20 kW	CoolSiC™
		Fully integrated, 600 V, 0.5-5 kW	CIPOS™
		Fully integrated, 600 V, <20 kW	EasyPIM™
		Fully integrated, 1200 V, 10-20 kW	CoolSiC™ Easy1B
	Gate driver ICs	12-100 V	IRS2000x
		12-1200 V, non-isolated	EiceDRIVER [™] 1EDN/2EDN
		12-1200 V, functional/safe isolation	EiceDRIVER [™] 1EDI/2ED/2EDF/2EDS
	Microcontroller	12-1200 V, three-phase	EiceDRIVER™ 6ED, 6EDL
		Integrated gate driver ICs	NovalithIC™
		Automotive embedded power ICs	TLE986x, TLE987x
		ARM [®] Cortex [®] -M0 microcontroller	XMC1000 microcontroller family
		ARM® Cortex®-M4 microcontroller	XMC4000 microcontroller family
		TriCore™ Safety certified security on-chip	AURIX™
		Fully integrated motor control ICs	iMOTION™
	Position & condition sensing	XENSIV [™] magnetic Hall switches	TLx496x
		XENSIV magnetic natiswitches XENSIV™ angle sensor, digital I/F	TLK490X TLE/TLI5012B, TLE5014SP
		XENSIV [™] angle sensor, analog I/F	
ancing:	_	XENSIV [™] angle sensor, analog I/F XENSIV [™] 3D magnetic sensor, digital I/F	TLE5009/5109/5309/5501 TLV/TLE/TLI493D
e nsing: Robot sensing			
nvironment sensing		XENSIV™ current sensor, digital I/F	TLI 4970
luman machine interface		XENSIV [™] current sensor, analog I/F	TLI4971
	Object & condition sensing	XENSIV [™] pressure/temperature sensor, digital I/F	DPS310
		XENSIV™ 24 GHz radar	BGT24MTR11/12, BGT24MR2
		XENSIV™ MEMS microphone, analog I/F	IM69D120/IM69D130
		XENSIV™ ToF 3D imaging @ 38-100k pixel	REAL3 [™] IRS1125C/IRS1645C/IRS2381C
eripherals:	Audio	Class D audio amplifier	IR43x1M, IR43x2M
/LAN/BT/GPS	Interface	CAN, CAN FD, CAN PD @ 1-5 MBit/s	Industrial CAN transceiver
uman machine interface		Industrial interface ICs	ISOFACE™
	LED drivers	Driving currents from 10-250 mA	Linear dirver ICs BCR3xx, BCR4xx
		Support currents from 150 mA to 3A	DCDC switch mode ILD4xxx, ILD6xxx
ecurity and safety	Controller	TriCore [™] Safety certified with security on-chip	AURIX™
Notion controller (incl. safety)	Sensors	Safe angle sensing - dual die structure	e.g. TLE5009xxxD
Security controller	Voltage regulators	DCDC voltage regulator 12 V/ 5V or 3.3 V; watchdog, error monitoring, safe state control, BIST etc.	e.g. TLF35584
	Security	Hardware-based, embedded security solutions, mutual authentication, secure communication, key protection, data signing etc.	OPTIGA™ TPM/Trust B/Trust X

For the complete portfolio, visit our website.

www.infineon.com/robotics

20-300 V MOSFETs

Packages

SMPS Right-fit portfolio for competitive design of laptop adapters

Manufacturing slimmer and lighter adapters requires ICs enabling high efficiency with good electromagnetic interference (EMI) performance and low standby power. There is also a need for cost-effective MOSFETs in small packages that feature good EMI and excellent thermal performance. Infineon offers a wide range of products specifically designed for adapters including high voltage MOSFETs and control ICs for PFC and PWM stages, as well as low voltage MOSFETs for synchronous rectification. With these products, Infineon supports the trend towards a significantly higher efficiency level, especially in partial load conditions, as well as miniaturization of the adapter.

Extremely versatile are the recently released CoolMOS[™] P7 SJ MOSFET series series, which combine high efficiency and optimized cost with the ease of use. Infineon developed a family of packages, characterized by having a short lead, IPAK Short Lead with ISO-Standoff and wide creepage that enable our customers' cheap and reliable manufacturing, specifically for adapters. High power density at low manufacturing cost can be delivered using Infineon's SOT-223 cost-effective package which enables SMT manufacturing, while maintaining very good thermal performances. For synchronous rectification, Infineon's OptiMOS[™] power MOSFET series offer extremely low on-state resistance and low capacitances.

New control ICs support topologies such as quasi-resonant flyback, and digital-based XDP controller can enable the forced frequency resonant flyback (zero voltage switching) operation, making it ideal to implement in high power density adapters and supporting USB-PD requirements.

Regional regulations and a general increased sensitivity toward the containment of electronic waste are pointing toward the adoption of universal adapters. The implementations, methodologies and protocols are not yet harmonized; however, Infineon is already closely monitoring and partnering with the decision makers to timely ensure the offer of a competitive semiconductor solution. The capability to efficiently manage different power classes and protocols are key in this application, and Infineon is getting ready to support adapter makers in this challenge.

Functional block	Product category	Topology	Product family	Benefits
Flyback converter	High voltage MOSFETs and HEMTs	Flyback	600 V/700 V/800 V CoolMOS™ P7 SJ MOSFETs	 Fast-switching speed for improved efficiency and thermals Reduced gate charge for enhanced light load efficiency Optimized gate-to-source voltage (V_{cs}) threshold for lower turn-off losses
		Flyback (ACF, FFR, etc.)	CoolGaN™ 600 V e-mode HEMTs	 > Highest efficiency > Highest power density
	Low voltage MOSFETs	Flyback/auxiliary synchronous rectification	OptiMOS™ 100-150 V	 Low conduction losses and reduced overshoot Logic level can support low voltage gate drive to achieve high efficiency
	Control ICs	QR flyback IC	ICE2QS03G, ICE5QSAG	High efficiency and low standby power
		FFR flyback IC	IDP2105, XDPS21061	 High power density and digital control
PFC	High voltage MOSFETs, HEMTs, and diodes	DCM PFC	600 V CoolMOS™ P7 SJ MOSFETs	 Fast-switching speed for improved efficiency Reduced gate charge for enhanced light load efficiency Optimized gate-to-source voltage (V_{cs}) threshold for lower turn-off losses
		DCM/CCM PFC	CoolGaN™ 600 V e-mode HEMTs	 > Highest efficiency contribution via less parasitic parameter > Space saving with SMD smaller package
	Boost diode	DCM/PFC	650 V Rapid 1 diodes	Low conduction losses
	Control ICs	DCM PFC ICs	TDA4863G, IRS2505LTRPBF	 Simple external circuitry High power factor and low THD
Main stage	High voltage MOSFETs and HEMTs	HBLLC	600 V CoolMOS™ P7 SJ MOSFETs	 Fast-switching speed for improved efficiency and thermals Reduced gate charge for enhanced light load efficiency Optimized gate-to-source voltage (V_{cs}) threshold for lower turn-off losses
			CoolGaN™ 600 V e-mode HEMTs	 > Highest efficiency > Highest power density
Synchronous rectification	Low voltage MOSFETs	Synchronous rectification	OptiMOS™ 5 100-150 V	 Low conduction losses, reduced overshoot Logic level switching
	Control ICs	Synchronous rectification	IR1161LTRPBF	 > High efficiency > Simple external circuitry

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Travelling with multiple and often clunky chargers and adapters for phones, tablets and laptops has been a nuisance for many consumers, and often leads to frustrations due to the additional weight and required space. Over the past years manufacturers of chargers and adapters became increasingly aware of these issues and a trend towards higher power density and consequently smaller devices has emerged. Today, the typical power topology used in such systems is a flyback power conversion topology and the form factor is limited by the efficiency achievable at 90 V_{AC} input voltage and full load. The highest power density systems available today reach ~12 W/in³ (for 65 W maximum output power). Infineon's CoolGaN[™] e-mode HEMTs enable a breakthrough with respect to power density for adapter and charger systems enabling ~20 W/in³ power density systems (for 65 W maximum output power). This advantage can be realized by implementing Infineon's CoolGaN[™] in a half-bridge topology that allows increasing switching frequency and efficiency simultaneously.



Infineon's 20 W/in³ adapter (cased) -24 W/in³ (uncased) with 65 W output power capability (LxWxH: 74.2 mm x 36.5 mm x 16.5 mm)

Motor control ICs

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Packages

Charger Best solutions for mobile charger

Modern mobile devices require a charger that provides faster charging but comes in a small size. High power density and cost-effective power supplies can be designed by operating the converter at a higher switching frequency to avoid a considerable increase in the transformer and the output capacitor size. In achieving the required thermal performance and EMI behavior, power devices with lower losses and controlled switching behavior enable effective and fast product development.

Infineon's state-of-the-art digital-based controller XDPS21061 enables the forced frequency resonant flyback (zero voltage switching) operation, ideal to implement in high power density adapters and well-supporting USB-PD requirements.

To address these requirements, Infineon offers its CoolMOS[™] P7 SJ MOSFET family for adapters and chargers. Special care has been taken to ensure very good thermal behavior, increased efficiency and fulfillment of all EMI requirements, enabling our customers to easily design products based on this new family. In addition, power devices in IPAK/SMD packages enable optimal PCB layout through minimal footprint. SMD packages offer additional benefits for automatized large volume production. Specifically, high power density at low manufacturing cost can be delivered using Infineon's SOT-223 cost-effective package, which enables SMT manufacturing maintaining very good thermal performances.

The digital soft switching controller, CoolMOS[™] high voltage MOSFETs, OptiMOS[™] low voltage MOSFETs and synchronous rectification IC portfolios, enable high power density designs whilst meeting the thermal requirements.



Functional block	Product category	Topology	Product family	Benefits
Flyback converter	High voltage MOSFETs	Flyback	700 V CoolMOS™ P7 (standard grade)	 > Best price competitive CoolMOS[™] SJ MOSFET family > Lower switching losses versus standard MOSFET
	Control ICs	QR flyback ICs	ICE5QSAG, ICE5QSAG	> High efficiency and low standby power
		FFR flyback IC	XDPS21061	> High power density and ideal for USB-PD
Synchronous rectification	Low voltage MOSFETs	Synchronous rectification	OptiMOS™ 5 40-120 V logic level	 Low conduction losses and reduced overshoot Logic level switching S308/PQFN 3.3 x 3.3 package available
	Control ICs	Synchronous rectification	IR1161LTRPBF	> High efficiency> Simple external circuitry
Load switch	Low voltage MOSFETs	Load switch	OptiMOS™ 30 V	 Low conduction losses \$308/PQFN 3.3 x 3.3 package available

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The PC power market is divided into high-end gaming PC and better cost-performance sectors to achieve a better price performance goal for desktop SMPS. The PC OEMs are implementing the desktop SMPS by removing the AUX power block, to save the cost of having a flyback circuit.

Infineon's IDP2321 is the first digital PFC + LLC combo IC worldwide to meet world-leading PC manufacturers' specifications, with integrated drivers and a 600 V depletion cell to achieve low standby power and lower cost. The PFC controlling loop is a configurable CrCM/DCM multimode to meet highest light-load efficiency. And the most important of all, IDP2321 has approximately 30 to 40 less part counts than traditional analog solutions, thanks to the state-of-the-art digital control.

Furthermore, Infineon's IDP2321 offers flexible IC parameter configuration with user-friendly GUI, which means R&D engineers can key in the parameters on the PC to fine-tune and debug the system performance instead of soldering the passive components. Infineon offers the best total system solutions for non-AUX PC power together with its SMD and through-hole MOSFETs.



Functional block	Product category	Topology	Technology	Benefits
PFC/Main stage	tage High voltage MOSFETs	High voltage MOSFETs CrCM/DCM PFC	600 V CoolMOS™ P7	 > Best thermal performance > Rugged body diode > ESD enhancement for production line > Wide R_{DS(m)} portfolio including both THD and SMD packages
			600 V CoolMOS™ P6	 Fast-switching speed for improved efficiency and thermals Low gate charge for enhanced light-load efficiency and low power consumption at no load condition Optimized V_{GS} threshold for low turn-off losses
			500 V CoolMOS™ CE	 Optimized cost/performance Lower transition losses versus standard MOSFET
	Boost diodes	DCM PFC	650 V Rapid 1	> Low conduction losses
		CCM PFC	650 V Rapid 2	> Low reverse recovery losses and PFC switch turn-on losses
	Control ICs	CCM PFC ICs	ICE3PCS0xG	> High PFC and low THD
Main stage	Control ICs	HB LLC ICs	650 V-ICE1HS01G-1/ ICE2HS01G	High efficiency and low EMI
Synchronous rectification	Medium voltage diodes	HB LLC + center-tap	OptiMOS™ 40 V	> Optimized cost/performance and low thermals
			OptiMOS™ 60 V	> Layout tolerance and low thermals

Gate driver ICs

Packages



SMPS

Diversify TV power supply with cost, performance and ease of use

In addition to their outstanding image quality, new generation TVs gain attention for their user interface, low power consumption and for their slim design. This requires the power supply unit (PSU) to either keep a low profile to maintain the slim appearance of a TV and a low thermal dissipation image or to have an external adapter. In addition, a growing number of TV manufacturers will use external adapters to deliver DC power to the TV. Infineon introduced two products based on digital power technology, designed to meet challenging efficiency and standby power requirements for Internet of Things (IoT) enabled TVs (both embedded PSU and adapter).

Thanks to digital power, our customers can reduce the number of TV power supplies by adapting the digital IC parameters to different TV and screen models by flexible and easy parameter setting. On top of that, Infineon recently introduced the digital based flyback controllers, ideal to implement low power adapters for TVs and monitors. With the digital soft switching, the adapter power density can be improved significantly. The new 600 V CoolMOS[™] P7 is the logical successor of the current 600 V CoolMOS[™] P6. The series has been developed to cover a broad spectrum of different applications where the excellent performance and perfect ease of use are required. The rugged body diode enables not only the use in hard switching topologies, such as power factor correction, boost, and two transistor forward, but also in resonant topologies such as LLC where the technologies lead to high efficiency in both hard-switching and resonant circuits.

For higher on-state resistance $(R_{DS(on)})$ classes, there is a new feature of an integrated ESD diode that helps improve the quality in manufacturing. At the same time, the low $R_{DS(on)}$ and gate charge (Q_G) enable high efficiency in the various topologies. The 600 V CoolMOSTM P7 comes with a wide variety of $R_{DS(on)}$ s and packages on consumer grade to make it best suitable for TV power by balancing the cost and performance. Infineon developed specifically for TV power supplies a family of packages, characterized by short lead, SOT-223 mold stopper and wide creepage distance, which enable our customers' cheap and reliable manufacturing.

Functional block	Product category	Topology	Product family	Benefits
Main stage/PFC combo High voltage non-AUX MOSFETs		DCM PFC, HB LLC	600 V CoolMOS™ P7	 > Fast-switching speed for improved efficiency > Low gate charge for enhanced light load efficiency and low power consumption at no load condition > Optimized V_{cs} threshold for lower turn-off losses > Rugged body diode for HB LLC application
			500 V/600 V CoolMOS™ CE	 > Easy control of switching behavior even in non-optimized layout > Lower switching losses in comparison with its predecessor > Rugged body diode which prevents device failure during hard commutation
	Control ICs	IDP2308	PFC-LLC non-AUX digital IC for TV embedded PSU	 > Low BOM count/system cost due to high integration > Low standby power > High system reliability > Shorter development cycles and higher design and production flexibility
		IDP2303A	PFC-LLC non-AUX digital IC for TV adapter	 Low BOM count/system cost due to high integration Low standby power Small form factor designs High system reliability
PFC	Boost diodes	DCM PFC	650 V Rapid diode	Low conduction losses
	Control ICs	CCM PFC ICs	ICE3PCS0xG	High PFC and low THD
Main stage	Control ICs	HB LLC ICs	ICE1HS01G-1/ICE2HS01G	> High efficiency and low EMI
Auxiliary power supply	Control ICs	QR/FF flyback CoolSET™	700 V/800 V – ICE5QRxx70/80A(Z)(G)	Low standby power, high efficiency and robustness
Flyback	Control ICs	Digital ZVS flyback	IDP2105	 Forced resonant ZVS control reduces the switching loss Multilevel protection enables the robust design Flexible firmware provides more differentiation for OEMs
	High voltage MOSFETs	Flyback	700 V CoolMOS™ P7	 > Optimized for flyback topologies > Best price competitive CoolMOS™ SJ MOSFET family > Lower switching losses versus standard MOSFET > Controlled dV/dt and di/dt for better EMI

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Non-AUX digital solution for large screen size



High power solution for larger screen size



Flyback solution for small screen size



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Microcontrollers

Packages



39



Benefiting from several advantage of organic light emitting diodes (OLED), varying TV manufacturers are developing OLED TVs to level up the user experience of their consumers. Comparing with LCD/LED TV panels, the OLED can be thinner, lighter and more flexible, also the power consumption is lower. With the excellent performance of wide bandgap GaN power MOSFETs from Infineon, the OLED TV become even thinner and more reliable.

CoolGaN™ portfolio

R _{DS(on)}	DSO-20-85 Bottom-side cooling	DSO-20-87 Top-side cooling	HSOF-8-3 TO-leadless	LSON-8-1 DFN 8x8
35	IGO60R035D1*	IGOT60R035D1*	IGT60R035D1*	
70	IGO60R070D1	IGOT60R070D1	IGT60R070D1	IGLD60R070D1
190			IGT60R190D1* IGT60R190D1S**	IGLD60R190D1*
340				IGLD60R340D1*



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SMPS

Full system solutions for embedded power supplies

Customers who design or manufacture a product that needs embedded intelligence typically want to focus on the system design of their product, be it white goods, a vending machine, an automatic door opener or any other product. They do not want to spend valuable efforts and time in designing the power supply systems. They just want to use them, having a trouble-free, EMI friendly, and reliable power supply.

Infineon decided to build a scalable broad range of products, and flexible, and easy to reuse reference designs aimed at helping its customers with best fitting solutions tailored for their different needs.

Depending on their specific needs, our customers can select very low-cost power supply reference designs featuring high integration or using a platform approach to reuse the same power designs for different products that need different power supplies. If high efficiency is needed, for example to meet ENERGY STAR label requirements or to improve overall thermal performance, Infineon offers highest efficiency power supply reference designs.

In addition, Infineon offers comprehensive reference designs and application notes helping customers to drastically improve the efficiency of their power supply by using secondary-side synchronous rectification instead of a rectifier diode. Benefits of synchronous rectification are better efficiency and better thermal performance of your power supply.



Functional block	Product category	Topology	Technology	Benefits
Auxiliary power supply	Control ICs	QR/FF flyback CoolSET™	700 V/800 V ICE5QRxx70/80A(Z)(G)	Low standby power, high efficiency and robustness
Flyback	Control ICs	QR flyback	ICE5QSAG	 High efficiency and low standby power
	High voltage MOSFET	Flyback	700 V/800 V CoolMOS™ P7	 > Best price competitive CoolMOS™ family > Lower switching losses versus standard MOSFET > Controlled dV/dt and di/dt for better EMI

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



SMPS

Highly efficient server power supply

The trend in the field of enterprise and data center server is to deliver more power per rack. Meanwhile, the higher rising cost of energy and environmental concerns make SMPS efficiency optimization a key requirement across the entire load range for server and data center design. This challenging task is combined with the requirement for higher power and higher power density with cost-effective design.

In the PFC stage and in general hard-switching topologies used in server applications, Infineon recommends its 600 V CoolMOS[™] C7 family with the lowest FOM R_{DS(on)} *Q_G and R_{DS(on)} *E_{oss}. This MOSFET series provides the lowest switching losses, which are necessary in fast switching needed in high-end server SMPS. In this way, the efficiency is optimized starting from a very light-load operation. The very compact SMD packages such as ThinPAK, DDPAK and TOLL offer benefits in space and power density and are used with Infineon's new industry standard non-isolated driver family 2EDN752x. Complementary to the 600 V CoolMOS[™] C7 in high efficiency PFC is the CoolSiC[™] Schottky diode generation family. The 600 V CoolMOS[™] P6 family offers a good compromise between price and performance. This is valuable in both PFC and HV DC-DC stages where the low Q_G and turn-off losses are important benefits, especially in the case of high-switching frequency operation and high light load efficiency requirements. In applications which require very high efficiency (Titanium and above) and power density, 650 V CoolMOS[™] G7 and 600 V CoolGaN[™] families enable the highest efficiency and power density at lower system cost for high power (2~3 kW above). Operating expenses (OPEX) and capital expenditures (CAPEX) are both reduced through simplified topologies and the power density in server PSU is doubled.

In applications with a low output voltage and a high output current, further efficiency improvements have been made possible by the continuous reduction of on-resistance by Infineon's low voltage OptiMOS[™] MOSFET series used in the synchronous rectification stage. Infineon's low voltage families are complemented by StrongIRFET[™] which is optimized for lower switching frequencies and highest system robustness.



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500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Functional block	Product category	Topology	Product family	Benefits
PFC	High voltage MOSFETs	CCM/interleaved PFC; TTF	600 V/650 V CoolMOS™ C7 650 V CoolMOS™ G7	 > Best FOM R_{DS(on)}*Q₆ and R_{DS(on)}*E_{oss} > Lowest R_{DS(on}) per package > Low dependency of switching losses form R_{g,ext}
	High voltage GaN	Totem pole PFC	600 V CoolGaN™	> Enable the highest efficiency and highest power density
	SiC diodes	CCM/interleaved PFC	650 V CoolSiC™ Schottky diode generation 5	\rightarrow Low FOM V _F *Q _G
	Control ICs	CCM PFC ICs	ICE3PCS0xG	> Ease of use
Main stage	High voltage MOSFETs	ITTF	600 V CoolMOS™ C7/P6	 Fast switching speed for improved efficiency and thermals Low gate charge for enhanced light load efficiency and low power consumption at no load condition Optimized V_{cs} threshold for lower turn-off losses Rugged body diode which prevents device failure during hard commutation
		LLC, half-bridge below 1 kW	600 V CoolMOS™ P7, CFD7	 > Low turn-off losses > Low Q_{oss} > Low Q_g
		LLC, phase shift full-bridge below 1 kW	600 V CoolMOS™ CFD7, 650 V CoolMOS™ CFD2	 Fast and rugged body diode Optimized low Q_G and soft commutation behavior to reach highest effciency Highest reliability for 650 V V_{DS}
		ZVS PS FB; LLC, TTF	650 V TRENCHSTOP™ F5	Improved ruggedness and high efficiency in low inductance designs
	Control ICs	HB LLC ICs	ICE1HS01G-1 ICE2HS01G	> High efficiency and low EMI
Sychronous rectification		HB LLC and center tap	OptiMOS [™] power MOSFET 40 V	> High efficiency over whole load range, layout tolerance
	Low voltage MOSFETs	ITTF	60 V OptiMOS™	\checkmark High efficiency, low thermals, low V_{\tiny DS} overshoot
	Low votage most 215	ZVS PS FB and center tap	80 V OptiMOS™	$$ High efficiency over whole load range, low $V_{\scriptscriptstyle DS}$ overshoot and oscillations
Auxiliary power supply	Control ICs	QR/FF flyback CoolSET™	800 V – ICE2QRxx80(Z)(G) ICE3xRxx80J(Z)(G) 700 V ICE5QRxx70A(Z)(G) 800 V ICE5QRxx80A(Z)(G)	 Low standby power, high efficiency and robustness An integrated 700 V/800 V superjunction power MOSFET with avalanche capability Burst mode entry/exit to optimize standby power at different low load conditions
Housekeeping	Microcontrollers	-	XMC1xxx	 Flexibility, HR PWM, digital communication ARM[®] based standard MCU family and wide family
Conversion	Microcontrollers	-	XMC4xxx	> Flexibility, HR PWM and digital communication
PFC, PWM/resonant converter, synchronous rectification	Gate driver ICs	-	1EDix EiceDRIVER™	 > 100 ns typical propagation delay time > Functional isolation > Separate source
		-	2EDNx EiceDRIVER™	 > 8 V UVLO option > -10 V input robustness > Output robust against reverse current

Power ICs

SMPS

Full system solution for telecom power supply

The telecommunication industry providing data, voice, and video services is continuously growing supported by the expansion into new markets and accelerated by the spread of wireless and broadband technologies. The outstanding improvements in telecom SMPS performance made in the past 10 years have been primarily brought about by the dramatic reduction of the on-resistance achieved in high voltage MOSFETs, using the revolutionary superjunction principle. This principle was introduced by Infineon at the end of the nineties with the CoolMOS[™] series.

Equally impressive improvements in reverse-recovery characteristics have been achieved for high voltage CoolSiC[™] (silicon carbide) diodes. Infineon's high voltage (HV) offerings are complemented by the newly introduced HV GaN switches – the CoolGaN[™] family, which enables highest electrical conversion efficiency at attractive system costs. In order to meet the new challenging efficiency targets, the synchronous rectification utilizing the unique performance of OptiMOS[™] low voltage MOSFETs has become increasingly popular even in the typically high output voltage of telecom rectifiers.



Functional block	Product category	Topology	Product family	Benefits
PFC	High voltage MOSFETs	CCM/interleaved PFC; TTF	600 V/650 V CoolMOS™ C7	 Best FOM R_{DS(on)}*Q_a and R_{DS(on)}*E_{oss} Lowest R_{DS(on)} per package Low dependency of switching losses form R_{g.ext}
			600 V CoolMOS™ P7	 > Low turn-off losses > Low Q_{oss} > Low Q_g
	High voltage GaN	CCM totem pole	CoolGaN™ 600 V	 Switching at high frequencies (> Si) Enables high power density
	SiC diodes	CCM/interleaved PFC	650 V CoolSiC™ Schottky diode generation 6	≻ Low FOM V _F *Q _c
	Control ICs	CCM PFC ICs	800 V – ICE3PCS0xG	> High PFC and low THD
	GaN driver ICs	Totem pole PFC	EiceDRIVER™ 1EDF5673F and 1EDF5673K	 Low driving impedance (on-resistance 0.85 Ω source, 0.35 Ω sink) Input-output propagation delay accuracy: ±5 ns Functional and reinforced isolation available

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Applications

Packages

44

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Functional block	Product category	Topology	Product family	Benefits
DC-DC main stage	High voltage MOSFETs	CCM/interleaved PFC; TTF HB LLC	600 V CoolMOS™ C7/P7	 Fast-switching speed for improved efficiency and thermals Low gate charge for enhanced light load efficiency and low power consumption at no load condition Optimized V_{GS} threshold for lower turn-off losses Rugged body diode which prevents device failure during hard commutation
		LLC	600 V CoolMOS™ P7	 > Low turn-off losses > Low Q_{oss} > Low Q₆
		CCM/interleaved PFC; TTF HB LLC	600 V CoolMOS™ CFD7	 > Best-in-class Q_n and t_n level > Significantly reduced Q₆ > Improved efficiency over previous CoolMOS[™] fast body diode series
	Control ICs	HB LLC ICs	ICE1HS01G-1, ICE2HS01G	High efficiency and low EMI
	GaN driver ICs	LLC, ZVS phase shift full-bridge	EiceDRIVER™ 1EDS5663H	 Low driving impedance (on-resistance 0.85 Ω source, 0.35 Ω sink) Input-output propagation delay accuracy: +/- 5 ns Functional and reinforced isolation available
	GaN e-mode HEMTs	LLC, ZVS phase shift full-bridge	CoolGaN™ 600 V	> Enable the highest efficiency and highest power density
Synchronous rectification	Low voltage MOSFETs	Synchronous rectification MOSFET	OptiMOS™ 80-150 V	 Industry's lowest FOM (R_{DS(m)}*Q_c) leading to high efficiency at good price/performance Low voltage overshoots enabling easy design-in Industry's lowest R_{DS(m)} Highest system efficiency and power density Outstanding quality and reliability Reduces the need for a snubber circuit
Auxiliary power supply	Control ICs	5 th generation QR/FF flyback CoolSET™	QR 800 V - ICE5QRxx80Ax FF 800 V - ICE5xRxx80AG	 Quasi-resonant switching operation for high efficiency and low EMI signature Fixed frequency switching operation for ease of design – 100 KHz and 125 KHz Fast and robust start-up with cascode configuration Robust protection with adjustable line input over-voltage protection, V_{cc} and CS pin short-to-ground protection Optimized light-load efficiency with selectable burst mode entry/exit profile Frequency reduction for mid- and light-load condition to reduce switching losses and increase efficiency Direct feedback and regulation with integrated error amplifier for non-isolated output High power delivery of up to 42 W with 800 V CoolSET™ in heatsink-free SMD package
Housekeeping	Microcontrollers	-	XMC1xxx	 > Flexibility, HR PWM, digital communication > ARM[®] based standard MCU family and wide family
Conversion	Microcontrollers	-	XMC4xxx	 > Flexibility, HR PWM, digital communication > ARM[®] based standard MCU family and wide family
PFC, PWM/ resonant converter,	Gate driver ICs	Single-channel non-isolated	EiceDRIVER™ 1EDN751x	 > 8 V UVLO option > (-)10 V input robustness > Output robust against reverse current
synchronous rectification		Single-channel non-isolated	EiceDRIVER™ 1EDN7550	 > 8 V UVLO option > (-)10 V input robustness > True differential inputs for >100 V_{AC} ground shift robustness
		Dual-channel non-isolated	EiceDRIVER™ 2EDN7x	 > 8 V UVLO option > (-)10 V input robustness > Output robust against reverse current
		Dual-channel junction isolated	EiceDRIVER™ 2EDL811x*	 20 ns typical propagation delay time 20 V bootstrap capability on high side (-)7 V input robustness
		Single-channel isolated	EiceDRIVER™ 1EDi Compact	 > 100 ns typical propagation delay time > Functional isolation 1.2 kV separate source and sync outputs
		Dual-channel isolated	EiceDRIVER [™] 2EDFx	 35 ns typical propagation delay time Functional isolation 1.5 kVCMTI > 150 V/ns
		Dual-channel isolated	EiceDRIVER [™] 2EDSx	 35 ns typical propagation delay time Reinforced (safe) isolation 6 kV CMTI > 150 V/ns
Or-ing	Low voltage MOSFETs	Or-ing MOSFET	OptiMOS™ 60-200 V	 Industry's lowest FOM (R_{DS(on)}*Q_G) leading to high efficiency at good price/performance Low voltage overshoots enabling easy design-in
Battery protection	Low voltage MOSFETs	MOSFET	OptiMOS™ 60-150 V	
Isolated DC-DC	Low voltage MOSFETs	Primary side PWM MOSFET	OptiMOS™ 60-200 V	 Industry's lowest R_{os(on)} Highest system efficiency and power density
			StrongIRFET [™] 60-200 V	Outstanding quality and reliability Reduces the need for a snubber circuit
			Small signal MOSFETs 60-200 V	
		Synchronous rectification MOSFET	OptiMOS™ 40-100 V	
			StrongIRFET [™] 40-100 V	
		Or-ing MOSFET	OptiMOS™ 25-30 V	
			StrongIRFET [™] 25-30 V	

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*Upcoming - Q2/2019

EV charger

Fast EV Charging Advanced solutions for DC EV charging

What speaks for off-board DC EV charging?

With the growing number of electric vehicles (EVs), which are in some markets becoming viable alternatives to traditional internal combustion engine vehicles, the demand for enhanced semiconductor solutions for charging stations increases too. Currently, all eyes are on China where EVs have gained traction in the rapidly expanding middle class, while Europe and the United States are expected to follow suit soon. However, to truly welcome EVs on a large scale, these markets need to provide widespread availability of DC charging infrastructure so that drivers can quickly charge their vehicles. DC charging systems are an attractive choice because they offer much faster charging than a standard AC EV charger which many EV drivers possess. Today a DC charger with e.g. 150 kW can put a 200 km charge on an EV battery in just 15 minutes. The improvement of charging technologies is expected to even further lower the charging time. Consequently, off-board charging is becoming more and more attractive.

Challenges on the horizon

Reaching the next level in designing DC EV chargers confronts engineers with many new challenges. For a DC charging design to be a long term success, you must:

- > Enhance output power to shorten the charging time
- > Improve power density within the set dimensions of the charging station
- > Increase efficiency by boosting the load and decreasing power dissipation
- > Reduce design cost per watt

Overcoming all of the mentioned issues is possible – with the right partner.

The right partner for successful DC EV charger designs

As a market leader and the global frontrunner in power electronics, Infineon enables you to bring energy-efficient DC EV charger designs to life, with our highly efficient components and in-depth technical support. We cover power ranges from kilowatt to megawatt in our broad portfolio of high-quality power semiconductors, microcontrollers, gate drivers and security, safety, and authentication solutions. Our CoolMOS[™] and CoolSiC[™] MOSFETs, for example, are ideal in a wide range of DC EV charging designs. Their matchless advantages include high frequency operation, high power density and reduced switching losses, allowing you to reach high levels of efficiency in any battery charging system.



System diagram DC EV charger

Through extensive interaction with DC EV charging designers and being a member of CharIN, we have vast system expertise in electric mobility as well as its automotive safety and data security. All this contributes to making vehicle chargers safe, efficient, and fast. Based on that knowledge, Infineon provides a comprehensive offering addressing application needs of DC EV charging:

- > Power semiconductor and gate driver solutions for highly efficient power conversion
- Authentication solutions for secure authentication and protection against misuse
- Encryption solutions ensuring secure communication for billing and roaming

Infineon's solution recommendation for DC EV charging system blocks

Our solutions are designed for harsh environmental conditions and long life time as we have an excellent understanding of quality requirements. Take the next step by exploring our product portfolio for DC EV charging systems.

PFC stage (three-phase input)

Product category	Product family	Product	Additional information
High voltage MOSFET /	650 V CoolMOS™ C7	IPW65R019C7	650 V, 19 mΩ, TO-247
SIC MOSFET / IGBT	600 V CoolMOS™ C7	IPW60R017C7	600 V, 17 mΩ, TO-247
	600 V CoolMOS™ P7	IPW60R024P7	600 V, 24 mΩ, TO-247
		IPW60R037P7	600 V, 37 mΩ, TO-247
		IPW60R060P7	600 V, 60 mΩ, TO-247
	650 V TRENCHSTOP [™] 5 H5	IKW50N65EH5/IKZ50N65EH5	650 V, 50 A, TO-247-3/4
		IKW75N65EH5/IKZ75N65EH5	650 V, 75 A, TO-247-3/4
	1200 V CoolSiC [™] MOSFETs	IMW120R045M1/IMZ120R045M1	1200 V, 45 mΩ, TO-247-3/4
	1200 V CoolSiC™ Easy modules	F3L15MR12W2M1_B69	1200 V, 15 mΩ, Easy 2B, Vienna rectifier phase leg
		FS45MR12W1M1_B11	1200 V, 45 mΩ, Easy 1B, sixpack
SiC diodes	diodes 1200 V CoolSiC [™] Schottky diodes generation 5		1200 V, 15 A, TO-247-3/2
		IDW20G120C5B/IDWD20G120C5	1200 V, 20 A, TO-247-3/2
		IDW30G120C5B/IDWD30G120C5	1200 V, 30 A, TO-247-3/2

HV DC-DC main stage

Product category	Product family	Product	Additional information
High voltage MOSFET /	600 V CoolMOS™ CFD7 / CSFD	IPW60R018CFD7	600 V, 18 mΩ, TO-247
SIC MOSFET		IPW60R024CFD7	600 V, 24 mΩ, TO-247
		IPW60R037CSFD	600 V, 37 mΩ, TO-247
		IPW60R040CFD7	600 V, 40 mΩ, TO-247
		IPW60R055CFD7	600 V, 55 mΩ, TO-247
		IPW60R070CFD7	600 V, 70 mΩ, TO-247
	600 V CoolMOS™ C7	IPW65R045C7	650 V, 45 mΩ, TO-247
	600 V CoolMOS™ P7	IPW60R080P7	600 V, 80 mΩ, TO-247
	1200 V CoolSiC [™] SiC MOSFET	IMW120R045M1/IMZ120R045M1	1200 V, 45 mΩ, TO-247-3/4
	1200 V CoolSiC™ Easy module	FF6MR12W2M1_B11	1200 V, 6 mΩ, Easy 2B, half-bridge
		FF8MR12W2M1_B11	1200 V, 8 mΩ, Easy 2B, half-bridge
		FF11MR12W1M1_B11	1200 V, 11 mΩ, Easy 1B, half-bridge
		FF23MR12W1M1_B11	1200 V, 23 mΩ, Easy 1B, half-bridge
		F4-23MR12W1M1_B11	1200 V, 23 mΩ, Easy 1B, fourpack
		FS45MR12W1M1_B11	1200 V, 45 mΩ, Easy 1B, sixpack
SiC Diodes	1200 V CoolSiC [™] Schottky diode generation 5	IDW15G120C5B/IDWD15G120C5	1200 V, 15 A, TO-247-3/2
Output rectification diodes		IDW20G120C5B/IDWD20G120C5	1200 V, 20 A, TO-247-3/2
		IDW30G120C5B/IDWD30G120C5	1200 V, 30 A, TO-247-3/2
	650 V CoolSiC [™] Schottky diode generation 5	IDW12G65C5	650 V, 12 A, TO-247
		IDW16G65C5	650 V, 16 A, TO-247
		IDW20G65C5	650 V, 20 A, TO-247
		IDW20G65C5B	650 V, 10 A, TO-247
		IDW24G65C5B	650 V, 24 A, TO-247
		IDW30G65C5	650 V, 30 A, TO-247
		IDW32G65C5B	650 V, 32 A, TO-247
		IDW40G65C5	650 V, 40 A, TO-247
		IDW40G65C5B	650 V, 40 A, TO-247
	650 V CoolSiC [™] Schottky diode generation 6	IDH20G65C6	650 V, 20 A, TO-220
		IDH16G65C6	650 V, 16 A, TO-220 real 2-pin
		IDH12G65C6	650 V, 12 A, TO-220 real 2-pin
		IDH10G65C6	650 V, 10 A, TO-220 real 2-pin
		IDH08G65C6	650 V, 8 A, TO-220 real 2-pin
		IDH06G65C6	650 V, 6 A, TO-220 real 2-pin
		IDH04G65C6	650 V, 4 A, TO-220 real 2-pin
		IDDD20G65C6	650 V, 20 A, Double DPAK
		IDDD16G65C6	650 V, 16 A, Double DPAK
		IDDD12G65C6	650 V, 12 A, Double DPAK
		IDDD10G65C6	650 V, 10 A, Double DPAK
		IDDD08G65C6	650 V, 8 A, Double DPAK
		IDDD06G65C6	650 V, 6 A, Double DPAK
		IDDD04G65C6	650 V, 4 A, Double DPAK

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Motor control ICs

Gate driver and galvanic isolation

Product category	Product family	Product	Additional information
Gate driver ICs	EiceDRIVER™ (non-isolated)	1EDN family, 2EDN family	Single-channel/dual-channel, non-isolated low-side gate driver ICs
	EiceDRIVER™ 500-700 V level shift gate driver	IR2214SS	1200 V half-bridge gate driver for IGBTs and MOSFETs with level-shift technology
	EiceDRIVER™	2EDF7175F, 2EDF7275F	Dual-channel functional isolated (1,5 kV)
	(galvanic isolation)	2EDS8265H, 2EDS8165H	Dual-channel reinforced (safe) isolated (6 kV)
		1EDI40I12AF/H, 1EDI60I12AF/H, 1EDC40I12AH, 1EDC60I12AH	600 V / 650 V single-channel, galvanic isolated driver with separate source and sink outputs to drive CoolMOS™ SJ MOSFETs in floating mode as in Vienna rectifier variants
		1EDC20H12AH, 1EDC60H12AH, 1ED020I12-F2, 2ED020I12-F2	1200 V, single-channel/dual-channel, galvanic isolated driver recommen- ded to drive CoolSiC™ MOSFETs and CoolSiC™ EasyPack™ power modules
		1EDI30I12MF/H, 1EDC30I12H, 1EDI10I12MF/H, 1EDC10I12MH	1200 V, single-channel, galvanic isolated driver with integrated Miller clamp to drive TRENCHSTOP™ 5 H5 IGBTs

Microcontroller

Product category	Product family	Product	Additional information
Microcontroller	XMC™	XMC1400 family (PFC stage)	ARM® Cortex® M0 based microcontroller
		XMC4500/4700 (HV DC-DC/PWM stage)	ARM® Cortex® M4F based microcontroller
	AURIX™	TC26X/TC27X TC36X/TC37X	TriCore™ AURIX™ 32-bit microcontroller HSM (hardware secure module) full EVITA compliance

Internal power supply

Product category	Product family	Product	Additional information
AC-DC power conversion	CoolSET™ 5 QR/FF flyback	ICE5QR0680AG	800 V, 42 W, 710 mΩ, PG-DSO-12
		ICE5AR0680AG	800 V, 42 W, 710 mΩ, PG-DSO-12
	5 th generation PWM controllers	ICE5QSAG and IPP80R360P7	800 V, 360 mΩ, TO-220
	and CoolMOS™ P7	ICE5QSAG and IPA95R450P7	950 V, 450 mΩ , TO-220 FP
	CoolMOS [™] HV SJ MOSFETs	IPN95R1K2P7	950 V, 450 mΩ, SOT-223
		IPN80R1K4P7	800 V, 1.4 Ω, SOT-223

Authentication and encryption

As embedded systems are increasingly becoming targets of attackers, Infineon offers OPTIGA™ - a turnkey security solution.

Product category	Product family	Product	Additional information
Security	OPTIGA [™] Trust B	B SLE952500000XTSA1 Assymetric ECC authentication with individual certificate an extended temperature range of -40 to 110°C	
	OPTIGA [™] Trust TPM SLB9670XQ2.0		Fully TCG TPM 2.0 standard compliant module with the SPI interface
	SLC37	SLC37ESA2M0, SLI97CSIFX1M00PE	New class of performance and security cryptocontroller adhering to CC EAL6+ high targeted and EMVCo targeted certifications for payment and eSIM applications





Uninterruptible power supply (UPS)

Attractive solutions for highest efficiency and power density

Today's uninterruptible power supply systems introduce a wide range of challenges. Overcoming them requires an increase in output power, power density and energy efficiency. For all your UPS power supply applications, Infineon's high quality products provide you with complete system level solutions. Equipped with our semiconductors, UPS applications can achieve best-possible power conversion efficiency and cutting-edge power density. The benefits are cost reduction and fewer passive components – regardless of the topology used.

By choosing Infineon's products for UPS applications you get solutions that fulfill the latest market requirements. This includes the trend of modularization of UPS brick units due to scalable power demand from data centers, as well as the topology shift from two-level to three-level to achieve higher efficiency. Our products are suitable for any kind of uninterruptible power supplies in telecom, data center, server or industrial automation environments.



500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



Full-bridge bidirectional power stage



	Battery voltage	Тороlogy	MOSFET breakdown voltage	TO-220	TO-247	D ² PAK and D ² PAK-7	Gate drivers
Inverter/charger MOSFETs	12 V	Push-pull	60 V	IRFB7530 IRFB7534 IRFB7540 IRFB7545	IRFP3006 IRFP7530 IRFP7537	IRFS7530 IRFS7530-7P	IRS44273 IRS4427 1EDN851X 2EDN852X
		Full-bridge	30 V 40 V	IRLB3813 IRLB8314 IRLB8743 IRFB7430 (40 V)	IRFP7430	IRFS7430 (40 V) IRFS7430-7P (40 V)	IRS211X IRS2186 2EDL811X
	24 V	Push-pull	75 V 100 V	IRFB3077 IRFB3207 IRFB7730 IRFB7734	IRFP7718	IRFS7730 IRFS7734 IRF3610S (100 V) IRFS4010 (100 V)	IRS44273 IRS4427 1EDN851X 2EDN852X
		Full-bridge	40 V 60 V	IRFB7430 IRFB7434 IRFB7545 (60 V) IRF60B217 (60 V)	IRFP7530 IRFP3006 IRFP7537	IRFS7430 IRFS7430-7P IRF7430 IRFS7530-7P	IRS211X IRS2186 2EDL811X
	48 V	Push-pull	150 V	IRFB4115 IRFB4321 IPP046N15N5 IRFB4228 IRFB4019	IRFP4568 IRFP4321 IRF150P220 IRF150P221	IRFS4321 IRFS4115 RB048N15N5 IRFS4615	IRS44273 IRS4427 1EDN851X 2EDN852X
		Full-bridge	100 V	IPP030N10N IRFB4110 IPP086N10N3G IRFB4510 IPP180N10N3G	IRFP4468 IRFP4110 IRF100P218 IRF100P219	IRFS3610 IRF3710S IRF8010S IRFS4510 IRFS4010	IRS211X IRS2186 2EDL811X
	72 V	Push-pull	200 V	IPP110N20N3 IRFB4127 IRFB4227 IPP320N20N3 IRFB4320	IRF200P222 IRFP4668 IRF200P223 IRFP4127 IRFP4227	IPB110N20N3LF IRFS4127 IRFS4227 IRFB117N20NFD IRF200S234	IRS44273 IRS4427 1EDN851X 2EDN852X
		Full-bridge	150 V	IRFB4321 IPP046N15N5	IRFP4568 IRF150P220	IRFS4321 IRB048N15N5	IRS211X IRS2186 2EDL811X
		Full-bridge	200 V	IPP110N20N3 IRFB4227	IRF200P222 IRFP4668	IPB110N20N3LF IRFS4127	IRS211X IRS2186 2EDL811X
Microcontrollers	12-72 V	XMC1300 series					

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Push-pull bidirectional power stage

51





Unidirectional power stage (output stage)



Unidirectional DC-DC stage

Battery voltage	Topology	MOSFET breakdown voltage	TO-220	TO-247	D ² PAK and D ² PAK-7	Gate drivers
12 V	Push-pull	40 V	IRFB7430 IRFB7434	IRFP7718	IRFS7430 IRFS7430-7P IRF7430	IRS44273 IRS4427 1EDN851X
		60 V	IRFB7540 IRFB7545 IRF60B217		IRFS7530-7P	2EDN852X
		75 V		IRFP7718		
24 V	Push-pull	75 V	IRFB3077 IRFB3207 IRFB7730 IRFB7734	IRFP7718	IRFS7730 IRFS7734	
		100 V		IRF100P218 IRFP4468	IRFS4010 IRF3610S	
		150 V	IRFB4115 IRFB4321 IPP046N15N5 IRFB4228 IRFB4019	IRF150P220	IRFS4321 IRFS4115 IRB048N15N5 IRFS4615	
Microcontrollers	·	XMC1300 series			·	



Unidirectional inverter stage

Battery voltage	Topology	MOSFET breakdown voltage	TO-220	TO-247	Gate drivers
200 V	Full-bridge inverter 120 V _{AC}	300 V	IPP410N30N IRFB4137	IRF300P226 IRF300P227 IRFP4868 IRFP4137	IRS211X IRS2186
400 V	Full-bridge inverter 220 V _{AC}	500 V	IPP50R280CE IPP50R380CE IPP50R190CE	IPW50R190CE	IRS211X IRS2186
Microcontrollers		XMC1300 series			

Unidirectional charger

Battery voltage	Topology	MOSFET breakdown voltage	TO-220	TO-247	PG-DIP-7		
12-72 V	Flyback	650 V	CoolSET™		ICE3RBR1765JZ ICE3RBR0665JZ		
12-72 V	Flyback	800 V	CoolMOS™ P7	IPP80R750P7 IPP80R600P7 IPP80R450P7 IPP80R360P7 IPP80R280P7			
Microcontrollers		Integrated, ICE3AS03LJG, ICE3E	Integrated, ICE3AS03LJG, ICE3BS03LJG				

Applications

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Motor control ICs

Online UPS

Online UPS power stage



Stage	Topology	Voltage class	Technology	Part number
Rectifier	Three-phase	800 V/1600 V	EasyBRIDGE, EconoBRIDGE™	
PFC	Boost PFC / Vienna "T-type"	1200 V	TRENCHSTOP™ IGBT6	IKW40N120CS6 IKQ75N120CS6
	Boost PFC / Vienna rectifier	1200 V	CoolSiC [™] MOSFET	F3L15MR12W2M1_B69
	Boost PFC / Vienna "T-type"	650 V	TRENCHSTOP [™] 5 H5	IKW50N65EH5 IKW75N65EH5
	Boost PFC	600 V/1200 V	EasyPACK™	
	Boost PFC	1200 V	CoolSiC ™ Schottky diode	
	PFC	600 V	CoolMOS™ P7	IPP60R060P7 IPB60R060P7
	PFC	600 V	CoolMOS™ C7	IPP60R040C7 IPB60R040C7
Inverter	NPC 1	650 V	TRENCHSTOP™ 5 H5	IKW50N65EH5 IKW75N65EH5 IKZ50N65EH5 IKZ75N65EH5
	NPC 1	650 V	TRENCHSTOP [™] 5 S5	IKW50N65ES5 IKW75N65ES5
	NPC 1	650 V	TRENCHSTOP™ HighSpeed3 IGBT Rapid diode	FS3L50R07W2H3F_B11
	NPC 2	1200 V	TRENCHSTOP™ IGBT6	IKW40N120CS6 IKQ75N120CS6
	NPC 2	1200 V	CoolSiC ™ Schottky diode	
	NPC 2	1200 V	TRENCHSTOP™ HighSpeed3 IGBT Rapid diode	FS3L25R12W2H3_B11 F3L200R12W2H3_B11 F3L200R12W2H3_B47
	NPC 2	650 V	TRENCHSTOP [™] 5 S5	IKW50N65ES5 IKW75N65ES5
	Two-level	1200 V	EconoPACK [™] , EasyPACK [™]	FS75R12W2T4_B11 FS200R12KT4R_B11
	Two-level	1200 V	EconoDUAL™	FF600R12ME4_B11
	Three-level NPC1	600 V/1200 V	EconoPACK™	F3L300R07PE4
Battery charger	Half-bridge	1200 V	TRENCHSTOP™ IGBT6	IKW40N120CS6 IKQ75N120CS6
		1200 V	CoolSiC [™] MOSFET	FF6MR12W2M1_B11
		650 V	TRENCHSTOP™ 5 H5	IKW50N65EH5 IKW75N65EH5
Gate driver ICs	Single-channel	1200 V	EiceDRIVER™ 1ED Compact	
AUX	-	650-800 V	CoolSET™	

Applications

Discrete IGBTs

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Solar

Solar

High efficiency designs for solar power systems

Infineon provides a comprehensive portfolio to deliver the best efficiency and reliability for solar applications. Infineon's cutting edge technologies such as CoolMOS[™] SJ MOSFETs, HighSpeed3 IGBT and TRENCHSTOP[™] 5, CoolSiC[™] Schottky diodes, CoolSiC[™] MOSFETs, coreless transformer, driver, etc. combined with the rich experience and highest quality ensure the company's leader position in solar applications. The newly added ARM[®] Cortex[™]-M4 based MCU enables easy and high efficiency design.

	Optimizer 250-750 W	Single/Dual microinverter 250-600 W; 900 W	String inverter 1-60 kw	Central inverter 500-5000 kW
MOSFETs	OptiMOS™ SuperSO8/DirectFET™ 75-150 V	OptiMOS™ SuperSO8 60-200 V	OptiMOS™ 150-300 V	
		CoolMOS™ D²PAK/ThinPAK 600-800 V	CoolMOS™ TO-247 600 V/650 V 19-99 mΩ	
			CoolSiC™ MOSFET TO-247-3/TO-247-4 1200 V	
SiC diodes		CoolSiC™ Schottky diodes DPAK/TO-220 600 V/1200 V D²PAK 650 V	CoolSiC™ Schottky diodes TO-220/TO-247 650 V/1200 V	
IGBTs			650 V TRENCHSTOP™ 5 / 1200 V TRENCHSTOP™ IGBT6 TO-247-3/TO-247-4/TO-247PLUS 600 V/650 V/1200 V	
10213			Easy 1B/2B	PrimePACK [™] / EconoDUAL [™] 3 / MIPAQ [™] Pro
Gate driver ICs		2EDN EiceDRIVER™	EiceDRIVER™ 1ED Compact EiceDRIVER™ Enhanced 1ED020I12-F2/2ED020I12-F2	EiceDRIVER™ Enhanced 1ED020I12-F2/2ED020I12-F2
Schottky diode			BAT165 Schottky diode	
Auxiliary power supply			CoolSET™ 800 V	
Microcontrollers	XMC1xxx ARM [®] Cortex [®] -M0	XMC1xxx ARM [®] Cortex [®] -M0	XMC1xxx ARM [®] Cortex [®] -M0	XMC1xxx ARM [®] Cortex [®] -M0
	XMC45xx ARM [®] Cortex [®] -M4	XMC45xx ARM [®] Cortex [®] -M4	XMC45xx ARM [®] Cortex [®] -M4	XMC45xx ARM [®] Cortex [®] -M4

Infineon's products for complete solar system



500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs



OptiMOS[™] power MOSFETs for microinverter

Input voltage	Тороlogy	MOSFET breakdown voltage	SuperSO8	DirectFET™	D²PAK
Up to 48 V	Half-bridge, full-bridge, LLC and other resonant topologies	60 V	BSC012N06NS BSC019N06NS BSC028N06NS BSC039N06NS	BSB028N06NN3G	-
Up to 64 V	Half-bridge, full-bridge, LLC and other resonant topologies	80 V	BSC030N08NS5 BSC037N08NS5 BSC052N08NS5	BSB044N08NN3G BSB104N08NP3	-
Up to 80 V	Half-bridge, full-bridge, LLC and other resonant topologies	100 V	BSC035N10NS5 BSC040N10NS5	-	IPB020N10N5
Up to 60 V	Flyback	150 V	BSC093N15NS5 BSC108N15NS5 BSC160N15NS5 BSC175N15NS5	BSB165N15NZ3	IPB041N15N5 IPB063N15N5 IPB108N15N3G
	Push-pull	200 V	BSC320N20NS3G	-	IPB107N20N3G

CoolSiC[™] Schottky diodes for microinverter

CoolMOS[™] SJ MOSFETs for microinverter

Topology	Package	Voltage class	Part number	Topology	Packag	e Vo	ltage class	
Current source	D ² PAK	800 V	SPB17N80C3	Rectifier	TO-252 (DPA	<) 1200 [·]	1	
Current/voltage	D ² PAK	650 V	IPB65R190C7					
source			IPB65R125C7					
			IPB65R095C7			600 V		
	IPB65R065C7	650 V						
			IPB65R045C7	Functional block	Product	Product		
	ThinPAK 8x8	600 V	IPL60R185P7	-	category	family		
	IPL60R125P7 PFC, PWM/ Gate driver ICs resonant	e driver ICs EiceDRIVER 1ED Compac						
			IPL60R105P7	converter,		11D compac	> Function	a
			IPL60R085P7	synchronous			> Separate	_
			IPL60R065P7	rectilication		EiceDRIVER™ 2EDNx	> 8 V UVLO > (-)10 V in	
			IPL60R185C7				> Output re	o
			IPL60R125C7	1			reverse c	:ι
			IPL60R104C7	Microcontrol	Microcontrollers for microinverter			
			IPL60R065C7	Topology	P	ackage	Voltage class	;
		650 V	IPL65R195C7	Microcontroller	All		All	
	IPI 65R130C7		tage regulator	Up to 20 V	+			
			IPL65R099C7	Microcontroller su	ppty Linear Vol	lage regulator	00 10 20 0	
			IPL65R070C7	Microcontroller	All		All	

www.infineon.com/solar

XENSIVTM sensors

Optimizer



OptiMOS[™] MOSFETs for optimizer DC-DC power conversion

Input voltage	Тороlogy	MOSFET breakdown voltage	SuperSO8	S308/PQFN 3.3 x 3.3	DirectFET™	D ² PAK and DPAK
Up to 48 V	Buck-boost	60 V	BSC012N06NS BSC016N06NS	BSZ042N06NS	BSB028N06NN3G	IPB026N06N
Up to 64 V	Buck-boost	80 V	BSC027N08NS5 BSC040N08NS5 BSC052N08NS5 BSC117N08NS5	BSZ075N08NS5 BSZ084N08NS5 BSZ110N08NS5	BSB044N08NN3G	IPB017N08N5 IPB031N08N5 IPB049N08N5
Up to 80 V	Buck-boost	100 V	BSC035N10NS5 BSC040N10NS5 BSC060N10NS3	BSZ097N10NS5	BSB056N10NN3 BSF134N10NJ3G	IPB020N10N5
Up to 125 V	Buck-boost	200 V	BSC320N20NS3G	BSZ900N20NS3 G	-	IPD320N20N3G

Microcontrollers for power optimizer

Тороlоду	Package	Voltage class	Technology
Microcontroller	All	All	XMC1000
Microcontroller supply	Linear voltage regulator	Up to 20 V	IFX1763, IFX54441, IFX54211
Microcontroller	All	All	XMC4000



Single-phase string inverter – multilevel topology

In multilevel inverter, four high voltage MOSFETs/IGBTs in H-bridge topology are replaced with a higher number of lower voltage MOSFETs. Compared to a conventional H-bridge inverter, a multilevel inverter, composed of lower voltage MOSFETs, offers several advantages:

- > With much lower R_{DS(on)} and switching loss parameters it significantly reduces conduction and switching losses
- > Higher effective output frequency (smaller magnetics) is possible with lower switching losses
- Improved EMC due to reduced switching voltages
- > Significant reduction in cooling system, size and weight

Discrete power devices for multilevel string inverter

Topology	MOSFET breakdown voltage	Family	SuperSO8	D²PAK	TO-220	TO-247
Flying-capacitor-based active neutral-point-clamp multilevel inverter	150 V	OptiMOS™ 5	BSC093N15NS5 BSC110N15NS5 BSC160N15NS5	IPB044N15N5 IPB048N15N5 IPB060N15N5 IPB073N15N5	IPP051N15N5 IPP076N15N5	-

Power ICs

Packages

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Single-phase string inverter (non-isolated) – standard solution



Three-phase string inverter



Discrete power devices for string inverter

Inverter type	Function	Product series	Voltage class	Part number
Single-phase	Boost	CoolMOS™ C7	600 V	IPW60R040C7
		CoolSiC™ diode	650 V	IDW20G65C5
	DC-DC	CoolMOS™ P7	600 V	IPW60R037P7
		CoolSiC™ diode	650 V	IDW20G65C5
		Rapid diode	650 V	IDW15E65D2
	Inverter	TRENCHSTOP™ IGBT3	600 V	IKW40N60H3
		TRENCHSTOP [™] 5 H5	650 V	IKW40N65H5
		CoolMOS™ P7	600 V	IPW60R037P7
Three-phase	Boost	TRENCHSTOP™ IGBT6	1200 V	IKW40N120CS6 IKQ75N120CS6 IKY75N120CS6
		CoolSiC™ MOSFET	1200 V	IMW120R045M1 IMZ120R045M1
		CoolSiC™Schottky diode generation 5	1200 V	IDW20G120C5B IDW30G120C5B IDW40G120C5B
	Inverter	TRENCHSTOP [™] IGBT6	1200 V	IKW40N120CS6 IKQ75N120CS6 IKY75N120CS6
		TRENCHSTOP™ 5 S5	650 V	IKW40N65ES5
		TRENCHSTOP [™] 5 L5	650 V	IKW30N65EL5

Gate driver ICs for string inverter

Power device	Driving method	Voltage class	Part number
IGBT/SIC MOSFET	Single-channel	1200 V	EiceDRIVER™ 1ED Compact EiceDRIVER™ Enhanced 1ED020I12-F2
IGBT/SIC MOSFET	Half-bridge and high- and low-side	1200 V	EiceDRIVER [™] Enhanced 2ED020I12-F2/FI

CoolSET[™] for string inverter

Voltage class	Part number
800 V	ICE3AR2280JZ
650 V	ICE3BR1765JZ

Microcontrollers for string inverter

Тороlоду	Package	Voltage class	Technology
Microcontroller	All	All	XMC1000
Microcontroller supply	Linear voltage regulator	Up to 20 V	IFX1763, IFX54441, IFX54211
Microcontroller	All	All	XMC4000

For Infineon's extensive module portfolio for string and central inverters, visit:

www.infineon.com/solar

www.infineon.com/igbtmodules1200v

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



Wireless charging solutions

Cost-effective and secure offerings for consumer, industrial and automotive applications

Over the last years, wireless charging has gained more and more traction in the market and is expected to heavily influence our daily lives in future. Infineon offers a broad portfolio of efficient, high-quality products and solutions to serve the key requirements of the dominant market standards: inductive (Qi (WPC)) and resonant (AirFuel). Whether you charge a smartphone (e.g. at home or in the car), a handful of wearables, a power tool, a laptop or a service robot, Infineon's components and solutions help you overcome a wide range of common wireless power transfer challenges for consumer, industrial and automotive wireless charging designs.

Wireless charging standards

	Inductive single-coil	Inductive multi-coil	Magnetic resonance
Standard	Qi indi 110-20	Resonant AirFuel 6.78 MHz	
Positioning of receiver application	Exact positioning	Positioning more flexible (X and Y direction)	Free positioning (up to >30 mm vertical freedom)
Number of devices charged	Charges only one device	Charges one device but with better user experience	Charges multiple devices
Rx-Tx communication	In-band com	Bluetooth low energy or in-band communication	

Many end markets for wireless battery charging



Infineon's key enabling products for consumer, industrial and automotive solutions

- > Low and medium voltage power MOSFETs OptiMOS[™] and StrongIRFET[™]
- > Gate driver ICs EiceDRIVER™ or DC-DC low voltage gate driver
- > 32-bit microcontrollers XMC[™] and AURIX[™]
- > Wireless power controller (including software IP) XMC[™]-SC and AURIX[™]
- > P-channel and N-channel small signal power MOSFETs
- > High voltage power MOSFETs CoolMOS[™] superjunction MOSFETs
- > PWM/flyback controllers and integrated power stage ICs CoolSET™
- > Gallium nitride (GaN) CoolGaN™ e-mode HEMTs
- > Dedicated automotive power products MOSFETs, DC-DC, LDO, PMIC with ASIL qualification
- > Voltage and buck regulators for component and bridge supply
- > Authentication OPTIGA[™] Trust UWP

Components for inductive designs for consumer and industrial applications

Especially for the emerging higher power (15 W+) transmitter applications equipping your half- or full-bridge topologies with components from the OptiMOS[™] product family, driver ICs, and voltage regulators pays off with superior power transfer performance. Single and dual N-channel OptiMOS[™] versions with excellent R_{DS(on)} and charge characteristics are available in small footprint packages for your wireless power transmitter design. For multicoil designs, there are very suitable IR MOSFET[™] devices in 2 x 2 mm packages ready to use. In addition, Infineon's XMC[™] 32-bit industrial microcontrollers provide the flexibility to charge "just about anything". Infineon's portfolio supports individual needs by either an ARM[®] Cortex[®]-M0 core (XMC1000 family) or a Cortex[®]-M4 core with a floating point unit (XMC4000 family). In addition, wireless power controllers – XMC[™]-SC, including software IP, are available for selected applications in our portfolio (for further details check **page 261**). Ensuring that you, your data, and your devices remain secured and safe during charging, Infineon adds a new member to its OPTIGA[™] Trust family – the OPTIGA[™] Trust UWP. Infineon readily supports the WPC Qi authentication standard with an integrated turnkey solution.

System diagram: inductive wireless charging



Inductive (Qi) and low frequency transmitter solutions

Products	Voltage class	Package	Part number	R _{DS(on)} max @ V _{GS} = 4.5 V [mQ]	Recommendation		
MOSFETs	20 V	PQFN 2 x 2	IRLHS6242	11.7 (= 2.5 V drive capable)	Right fit		
	25 V		IRFHS8242	21	Right fit		
	30 V	Super SO8	BSC0996NS	11.8	Right fit		
			BSC0993ND	7	Best performance		
		PQFN 3.3 x 3.3	BSZ0589NS	4.4	Best performance		
			BSZ0994NS	8.6	Right fit		
			BSZ0909NS	15	Right fit		
		PQFN 3.3 x 3.3 dual	BSZ0909ND	25	Best performance		
			BSZ0910ND	13	Best performance		
		PQFN 2 x 2	IRFHS8342	25	Right fit		
			IRLHS6342	15.5 (= 2.5 V drive capable)	Best performance		
	40 V	PQFN 3.3 x 3.3	BSZ097N04LS	14.2	Right fit		
Driver ICs	PX3519, IRS23	01S, WCDSC006*					
Microcontroller or wireless power controller	XMC [™] MCU and wireless power controller XMC [™] -SC [*] (including software IP)						
Voltage regulators	IR3841M, IFX20002, IFX91041EJV50, IFX90121ELV50, IFX81481ELV						
Small signal MOSFETs	Please check <u>o</u>	nline ¹⁾					
Authentication	SLS32AIA020U	x – OPTIGA™ Trust UWP	(USON10 3 x 3 package	2)			

Find here additional MOSFET and driver IC offerings!

www.infineon.com/cms/en/tools/solution-finder/product-finder/gate-driver www.infineon.com/cms/en/tools/solution-finder/product-finder/mosfet-finder

61

Components for resonant designs for consumer and industrial

Infineon offers superior power MOSFET technology especially in the 30-100 V classes for class D inverter designs and in the 150-250 V voltage classes for class E inverters to address MHz switching implementations. We provide industry leading products when it comes to fast switching and have the best figure of merit for gate charge times R_{DS(on)} and for C_{oss} thus enabling our customer to achieve 6.78 MHz inverter designs using robust silicon MOSFET technology. CoolGaN[™] 600 V with low and highly linear C_{oss}, as well as low Q_c, enables high efficiency at higher power levels, especially in higher power class E designs. The CoolGaN[™] portfolio qualifying for the use in wireless charging applications will be extended by adding 100 V and 200 V products over the next years. Infineon offers the "coolest" driver ICs in the industry, already available as low-side drivers for class E implementations and very soon as level shifted half-bridge driver for class D topologies. If your transmitter design uses a pre-regulator (buck or buck/boost) to control the input voltage of your amplifier you can find OptiMOS[™] solutions in the **20-300 V MOSFETs** section. Here again, the XMC[™] industrial mircocontroller and the XMC[™]-SC wireless power controller, including software IP, are a great fit to charge "just about anything".



Make use of our evaluation boards for low cost charger and adapter applications (see **pages 34** and **36**).

Components for resonant (AirFuel) and high frequency solutions

Products	Voltage class	Package	Part number	R _{DS(on)} max @ V _{GS} = 4.5 [mQ]	Q _G typical [nC]	C _{oss} typical [pF]	Topology
MOSFETs	30 V	PQFN 2 x 2 dual	IRLHS6376PBF	48	2.8	32	Class D
		PQFN 3.3 x 3.3	BSZ0909ND	25	1.8	120	Class D
		dual	BSZ0910ND	13	5.6	230	Class D
		SOT-23	IRLML0030PBF	33	2.75	84	Class D
	40 V	SOT-23	IRLML0040	62	2.8	49	Class D
	60 V	SOT-23	IRLML0060	98	2.6	37	Class D
	80 V	PQFN 2 x 2	IRL80HS120	32	3.5	68	Class D/E
	100 V	PQFN 2 x 2	IRL100HS121	42	2.7	62	Class D/E
	150 V	PQFN 3.3 x 3.3	BSZ900N15NS3	75**	4.1**	46	Class E
		-	BSZ520N15NS3	42**	7.2**	80	Class E
	200 V		BSZ900N20NS3	78**	7.2**	52	Class E
			BSZ22DN20NS3	200**	3.5**	24	Class E
			BSZ12DN20NS3	111**	5.4**	39	Class E
	250 V		BSZ42DN25NS3	375**	3.6**	21	Class E
Driver ICs	EiceDRIVER™ 2	EDL71*, 1EDN7512	2, 2EDN7524				
	GaN EiceDRIVE	R™ ICs 1EDS5663H	I, 1EDF5673F, 1EDF	5673K			
GaN e-mode HEMT	CoolGaN™ 600	V e-mode GaN HE	MT IGT60R190D1S	(HSOF-8-3)			
Microcontroller or wireless power controller	XMC [™] MCU and	d wireless power co	ontroller XMC [™] -SC	(including software IP)			
Voltage regulators	IR3841M, IFX20	0002, IFX91041EJV	50, IFX90121ELV50,	IFX81481ELV			
Small signal MOSFETs	Please check o	nline ¹⁾					

Find here additional MOSFET and driver IC offerings!

www.infineon.com/cms/en/tools/solution-finder/product-finder/gate-driver www.infineon.com/cms/en/tools/solution-finder/product-finder/mosfet-finder 20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Packages

Wireless in-car charging (automotive)

The next generation of in-cabin wireless charging systems have to meet strict automotive safety, security, environmental and regulatory requirements while still enabling industry-leading charging performance and efficiency. Infineon's AURIX[™] microcontroller, voltage regulators, power MOSFET technologies and network ICs will easily support these requirements with a complete charging solution. With 15 W charging that meets existing standards, including fast charge smartphones, the solution easily supports future changes with a software update. Infineon's new innovative foreign object detection (FOD) system or our unique improved power drive architecture that provides unparalleled EMI performance are just two benefits out of many to address the design challenges in the automotive wireless charging market. Discover our complete offerings for in-cabin charging on a system level on **Infineon's wireless charging webpage** – something you will not find just anywhere.



System diagram: AURIX™-based wireless charger – three-coil

Automotive products for wireless charging	Voltage class	Package	Part number	R _{DS(on)} max @ V _{GS} = 4.5 V [mQ]	Q _G typical [nC]		
Inverter automotive grade MOSFETs	40 V	SuperSO8 5 x 6 Dual	IPG20N04S4-12A	15.5	9		
		S3O8 3.3 x 3.3	IPZ40N04S5L-4R8	6.7	11		
			IPZ40N04S5L-7R4	10.7	6.5		
Automotive products for wireless charging	Voltage class	Package	Part number	R _{DS(on)} max @ V _{GS} = 4.5 V [mQ]	R _{DS(on)} max @ V _{GS} = 10 V [mQ]		
Coil selection switch	60 V	TDSON-8	IPG20N06S4L-11A	15.8	11.2		
	100 V	SuperSO8 5 x 6 Dual	IPG20N10S4L-22A	28	22		
			IPG20N10S4L-35A	45	35		
			IPG16N10S4L-61A	78	61		
Microcontroller and wireless power controller	AURIX™ SAK-TC2	212S-4F100N, SAK-TC21	12S-8F133SC				
Power supply	TLD5190 – buck-boost controller/TLE8366, TLS4120x, TLS203x/TLF35584 – safety MCU supply + CAN supply						
CAN	TLE7250SJ – high performance CAN transceiver						
Drivers	AUIRS2301S	AUIRS2301S					

www.infineon.com/wirelesscharging

System solutions for wireless charging

Master your design challenges with Infineon. With our broad range of designs, customers have the possibility to make wireless charging available for different kinds of applications. For more information on the availability of our boards please visit www.infineon.com/wirelesscharging or get in contact with us via www.infineon.com/support.



Find the right solutions for your wireless charging designs in four steps

Infineon's selection tool for wireless charging allows you to find the right solutions for your designs in just four steps: select the application, power range, standard and the topology you want to apply and get an overview of Infineon's most recommended offerings.

Try now!

Gate driver ICs



Infineon support for applications

Useful links and helpful information

Learn more about our system solutions for your application. Find block diagrams, evaluation boards, interactive 3D models, videos, tools and related material for download.

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XENSIVTM sensors

Gate driver ICs

Motor control ICs

Microcontrollers

OptiMOS[™] and StrongIRFET[™] 20-300 V MOSFETs N-channel power MOSFETs

Infineon's semiconductors are designed to bring greater efficiency, power density and cost-effectiveness. The full range of OptiMOS[™] and StrongIRFET[™] power MOSFETs enables innovation and performance in applications such as switch mode power supplies (SMPS), battery powered applications, motor control and drives, inverters, and computing.

Infineon's highly innovative OptiMOS[™] and StrongIRFET[™] families consistently meet the highest quality and performance demands in key specifications for power system designs such as on-state resistance (R_{DS(on)}) and figure of merit (FOM).

OptiMOS[™] power MOSFETs provide best-in-class performance. Features include ultralow R_{DS(on)}, as well as low charge for high switching frequency applications. StrongIRFET[™] power MOSFETs are designed for drives applications and are ideal for designs with a low switching frequency, as well as those that require a high current carrying capability.

StrongIRFET™	OptiMOS™		
Robust and excellent price/performance ratio	Best-in-class technology		
Designed for industrial applications	Designed for high performance applications		
Optimized for low switching frequency	Optimized for high switching frequency		
High current carrying capability	Industry's best figure of merit		
Rugged silicon	High efficiency and power density		
a minute and a min	And		

500-950 V MOSFETs

Packages



Technology development and product family positioning

Infineon's power MOSFET 20-300 V product portfolio is divided into "active and preferred", referring to the latest technology available offering best-in-class performance, as well as "active", which consists of well-established technologies which complete this broad portfolio.

OptiMOS[™] 6 power MOSFETs 40 V are the newest addition to the OptiMOS[™] product family available either in SuperSO8 or PQFN 3.3 x 3.3 packages. This technology is the perfect solution when best-in-class (BiC) products and high efficiency over a wide range of output power are required. For the other voltage classes, from 25 V up to 150 V, OptiMOS[™] 5 represents the latest generation in the market, offering either best in class (BiC) or price/performance solutions. For high frequency applications, the product portfolio is complemented by OptiMOS[™] 3 power MOSFETs 40-50 V as standard components. The "active and preferred" OptiMOS[™] 3 power MOSFETs 75-120 V, as well as 200-300 V is the best fit portfolio either in low or high frequency applications with a range of products covering from BiC to standard parts.

StrongIRFET[™] Gen. 1 is recommended for 20-300 V applications when BiC performance is not essential and cost is a more significant consideration.

The diagrams below summarize the recommended technology for best fit standard components, price/performance and differentiated products according to switching frequency.



www.infineon.com/powermosfet-12V-300V

Motor control ICs

Packages

Guidance for applications and voltage classes

OptiMOS[™] and StrongIRFET[™] portfolio, covering 20 up to 300 V MOSFETs, can address a broad range of needs from low to high switching frequencies. The tables below provide a guidance overview for the recommended OptiMOS™ or StrongIRFET™ products for each major sub-application and voltage class.

Rec	Recommended voltage		20 V to 30 V	40 V	60 V	75 V to 80 V	100 V	135 V to 150 V	200 V	250 V	300 V
red	Low power Power tools,	OptiMOS™	\checkmark	\checkmark	\checkmark	\checkmark					
Battery powered	Multicopter, Battery, Industrial Drives	StrongIRFET™	\checkmark	\checkmark	\checkmark	\checkmark					
attery	High power	OptiMOS™			\checkmark	\checkmark	\checkmark	\checkmark	√		
B	(LEV, LSEV)	StrongIRFET™			\checkmark	\checkmark	✓	\checkmark	\checkmark		
		OptiMOS™			✓	\checkmark	√	√			
	Solar	StrongIRFET™			√	√	√				
					,	slow sw	itching	1			
		OptiMOS™	✓	✓	✓	√	√	√	√	√	√
Inverters	UDC	StrongIRFET™	√	√	√	√	√	√	√	√	✓
Inve	UPS					fast swi	tching				
		OptiMOS™	\checkmark	\checkmark	\checkmark	\checkmark	✓	\checkmark	√	✓	✓
		StrongIRFET™	\checkmark	\checkmark	\checkmark	\checkmark	√	\checkmark	√	\checkmark	\checkmark
	Offling	OptiMOS™		\checkmark	\checkmark						
	Offline	StrongIRFET™		\checkmark	\checkmark						
	Adapter /	OptiMOS™		\checkmark	\checkmark	\checkmark	√				
	Charger	StrongIRFET™		√	<i>√</i>	√	√				
		OptiMOS™		√	√						
	PC Power	StrongIRFET™		√	√						
		OptiMOS™			√	\checkmark	✓				
SMPS	LCD TV	StrongIRFET™			\checkmark	\checkmark	√				
SM		OptiMOS™		\checkmark	√	√					
	Server	StrongIRFET™		\checkmark	\checkmark	\checkmark					
		OptiMOS™				√	✓	√	✓		
	AC-DC	StrongIRFET™				√	\checkmark				
	Telesen	OptiMOS™	\checkmark	\checkmark	√	√	✓	√			
	Telecom	StrongIRFET™	✓	\checkmark	\checkmark	\checkmark	\checkmark				

500-950 V MOSFETs

OptiMOS[™] recommended

StrongIRFET[™] recommended OptiMOS[™] available

StrongIRFET[™] available

www.infineon.com/powermosfet-12V-300V

Space saving and high performance packages

TO-247	TO-220	D ² PAK	D²PAK 7-pin	TO-leadless
	N	A	ALL THE THE	

	Optimized for high power applications and high current capability						
Height [mm]	5.0	4.4	4.4	4.4	2.3		
Outline [mm]	40.15 x 15.9	29.5 x 10.0	15.0 x 10.0	15.0 x 10.0	11.68 x 9.9		
Current capability [A]	195.0	195.0	195.0	240.0	300.0		
Thermal resistance R _{thJc} [K/W]	2.0	0.5	0.5	0.5	0.4		

	SuperSO8	Power Block	PQFN 3.3 x 3.3	PQFN 2 x 2	DirectFET™
	a de la				e state
	For highest efficiency and power management	Significant design shrink	For highest efficiency and power management	Enables significant space saving	Best thermal behavior in a tiny footprint
Height [mm]	1.0	1.0	1.0	0.9	Small: 0.65 Medium: 0.65 Large: 0.71
Outline [mm]	5.15 x 6.15	5.0 x 6.0	3.3 x 3.3	2.0 x 2.0	Small: 4.8 x 3.8 Medium: 6.3 x 4.9 Large: 9.1 x 6.98
Current capability [A]	100.0	50.0	40.0	18.5	Small: 75.0 Medium: 180.0 Large: 375.0
Thermal resistance R _{thJC} [K/W]	0.8	1.5	3.2	11.1	0.5

Discrete and integrated packages

OptiMOS[™] and StrongIRFET[™] technologies are available in different packages to address the demands for higher current carrying capability and significant space saving.

The broad portfolio enables footprint reduction, boosted current rating, and optimized thermal performance. While the surface mount leadless devices enable footprint reduction, through-hole packages are characterized by a high power rating.

Furthermore, Infineon offers innovative packages such as DirectFET[™] and TO-leadless. DirectFET[™] is designed for high frequency applications by offering lowest parasitic resistance. This package is available in three different sizes: small, medium and large. TO-leadless is optimized to handle currents of up to 300 A, increasing power density with a substantial reduction in footprint.





Small signal and small power MOSFETs



Small signal and small power MOSFETs are available in eight industry-standard package types ranging from the largest SOT-223 to the smallest SOT-363.

Products are offered in single, dual and complementary configurations and are suitable for a wide range of applications, including battery protection, LED lighting, low voltage drives and DC-DC converters.

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OptiMOS™ Linear FET

Combining low on-state resistance $(R_{DS(on)})$ with wide safe operating area (SOA)

OptiMOS[™] Linear FET is a revolutionary approach to avoid the trade-off between on-state resistance (R_{DS(on)}) and linear mode capability operation in the saturation region of an enhanced mode MOSFET. It offers the state-of-the-art R_{DS(on)} of a trench MOSFET, as well as the wide safe operating area of a classic planar MOSFET.

This new product is the perfect fit for hot swap and e-fuse applications commonly found in telecom and battery management systems. OptiMOS[™] Linear FET prevents damage at the load in case of a short circuit by limiting high inrush currents.

OptiMOS[™] Linear FET is currently available in three voltage classes – 100 V, 150 V, and 200 V – in either D²PAK or D²PAK 7-pin package.

SOA comparison

Whilst the OptiMOSTM 5 100 V, 1.7 m Ω power MOSFET has a SOA of 0.5 A, the OptiMOSTM Linear FET version at the same R_{DS(on)} offers a much wider SOA of 11.5 A (@ 54 V, 10 ms).





OptiMOS[™] Linear FET $R_{DS(on)} = 1.7 \text{ m}\Omega$ 103 1 us 10 µs 10 ms 100 µs 10² 1 ms P [A] DC 10¹ 10⁰ 10-1 10-1 10⁰ 10¹ 10² 10³ $V_{DS}[V]$ 11.5 A @ 54 V t_{pulse}= 10 ms

500-950 V MOSFETs



OptiMOS[™] 6 power MOSFETs 40 V

Next generation of cutting edge MOSFETs

OptiMOS[™] 6 40 V devices are setting a new technology standard in the field of discrete MOSFET devices. Compared to alternative products, Infineon's leading thin wafer technology enables significant performance benefits compared to OptiMOS[™] 5:

- > R_{DS(on)} reduced by 30%
- > Improved FOM $Q_g x R_{DS(on)} by 29\%$
- > Improved FOM Q_{gd} x R_{DS(on)} by 46%

Infineon's OptiMOS[™] 6 power MOSFET 40 V family offers an optimized solution for synchronous rectification in switched mode power supplies (SMPS) in servers, desktop PCs, wireless and quick chargers. The improved performance in on-state resistance (R_{DS(on)}) and figure of merits (FOM - R_{DS(on)} x Q_g and Q_{gd}) yields an efficiency improvement, allowing easier thermal design and less paralleling, leading to system cost reduction. In addition, the best-in-class R_{DS(on)} makes these devices suitable for ORing circuits.

Infineon's market-leading OptiMOS[™] 6 power MOSFETs 40 V are available in two different packages:

- > SuperSO8 5 x 6 mm with $R_{DS(on)}$ ranging from 5.9 m Ω down to 0.7 m Ω
- > PQFN 3x3 3.3 x 3.3 mm with $R_{_{DS(on)}}$ ranging from 6.3 m Ω down to 1.8 m Ω





SMPS application: syncronous rectification

Application

Discrete IGBTs

Packages

www.infineon.com/optimos6
Lowest $R_{DS(on)}$ and Q_g enabling high efficiency over a wide load range in SMPS applications

In SMPS applications, OptiMOS[™] 6 is the perfect solution for high efficiency over a wide range of output power, avoiding the trade-off between low and high load conditions.

At the low output power range, where switching losses due to parasitic capacitance in the MOSFET are dominating, OptiMOS[™] 6 power MOSFET BSC010N04LS6 achieves the same efficiency as the OptiMOS[™] 5 power MOSFET BSC014N04LS at 40% lower R_{DS(on)}.

Moreover, compared to the OptiMOSTM 5 40 V 1.0 m Ω power MOSFET, the OptiMOSTM 6 generation achieves lower switching losses at high load with the same R_{DS(on)}. This combination leads to an overall efficiency optimization in low and high load operating points.



500-950 V MOSFETs

Packages

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

OptiMOS	S™ and Stron	gIRFET™ 20 V (s	uper) logic leve	el			Notebook Orisourd Vib/VRM
$\begin{array}{c} R_{\text{DS(on)}} \max \\ @ V_{\text{GS}} = 10 \text{ V} \\ [m\Omega] \end{array}$	TO-252 (DPAK)	DirectFET™	PQFN 2 x 2	PQFN 3.3 x 3.3	SuperSO8	SO-8	SOT-23
- 1		IRL6283MTRPBF			IRFH6200TRPBF		
<1		$R_{DS(on)}$ =0.65 m Ω			R _{DS(on)} =0.99 mΩ		
					BSC026N02KS G	IRF6201TRPBF	
2.4					R _{DS(on)} =2.6 mΩ	R _{DS(on)} =2.45 mΩ	
2-4	IRLR6225TRPBF	IRL6297SDTRPBF**			IRLH6224TRPBF		
	R _{DS(on)} =4.0 mΩ	R _{DS(on)} =3.8 mΩ; dual			$R_{DS(on)}$ =3.0 m Ω		
					BSC046N02KS G	IRF3717	
4-10					$R_{DS(on)}$ =4.6 m Ω	$R_{DS(on)}$ =4.4 m Ω	
			IRLHS6242TRPBF				IRLML6244 ¹⁾ ***
			R _{DS(on)} =11.7 mΩ				$R_{DS(on)}=21 \text{ m}\Omega$
> 10			IRLHS6276TRPBF**				IRLML62461) ***
			$R_{DS(on)}$ =45.0 m Ω ; dual				R _{DS(on)} =46 mΩ

punios	S™ and StrongIR					
_{DS(on)} max V _{GS} =10 V [mΩ]	DirectFET™	PQFN 2 x 2	PQFN 3.3 x 3.3	SuperSO8	SO-8	SOT-23
	IRF6718L2TRPBF R _{DS(on)} =0.7 mΩ			BSC009NE2LS R _{DS(on)} =0.9 mΩ		
<1	BSB008NE2LX R _{DS(on)} =0.8 mΩ		BSZ009NE2LS5 ²⁾ R _{DS(on)} =0.9 mΩ	BSC009NE2LS5 R _{DS(on)} =0.9 mΩ		
	03(01)		53(60)	BSC009NE2LS5I** R _{DS(on)} =0.95 mΩ		
	IRF6898MTRPBF**		BSZ010NE2LS5 ²⁾	BSC010NE2LS		
	$R_{DS(on)}$ =1.1 m Ω		R _{DS(on)} =1.0 mΩ	R _{DS(on)} =1.0 mΩ		
	BSB012NE2LXI**		BSZ011NE2LS5 ²⁾	BSC010NE2LSI**		
	$R_{DS(on)}$ =1.2 m Ω		$R_{DS(on)}=1.1 \text{ m}\Omega$	R _{DS(on)} =1.05 mΩ		
	IRF6717MTRPBF		BSZ013NE2LS5I**	BSC014NE2LSI**		
	R _{DS(on)} =1.25 mΩ		R _{DS(on)} =1.3 mΩ	R _{DS(on)} =1.4 mΩ		
	IRF6894MTRPBF**		BSZ014NE2LS5IF * **	IRFH5250D		
	$R_{DS(on)}=1.3 \text{ m}\Omega$		R _{DS(on)} =1.45 mΩ	R _{DS(on)} =1.4 mΩ		
	BSB013NE2LXI**		BSZ017NE2LS5I**	BSC015NE2LS5I**		
	$R_{DS(on)}=1.3 \text{ m}\Omega$		R _{DS(on)} =1.7 mΩ	R _{DS(on)} =1.5 mΩ		
1-2	IRF6797MTRPBF**		BSZ018NE2LS	BSC018NE2LS		
	R _{DS(on)} =1.4 mΩ		R _{DS(on)} =1.8 mΩ	R _{DS(on)} =1.8 mΩ		
	IRF6716M		BSZ018NE2LSI**	BSC018NE2LSI**		
	R _{DS(on)} =1.6 mΩ		R _{DS(on)} =1.8 mΩ	R _{DS(on)} =1.8 mΩ		
	IRF6715MTRPBF					
	R _{DS(on)} =1.6 mΩ IRF6893MTRPBF**					
	$R_{DS(on)}=1.6 \text{ m}\Omega$					
	IRF6892STRPBF**					
	$R_{DS(on)}=1.7 \text{ m}\Omega$					
	IRF6795MTRPBF**					
	$R_{DS(on)}=1.8 \text{ m}\Omega$					
	IRF6714MTRPBF		BSZ031NE2LS5	BSC024NE2LS		
	$R_{DS(on)}=2.1 \text{ m}\Omega$		$R_{DS(on)}=3.1 \text{ m}\Omega$	$R_{DS(on)}=2.4 \text{ m}\Omega$		
	BSF030NE2LQ		BSZ033NE2LS5	BSC026NE2LS5	IRF8252	
	$R_{DS(on)}$ =3.0 m Ω		$R_{DS(on)}$ =3.3 m Ω	$R_{DS(on)}$ =2.6 m Ω	$R_{DS(on)}=2.7 \text{ m}\Omega$	
~ .	BSF035NE2LQ		BSZ036NE2LS	BSC032NE2LS	55(01)	
2-4	$R_{DS(on)}$ =3.5 m Ω		$R_{DS(on)}=3.6 \text{ m}\Omega$	$R_{DS(on)}=3.2 \text{ m}\Omega$		
	IRF6811STRPBF**		BSZ037NE2LS5 ²⁾			
	$R_{DS(on)}=3.7 \text{ m}\Omega$		RDS(on)= 3.7mΩ			
			BSZ039NE2LS5 ²⁾ R _{DS(on)} = 3.9 m Ω			
	IRF6802SD					
	R _{DS(on)} =4.2 mΩ					
	IRF6710S2TRPBF		IRFHM8228TRPBF	BSC050NE2LS		
4-10	$R_{DS(on)}$ =4.5 m Ω		R _{DS(on)} =5.2 mΩ	$R_{DS(on)}$ =5.0 m Ω		
4-10	IRF6712STRPBF		BSZ060NE2LS			
	R _{DS(on)} =4.9 mΩ		R _{DS(on)} =6.0 mΩ			
	IRF6810STRPBF**		IRFHM8235TRPBF			
	$R_{DS(on)}$ =5.2 m Ω		$R_{DS(on)}=7.7 \text{ m}\Omega$			
> 10		IRFHS8242				IRFML8244

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* Optimized for resonant applications (e.g. LLC converter) ** Monolithically integrated Schottky-like diode

Part number	Package	Monolithically	$BV_{DSS}[V]$	$R_{DS(on), max.} [m\Omega]$	@ V _{gs} =4.5 V max.	Q _g [nC] @ V	_{gs} =4.5 V typ.
		integrated Schottky like diode		High-side	Low-side	High-side	Low-side
BSZ0910ND	TISON 3 x 3	-	30	13	13	4.0	4.0
BSZ0909ND	TISON 3 x 3	-	30	25	25	1.8	1.8
BSC0910NDI	TISON 5 x 6	✓	25	5.9	1.6	7.7	25.0
BSC0911ND	TISON 5 x 6	-	25	4.8	1.7	7.7	25.0
BSC0921NDI	TISON 5 x 6	✓	30	7.0	2.1	5.8	21.0
BSC0923NDI	TISON 5 x 6	✓	30	7.0	3.7	5.2	12.2
BSC0924NDI	TISON 5 x 6	✓	30	7.0	5.2	5.2	8.6
BSC0925ND	TISON 5 x 6	-	30	6.4	6.4	5.2	6.7

OptiMOS[™] and StrongIRFET[™] 25 V/30 V in Power Block 5x6 and 5x4

Part number	Package	Monolithically	$BV_{DSS}[V]$	$R_{DS(on), max.} [m\Omega]$ (@ V _{gs} =4.5 V max.	Q _g [nC] @ V	_{ss} =4.5 V typ.
		integrated Schottky like diode		High-side	Low-side	High-side	Low-side
BSG0810NDI	TISON 5 x 6	√	25	4.0	1.2	5.6	16.0
BSG0811ND	TISON 5 x 6	-	25	4.0	1.1	5.6	20.0
BSG0813NDI	TISON 5 x 6	√	25	4.0	1.7	5.6	12.0
IRFH4257DTRPBF	PQFN 5 x 4	✓	25	4.7	1.8	9.7	23.0

Discrete IGBTs

Server

Packages

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

OptiMOS	S™ and StrongIRFET™ 30 `	V logic level	UCCC ==	
R _{DS(on), max.} @ V _{GS} =10 V [mΩ]	ТО-252 (DPAK)	TO-263 (D ² PAK)	TO-263 (D ² PAK 7-pin)	TO-220
<1			IPB009N03L G R _{DS(on)} =0.95 mΩ	
1-2		IRLS3813TRLPBF $R_{DS(on)}$ =1.95 m Ω		IRLB3813PBF $R_{DS(on)}$ =1.95 m Ω
	IRLR8743TRPBF $R_{DS(on)}$ =3.1 mΩ IPD031N03L G $R_{nS(on)}$ =3.1 mΩ			$\label{eq:response} \begin{array}{l} \mbox{IRLB8314PBF} \\ \mbox{R}_{\mbox{DS(m)}}\mbox{=}2.4\mbox{ m}\Omega \\ \mbox{IRL3713PBF} \\ \mbox{R}_{\mbox{DS(m)}}\mbox{=}3.0\mbox{ m}\Omega \end{array}$
2-4	IPD040N03L G	IPB034N03L G $R_{DS(on)}$ =3.4 m Ω		IRLB8743PBF R _{D5(on)} =3.2 mΩ IPP034N03L G
4-10	$\begin{array}{l} R_{\text{DS}(on)} = \!$	IPB042N03L G RpS(on)=4.2 mΩ IPB055N03L G RpS(on)=5.5 mΩ IPB065N03L G RpS(on)=6.5 mΩ IPB080N03L G RpS(on)=8.0 mΩ		$\begin{array}{l} R_{\text{DS(on)}}=\!$
	IPD090N03L G R _{DS(on)} =9.0 mΩ			
10-25	IPD135N03L G R _{D5(on)} =13.5 mΩ IRLR3103 R _{D5(on)} =19.0 mΩ			

OptiMO	S™ and StrongIRFET	™ 30 V logic level		DC-DC Thinkourd	Meter centrel Reference
$\begin{array}{c} R_{\text{DS(on), max.}} \\ @ V_{\text{GS}} = 10 \text{ V} \\ [m\Omega] \end{array}$	Bare die $(R_{DS(on) typ})$	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	TO-Leadless
<1					IPT004N03L
				$IRFH8303TRPBF R_{DSlonj}=1.1 m\Omega BSC011N03LS R_{DSlonj}=1.1 m\Omega BSC011N03LSI** R_{DSlonj}=1.1 m\Omega BSC011N03LST D = 11 m\Omega D = 11 m\Omega D = 10 m\Omega D $	R _{DS(on)} =0.4 mΩ
1-2		IRF8301MTRPBF R _{DS(on)} =1.5 mΩ	BSZ0500NSI**	$R_{DSIom} = 1.1 mΩ$ IRFH8307TRPBF $R_{DSIom} = 1.3 mΩ$ BSC0500NSI** $R_{DSIom} = 1.3 mΩ$ BSC014N03LS G	
		IRF8302MTRPBF** R _{DS(on)} =1.8 mΩ	R _{DSIGN} =1.5 mΩ BSZ019N03LS R _{DSIGN} =1.9 mΩ BSZ0901NS R _{DSIGN} =2.0 mΩ DSC70F01NSL**	R _{oSion} =1.4 mΩ BSC0901NS R _{oSion} =1.9 mΩ BSC0501NSI** R _{oSion} =1.9 mΩ DSC0001NSI** R _{oSion} =1.9 mΩ	
	IPC055N03L3*** R _{DS(on)} =2.7 mΩ		BSZ0501NSI** R _{DS(on)} =2.0 mΩ	BSC0901NSI** R _{DS(on)} =2.0 mΩ	

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** Monolithically integrated Schottky-like diode *** $R_{_{DS(on)}}$ typ. @V_{_{GS}}=4.5 V

Mail Part of the second s	DS(on), max.	Bare die	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	SO-8	SO-8	PQFN 2 x
PCOLVED13**** Reg. 22.m0 Reg. 2.m0 Reg. 2.m0 Reg. 2	′ _{GS} =10 V	(R _{DS(on) typ.})					Dual	
PEOGANOLIS**** IRIHABZO INPERP RECOUNDATION REPAIL OF THE PERPERPORT RECOUNDATION REPAIL OF THE PERPERPERPERPERPERPERPERPERPERPERPERPERP								
Regression Regress		IDC042N02L2****	$R_{DS(on)}$ =2.2 m Ω					
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No. Result 2.5 m0		DS(on) Str This	IRF8306MTRPBF**					
Part Part Part Part Part Part Part Part			$R_{DS(on)}$ =2.5 m Ω		$R_{DS(on)}$ =2.5 m Ω			
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2-4 Image: Second								
Part of the state of				BSZ0902NSI**		IRF8788TRPBF		
2.4 Image: 1 and the second seco								
Image: 22.8 mL Regime 22.9 mL Regime 23.0 mL Regim 23.0 mL Regime 23.0 mL Regime 2	2-4				IRFH8316TRPBF			
Image: start in the s	2 7			R _{DS(on)} =2.8 mΩ				
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μ μ				B\$70503N\$I**				
Image: start of the start o								
Image: state in the second state in the sec						IRF7862TRPBF		
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4-10 IPC022N03L3 Rs20s8N03LS G Rosen=5.8 mΩ Rs20s8N03LS G Rosen=5.0 mΩ Rs20s8N03LS G Rosen=5.0 mΩ IPC022N03LS IPC02PN03LS IPC02PN02PNS								
μ μ		R _{DS(on)} =5.0 mΩ				R _{DS(on)} =4.8 mΩ		
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44-10 BSZ065N03LS R _{psiem} =6.5 mΩ R _{psiem} =6.5 mΩ R _{psiem} =6.6 mΩ BSC057N03LS G R _{psiem} =6.6 mΩ BSC057N03LS G R _{psiem} =7.3 mΩ BSC057N03LS G R _{psiem} =6.6 mΩ BSC057N03LS G R _{psiem} =7.3 mΩ BSC057N03LS G R _{psiem} =6.6 mΩ BSC057N03LS G R _{psiem} =7.0 mΩ BSC057N03LS G R _{psiem} =7.5 mΩ BSC057N03LS G R _{psiem} =8.5 mΩ BSC057N03LS G R _{psiem} =7.0 mΩ BSC057N03LS G R _{psiem} =9.2 mΩ BSC057N03LS G R _{psiem} =9.2 mΩ BSC057N03LS G R _{psiem} =12.0 mΩ BSC120N03LS G R _{psiem} =12.0 m		IPC022N03L3						
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IRFB32752 IRFHM330TRPBF IRFH333TRPBF IRFH333TRPBF IRFM330TRPBF IRFM330TRPBF IRFM330TRPBF IRFM330TRPBF IRFM330TRPBF IRFM330TRPBF IRFM330TRPBF IRFM330TRPBF IRFM34TRPBF IRFM34TRPBF IRFM334TRPBF IRFM334TRPBF IRFM334TRPBF IRFM334TRPBF IRFM34TRPBF IRFM34TRPFF IRFM34TR	- 10							
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Image: https://width BSZ088N03LS G Rosionj=8.8 mΩ BSC090N03LS G Rosionj=9.0 mΩ IRF8714TRPBF Rosionj=8.7 mΩ IRF8714TRPBF Rosionj=8.7 mΩ Image: https://width <				IRFHM831				
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ID-63 IRFM IRFM8337TRPBF IRFM8337TRPBF IRFM337TRPBF IRL6342 ¹ IREA IRF8513TRPBF IRFM8337TRPBF 10-63 BSZ130N03LS G BSZ130N03LS G Rgs(m)=12.8 mΩ IRL6372 ¹ IRF8313TRPBF IRFM333TRPBF IRFM337TRPBF IRF8513TRPBF IRFM333TRPBF IRFM337TRPBF IRFM337TRPBF IRFM337TRPBF IRFM337TRPBF IRFM333TRPBF IRFM337TRPBF IRFM333TRPBF IRFM335TRPBF IRS050m195 IRFM335TRPBF								
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ID-53 BSZ130N03LS G R _{DS(on)} =13.0 mΩ IRL6372 ¹⁾ *** IRF8313TRPBF R _{DS(on)} =15.5 mΩ+15.5 mΩ IRLHS6376** IRF IRFHM8363TRPBF R _{DS(on)} =14.9 mΩ IRF4000000000000000000000000000000000000								
	10-63							IRLHS6376***
IRFHM8363TRPBF R _{DS[on]} =14.9 mΩ IRF7905TRPBF R _{DS[on]} =17.1 mΩ+21.8 mΩ 2 x 7.2 BSC072N03LD G R _{DS[on]} =7.2 mΩ BSC072N03LD G R _{DS[on]} =7.2 mΩ								
BSC072N03LD G R _{DSI07} =7.2 mΩ				IRFHM8363TRPBF			IRF7905TRPBF	
2 x 7.2 R _{oS(on} =7.2 mΩ				R _{DS(on)} =14.9 mΩ			$R_{DS(on)}$ =17.1 m Ω +21.8 m Ω	
$R_{\text{DS(on)}} = 1.2 \text{ m}\Omega$	2 x 7.2							

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

www.infineon.com/powermosfet-12V-300V *** $R_{DS(on)} \max @V_{GS}=4.5 V$ **** $R_{DS(on)} typ. @V_{GS}=4.5 V$

Packages

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIV[™] sensors

OptiMOS	5™ and StrongIRF	ET™ 30 V logic lev	vel 5 V optimized			er Herebook
R _{DS(on), max.} @V _{GS} =10 V [mΩ]	PQFN 3.3 x 3.3	SuperSO8	SO-8	SO-8 Dual	SOT-23	TSOP-6
1-2		$\begin{array}{c} BSC014N03MSG\\ R_{_{DS(on)}}=1.4m\Omega\\ BSC016N03MSG\\ R_{_{DS(on)}}=1.6m\Omega\\ BSC020N03MSG\\ R_{_{DS(on)}}=2.0m\Omega\\ \end{array}$				
2-4	BSZ035N03MS G R _{DS(on)} =3.5 mΩ	BSC025N03MS G R _{DS(on)} =2.5 mΩ BSC030N03MS G R _{DS(on)} =3.0 mΩ	BSO033N03MS G R _{DS(on)} =3.3 mΩ BSO040N03MS G R _{DS(on)} =4.0 mΩ			
4-10	BSZ050N03MS G R _{DS(on)} =5.0 mΩ BSZ058N03MS G R _{DS(on)} =5.8 mΩ BSZ088N03MS G R _{DS(on)} =8.8 mΩ BSZ100N03MS G R _{DS(on)} =10.0 mΩ	$\begin{array}{c} BSC042N03MSG\\ R_{DS(on)}=4.2m\Omega\\ BSC050N03MSG\\ R_{Ds(on)}=5.0m\Omega\\ BSC057N03MSG\\ R_{DS(on)}=5.7m\Omega\\ BSC080N03MSG\\ R_{DS(on)}=8.0m\Omega\\ BSC090N03MSG\\ R_{DS(on)}=9.0m\Omega\\ BSC100N03MSG\\ R_{DS(on)}=9.0m\Omega\\ BSC100N03MSG\\ R_{DS(on)}=10.0m\Omega\\ \end{array}$				
>10	BSZ130N03MS G R _{DS(on)} =13.0 mΩ	BSC120N03MS G R _{DS(on)} =12.0 mΩ	BSO110N03MS G R _{DS(on)} =11.0 mΩ		$\label{eq:resonance} \begin{array}{l} \text{IRLML0030} \\ R_{\text{DS}(on)} = 27 \ \text{m}\Omega \\ \text{IRLML6344}^{11} * * * * \\ R_{\text{DS}(on)} = 29 \ \text{m}\Omega \\ \text{IRLML6346}^{11} * * * * \\ R_{\text{DS}(on)} = 63 \ \text{m}\Omega \\ \text{IRLML2030} \\ R_{\text{DS}(on)} = 100 \ \text{m}\Omega \end{array}$	$\begin{array}{l} \text{IRLTS6342}^{\star\star\star} \\ \text{R}_{\text{DS(cm)}} = 14.6 \text{ m}\Omega \\ \text{IRFTS8342} \\ \text{R}_{\text{DS(cm)}} = 19 \text{ m}\Omega \end{array}$
2 x 15				BSO150N03MD G R _{DS(on)} =15.0 mΩ BSO220N03MD G		
2 x 22				BSO220N03MD G R _{DS(on)} =22.0 mΩ		

× =	Battery	Consumer	DC-DC	Electric Toys	Industrial Drives	
-	PC Power	Power Tools	Server	SMPS	Solar	UPS

OptiMOS[™] and StrongIRFET[™] 40 V normal level

							AC-DC	Battery Consumer	DC-DC Electric Toys Server SMPS	Induttrial Drives
OptiMO	S™ and St	rongIRFET	™ 40 V noi	mal level						
$R_{DS(on), max.}$ @V _{GS} =10 V [mΩ]	TO-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D²PAK 7-pin)	TO-220	TO-247	Bare die (R _{DS(on) typ.})	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	TO-220 FullPAK
<1			IRFS7430TRL7PP R _{DS(op)} =0.75 mΩ			IPC218N04N3 R _{DS(op)} =0.9 mΩ				
		$\label{eq:response} \begin{array}{l} IRFS7430TRLPBF \\ R_{DS(on)} = 1.3 \ m\Omega \\ \\ IPB015N04N \ G \\ R_{DS(on)} = 1.5 \ m\Omega \end{array}$		IRFB7430PBF $R_{DS(on)}$ =1.3 m Ω IPP015N04N G $R_{DS(on)}$ =1.5 m Ω	$\begin{array}{c} \text{IRFP7430PBF} \\ \text{R}_{\text{DS(on)}} = 1.3 \text{ m}\Omega \end{array}$	IPC171N04N R _{DS(on)} =1.1 mΩ	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		$\label{eq:started} \begin{split} & \text{IRFH7084TRPBF} \\ & \text{R}_{\text{DS(on)}} = 1.25 \text{ m}\Omega \\ & \text{IRFH7004TRPBF} \\ & \text{R}_{\text{DS(on)}} = 1.4 \text{ m}\Omega \end{split}$	
1-2		$\frac{R_{DS(on)}}{R_{DS(on)}=1.75 \text{ m}\Omega}$ $\frac{RFS7434TRLPBF}{R_{DS(on)}=1.6 \text{ m}\Omega}$	IRFS3004-7P R _{DS(on)} =1.25 mΩ	IRFB7434PBF R _{DS(on)} =1.6 mΩ			$\frac{(RF7946TRPBF)}{(RF7946TRPBF)}$ $\frac{(RF7946TRPBF)}{(R_{DS(on)})}$ $= 1.4 m\Omega$ $\frac{(RF7946TRPBF)}{(R_{DS(on)})}$ $= 1.5 m\Omega$		$\frac{R_{DS(on)}}{R_{DS(on)}=1.7 \text{ m}\Omega}$ $RF40H210$ $R_{DS(on)}=1.7 \text{ m}\Omega$	
	IRFR7440TRPBF	RFS7437TRLPBF R _{DS(on)} =1.8 mΩ		R _{DS(on)} =1.0 mΩ IRFB7437PBF R _{DS(on)} =2.0 mΩ IPP023N04N G			$R_{DS(on)}$ = 1.5 mΩIRF40DM229 $R_{DS(on)}$ = 1.85 mΩIRF7483MTRPBF		$R_{DS(on)}$ =1.7 HM2 BSC019N04NS G $R_{DS(on)}$ =1.9 mΩ IRFH7440TRPBF	
2-4	$\frac{R_{DS(on)}=2.4 \text{ m}\Omega}{\text{IRFR7446TRPBF}}$ $R_{DS(on)}=3.9 \text{ m}\Omega$	IRFS7440TRLPBF R _{DS(on)} =2.5 mΩ IRF1404S		$R_{DS(on)} = 2.3 mΩ$ IRFB7440PBF $R_{DS(on)} = 2.5 mΩ$ IRFB7446PBF			$R_{DS(on)}$ =2.3 mΩ		$\begin{array}{l} R_{DS(on)}=2.4 \text{ m}\Omega\\ BSC030N04NS \text{ G}\\ R_{DS(on)}=3.0 \text{ m}\Omega\\ IRFH7446TRPBF \end{array}$	
	IRF40R207	R _{DS(on)} =4.0 mΩ		$R_{DS(on)}$ =3.3 mΩ IPP041N04N G $R_{DS(on)}$ =4.1 mΩ IRF40B207					$\begin{array}{l} R_{\text{DS(on)}} = 3.3 \ m\Omega \\ \text{BSC054N04NS G} \\ R_{\text{DS(on)}} = 5.4 \ m\Omega \end{array}$	IPA041N04N G R _{DS(on)} =4.1 mΩ
4-10	$R_{DS(on)}$ =5.1 mΩ			$\frac{R_{DS(on)}=4.5 \text{ m}\Omega}{\text{IPP048N04N G}}$ R _{DS(on)} =4.8 mΩ						
>10								BSZ105N04NS G R _{DS(on)} =10.5 mΩ BSZ165N04NS G R _{DS(on)} =16.5 mΩ		

1) 2.5 $V_{\mbox{\tiny GS}}$ capable *** $R_{\mbox{\tiny DS(on)}}$ max @ $V_{\mbox{\tiny GS}}$ =4.5 V

<image/> Mathematical Strong REFT ^{MA} 40 V logic Level No.223 No.223 No.220 No.224 No.226 No.225 No.226 No.225 No.226 No.225 No.226	Applications	20-300 V MOSFETs	500-950 V MOSFETs	WBG semiconductors				
TO-252 (DPAK) TO-263 (D ² PAK 7-pin) TO-220 TO-247 DirectFET [™] PQFN 3.3 x 3.3 IRL40SC228 R _{DS(on)} =0.65 mΩ IRL7472L1TRPBF R _{DS(on)} =0.45 mΩ IRL7472L1TRPBF R _{DS(on)} =0.45 mΩ IRL40SC209 IRL40SC209 R _{OS(on)} =0.8 mΩ IRL40SC209 IRL40SC209 IRL40SC209 R _{DS(on)} =0.45 mΩ IRL40SC209 IRL40SC209								3SC010N04LS R _{DS(on)} =1.0 mΩ 3SC010N04LS6 R _{DS(on)} =1.0 mΩ
TO-252 (DPAK) TO-263 (D ² PAK) TO-263 (D ² PAK 7-pin) TO-220 TO-247 DirectFET™ IRL40SC228 R _{DS(on)} = 0.65 mΩ IRL7472L1TRPBF R _{DS(on)} = 0.45 mΩ IRL7472L1TRPBF R _{DS(on)} = 0.45 mΩ			*	CCC Bittery Course	-			
TO-252 (DPAK) TO-263 (D*PAK) TO-263 (D*PAK 7-pin) TO-220 TO-247 IRL40SC228 R _{05(on)} =0.65 mΩ IRL40SC209 R _{os(on)} =0.8 mΩ IRL40SC209 IRL40SC209 <td< td=""><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td>$\begin{array}{l} \text{BSB014N04LX3 G} \\ \text{R}_{\text{DS(on)}} = 1.4 \text{ m}\Omega \\ \\ \text{IRL7486MTRPBF} \\ \text{R}_{\text{DS(on)}} = 1.4 \text{ m}\Omega \end{array}$</td></td<>								$\begin{array}{l} \text{BSB014N04LX3 G} \\ \text{R}_{\text{DS(on)}} = 1.4 \text{ m}\Omega \\ \\ \text{IRL7486MTRPBF} \\ \text{R}_{\text{DS(on)}} = 1.4 \text{ m}\Omega \end{array}$
TO-252 (DPAK) TO-263 (D ² PAK) TO-263 (D ² PAK 7-pin) TO-220 IRL40SC228 R _{D5(on)} =0.65 mΩ IRL40SC209 R _{o5(on)} =0.8 mΩ IRL40SC209			1		TO-247		L	$\label{eq:linear} \begin{array}{l} \text{IRLP3034PBF} \\ \text{R}_{\text{DS(on)}} \texttt{=} \texttt{1.7} \ \text{m} \Omega \end{array}$
TO-252 (DPAK) TO-263 (D*PAK) TO-263 (D*PAK 7-pin) IRL40SC228 R _{D5(on)} = 0.65 mΩ IRL40SC209				evel	TO-220			IRL40B209 R _{DS(on)} =1.25 mΩ IRLB3034PBF R _{DS(on)} =1.7 mΩ
TO-252 TO-263 (DPAK) (D²PAK)	5	-	N	10 V logic le	(D²PAK 7-pin)	R _{DS(on)} =0.65 mΩ IRL40SC209		$\frac{\text{IPB011N04L G}}{\text{IPB011N04L G}}$ $\frac{\text{R}_{\text{DS(on)}}=1.1 \text{ m}\Omega}{\text{IRLS3034TRL7P}}$ $\frac{\text{R}_{\text{DS(on)}}=1.4 \text{ m}\Omega}{\text{R}_{\text{DS(on)}}=1.4 \text{ m}\Omega}$
TO-252				ongIRFET™4	TO-263 (D²PAK)		1	$\label{eq:states} \begin{array}{l} \text{IPB015N04L G} \\ \text{R}_{\text{DS(on)}} = 1.5 \ \text{m}\Omega \\ \\ \text{IRLS3034TRLPBF} \\ \text{R}_{\text{DS(on)}} = 1.7 \ \text{m}\Omega \end{array}$
				™ and Strc				

IRL40B215

 $R_{DS(on)}$ =2.7 m Ω

IPP039N04L G

 $R_{\text{DS(on)}}$ =3.9 m Ω

Motor control ICs

BSC016N04LS G R_{DS(on)}=1.6 mΩ

BSC018N04LS G

R_{DS(on)}=1.8 mΩ BSC019N04LS

 $\begin{aligned} R_{DS(on)} = 1.9 \text{ m}\Omega \\ BSC019N04LST \\ R_{DS(on)} = 1.9 \text{ m}\Omega \end{aligned}$

BSC022N04LS

 $R_{DS(on)}$ =2.2 m Ω

 $\begin{array}{l} BSC022N04LS6 \\ R_{_{DS(on)}} = 2.2 \ m\Omega \end{array}$

BSC026N04LS

 $R_{DS(on)}$ =2.6 m Ω

 $\begin{array}{l} BSC032N04LS \\ R_{_{DS(on)}}=3.2\ m\Omega \\ BSC035N04LS\ G \end{array}$

 $R_{DS(on)}$ =3.5 m Ω

 $R_{_{DS(on)}}{=}5.0\ m\Omega$

 $R_{DS(on)}$ =5.9 m Ω

BSC059N04LS6 R_{DS(on)} =5.9 m Ω

BSC093N04LS G

 $R_{\text{DS(on)}}$ =9.3 m Ω

BSC050N04LS G

BSC059N04LS G

BSC027N04LS G R_{DS(on)}=2.7 m Ω

BSZ018N04LS6

BSZ021N04LS6

 $R_{DS(on)}$ =2.1 m Ω

BSZ024N04LS6 R_{DS(on)} =2.4 mΩ

BSZ025N04LS

 $R_{DS(on)}=2.5 \text{ m}\Omega$

BSZ028N04LS

 $R_{DS(on)}$ =2.8 m Ω

BSZ034N04LS

 $R_{DS(on)}=3.4 \text{ m}\Omega$

BSZ040N04LS G

 $R_{\text{DS(on)}}$ =4.0 m Ω

BSZ063N04LS6

 $R_{\text{DS(on)}}$ =6.3 m Ω

BSZ097N04LS G

 $R_{\text{DS(on)}}$ =9.7 m Ω

 $R_{_{DS(on)}}{=}1.8\ m\Omega$

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IRL1404S

 $R_{DS(on)}$ =4.0 m Ω

3) Coming soon * Increased creepage distance

IPD036N04L G

 $R_{DS(op)}=3.6 \text{ m}\Omega$

 $R_{_{DS(on)}}$ =4.5 m Ω

IRLR31142TRPBF

2-4

4-10

R

€ =

^{DS(on), max.} / _{GS} =10 V [mΩ]	TO-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D²PAK 7-pin)	TO-262 (I²PAK)	TO-220	TO-220 FullPAK	TO-247
			IPB010N06N ²⁾ R _{DS(on)} =1.0 mΩ				
			IRFS7530TRL7PP R _{DS(on)} =1.4 mΩ				
1-2			IPB014N06N ²⁾ R _{DS(on)} =1.4 mΩ				
			IPB017N06N3 G R _{DS(on)} =1.7 mΩ				
		IRFS7530TRLPBF $R_{DS(on)}$ =2.0 m Ω	$\begin{array}{l} \text{IRFS7534TRL7PP} \\ \text{R}_{\text{DS(on)}} = 1.95 \text{ m}\Omega \end{array}$	IPI020N06N ²⁾ R _{DS(on)} =2.0 mΩ	IRFB7530PBF $R_{DS(on)}$ =2.0 m Ω		$\begin{array}{l} \text{IRFP7530PBF} \\ \text{R}_{\text{DS(on)}} = 2.0 \text{ m}\Omega \end{array}$
	$\frac{\text{IPD025N06N}^{2}}{\text{R}_{\text{DS(on)}}\text{=}2.5\ \text{m}\Omega}$	$\begin{array}{l} \text{IRFS7534TRLPBF} \\ \text{R}_{\text{DS(on)}} = 2.4 \ \text{m}\Omega \end{array}$	$\begin{array}{l} \text{IRFS3006TRL7PP} \\ \text{R}_{\text{DS(on)}} = 2.1 \ \text{m}\Omega \end{array}$		IPP020N06N ²⁾ R _{DS(on)} =2.0 mΩ		
		IRFS3006 R _{DS(on)} =2.5 mΩ		IPI024N06N3 G R _{DS(on)} =2.4 mΩ	IRFB7534PBF R _{DS(on)} =2.4 mΩ		
		IPB026N06N ²⁾ R _{DS(on)} =2.6 mΩ			IPP024N06N3 G ²⁾ R _{DS(on)} =2.4 mΩ		IRFP3006PBF $R_{DS(on)}$ =2.5 m Ω
2-4		IPB029N06N3 G R _{DS(on)} =2.9 mΩ		IPI029N06N ²⁾ R _{DS(on)} =2.9 mΩ	$\frac{IPP029N06N^{2)}}{R_{DS(on)}}=2.9\ m\Omega$	IPA029N06N ²⁾ R _{DS(on)} =2.9 mΩ	IRFP3206PBF $R_{DS(on)}$ =3.0 m Ω
2-4	IPD033N06N ²⁾ R _{DS(on)} =3.3 mΩ	IRFS3206 R _{DS(on)} =3.0 mΩ		IPI032N06N3 G R _{DS(on)} =3.2 mΩ	IPP032N06N3 G R _{DS(on)} =3.2 mΩ	IPA032N06N3 G R _{DS(on)} =3.2 mΩ	
	IPD034N06N3 G R _{DS(on)} =3.4 mΩ	IRFS7537TRLPBF $R_{DS(on)}$ =3.3 m Ω			IRFB7537PBF R _{DS(on)} =3.3 mΩ		IRFP7537PBF R _{DS(on)} =3.3 mΩ
	IPD038N06N3 G R _{DS(on)} =3.8 mΩ	IPB037N06N3 G R _{DS(on)} =3.7 mΩ			IPP040N06N3 G R _{DS(on)} =4.0 mΩ		
		IRFS3306 R _{DS(on)} =4.2 mΩ		IPI040N06N3 G R _{DS(on)} =4.0 mΩ	$\frac{\text{IPP040N06N}^{2)}}{\text{R}_{\text{DS(on)}}\text{=}4.0\ \text{m}\Omega}$	IPA040N06N ² R _{DS(on)} =4.0 mΩ	
	IRFR7540TRPBF R _{DS(on)} =4.8 mΩ	IRFS7540TRLPBF $R_{DS(on)}$ =5.1 m Ω			IRFB7540PBF R _{DS(on)} =5.1 mΩ	IPA057N06N3 G R _{DS(on)} =5.7 mΩ	
	IPD053N06N ²⁾ R _{DS(on)} =5.3 mΩ	IPB054N06N3 G R _{DS(on)} =5.4 mΩ			IPP057N06N3 G ²⁾ R _{DS(on)} =5.7 mΩ		
4-10		IPB057N06N ² R _{DS(on)} =5.7 mΩ			IRFB7545PBF R _{DS(on)} =5.9 mΩ		
	IRFR7546TRPBF $R_{DS(on)}$ =7.9 mΩ	IRF1018ES R _{DS(on)} =8.4 mΩ			IPP060N06N ²⁾ R _{DS(on)} =6.0 mΩ	IPA060N06N ² $R_{DS(on)} = 6.0 mΩ$	
	IPD088N06N3 G R _{DS(on)} =8.8 mΩ IRF60R217	IPB090N06N3 G			IRF60B217 R _{DS(on)} =9.0 mΩ IPP093N06N3 G	IPA093N06N3 G R _{DS(on)} =9.3 mΩ	
	$R_{DS(on)}$ =9.9 mΩ	$R_{DS(on)}$ =9.0 mΩ IRFS3806			$R_{DS(on)}=9.3 \text{ m}\Omega$		
>10		$R_{DS(on)} = 15.8 \text{ m}\Omega$					

2) 6 V rated ($R_{\scriptscriptstyle DS(on)}$ also specified @ $V_{\scriptscriptstyle GS}{=}6$ V)

Motor control ICs

Microcontrollers

XENSIVTM sensors

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

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Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

)ptiMO	S™ and StrongIRF	ET™ 60 V normal level			
R _{DS(on), max.} @V _{GS} =10 V [mΩ]	Bare die (R _{DS(on) typ.})	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	TO-Leadless
<1					IPT007N06N ²⁾
				Decenteries	$R_{DS(on)} = 0.7 \text{ m}\Omega$
	IPC218N06N3	IRF7749L1TRPBF		BSC012N06NS	IPT012N06N ²⁾
	R _{DS(on)} =1.3 mΩ	R _{DS(on)} =1.5 mΩ		$R_{DS(on)} = 1.2 \text{ m}\Omega$	R _{DS(on)} =1.2 mΩ
				BSC014N06NS ²⁾	
				$R_{DS(on)} = 1.4 \text{ m}\Omega$	
				BSC014N06NST ²⁾	
1-2				$R_{DS(on)} = 1.45 \text{ m}\Omega$	
				BSC016N06NST ²⁾	
				$R_{DS(on)} = 1.6 \text{ m}\Omega$	
				BSC016N06NS ²⁾	
				R _{DS(on)} =1.6 mΩ	
				BSC019N06NS ²⁾	
				$R_{DS(on)} = 1.9 \text{ m}\Omega$	
		IRF7748L1TRPBF		BSC028N06NS ²⁾	
		R _{DS(on)} =2.2 mΩ		R _{DS(on)} =2.8 mΩ	
				BSC028N06NST ²⁾	
		BSB028N06NN3 G		R _{DS(on)} =2.8 mΩ BSC031N06NS3 G	
2-4		R _{DS(on)} =2.8 mΩ IRF60DM206		R _{DS(on)} =3.1 mΩ IRFH7085TRPBF	
		R _{DS(on)} =2.9 mΩ		R _{DS(on)} =3.2 mΩ BSC034N06NS ²⁾	
		IRF7580MTRPBF		R _{DS(on)} =3.4 mΩ BSC039N06NS ²⁾	
		$R_{DS(on)} = 3.6 \text{ m}\Omega$		$R_{DS(on)}$ = 3.9 m Ω	
		IRF6648	BSZ042N06NS ²⁾	IRLH5036TRPBF	
		$R_{DS(on)} = 7.0 \text{ m}\Omega$	$R_{DS(on)} = 4.2 \text{ m}\Omega$	$R_{DS(on)} = 4.4 \text{ m}\Omega$	
		IRF6674	T(DS(on)	IRFH7545TRPBF	
		$R_{DS(on)}$ =11.0 mΩ		$R_{DS(on)}$ =5.2 mΩ	
		US(on)	BSZ068N06NS ²⁾	BSC066N06NS ²⁾	
			$R_{DS(on)} = 6.8 \text{ m}\Omega$	$R_{DS(on)} = 6.6 \text{ m}\Omega$	
4-10			US(OR)	BSC076N06NS3 G	
				$R_{\text{DS(on)}} = 7.6 \text{ m}\Omega$	
			BSZ100N06NS ²⁾	BSC097N06NS ²⁾	
			$R_{DS(on)} = 10.0 \text{ m}\Omega$	$R_{DS(on)}=9.7 \text{ m}\Omega$	
			05(01)	BSC097N06NST ²⁾	
				$R_{\text{DS(on)}}=9.7 \text{ m}\Omega$	
			BSZ110N06NS3 G	BSC110N06NS3 G	
>10			$R_{\text{DS(on)}}=11.0 \text{ m}\Omega$	$R_{DS(on)}=11.0 \text{ m}\Omega$	

OptiMO	S™ and Str	ongIRFET	™ 60 V logi	c level				Battery		Industrial December 2010 Solar Sol
$\begin{array}{c} R_{\text{DS(on), max.}} \\ @V_{\text{GS}} = 10 \text{ V} \\ [m\Omega] \end{array}$	TO-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D²PAK 7-pin)	TO-262 (I²PAK)	TO-220	Bare die (R _{DS(on) typ.})	PQFN 2 x 2	PQFN 3.3 x 3.3	SuperSO8	SOT-23
1-2		$\begin{array}{l} \text{IPB019N06L3 G} \\ \text{R}_{\text{DS(on)}} = 1.9 \ \text{m}\Omega \end{array}$	$\begin{array}{l} \text{IPB016N06L3 G} \\ \text{R}_{_{\text{DS(on)}}}\text{=}1.6 \text{ m}\Omega \end{array}$			IPC218N06L3 R _{DS(on)} =1.2 mΩ			$\frac{\text{BSC014N06LS5}}{\text{R}_{\text{DS(on)}}=1.4\ \text{m}\Omega}$	
		IRL60S216 R _{DS(on)} =1.95 mΩ		IRL60SL216 R _{DS(on)} =1.95 mΩ	IRL60B216 R _{DS(on)} =1.9 mΩ					
2-4		IRLS3036TRLPBF R _{DS(on)} =2.4 mΩ			IRLB3036PBF R _{DS(on)} =2.4 mΩ				BSC027N06LS5 R _{DS(on)} =2.7 mΩ	
2-4	IPD031N06L3 G R _{DS(nn)} =3.1 mΩ	IPB034N06L3 G R _{DS(op)} =3.4 mΩ			IPP037N06L3 G R _{DS(op)} =3.7 mΩ				BSC028N06LS3 G R _{DS(op)} =2.8 mΩ	
	IPD048N06L3 G R _{DS(on)} =4.8 mΩ				IPP052N06L3 G R _{DS(on)} =5.2 mΩ			BSZ040N06LS5 R _{DS(on)} =4.0 mΩ	IRLH5036TRPBF $R_{DS(op)}$ =4.4 m Ω	
	IRLR3636TRPBF R _{DS(nn)} =6.8 mΩ							BSZ065N06LS5 R _{DS(on)} =6.5 mΩ	BSC065N06LS5 R _{DS(op)} =6.5 m Ω	
4-10	IPD079N06L3 G R _{DS(on)} =7.9 mΩ	IPB081N06L3 G R _{DS(on)} =8.1 mΩ		IPI084N06L3 G R _{DS(op)} =8.4 mΩ	IPP084N06L3 G R _{DS(op)} =8.4 mΩ			BSZ067N06LS3 G R _{DS(on)} =6.7 mΩ	BSC067N06LS3 G R _{DS(op)} =6.7 mΩ	
								BSZ099N06LS5 R _{DS(op)} =9.9 mΩ	BSC094N06LS5 R _{DS(op)} = 9.4 m Ω	
								BSZ100N06LS3 G R _{DS(on)} =10.0 mΩ		
>10	IPD350N06L G R _{DS(on)} =35.0 mΩ						IRL60HS118 R _{DS(on)} =17.0 mΩ			IRLML0060 R _{DS(on)} =92 mΩ
. 10										IRLML2060 R _{DS(on)} =480 mΩ

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2) 6 V rated ($R_{\mbox{\tiny DS(on)}}$ also specified @ $V_{\mbox{\tiny GS}}$ = 6 V) 3) Coming soon

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

OptiMO	S™ and Stror	ngIRFET™ 75	V normal lev	el			Contente Contente Peret Total Peret Total Server Server S	
R _{DS(on), max.} @V _{GS} =10 V [mΩ]	TO-252 (DPAK)	ТО-263 (D²РАК)	TO-263 (D ² PAK 7-pin)	TO-220	TO-247	Bare die (R _{DS(on) typ.})	DirectFET™	SuperSO8
1-2		IPB020NE7N3 G R _{DS(op)} =2.0 mΩ	IRFS7730TRL7PP R _{DS(on)} =2.0 mΩ		IRFP7718PBF R _{DS(on)} =1.8 mΩ	IPC302NE7N3 R _{DS(on)} =1.2 mΩ		
2-4		$[RFS7730TRLPBF] \\ R_{DS(cm]} = 2.6 \ m\Omega \\ [PB031NE7N3 \ G] \\ R_{DS(cm]} = 3.1 \ m\Omega \\ [RFS7734TRLPBF] \\ R_{DS(cm]} = 3.5 \ m\Omega \\ [RFS704DF] \\ R_{DS(cm]} = 3.5 \ m\Omega \\ R_{DS(cm]} = 3.5 $	IRFS7734TRL7PP R _{DS(on)} =3.05 mΩ	$\begin{array}{l} \text{IPP023NE7N3 G} \\ \text{R}_{\text{DS(on)}} = 2.3 \ \text{m}\Omega \\ \text{IRFB7730PBF} \\ \text{R}_{\text{DS(on)}} = 2.6 \ \text{m}\Omega \\ \text{IPP034NE7N3 G} \\ \text{R}_{\text{DS(on)}} = 3.4 \ \text{m}\Omega \\ \text{IRFB7734PBF} \\ \text{R}_{\text{DS(on)}} = 3.5 \ \text{m}\Omega \end{array}$				BSC036NE7NS3 G R _{DS(on)} =3.6 mΩ
4-10	IRFR7740TRPBF R _{DS(on)} =7.2 mΩ	IPB049NE7N3 G R _{b5(on)} =4.9 mΩ IRFS7762TRLPBF R _{b5(on)} =6.7 mΩ IRFS7787TRLPBF		IPP052NE7N3 G $R_{DS(on)}$ =5.2 mΩ IPP062NE7N3 G $R_{DS(on)}$ =6.2 mΩ IRFB7740PBF $R_{DS(on)}$ =7.3 mΩ IRFB7787PBF			IRF7780MTRPBF R _{DS(on)} =5.7 mΩ	BSC042NE7NS3 G R _{DS(on)} =4.2 mΩ
>10	IRFR7746TRPBF R _{DS(on)} =11.2 mΩ	R _{DS(on)} =8.4 mΩ		$R_{DS(on)} = 8.4 \text{ m}\Omega$ $IRFB7746PBF$ $R_{DS(on)} = 10.6 \text{ m}\Omega$			BSF450NE7NH3 ¹⁾ R _{DS(on)} =45.0 mΩ	R _{DS(on)} =8.0 mΩ

	Adapter	Battery			Electric Toys	Industrial Drives	
Motor control	Offline - +	PC Power	Power Tools	Server	SMPS	Solar	

OptiMO:	S™ and S	trongIRF	ET™ 80 V	′ normal	level – lo	gic level				Power Tools Serve		
$\begin{array}{c} R_{\text{DS(on), max.}} \\ @V_{\text{GS}} = 10 \text{ V} \\ [m\Omega] \end{array}$	TO-252 (DPAK)	TO-263 (D ² PAK)	TO-263 (D ² PAK 7-pin)	TO-262 (I²PAK)	TO-220	TO-220 FullPAK	Bare die (R _{DS(on) typ.})	DirectFET™	PQFN 2 x 2	PQFN 3.3 x 3.3	SuperSO8	TO-Leadless
		IPB017N08N5	IPB015N08N5				IPC302N08N3					IPT012N08N5
1-2		$R_{DS(on)}=1.7 \text{ m}\Omega$	$R_{DS(on)}$ =1.5 m Ω				$R_{DS(on)}$ =1.2 m Ω					$R_{DS(on)}$ =1.2 m Ω
12		IPB020N08N5	IPB019N08N3 G		IPP020N08N5						BSC021N08NS5	
		$R_{DS(on)}$ =2.0 m Ω	R _{DS(on)} =1.9 mΩ		R _{DS(on)} =2.0 mΩ						$R_{DS(on)}$ =2.1 m Ω	
		IPB024N08N5			IPP023N08N5						BSC025N08LS5	
		$R_{DS(on)}$ =2.4 m Ω			$R_{DS(on)}$ =2.3 m Ω						$R_{\text{DS(on)}}$ =2.5 m Ω	
		IPB025N08N3 G	IPB030N08N3 G		IPP027N08N5						BSC026N08NS5	
		$R_{DS(on)}$ =2.5 m Ω	$R_{DS(on)}$ =3.0 m Ω		$R_{DS(on)}$ =2.7 m Ω						$R_{\text{DS(on)}}$ =2.6 m Ω	
					IPP028N08N3 G	IPA028N08N3 G					BSC030N08NS5	IPT029N08N5
2.4					R _{DS(on)} =2.8 mΩ	R _{DS(on)} =2.8 mΩ					$R_{DS(on)}$ =3.0 m Ω	$R_{DS(on)}$ =2.9 m Ω
2-4		IPB031N08N5			IPP034N08N5						BSC037N08NS5	
		$R_{DS(on)}$ =3.1 m Ω			R _{DS(on)} =3.4 mΩ						$R_{DS(on)}$ =3.7 m Ω	
											BSC037N08NS5T	
											$R_{DS(on)}$ = 3.7 m Ω	
		IPB035N08N3 G		IPI037N08N3 G	IPP037N08N3 G	IPA037N08N3 G					BSC040N08NS5	
		$R_{DS(on)}$ =3.5 m Ω		$R_{DS(on)}$ =3.7 m Ω	$R_{DS(on)}$ =3.7 m Ω	$R_{DS(on)}=3.7 \text{ m}\Omega$					$R_{DS(on)}$ =4.0 m Ω	
	IPD046N08N5	IPB049N08N5			IPP052N08N5			BSB044N08NN3 G			BSC047N08NS3 G	
	R _{ps/op} =4.6 mΩ	R _{DS(on)} =4.9 mΩ			R _{DS(on)} =5.2 mΩ			R _{DS(on)} =4.4 mΩ			$R_{DS(on)}$ =4.7 m Ω	
	IPD053N08N3 G	IPB054N08N3 G			IPP057N08N3 G	IPA057N08N3 G					BSC052N08NS5	
	R _{ttS(op)} =5.3 mΩ	R _{05(op)} =5.4 mΩ			R _{DS(op)} =5.7 mΩ	R _{ttS(op)} =5.7 mΩ					$R_{IIS(on)}=5.2 \text{ m}\Omega$	
		IPB067N08N3 G								BSZ070N08LS5	BSC057N08NS3 G	
4-10		R _{DS(on)} =6.7 mΩ								R _{DS(on)} =7.0 mΩ	$R_{DS(on)}=5.7 \text{ m}\Omega$	
										BSZ075N08NS5	BSC061N08NS5	
										R _{DS(on)} =7.5 mΩ	$R_{DS(on)}=6.1 \text{ m}\Omega$	
	IPD096N08N3 G				IPP100N08N3 G					BSZ084N08NS5	BSC072N08NS5	
	R _{DS(on)} =9.6 mΩ				$R_{pS(on)}=9.7 \text{ m}\Omega$					R _{DS(on)} =8.4 mΩ	$R_{DS(on)} = 7.2 \text{ m}\Omega$	
								BSB104N08NP3	IRL80HS120	BSZ110N08NS5	BSC117N08NS5	
								R _{DS(on)} =10.4 mΩ	R _{pS(on)} =32.0 mΩ	R _{pS(on)} =11.0 mΩ	R _{DS(on)} =11.7 mΩ	
	IPD135N08N3 G							()	==(400)	BSZ123N08NS3 G		
>10	R _{05(op)} =13.5 mΩ									R _{ttS(op)} =12.3 mΩ	R _{05(op)} =12.3 mΩ	
											BSC340N08NS3 G	i
										R _{pS(on)} =34.0 mΩ	R _{DS(on)} =34.0 mΩ	

1) DirectFET™ S

timo	S' ^m and Stron	gIRFET™ 100 V	normal level				
^{S(on), max.} _{GS} =10 V mΩ]	TO-252 (DPAK)	TO-263 (D ² PAK)	TO-263 (D²PAK 7-pin)	TO-262 (I²PAK)	TO-220	TO-220 FullPAK	TO-247
-		IPB020N10N5	IPB017N10N5				IRF100P218
		$R_{DS(on)} = 2.0 \text{ m}\Omega$	$R_{DS(on)} = 1.7 \text{ m}\Omega$				$R_{DS(on)}=1.1 \text{ m}\Omega$
1-2		IPB020N10N5LF	IPB017N10N5LF				IRF100P219
		$R_{DS(on)}=2.0 \text{ m}\Omega$	$R_{DS(on)}=1.7 \text{ m}\Omega$				$R_{DS(on)}=2.1 \text{ m}\Omega$
		IPB027N10N3 G	IPB024N10N5		IPP023N10N5		IRFP4468PBF
		$R_{DS(on)} = 2.7 \text{ m}\Omega$	$R_{DS(on)} = 2.4 \text{ m}\Omega$		$R_{DS(on)} = 2.3 \text{ m}\Omega$		$R_{DS(on)} = 2.6 \text{ m}\Omega$
		IPB027N10N5	IPB025N10N3 G	IPI030N10N3 G	IPP030N10N3 G	IPA030N10N3 G	55(61)
		$R_{DS(on)}$ =2.7 m Ω	$R_{DS(on)} = 2.5 \text{ m}\Omega$	$R_{DS(on)}$ =3.0 m Ω	$R_{DS(on)} = 3.0 \text{ m}\Omega$	$R_{DS(on)}$ =3.0 m Ω	
2-4		IPB033N10N5LF	IPB032N10N5	03(01)	IPP030N10N5	53(01)	
		$R_{DS(on)}$ =3.3 m Ω	$R_{DS(on)}=3.2 \text{ m}\Omega$		$R_{DS(on)}=3.0 \text{ m}\Omega$		
		03(01)	IPB039N10N3 G		IPP039N10N5		
			$R_{DS(on)}$ = 3.9 m Ω		$R_{DS(on)}$ =3.9 m Ω		
	IPD050N10N5	IPB042N10N3 G	- DS(01)	IPI045N10N3 G	IRFB4110PBF	IPA045N10N3 G	IRFP4110PBF
	$R_{DS(on)}$ =5.0 m Ω	$R_{DS(on)}$ =4.2 m Ω		$R_{DS(on)}$ =4.5 mΩ	$R_{DS(on)}=4.5 \text{ m}\Omega$	$R_{DS(on)}$ =4.5 mΩ	$R_{DS(on)}$ =4.5 m Ω
	IPD068N10N3 G	IRFS4010TRLPBF			IPP045N10N3 G	IPA083N10N5	IRFP4310ZPBF
	$R_{DS(on)} = 6.8 \text{ m}\Omega$	$R_{DS(on)} = 4.7 \text{ m}\Omega$			$R_{DS(on)}$ =4.5 m Ω	$R_{DS(on)} = 8.3 \text{ m}\Omega$	$R_{DS(on)} = 6.0 \text{ m}\Omega$
	···DS(on)	IPB065N10N3 G			IRFB4310ZPBF	IPA086N10N3 G	DS(0R)
		$R_{DS(on)}=6.5 \text{ m}\Omega$			$R_{DS(on)} = 6.0 \text{ m}\Omega$	$R_{DS(on)} = 8.6 \text{ m}\Omega$	
		IRFS4310ZTRLPBF			TDS(on) OTO THEE	DS(on) OTO THE	
		$R_{DS(on)} = 7.0 \text{ m}\Omega$					
4-10		US(on)		IPI072N10N3 G	IPP072N10N3 G		
				$R_{DS(on)} = 7.2 \text{ m}\Omega$	$R_{DS(on)} = 7.2 \text{ m}\Omega$		
	IPD082N10N3 G			· · DS(0R)	IPP083N10N5		
	$R_{DS(on)} = 8.2 \text{ m}\Omega$				$R_{DS(on)} = 8.3 \text{ m}\Omega$		
		IPB083N10N3 G		IPI086N10N3 G	IPP086N10N3 G		
		$R_{DS(on)}$ =8.3 m Ω		$R_{DS(on)} = 8.6 \text{ m}\Omega$	$R_{DS(on)} = 8.6 \text{ m}\Omega$		
		IRFS4410ZTRLPBF		NDS(on) OTO THEE	IRFS4410ZTRLPBF		IRFP4410ZPBF
		$R_{DS(on)}$ =9.0 m Ω			$R_{DS(on)}$ =9.0 m Ω		$R_{DS(on)}$ =9.0 m Ω
	IPD122N10N3 G	US(on)			US(OR)		US(on)
	$R_{DS(on)} = 12.2 \text{ m}\Omega$						
	IPD12CN10N G	IPB123N10N3 G					
	$R_{DS(on)}$ =12.4 m Ω	$R_{DS(on)}$ =12.3 m Ω					
	IRFR4510TRPBF	IRFS4510TRLPBF					
L0-25	$R_{DS(on)}$ =13.9 m Ω	$R_{DS(on)}$ =13.9 m Ω					
	IPD180N10N3 G	TUDS(ON) LOTO THEE		IPI180N10N3 G			
	$R_{\text{DS(on)}} = 18.0 \text{ m}\Omega$			$R_{DS(on)}$ =18.0 m Ω			
	IPD25CN10N G			us(on) 2010 1112			
	$R_{DS(on)}$ =25.0 m Ω						
	IPD33CN10N G						
	$R_{DS(on)}$ = 33.0 mΩ						
>25	IPD78CN10N G						
	$R_{DS(op)} = 78.0 \text{ m}\Omega$						

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

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2 x 195

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

= = **(1**)

TO-Leadless

OptiMO:	S™ and StrongI	RFET™ 100 V nor	mal level			
R _{DS(on), max.} @V _{GS} =10 V [mΩ]	Bare die (R _{DS(on) typ.})	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	SO-8	TO-Leadl
1-2				BSC027N10NS5 R _{DSion} =2.7 mΩ		$[PT015N10N5] \\ R_{DS(on)}=1.5 m\Omega$ $[PT020N10N3] \\ R_{DS(on)}=2.0 m\Omega$
2-4	IPC26N10NR R _{D5(on)} =3.2 mΩ IPC173N10N3 R _{D5(on)} =3.6 mΩ	$\begin{array}{c} \text{IRF7769L1TRPBF} \\ \text{R}_{\text{DS(on)}} \text{=} 3.5 \text{ m} \Omega \end{array}$		BSC035N10NS5 $R_{DS(on)}$ = 3.5 mΩ BSC040N10NS5 $R_{DS(on)}$ = 4.0 mΩ		
4-10		IRF100DM116 ³ R _{D5(on)} =4.3 mΩ BSB056N10NN3 G R _{D5(on)} =5.6 mΩ	BSZ097N10NS5 R _{pS(on)} =9.7 mΩ	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		
10-25	IPC045N10N3 R _{05(on)} =15.2 mΩ	BSF134N10NJ3 G ¹⁾ R _{D5(on)} =13.4 mΩ IRF6662TRPBF R = 72.0 mΩ	BSZ160N10NS3 G R _{DS(on)} =16.0 mΩ	BSC109N10NS3 G RDS(on)=10.9 mΩ BSC118N10NS G RDS(on)=11.8 mΩ IRFH7110TRPBF RDS(on)=13.5 mΩ BSC160N10NS3 G RDS(on)=16.0 mΩ BSC196N10NS G R = -19.6 mΩ	IRF7853TRPBF	
>25		$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	BSZ440N10NS3 G R _{DS(on)} =44.0 mΩ	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	R _{DS(on)} =18.0 mΩ	
2 x 75				$\begin{array}{l} BSC750N10ND\ G\\ R_{DS(on)} = 75.0\ m\Omega;\ dual \end{array}$		
			IREHM792TRPRE			

 $\begin{array}{l} \text{IRFHM792TRPBF} \\ \text{R}_{\text{DS(on)}} \text{=} 195.0 \text{ m}\Omega \end{array}$

OptiMC)S™ and Stro	ongIRFET™	100 V logic	level					
R _{DS(on), max.} @V _{GS} =10 V [mΩ]	TO-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D ² PAK 7-pin)	TO-220	Bare die (R _{DS(on) typ.})	PQFN 2 x 2	PQFN 3.3 x 3.3	SuperSO8	SOT-23
2-4			IRLS4030TRL7PP $R_{DS(on)}$ =3.9 m Ω					BSC034N10LS5 R _{DS(on)} =3.4 mΩ	
4-10		IRLS4030TRLPBF R _{DS(on)} =4.3 mΩ		IRLB4030PBF R _{DS(on)} =4.3 mΩ			BSZ096N10LS5 R _{DS(on)} =9.6 mΩ		
10-25	IRLR3110ZTRPBF			$\frac{\text{IPP12CN10L G}}{\text{R}_{\text{DS(on)}}=12.0 \text{ m}\Omega}$	$\frac{IPC045N10L3^{2)}}{R_{DS(on)}} = 16.0 \text{ m}\Omega$		$\begin{array}{l} \text{BSZ146N10LS5} \\ \text{R}_{\text{DS(on)}} = 14.6 \text{ m}\Omega \\ \text{BSZ150N10LS3} \end{array}$	$\begin{array}{l} \text{BSC123N10LS G} \\ \text{R}_{\text{DS(on)}} = 12.3 \text{ m}\Omega \\ \text{BSC146N10LS5} \end{array}$	
>25	R _{DS(on)} =14.0 mΩ				IPC020N10L3 ²⁾ R _{DS(on)} =42.0 mΩ	IRL100HS121 R _{DS(on)} =42.0 mΩ	R _{DS(on)} =15.0 mΩ	$ \begin{array}{c} R_{DS(on)} = 14.6 \ \text{m}\Omega \\ \\ BSC265N10LSFG \\ R_{DS(on)} = 26.5 \ \text{m}\Omega \end{array} $	IRLML0100 R _{DS(on)} =220 mΩ

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 DirectFET[™] S
 R_{DS(on)} typ. specified @ 4.5 V
 Coming soon 84



0							Notor control	
Optimo	S and Strol	ngIRFET™ 12	u v normai le	evel				
$\begin{array}{c} R_{\text{DS(on), max.}}\\ @V_{\text{GS}} = 10 \ V\\ [m\Omega] \end{array}$	TO-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D²PAK 7-pin)	TO-262 (I²PAK)	TO-220	Bare die (R _{DS(on) typ.})	PQFN 3.3 x 3.3	SuperSO8
						IPC302N12N3 R _{DS(on)} =2.5 mΩ		
2-4						IPC26N12N R _{DS(on)} =3.0 mΩ		
		IPB038N12N3 G R _{DS(on)} =3.8 mΩ	IPB036N12N3 G R _{DS(on)} =3.6 mΩ			IPC26N12NR R _{DS(on)} =3.2 mΩ		
				IPI041N12N3 G R _{DS(on)} =4.1 mΩ	IPP041N12N3 G R _{DS(on)} =4.1 mΩ			
4-10					IPP048N12N3 G R _{DS(on)} =4.8 mΩ			
				IPI076N12N3 G R _{DS(on)} =7.6 mΩ	IPP076N12N3 G R _{DS(on)} =7.6 mΩ			$\begin{array}{l} BSC077N12NS3\ G\\ R_{_{DS(on)}} = 7.7\ m\Omega \end{array}$
10-25	IPD110N12N3 G R _{DS(on)} =11.0 mΩ				IPP114N12N3 G R _{DS(on)} =11.4 mΩ			
10-25		IPB144N12N3 G R _{DS(on)} =14.4 mΩ		IPI147N12N3 G R _{DS(on)} =14.7 mΩ	$\begin{array}{c} \text{IPP147N12N3 G} \\ \text{R}_{\text{DS(on)}} \text{=} 14.7 \ \text{m}\Omega \end{array}$		BSZ240N12NS3 G R _{DS(on)} =24.0 mΩ	$\begin{array}{l} \text{BSC190N12NS3 G} \\ \text{R}_{\text{DS(on)}} \text{=} 19.0 \text{ m}\Omega \end{array}$

лс-DC	Adapter	Consumer	DC-DC	
		SMPS	Solar	Telecom

Power ICs

OptiMOS	and StrongIRFE™	T™ 135-150 V norma	l level		
$\begin{array}{c} R_{\text{DS(on), max.}} \\ @V_{\text{GS}} = 10 \text{ V} \\ [m\Omega] \end{array}$	Bare die (R _{DS(on) typ.})	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	TO-Leadless
	IPC302N15N3			BSC093N15NS5	IPT059N15N3
4-10	R _{DS(on)} =4.9 mΩ IPC300N15N3R			R _{DS(on)} =9.3 mΩ	$R_{DS(on)} = 5.9 \text{ m}\Omega$
	$R_{DS(on)}$ =4.9 m Ω				
		IRF7779L2TRPBF ⁵⁾		BSC110N15NS5	
		R _{DS(on)} =11.0 mΩ		R _{DS(on)} =11.0 mΩ	
10.25				BSC160N15NS5	
10-25				R _{DS(on)} =16.0 mΩ	
		BSB165N15NZ3 G		BSC190N15NS3 G	
		R _{DS(on)} =16.5 mΩ		R _{DS(on)} =19.0 mΩ	
		BSB280N15NZ3 G	BSZ300N15NS5	BSC360N15NS3 G	
		R _{DS(on)} =28.0 mΩ	R _{DS(on)} =30.0 mΩ	R _{DS(on)} =36.0 mΩ	
05		IRF6643TRPBF	BSZ520N15NS3 G	BSC520N15NS3 G	
>25		R _{DS(on)} =34.5 mΩ	R _{DS(on)} =52.0 mΩ	R _{DS(on)} =52.0 mΩ	
		IRF6775MTRPBF	BSZ900N15NS3 G		
		R _{DS(on)} =56.0 mΩ	R _{DS(on)} =90.0 mΩ		

OptiMOS	S™ and Stro	ngIRFET™:	135-150 V n	ormal leve	l				
$\begin{array}{c} R_{\text{DS(on), max.}} \\ @V_{\text{GS}} = 10 \text{ V} \\ [m\Omega] \end{array}$	TO-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D ² PAK 7-pin)	TO-263 (D ² PAK 7-pin+)	TO-251/ TO-251 Short Lead (IPAK/IPAK Short Lead)	ТО-262 (І²РАК)	TO-220	TO-220 FullPAK	TO-247
		IPB048N15N5	IPB044N15N5			IPI051N15N5	IPP051N15N5 2)		IRF150P220
		$R_{DS(on)}$ =4.8 m Ω	$R_{DS(on)}$ =4.4 m Ω			$R_{DS(on)}$ =5.1 m Ω	$R_{DS(on)}$ =5.1 m Ω		$R_{DS(on)}$ =2.5m Ω
		IPB048N15N5LF	IRF135SA204 5)	IRF135SA204					IRF150P221
		R _{DS(on)} =4.8 mΩ	$R_{DS(on)}$ =5.9 m Ω	$R_{DS(on)}$ =5.9 m Ω					R _{DS(on)} =4.8mΩ
4.10		IPB072N15N3 G R _{DS(on)} =7.2 mΩ	IPB060N15N5 R _{DS(on)} = 6.0 mΩ			IPI075N15N3 G R _{DS(on)} =7.5 mΩ	IPP075N15N3 G R _{DS(on)} =7.5 mΩ		IRFP4568PBF $R_{DS(on)}$ =5.9 m Ω
4-10		IPB073N15N5	IPB065N15N3 G			IPI076N15N5	IPP076N15N5	IPA075N15N3 G	
		$R_{DS(on)}$ =7.3 m Ω	$R_{DS(on)}$ =6.5 m Ω			$R_{DS(on)}$ =7.6 m Ω	$R_{DS(on)}$ =7.6 m Ω	$R_{DS(on)}=7.5 \text{ m}\Omega$	
		IPB083N15N5LF R _{DS(on)} =8.3 mΩ							
		IRF135S2035)					IRF135B203 5)		
		R _{DS(on)} =8.4 mΩ					$R_{DS(on)}$ =8.4 m Ω		
		IPB108N15N3 G	IRFS4115TRL7PP			IPI111N15N3 G	IPP111N15N3 G	IPA105N15N3 G	
		R _{DS(on)} =10.8 mΩ	R _{DS(on)} =11.8 mΩ			R _{DS(on)} =11.1 mΩ	$R_{DS(on)}$ =11.1 m Ω	$R_{DS(on)}$ =10.5 m Ω	
		IRFS4321	IRFS4321TRL7PP				IRFB4321PBF		IRFP4321PBF
10-25		$R_{DS(on)}$ =15.0 m Ω	$R_{DS(on)}$ =14.7 m Ω				$R_{DS(on)}$ =15.0 m Ω		$R_{DS(on)}$ =15.5 m Ω
	IPD200N15N3 G R _{DS(on)} =20.0 mΩ	IPB200N15N3 G R _{DS(on)} =20.0 mΩ					IPP200N15N3 G ²⁾ R _{DS(on)} =20.0 mΩ		
		IRFS4615PBF					IRFB4615PBF		
		$R_{DS(on)}$ =42.0 m Ω					$R_{DS(on)}$ =39.0 m Ω		
	IRFR4615	IRFS5615PBF			IRFU4615PBF		IRFB5615PBF		
	$R_{DS(on)}$ =42.0 m Ω	$R_{DS(on)}$ =42.0 m Ω			$R_{DS(on)}$ =42.0 m Ω		$R_{DS(on)}$ =39.0 m Ω		
>25	IPD530N15N3 G	IPB530N15N3 G				IPI530N15N3 G ²⁾	IPP530N15N3		
	$R_{DS(on)}$ =53.0 m Ω	$R_{DS(on)}$ =53.0 m Ω				$R_{DS(on)}$ =53.0 m Ω	$G^{2)}$ R _{DS(on)} =53.0 m Ω		
							IRFB4019PBF R _{DS(on)} =95.0 mΩ		

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2) 8 V rated ($R_{\mbox{\tiny DS}(\mbox{\scriptsize on})}$ also specified @ $V_{\mbox{\tiny GS}}$ = 8 V) 3) In development 5) 135 V

20-300 V MOSFETs

500-950 V MOSFETs

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Motor control ICs

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Power ICs

OptiMO	S™ and StrongI	RFET™ 200 V nor	mal level			
R _{DS(on), max.} @V _{GS} =10 V [mΩ]	ТО-252 (DPAK)	TO-263 (D²PAK)	TO-263 (D²PAK+)	TO-262 (I²PAK)	TO-220	TO-247
4-10						IRF200P222 R _{DS(on)} =6.6 mΩ IRFP4668PBF R _{DS(on)} =9.7 mΩ
		IPB107N20N3 G R _{DS(on)} =10.7 mΩ IPB107N20NA ⁴ R _{DS(on)} =10.7 mΩ	IRF200S234 R _{DS(on)} = 16.9 mΩ	IPI110N20N3 G R _{D5(on)} =11.0 mΩ	IPP110N20N3 G R _{DS(on)} =11.0 mΩ	IRF200P223 R _{DS(on)} =11.5 mΩ
10-25		IPB110N20N3LF R _{DS(on)} =11.0 mΩ IPB117N20NFD R _{DS(on)} =11.7 mΩ			IPP120N20NFD R _{DS(on)} =12.0 mΩ IRFB4127PBF R _{DS(on)} =20.0 mΩ	$\label{eq:response} \begin{array}{c} IRFP4127PBF \\ R_{DS(on)} = 21.0 \ \text{m}\Omega \\ \\ IRFP4227PBF \\ R_{DS(on)} = 25.0 \ \text{m}\Omega \end{array}$
		$\begin{tabular}{lllllllllllllllllllllllllllllllllll$			hbs(on) -20.0 mm2	
	IPD320N20N3 G R _{DS(on)} =32.0 mΩ	R _{DS(on)} =22.0 mΩ IRFS4227TRLPBF R _{DS(on)} =26.0 mΩ IPB320N20N3 G R _{DS(on)} =32.0 mΩ		IPI320N20N3 G R _{DSion} =32.0 mΩ	IRFB4227PBF R _{DS(on)} =26.0 mΩ IPP320N20N3 G R _{DS(on)} =32.0 mΩ	
>25	IRFR4620TRLPBF R _{DS(on)} =78.0 mΩ	IRFS4620TRLPBF R _{DS(on)} =78.0 mΩ			$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	
		IRFS4020TRLPBF R _{DS(on)} =105.0 mΩ			IRFB4020PBF R _{D5(ort)} =100.0 mΩ IRF200B211 R _{D5(ort)} =170.0 mΩ	

OptiMO:	S™ and Stron	gIRFET™ 200 V	normal level				
$\begin{array}{c} R_{_{DS(on),max.}}\\ @V_{_{GS}} = 10 \ V\\ [m\Omega] \end{array}$	Bare die (R _{DS(on) typ.})	DirectFET™	PQFN 3.3 x 3.3	SuperSO8	SO-8	TO-Leadless	TO-247
4-10	IPC300N20N3 R _{DS(on)} =9.2 mΩ IPC302N20N3 R _{DS(on)} =9.2 mΩ						$\frac{\text{IRF200P222}}{\text{R}_{\text{DS(on)}}\text{=}6.6 \text{ m}\Omega}$
10-25	1000000000000000000000000000000000000			BSC220N20NSFD R _{DS(on)} =22.0 mΩ		IPT111N20NFD R _{pS(on)} =11.1 mΩ	IRF200P223 R _{pS(on)} = 11.5 mΩ
>25		IRF6641TRPBF R _{DS(on)} =59.9 mΩ	BSZ900N20NS3 G R _{DS(on)} =90.0 mΩ	$\begin{array}{c} BSC320N20NS3 \ G \\ R_{DS(or)} = 32.0 \ m\Omega \\ \\ BSC350N20NSFD \\ R_{DS(or)} = 35.0 \ m\Omega \\ \\ BSC500N20NS3G \\ R_{DS(or)} = 50.0 \ m\Omega \\ \\ IRFH5020 \\ R_{DS(or)} = 55.0 \ m\Omega \\ \\ BSC900N20NS3 \ G \\ R_{DS(or)} = 90.0 \ m\Omega \\ \end{array}$	IRF7820TRPBF R _{D5(on)} =78.0 mΩ		
		IRF6785TRPBF R _{DS(on)} =100.0 mΩ	BSZ12DN20NS3 G R _{DS(m)} =125.0 mΩ BSZ22DN20NS3 G R _{DS(m)} =225.0 mΩ	BSC12DN20NS3 G R _{DS(on)} =125.0 mΩ BSC22DN20NS3 G R _{DS(on)} =225.0 mΩ	us(on) · · · · · · · · · · · · · · · · · · ·		

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20-300 V MOSFETs

500-950 V MOSFETs

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OptiMO	S™ and Stro	ongIRFET™:	250 V norm	al level					
$\begin{array}{c} R_{\text{DS(on), max.}}\\ @V_{\text{GS}}\text{=}10 \text{ V}\\ [m\Omega] \end{array}$	TO-252 (DPAK)	TO-263 (D²PAK)	TO-262 (I²PAK)	TO-220	TO-247	Bare die (R _{DS(on) typ.})	PQFN 3.3 x 3.3	SuperSO8	TO-Leadless
		IPB200N25N3 G	IPI200N25N3 G	IPP200N25N3 G	IRF250P224				
		$R_{DS(on)}$ =20.0 m Ω	$R_{DS(on)}$ =20.0 m Ω	$R_{DS(on)}$ =20.0 m Ω	R _{DS(on)} =12.0 mΩ				
10-25				IPP220N25NFD	IRFP4768PBF	IPC302N25N3			IPT210N25NFD
10-25				$R_{DS(on)}$ =22.0 m Ω	$R_{DS(on)}$ =17.5 m Ω	$R_{DS(on)}$ =16.0 m Ω			$R_{DS(on)}$ =21.0 m Ω
					IRF250P225				
					R _{DS(on)} =22.0 mΩ				
								BSC430N25NSFD	
								R _{DS(on)} =43.0 mΩ	
		IRFS4229TRLPBF		IRFB4332PBF	IRFP4332PBF			BSC600N25NS3 G	
		$R_{DS(on)}$ =48.0 m Ω		R _{DS(on)} =33.0 mΩ	R _{DS(on)} =33.0 mΩ			R _{DS(on)} =60.0 mΩ	
>25								BSC670N25NSFD	
-25								R _{DS(on)} =67.0 mΩ	
	IPD600N25N3 G	IPB600N25N3 G	IPI600N25N3 G	IRFB4229PBF	IRFP4229PBF		BSZ16DN25NS3 G	IRFH5025	
	$R_{DS(on)}$ =60.0 m Ω	$R_{DS(on)}$ =60.0 m Ω	$R_{DS(on)}$ =60.0 m Ω	$R_{DS(on)}$ =46.0 m Ω	$R_{DS(on)}$ =46.0 m Ω		$R_{DS(on)}$ =165.0 m Ω	$R_{DS(on)}$ =100.0 m Ω	
				IPP600N25N3 G		IPC045N25N3	BSZ42DN25NS3 G	BSC16DN25NS3 G	
				$R_{DS(on)}$ =60.0 m Ω		R _{DS(on)} =146.0 mΩ	$R_{DS(on)}$ =425.0 m Ω	$R_{DS(on)}$ =165.0 m Ω	

OptiMOS[™] and StrongIRFET[™] 300 V normal level

OptiMOS [™] and StrongIRFET [™] 300 V normal level									
$\begin{bmatrix} R_{DS(on), max.} \\ @V_{GS} = 10 V \\ [m\Omega] \end{bmatrix}$	TO-263 (D²PAK)	TO-220	TO-247	SuperSO8					
0-25			IRF300P226 R _{DS(on)} =19.0 mΩ						
>25	IPB407N30N R _{DS(on)} =40.7 mΩ	$\frac{IPP410N30N}{R_{DS(on)}}=41.0\ m\Omega$	IRFP4868PBF R _{D5(on)} =32.0 mΩ IRF300P227 R _{D5(on)} =40.0 mΩ						
		$\begin{array}{l} \text{IRFB4137PBF} \\ \text{R}_{\text{DS(on)}} = 69.0 \text{ m}\Omega \end{array}$	$\begin{array}{l} \text{IRFP4137PBF} \\ \text{R}_{\text{DS(on)}} = 69.0 \text{ m}\Omega \end{array}$	BSC13DN30NSFD R _{DS(on)} =130.0 mΩ					

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Voltage [V]	SOT-223	TSOP-6	SOT-89	SC59	SOT-23	SOT-323	SOT-363
-250	BSP317P 4 Ω, -0.43 A, LL		BSS192P 12 Ω, -0.19 A, LL	BSR92P 11 Ω, -0.14 A, LL			
	BSP92P 12 Ω, -0.26 A, LL BSP321P						
100	900 mΩ, -0.98 A, NL BSP322P						
-100	800 mΩ, -1.0 A, LL BSP316P			BSR316P			
	1.8 Ω, -0.68 A, LL BSP612P			1.8 Ω, -0.36 A, LL	ISS17EP06LM		
	120 mΩ, 3 A, LL BSP613P				1.7Ω, -0.3 A, LL BSS83P	BSS84PW	
	130 mΩ, 2.9 A, NL BSP170P				2 Ω, -0.33 A, LL	8 Ω, -0.15 A, LL	
	300 mΩ, -1.9 A, NL				ISS55EP06LM 5.5 Ω, -0.18 A, NL		
	BSP171P				BSS84P		
	300 mΩ, -1.9 A, LL BSP315P				8 Ω, -0.17 A, LL		
-60	800 mΩ, -1.17 A, LL ISP650P06NM			BSR315P			
	65 mΩ, -3.7 A, NL			800 mΩ, -0.62 A, LL			
	ISP12DP06NM						
	125 mΩ, -2.8, NL ISP25DP06LM 250 mΩ, -1.9 A, LL						
	SP25DP06NM						
	250 mΩ, -1.9 A, NL SP75DP06LM						
	750 mΩ, -1.1 A, LL						
		BSL303SPE 33 mΩ, -6.3 A, LL			BSS308PE 80 mΩ, -2.1 A, LL, ESD		BSD314SPE 140 mΩ, -1.5 A, LL, ESD
		IRFTS9342TRPBF*			BSS314PE		
		40 mΩ, -5.8 A, LL			140 mΩ, -1.5 A, LL, ESD		
		BSL307SP 43 mΩ, -5.5 A, LL			BSS315P 150 mΩ, -1.5 A, LL		
- 30		BSL305SPE					
		45 mΩ, -5.5 A, LL BSL308PE					
		80 mΩ, -2.1 A, LL, dual, ESD					
		BSL314PE 140 mΩ, -1.5 A, LL,					
		ESD, dual BSL207SP			IRLML2244* 1)		
		41 mΩ, -6 A, SLL			54 mΩ, 4.3 A, LL	20000000	201/00/005
-20		BSL211SP 67 mΩ, -4.7 A, SLL			IRLML2246 ^{* 1)} 135 mΩ, 2.6 A, LL	BSS209PW 550 mΩ, -0.58 A, SLL	BSV236SP 175 mΩ, -1.5 A, SLL
					BSS215P	BSS223PW	BSD223P
					150 mΩ, -1.5 A, SLL	1.2 Ω, -0.39 A, SLL	1.2 Ω, -0.39 A, SLL, dual

Sı	nall sig	nal complem	nentary					Industrial Drives
	Voltage [V]	SOT-223	TSOP-6	SOT-89	SC59	SOT-23	SOT-323	SOT-363
ary	-20/20		BSL215C N: 140 mΩ, 1.5 A, SLL P: 150 mΩ, 1.5 A, SLL					BSD235C N: 350 mΩ, 0.95 A, SLL P: 1.2 Ω, 0.53 A, SLL
Complementary	20/20		BSL308C N: 57 mΩ, 2.3 A, LL P: 80 mΩ, -2.0 A, LL					
Con	-30/30		BSL316C N: 160 mΩ, 1.4 A, LL P: 150 mΩ, -1.5 A, LL					

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All products are qualified to Automotive AEC Q101 (except the parts marked with *) 1) $R_{\rm _{DS(co)}}$ 4.5 V rated

Voltage	gnal N-channe sot-223	TSOP-6	SOT-89	SC59	SOT-23	SOT-323	SOT-363
[V]	301 223		50105	5005	50125	501 525	001000
		BSL802SN 22 mΩ, 7.5 A, ULL		BSR802N 23 mΩ, 3.7 A, ULL	IRLML6244 ^{* 1)} 21 mΩ, 6.3 A, LL		
		BSL202SN		BSR202N	IRLML6246*1)		
		22 mΩ, 7.5 A, SLL BSL205N		21 mΩ, 3.8 A, SLL	46 mΩ, 4.1 A, LL BSS205N		BSD214SN
		50 mΩ, 2.5 A, SLL, dual			50 mΩ, 2.5 A, SLL		140 mΩ, 1.5 A, SLL
20					BSS806NE 57 mΩ, 2.3 A, ULL, ESD		BSD816SN 160 mΩ, 1.4 A, ULL
		BSL207N 70 mΩ, 2.1 A, SLL, dual			BSS806N 57 mΩ, 2.3 A, ULL	BSS214NW 140 mΩ, 1.5 A, SLL	BSD235N 350 mΩ, 0.95 A, SLL, dua
		BSL214N 140 mΩ, 1.5 A, SLL, dual			BSS214N 140 mΩ, 1.5 A, SLL	BSS816NW 160 mΩ, 1.4 A, ULL	BSD840N 400 mΩ, 0.88 A, ULL, dua
25					IRFML8244*		
		IRLTS6342*1)		BSR302N	24 mΩ, 5.8 A, NL IRLML0030*		BSD316SN
		17.5 mΩ, 8.3 A, LL IRFTS8342*		23 mΩ, 3.7 A, LL	27 mΩ, 5.3 A, LL IRLML6344 ^{* 1)}		160 mΩ, 1.4A, LL
		19 mΩ. 8.2 A, NL			29 mΩ, 5.0 A, LL		
		BSL302SN 25 mΩ, 7.1 A, LL			BSS306N 57 mΩ, 2.3 A, LL		
30		BSL306N			IRLML6346* ¹⁾ 63 mΩ, 3.4 A, LL		
		57 mΩ, 2.3 A, LL, dual			IRLML2030*		
					100 mΩ, 1.4 A, LL BSS316N		
					160 mΩ, 1.4 A, LL		
55					BSS670S2L 650 mΩ, 0.54 A, LL	BSS340NW 400 mΩ, 0.88 A, LL	
	BSP318S	BSL606SN	BSS606N	BSR606N	IRLML0060*	BSS138W	2N7002DW
	90 mΩ, 2.6 A, LL BSP320S	60 mΩ, 4.5 A, LL	60 mΩ, 3.2 A, LL	60 mΩ, 2.3 A, LL	92 mΩ, 2.7 A, LL IRLML2060*	3.5 Ω, 0.28 A, LL SN7002W	3 Ω, 0.3 A, LL, dual
	120 mΩ, 2.9 A, NL				480 mΩ, 1.2 A, LL	5 Ω, 0.23 A, LL	
	BSP295 300 mΩ, 1.8 A, LL				BSS138N 3.5 Ω, 0.23 A, LL		
60					BSS7728N 5 Ω, 0.2 A, LL		
					SN7002N		
					5 Ω, 0.2 A, LL 2N7002		
					3 Ω, 0.3 A, LL		
					BSS159N 8 Ω, 0.13 A, depl.		
75	BSP716N 160 mΩ, 2.3 A, LL	BSL716SN 150 mΩ, 2.5 A, LL					
80	100 1112, 2.3 A, EL	130 112, 2.3 A, LL					
00	BSP372N	BSL372SN			IRLML0100*		
	230 mΩ, 1.8 A, LL	220 mΩ, 2.0 A, LL			220 mΩ, 1.6 A, LL		
	BSP373N 240 mΩ, 1.8 A, NL	BSL373SN 230 mΩ, 2.0 A, NL			BSS119N 6 Ω, 0.19 A, LL		
100	BSP296N	BSL296SN			V _{GS(th)} 1.8 V to 2.3 V BSS123N		
	600 mΩ, 1.2 A, LL	460 mΩ, 1.4 A, LL			6 Ω, 0.19 A, LL		
					V _{GS(th)} 0.8 V to 1.8 V BSS169		
	BSP297				12 Ω, 0.09 A, depl.		
200	1.8 Ω, 0.66 A, LL						
200	BSP149 3.5 Ω,0.14 A, depl.						
	BSP88		BSS87		BSS131		
242	6 Ω, 0.35 A, 2.8 V rated BSP89		6 Ω, 0.26 A, LL		14 Ω, 0.1 A, LL		
240	6 Ω, 0.35 A, LL BSP129						
	6 Ω, 0.05 A, depl.						
250					BSS139 30 Ω, 0.03 A, depl.		
	BSP298						
	3 Ω, 0.5 A, NL BSP179						
400	24 Ω, 0.04 A, depl.						
	BSP324 25 Ω, 0.17 A, LL						
500	BSP299 4 Ω, 0.4 A, NL						
	BSP125		BSS225		BSS127		
600	45 Ω, 0.12 A, LL BSP135		45 Ω, 0.09 A, LL		500 Ω, 0.023 A, LL BSS126		
	60 Ω, 0.02 A, depl.				700 Ω, 0.007 A, depl.		
	BSP300						

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20-300 V MOSFETs

500-950 V MOSFETs

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Packages

ЪС	ower P	-channel M	OSFETs				Automotive		
V	/oltage [V]	TO-252 (DPAK)	DirectFET™	SOT-23	PQFN 3.3 x 3.3	SuperSO8	SO-8	PQFN 2 x 2	TSOP-6
							BSO201SP H		
							$R_{DS(on)}$ =7.0 m Ω		
							BSO203SP H		
							R _{DS(on)} =21.0 mΩ BSO203P H		
							$R_{DS(on)}$ =21.0 m Ω		
	-20						N _{DS(on)} =21.0 1112	IRLHS2242TRPBF**	IRLTS2242
								$R_{DS(on)}$ =31.0 m Ω	$R_{DS(on)}$ =39 m Ω
				IRLML2244 ²⁾ ***			BSO207P H	5(01)	03(01)
				$R_{DS(on)}$ =54 m Ω			R _{DS(on)} =45.0 mΩ		
				IRLML2246 ²⁾ ***			BSO211P H		
				R _{DS(on)} =135 mΩ			R _{DS(on)} =67.0 mΩ		
						BSC030P03NS3 G	IRF9310		
		IPD042P03L3 G				R _{DS(on)} =3.0 mΩ BSC060P03NS3E G	R _{DS(on)} =4.6 mΩ IRF9317		
		$R_{DS(on)}$ =4.2 m Ω				$R_{DS(on)} = 6.0 \text{ m}\Omega; \text{ESD}$	$R_{DS(op)} = 6.6 \text{ m}\Omega$		
		TVDS(on) TVZ TTXZ			BSZ086P03NS3 G	NDS(on) 0.0 mill, LOD	IRF9321		
					$R_{DS(on)} = 8.6 \text{ m}\Omega$		$R_{DS(on)}=7.2 \text{ m}\Omega$		
		SPD50P03L G 1)*	IRF9395M		BSZ086P03NS3E G		BSO080P03NS 3 G		
		R _{DS(on)} =7.0 mΩ	$R_{DS(on)}$ =7.0 m Ω ; dual		R _{DS(on)} =8.6 mΩ		R _{DS(on)} =8.0 mΩ		
						BSC084P03NS3 G	BSO080P03NS3E G		
						$R_{DS(on)} = 8.4 \text{ m}\Omega$	$R_{DS(on)}$ =8.0 m Ω ; ESD		
						BSC084P03NS3E G	BSO080P03S H		
					BSZ120P03NS3 G	$R_{DS(on)}$ =8.4 mΩ; ESD	R _{DS(on)} =8.0 mΩ BSO301SP H		
					$R_{DS(on)}$ =12.0 m Ω		$R_{DS(on)} = 8.0 \text{ m}\Omega$		
					BSZ120P03NS3E G		IRF9328		
					R _{DS(on)} =12.0 mΩ; ESD		R _{DS(on)} =11.9 mΩ		
							IRF9388TRPBF		
							R _{DS(on)} =11.9 mΩ		
	-30						BSO130P03S H		
							R _{DS(on)} =13.0 mΩ IRF9358		
							$R_{DS(on)}$ =16 mΩ; dual		
					IRFHM9331 ²⁾		IRF9332		
					$R_{DS(on)}=15 \text{ m}\Omega$		$R_{DS(on)}=17.5 \text{ m}\Omega$		
					5(01)		IRF9392TRPBF		
							R _{DS(on)} = 17.5 mΩ		
					BSZ180P03NS3 G		IRF9333		
					R _{DS(on)} =18.0 mΩ		R _{DS(on)} =19.4 mΩ		
					BSZ180P03NS3E G		BSO200P03S H		
					$R_{DS(on)}$ =18.0 m Ω ; ESD		R _{DS(on)} =20.0 mΩ BSO303SP H	IRFH9301TRPBF	
							$R_{DS(op)} = 21.0 \text{ m}\Omega$	$R_{DS(on)}$ =37.0 m Ω	
				IRLML9301TRPBF			BSO303P H	US(OR)	
				$R_{DS(on)} = 64 \text{ m}\Omega$			$R_{DS(on)}$ =21.0 m Ω ; dual		
				IRLML9303TRPBF			IRF9362	IRFHS9351TRPBF	IRFTS9342***
				$R_{DS(on)}$ =165 m Ω			$R_{DS(on)}$ =21 m Ω ; dual	$R_{DS(on)}$ =170.0 m Ω ; dual	$R_{DS(on)}=32 \text{ m}\Omega$
							IRF9335		
							R _{DS(on)} =59 mΩ		

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Packages

www.infineon.com/pchannel

1)5-leg 2)2.5 V_{GS} capable

91



Po	ower P	-channel MOS	FETs				
\	/oltage [V]	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	PQFN 3.3 x 3.3	SuperSO8	SO-8
		IPD380P06NM	IPB110P06LM	SPP80P06P H*			
		$R_{DS(on)} = 38 \text{ m}\Omega$	$R_{DS(on)} = 11 \text{ m}\Omega$	R _{DS(on)} =23.0 mΩ			
		IPD650P06NM	SPB80P06P G*				
		$R_{DS(on)} = 65 \text{ m}\Omega$	R _{DS(on)} =23.0 mΩ				
		SPD30P06P G*					
		R _{DS(on)} =75.0 mΩ					
		IPD900P06NM					
	-60	$R_{DS(on)} = 90 \text{ m}\Omega$					
		SPD18P06P G*	SPB18P06P G*	SPP18P06P H*			BSO613SPV G*
		R _{DS(on)} =130.0 mΩ	R _{DS(on)} =130.0 mΩ	R _{DS(on)} =130.0 mΩ			R _{DS(on)} =130.0 mΩ
		SPD09P06PL G*					
Ts		R _{DS(on)} =250.0 mΩ					
P-channel MOSFETs		IPD25DP06LM					
ő		$R_{DS(on)} = 250 \text{ m}\Omega$					
		IPD25DP06NM					
un e		R _{DS(on)} = 250 mΩ SPD08P06P G*	SPB08P06P G*	SPP08P06P H*			
hai							
P-C		R _{DS(on)} =300.0 mΩ IPD40DP06NM	R _{DS(on)} =300.0 mΩ	R _{DS(on)} =300.0 mΩ			
		$R_{DS(on)} = 400 \text{ m}\Omega$					
-		SPD15P10PL G*		SPP15P10PL H*			
		$R_{\text{DS(on)}}=200.0 \text{ m}\Omega$		$R_{DS(on)}$ =200.0 m Ω			
		SPD15P10P G*		SPP15P10P H*			
		$R_{DS(op)} = 240.0 \text{ m}\Omega$		$R_{\rm DS(op)} = 240.0 \rm m\Omega$			
		DS(0II)		US(01)			
	-100						
		SPD04P10PL G*					
		R _{DS(on)} =850.0 mΩ					
		SPD04P10P G*					
		R _{DS(on)} =1000.0 mΩ					

P	Power MOSFETs complementary								
	Voltag [V]	ge	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	PQFN 3.3 x 3.3	SuperSO8	SO-8	
	20/20					BSZ15DC02KD H*/** N: 55 mΩ, 5.1 A P: 150 mΩ, -3.2 A			
Complementary	-20/20 >50 mΩ	>50 mΩ				BSZ215C H*/** N: 55 mΩ, 5.1 A P: 150 mΩ, -3.2 A			
Compler	<u>co/co</u>	11 20 0						BSO612CV G* N: 0.12 Ω, 3.0 A P: 0.30 Ω, -2.0 A	
	-60/60 11-30 Ω						BSO615C G* N: 0.11 Ω, 3.1 A P: 0.30 Ω, -2.0 A		

www.infineon.com/complementary

*Products are qualified to Automotive AEC Q101 $^{\star\star}R_{_{DS(on)}}$ specified at 4.5 V

92

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

DC-DC eMobility

Nomenclature

OptiMOS™



OptiMOS[™] 30 V



N = N-channel

P = P-channel

500-950 V MOSFETs

Motor control ICs

500-950 V MOSFETs

Packages

Small signal



StrongIRFET™ (from May 2015 onwards)





Infineon support for low voltage MOSFETs Useful links and helpful information

Further information, data sheets and documents

www.infineon.com/powermosfet-12V-300V www.infineon.com/smallsignal www.infineon.com/pchannel www.infineon.com/depletion www.infineon.com/complementary www.infineon.com/baredie

Evaluation boards and simulation models www.infineon.com/to-leadless-evaluationboard www.infineon.com/powermosfet-simulationmodels

Videos

www.infineon.com/mediacenter





Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Trusted leader in high voltage MOSFETs

The revolutionary CoolMOS[™] power MOSFET family sets new standards in the field of energy efficiency. Our CoolMOS[™] products offer a significant reduction of conduction, switching and driving losses, and enable high power density as well as efficiency for superior power conversion systems.



High voltage superjunction MOSFETs address consumer applications, such as smartphone/tablet chargers, notebook adapters, LED lighting, PC power, as well as audio and TV power supplies. Customers are increasingly replacing standard MOSFETs with superjunction MOSFETs to benefit from higher efficiency and lower power consumption for end users. CoolMOS[™] P7 sets a new benchmark by offering high performance and competitive price all at once.

Also for industrial applications such as server, telecom, PC power, solar, UPS, EV-charging and others, Infineon's latest CoolMOS[™] 7 superjunction MOSFETs with C7, G7, CFD7 and P7 product families offer what you need - from highest efficiency to best price performance. Infineon has meanwhile also complemented the portfolio with first CoolGaN[™] e-mode HEMTs products to further optimize efficiency and system cost.

Infineon's CoolMOS[™] superjunction MOSFET offering is complemented by the automotive qualified series 600 V CPA, 650 V CFDA and 800 V C3A. Gain your momentum in the rapidly growing on-board charger and DC-DC converter markets with our excellent performing automotive series with proven outstanding quality standards that go well beyond AEC Q101.

96

Motor control ICs

950 V CoolMOS™ P7 SJ MOSFET

Perfect fit for PFC and flyback topologies

Designed to meet the growing consumer needs in the high voltage MOSFETs arena, the latest 950 V CoolMOS[™] P7 technology focuses on the low-power SMPS market. This new P7 family addresses applications ranging from lighting, smart meter, mobile phone charger, notebook adapter, to AUX power supply and industrial SMPS. Offering 50 V more blocking voltage than its predecessor 900 V CoolMOS[™] C3, the new 950 V CoolMOS[™] P7 series delivers outstanding performance in terms of efficiency, thermal behavior and ease of use. As the all other P7 family members, the 950 V CoolMOS[™] P7 series comes with an integrated Zener diode ESD protection. The integrated diode considerably improves ESD robustness, thus reducing ESD-related yield loss and reaching exceptional ease-of-use levels. CoolMOS[™] P7 is developed with best-in-class threshold voltage (V_{GS(th)}) of 3 V and a narrow tolerance of only ± 0.5 V, which makes it easy to drive and design-in.



Compared to competition, the 950 V CoolMOSTM P7 delivers best-in-class efficiency and thermal performance. Plug-and-play at 90 V_{AC} in a 40 W adapter reference design, featuring the snubberless concept, demonstrates excellent efficiency gains of up to 0.2 % and lower MOSFET temperature of up to 5.2°C compared to similar competitor technology. With over 20 years of experience in superjunction technology, Infineon introduces 950 V CoolMOSTM P7 with best-in-class DPAK on-resistance ($R_{DS(on)}$). This SMD device comes with the $R_{DS(on)}$ of 450 m Ω - more than 60% lower $R_{DS(on)}$ compared to the nearest competitor. Such low $R_{DS(on)}$ value enables higher density designs while decreasing BOM and assembly cost.



www.infineon.com/950v-p7

Best-in-class DPAK R_{DS(on)} Customer benefits:

- Possible change from leaded to SMD packages
- > High power density
- Lower BOM cost
- > Less production cost



Motor control ICs

800 V CoolMOS™ P7 SJ MOSFET

A benchmark in efficiency and thermal performance

With the 800 V CoolMOS[™] P7 series, Infineon sets a benchmark in 800 V superjunction technologies and combines best-in-class performance with the remarkable ease of use. This new product family is a perfect fit for flyback-based consumer and industrial SMPS applications. In addition, it is also suitable for PFC stages within consumer, as well as solar applications, fully covering the market needs in terms of its price/performance ratio.

The technology offers fully optimized key parameters to deliver best-in-class efficiency as well as thermal performance. As demonstrated on an 80 W LED driver, bought on the market, the >45 percent reduction in switching losses (E_{oss}) and output capacitance (C_{oss}) as well as the significant improvement in input capacitance (C_{iss}) and gate charge (Q_G), compared to competitor technologies, lead to 0.5 percent higher efficiency at light load which helps to reduce standby power in the end application. At full load, the observed improvement is up to 0.3 percent higher efficiency and 6°C lower device temperature.



EMI is a system level topic, and the optimization needs to be done on the system level only. Nevertheless, a pure plug-and-play measurement on Infineon's 45 W adapter reveals that 800 V CoolMOS[™] P7 shows similar EMI performance to Infineon's previous technologies as well as to competitors' technologies.

Compared to competition, the 800 V CoolMOS[™] P7 technology allows to integrate much lower R_{DS(on)} values into small packages, such as a DPAK. This finally enables high power density designs at highly competitive price levels.



CoolMOS[™] P7 sets a new benchmark in best-in-class DPAK R_{DS(on)}

Customer benefits:

- > High power density
- Lower BOM cost
- Less production cost

The complete P7 platform has been developed with an integrated Zener diode that is used as an electrostatic discharge (ESD) protection mechanism, which increases the overall device ruggedness up to Human body model (HBM) class 2 level.



20-300 V MOSFETs

Discrete IGBTs

www.infineon.com/800V-p7

700 V CoolMOS™ P7 SJ MOSFET

Our answer for flyback topologies

The 700 V CoolMOS[™] P7 family has been developed to serve today's and, especially, tomorrow's trends in flyback topologies. The family products address the low power SMPS market, mainly focusing on mobile phone chargers and notebook adapters, but are also suitable for power supplies, used within lighting applications, home entertainment (TV, game consoles or audio), and auxiliary power supplies. 700 V CoolMOS[™] P7 achieves outstanding efficiency gains of up to 4 percent and a decrease in device temperature of up to 16 K compared to competition. In contrast with the previous 650 V CoolMOS[™] C6 technology, 700 V CoolMOS[™] P7 offers 2.4 percent gain in efficiency and 12 K lower device temperature, measured at a flyback-based charger application, operated at 140 kHz switching speed.





Key features

- Highly performant technology
 - Low switching losses (E_{oss})
 - Highly efficient
- Excellent thermal behavior
- Allowing high speed switching
- Integrated protection Zener diode
- > Optimized $V_{\mbox{\tiny GS(th)}}$ of 3 V with very narrow tolerance of ± 0.5 V
- Finely graduated portfolio





Competitor 1 Competitor 2
Keeping the ease of use in mind, Infineon has launched

CoolMOS[™] P7 CoolMOS[™] C6

the technology with a low threshold voltage (V_{GS(th)}) of 3 V and a very narrow tolerance of ±0.5 V. This makes the CoolMOS[™] P7 easy to design-in and enables the usage of lower gate source voltage, which facilitates its driving and leads to lower idle losses. To increase the ESD ruggedness up to HBM class 2 level, 700 V CoolMOS[™] P7 has an integrated Zener diode. This helps to support increased assembly yield, leads to reduction of production related failures and, finally, manufacturing cost savings on customer side.

Key benefits

- Cost competitive technology
- > Further efficiency gain at higher switching speed
- Supporting less magnetic size with lower BOM costs
- > High ESD ruggedness up to HBM class 2 level
- > Easy to drive and design-in
- > Enabler for smaller form factors and high power density designs
- > Excellent choice in selecting the best fitting product



600 V CoolMOS[™] P7 SJ MOSFET

Perfect combination between high efficiency and ease of use

The 600 V CoolMOS[™] P7 is a general purpose series, targeting a broad variety of applications, ranging from low power SMPS up to the highest power levels. In the low power arena, it is the successor of the 600 V CoolMOS™ CE, and for high power SPMS applications, it is the replacement for the 600 V CoolMOS™ P6, which makes it the perfect choice for applications such as chargers, adapters, lighting, TV power supply, PC power supply, solar, small light electric vehicles, server power supply, telecom power supply, and electric vehicle (EV) charging.

The 600 V CoolMOS[™] P7 is Infineon's most well-balanced CoolMOS[™] technology in terms of combining the ease of use and excellent efficiency performance. Compared to its predecessors, it offers highest efficiency and improved power density due to the significantly reduced gate charge (Q_G) and switching losses (E_{OSS}) levels, as well as optimized on-state resistance (R_{DS(on})). The carefully selected integrated gate resistors enable very low ringing tendency and, thanks to its outstanding robustness of body diode against hard commutation, it is suitable for hard as well as soft switching topologies, such as LLC. In addition, an excellent ESD capability helps to improve the quality in manufacturing. The 600 V CoolMOS[™] P7 familiy offers a wide range of on-resistance (R_{DS(on})/package combinations, including THD, as well as SMD devices, at an R_{DS(on)} granularity from 24 to 600 mΩ and comes along with the most competitive price/performance ratio of all 600 V CoolMOS[™] offerings.



Key features

- > Suitable for hard and soft switching (PFC and LLC) due to > Ease of use and fast design-in through low ringing an outstanding commutation ruggedness
- Optimized balance between efficiency and ease of use
- > Significant reduction of switching and conduction losses leading to low MOSFET temperature
- > Excellent ESD robustness >2 kV (HBM) for all products
- > Better R_{DS(on)}/package products compared to competition > Increased power density solutions enabled by using
- > Large portfolio with granular R_{DS(on)} selection qualified for a variety of industrial and consumer applications

Key benefits

- tendency and usage across PFC and PWM stages
- Improved efficiency and simplified thermal management due to low switching and conduction losses
- Higher manufacturing quality due to >2 kV ESD protection
- products with smaller footprint
- > Suitable for a wide variety of applications and power ranges



www.infineon.com/600V-p7

600 V and 650 V CoolMOS™ C7 and C7 Gold (G7) SJ MOSFET

Infineon's highest efficiency superjunction MOSFET series

The 600 V and 650 V CoolMOSTM C7 and C7 Gold (G7) superjunction MOSFET series are designed to achieve record level efficiency performance – they offer substantial efficiency benefits over the whole load range in hard switching applications compared to previous series and competition. This is achieved by minimizing switching losses via ultralow levels of switching losses (E_{oss}) (approximately 50 percent reduction compared to the CoolMOSTM CP), reduced gate charge (Q_G) and a careful balance of other relevant product key parameters. The low E_{oss} and Q_G also enable operation at higher switching frequency and related size reduction of the circuit magnetics.



The outstanding figures of merit (FOM) and the best-in-class on-state resistance (R_{DS(on)}) offerings make the CoolMOS[™] C7 and C7 Gold series key enablers for highest efficiency and power density. While the 650 V CoolMOS[™] C7 and G7 (C7 Gold) superjunction MOSFETs are solely designed for hard switching applications such as PFC, the 600 V version is also well suited for high-end LLC stages due to its rugged body diode that withstands slew rates up to 20 V/ns. The product portfolio contains TO-247 4-pin, ThinPAK 8x8, TO-leadless and top-side cooled Double DPAK (DDPAK) packages which come with additional Kelvin source contacts enabling further efficiency advantages over the classical 3-pin approach.

Key features of CoolMOS[™] C7 and C7 Gold (G7)

- Reduced switching loss parameters such as Q_G and C_{oss}, enabling higher switching frequency
- ightarrow 50 percent E_{oss} reduction compared to older CoolMOS[™] CP
- > Suitable for hard switching topologies (650 V and 600 V)
- > Suitable for high-end resonant (600 V only) topologies

Key benefits of CoolMOS[™] C7 and C7 Gold (G7)

- Increased efficiency in hard switching topologies such as PFC and TTF
- Reduced size and cost of magnetic components by increased switching frequency (e.g. 65 -130 kHz)
- Increased power density by smaller packages for same R_{DS(on)}



PFC CCM 1200 W efficiency difference for 90 V_{AC} (PFC CCM, 1.150 W @ 65 kHz)

MOSFET losses [W] IPW60R045CP vs. IPZ60R060C7, highline 2.5 kW



Power ICs

Motor control ICs

www.infineon.com/c7

600 V CoolMOS™ CFD7 SJ MOSFET

Infineon's answer to resonant switching high power applications

The 600 V CoolMOS[™] CFD7 is Infineon's latest high voltage superjunction MOSFET series with an integrated fast body diode. It is the ideal choice for resonant topologies, such as LLC and ZVS PSFB, and targets the high SMPS market.

As a result of significantly reduced gate charge (Q_G) , improved turn-off behavior, a reverse recovery charge (Q_r) of up to 69 percent lower compared to the competition, as well as the lowest reverse recovery time (t_r) in the market, it combines highest efficiency and best-in-class reliability in soft switching applications, without sacrificing the easy implementation in the design-in process.

In addition, the 600 V CoolMOS[™] CFD7 enables higher power density solutions by offering best-in-class on-state resistance (R_{DS(on)}) package combinations in through-hole devices, as well as in surface-mount devices. In ThinPAK 8x8 and TO-220 with CoolMOS[™] CFD7, a R_{DS(on)} of around 30 percent below the next best competitor offering can be achieved. All this together makes CoolMOS[™] CFD7 the perfect fit for server and telecom applications, and it is also suitable for EV-charging stations.



Efficiency comparison of CFD7 vs. CFD2 and competition in 2 kW ZVS



Key features

- > Ultrafast body diode
- > Best-in-class reverse recovery charge (Q_{rr})
- > Improved reverse diode dv/dt and dif/dt ruggedness
- Lowest figure of merit (R_{DS(on)} x Q_G x E_{oss})
- > Best-in-class R_{DS(on)}/package combinations

Key benefits

- Best-in-class hard commutation ruggedness
- > Highest reliability for resonant topologies
- Highest efficiency with outstanding ease of use/performance trade-off
- Enabling increased power density solutions



Motor control ICs

CoolMOS™ CE SJ MOSFET

High voltage superjunction MOSFETs for consumer

CoolMOS[™] CE is a product family launched by Infineon to address consumer and lighting applications. It offers benefits in efficiency and thermal behavior versus standard MOSFETs and is optimized for ease of use and cost-competitiveness, while delivering the right fit performance and excellent Infineon quality.

Application example: 10 W and 15 W smartphone charger



CoolMOS[™] CE meets the standard efficiency requirements in charger application



CoolMOS[™] CE case temperature:

The maximum MOSFET case temperature is required to be below 90°C. CoolMOS[™] CE meets this requirement and offers enough margin required for design-in flexibility. CoolMOS[™] CE efficiency performance:

CoolMOS[™] CE meets the 80 percent standard efficiency requirement and offers enough margin required for design-in flexibility.





15 W design: IPS65R1K0CE

EN 55022 B radiated HF-field

The performance of CoolMOS[™] CE in the 10 W and 15 W design demonstrates that the series meets common EMI requirements for charger applications and thus, is also offering design-in flexibility.

CoolMOS™ CE customer benefits	CoolMOS™ CE customer benefits							
Product portfolio	We offer a broad portfolio covering five voltage classes in both through-hole and SMD packages							
Capacity	We own the world largest capacity for power devices, with three dedicated frontends and four backends							
Quality	Our field failure rates are as low as 0.1 DPM							
Design-in support	We have a large field application engineering team to provide professional and flexible support for your design							



Motor control ICs

CoolMOS™ SJ MOSFET high power package innovations

Space-saving and high performance packages



Innovative top-side cooled SMD solution for high power applications



For highest efficiency and controllability in high power SMPS markets



Enabling significant space savings



Optimized for high power applications

Top-side cooled Double DPAK (DDPAK)

This is the first top-side cooled surface mount device (SMD) package addressing high power SMPS applications such as PC power, solar, server and telecom. SMD-based SMPS designs support fast switching and help to reduce the parasitic inductance associated with long leaded packages such as the common TO-220 package. In today's SMD-based designs, the output power is restricted by the thermal limit of the PCB material because the heat must be dissipated through the board. Thanks to the top-side cooling concept of DDPAK, the thermal decoupling of board and semiconductor is possible, enabling higher power density or improved system lifetime.

TO-247 4-pin with asymmetric leads

The TO-247 4-pin package with asymmetric leads is an optimized version of the standard TO-247 4-pin and enables highest efficiency and controllability in the high power SMPS market. The fourth pin acts as a Kelvin source. The main current of the switch is placed outside of the gate loop and the feedback is eliminated. This leads to less switching losses, especially at high currents. Secondly, the EMI will be reduced due to cleaner waveforms. In addition, the asymmetric leads further improve the ease of use in the design-in process. Compared to the standard TO-247 4-pin the distance between the critical pins has been increased to enable simplified wave soldering and reduced board yield loss.

ThinPAK 8x8

With very small footprint of only 64 mm² (vs. 150 mm² for the D²PAK) and a very low profile with only 1 mm height (vs. 4.4 mm for the D²PAK) the ThinPAK 8x8 leadless SMD package for high voltage MOSFETs is a first choice to decrease system size in power-density driven designs. Low parasitic inductance and a separate 4-pin Kelvin source connection offer best efficiency and ease of use. The package is RoHS compliant with halogen-free mold compound.

TO-leadless

Combined with the latest CoolMOS[™] C7 Gold (G7) technology, the TO-leadless (TOLL) package is Infineon's flagship SMD package for high power/high current SMD solutions. Compared to D²PAK 7-pin, TO-leadless shows a 30 percent reduction in footprint, yet offers improved thermal performance. This and the 50 percent height reduction result in a significant advantage whenever highest power density is demanded. Equipped with 4-pin Kelvin source connection and low parasitic inductances the package offers best efficiency and ease of use. The package is MSL1 compliant and reflow solderable. 500-950 V MOSFETs

CoolMOS[™] SJ MOSFET low power package innovations

Addressing today's consumer needs



Cost-effective drop-in replacement for DPAK



Solution for slim and small adapters and chargers



Solution for height reduction in adapters and chargers



Improved creepage distance for open frame power supplies

SOT-223

The SOT-223 package without middle pin is a cost-effective alternative to DPAK, addressing the need for cost reductions in price sensitive applications. It offers a smaller footprint, while still being pin-to-pin compatible with DPAK, thus, allowing a drop-in replacement for DPAK and second sourcing. Moreover, SOT-223 achieves comparable thermal performance to DPAK and enables customers to achieve improved form factors or space savings in designs with low power dissipation.

ThinPAK 5x6

ThinPAK 5x6 reduces the PCB area by 52 percent and height by 54 percent when compared to the DPAK package which is widely used in chargers and adapters. ThinPAK 5x6 is the right device to replace DPAK and meet the market demands of slimmer and smaller designs. Also ThinPAK 5x6 enables a reduced charger and adapter case hot spot temperature by increasing the space between the MOSFET and the charger and adapter case.

TO-220 FullPAK Narrow Lead

Infineon's TO-220 FullPAK Narrow Lead addresses customer needs with regards to height reduction requirements in adapter and charger applications. By offering an optimized standoff width and height and improved creepage distance, the package can be fully inserted into the PCB without any production concerns and, therefore, is especially suitable for slim and semi-slim adapter solutions.

TO-220 FullPAK Wide Creepage

This package solution has an increased creepage distance between the pins to 4.25 mm compared to 2.54 mm of a TO-220 FullPAK package. It targets open frame power supplies such as TV sets and PC power, where dust can enter the case through air vents. Dust particles can reduce the effective creepage between pins over time, which may lead to high voltage arcing. The package meets the requirements of open frame power supplies without any additional measures. Thus, it reduces system cost by offering an alternative to frequently used approaches to increase creepage distance. 500-950 V MOSFETs

Motor control ICs

Packages

CoolMOS[™] SJ MOSFET for automotive

600 V CoolMOS[™] CPA and 650 V CoolMOS[™] CFDA – on the fast lane in automotive applications

Highest system performance in a size and weight constrained environment, outstanding and proven product quality and reliability, as well as 100 percent reliable delivery are the needs of our automotive customers. With the high voltage automotive MOSFET series 600 V CoolMOS[™] CPA and 650 V CoolMOS[™] CFDA, Infineon is perfectly prepared to take the challenges in the strongly growing automotive market.

Product series	Key features	Applications	Quality	
600 V CoolMOS™ CPA	Best choice for demanding hard switching applications > Lowest R _{DS(on)} per package > Lowest gate charge value Q ₆	 Hard switching topologies PFC boost stages in on-board charger Active clamp or two transistor forward in DC-DC converter 	Quality level well beyond the formal	
650 V CoolMOS™ CFDA	Easy implementation of layout and design Integrated fast body diode Limited voltage overshoot during hard commutation – self-limiting dl/dt and dV/dt Low Q _r at repetitive commutation on body diode and low Q _{oss}	 Resonant switching topologies DC-DC stage of OBC LLC or full-bridge ZVS in DC-DC converter HID lamp 	 requirements of the AEC Q101 standard through Special screening measures in front end, back end Mission-profile based qualification procedures 	

CoolMOS[™] SJ MOSFET automotive – benchmark in quality and reliability

Focus on top-notch quality and reliability without any compromise – that is the principle Infineon applies during development and qualification of all CoolMOS[™] superjunction technologies. For our automotive grade derivatives, the great quality levels of the industrial base technologies are further boosted by special screening measures in front and back end, as well as by extended qualification procedures. The Infineon robustness validation approach with extended stress-test procedures, doubling the real application requirements, is one of our key measures to ensure a quality level well beyond the formal requirements of the AEC Q101 standard. Aside from extended stress times on standard qualification tests, it comprises test procedures, specially developed by Infineon to ensure highest quality of e.g., the power metallization of our devices. Usage of robust package technologies, 100 percent gate oxide screening, and top-notch production monitoring, including yield screening measures, part average testing (PAT), statistical bin alarm (SBA), and pattern recognition procedures, complete our package to guarantee highest automotive quality. This holistic approach results in an unrivalled quality position of our 600 V CoolMOS[™] CPA and 650 V CoolMOS[™] CFDA.



Robustness validation - example for thermal cycling test

www.infineon.com/cfda www.infineon.com/coolmos-automotive



Motor control ICs



Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

106

Packages

CoolMOS[™] SJ MOSFET automotive – ready to support future application trends

Driven by the carbon dioxide (CO₂) reduction initiatives, the market of plug-in hybrid PHEV and pure EV is strongly growing. Higher ranges of the electric vehicles are realized by increasing the battery capacity and the energy efficiency of the used electric components. The used battery voltage classes tend to become standardized at 270 V, 480 V and 870 V with a trend towards the higher voltages, as this supports faster charging times and enables lighter cabling within the vehicle. Discrete high voltage components are widely used for on board charger (OBC) and DC-DC converter (LDC) applications, as price pressure increasingly displaces module-based solutions. The trend towards fast charging impacts on the power range demanded from OBC topologies. Presently, as well as in the past, a vast majority of OBC topologies have been found in the range from 3.2 kW to 7.2 kW, whereas the future tends to stir the trend towards 11 kW or even up to 22 kW. This development, paired with a demand for high efficiency and power density at low system cost, is a strong driver for the usage of three-phase solutions.



While for the lower power OBC solutions classic PFC approaches are the well-established approaches in the market, the Vienna rectifier is the optimal solution for the higher power levels. As a true three-phase topology, it delivers full power if attached to a three-phase input but is flexible enough to run on a single-phase if required. The three-level topology minimizes the filter effort compared to other solutions. By using the doubled frequency on the magnetic components, it also helps to significantly reduce the size of the passives. As a three-level topology, the Vienna rectifier, followed by two paralleled DC-DC stages, furthermore leads to a relaxed voltage stress level on the power MOSFETs. This way, it enables to handle upcoming higher battery voltage levels. The $R_{DS(on)}$, required to yield a desired efficiency level in a Vienna Rectifier, is a function of applied switching frequency and demanded power level. With our 600 V CoolMOSTM CPA and 650 V CoolMOSTM CFDA portfolio, covering an $R_{DS(on)}$ range from 45 to 660 m Ω , we are well prepared to support your next generation three-phase Vienna rectifier design. With CoolMOSTM you are ready to seize your share in the emerging high-power onboard-charger markets.

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 $R_{DS(on)}$ [m Ω]

450

750

1200

2000

3700

950 V CoolMOS[™] P7 ACTIVE & PREFERRED

TO-220

FullPAK

IPA95R450P7

IPA95R750P7

IPA95R1K2P7

TO-220

900 V CoolMOS[™] C3 ACTIVE

Industrial SMPS

5

AUX pomer

D²PAK

1822

ThinPAK 8x8

TO-220

Wide creepage

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ac	
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$\begin{array}{c} R_{\text{DS(on)}} \\ [m\Omega] \end{array}$	TO-220	TO-262 (I²PAK)	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	
120					IPW90R120C3	
340	IPP90R340C3	IPI90R340C3	IPB90R340C3	IPA90R340C3	IPW90R340C3	
500		IPI90R500C3		IPA90R500C3	IPW90R500C3	
800	IPP90R800C3			IPA90R800C3		
1000	IPP90R1K0C3			IPA90R1K0C3		
1200	IPP90R1K2C3	IPI90R1K2C3		IPA90R1K2C3		IPD90R1

SOT-223

IPN95R1K2P7

IPN95R2K0P7

IPN95R3K7P7

TO-251

Long lead

IPU95R450P7

IPU95R750P7

IPU95R1K2P7

IPU95R2K0P7

IPU95R3K7P7

TO-252

(DPAK)

IPD95R450P7

IPD95R750P7

IPD95R1K2P7

IPD95R2K0P7

$R_{DS(on)}$ [m Ω]	TO -220	TO-220 FullPAK	TO-247	TO-252 (DPAK)	TO-251 (IPAK)	TO-251 (IPAK Short Lead)	SOT-223	TO-220 FullPAK narrow lead	ThinPAK 5x6*
280	IPP80R280P7	IPA80R280P7	IPW80R280P7	IPD80R280P7				IPAN80R280P7	
360	IPP80R360P7	IPA80R360P7	IPW80R360P7	IPD80R360P7				IPAN80R360P7	
450	IPP80R450P7	IPA80R450P7		IPD80R450P7				IPAN80R450P7	
600	IPP80R600P7	IPA80R600P7		IPD80R600P7	IPU80R600P7	IPS80R600P7	IPN80R600P7		IPLK80R600P7*
750	IPP80R750P7	IPA80R750P7		IPD80R750P7	IPU80R750P7	IPS80R750P7	IPN80R750P7		IPLK80R750P7*
900	IPP80R900P7	IPA80R900P7		IPD80R900P7	IPU80R900P7	IPS80R900P7	IPN80R900P7		IPLK80R900P7*
1200	IPP80R1K2P7	IPA80R1K2P7		IPD80R1K2P7	IPU80R1K2P7	IPS80R1K2P7	IPN80R1K2P7		IPLK80R1K2P7*
1400	IPP80R1K4P7	IPA80R1K4P7		IPD80R1K4P7	IPU80R1K4P7	IPS80R1K4P7	IPN80R1K4P7		IPLK80R1K4P7*
2000				IPD80R2K0P7	IPU80R2K0P7	IPS80R2K0P7	IPN80R2K0P7		IPLK80R2K0P7*
2400				IPD80R2K4P7	IPU80R2K4P7	IPS80R2K4P7	IPN80R2K4P7		
3300				IPD80R3K3P7	IPU80R3K3P7		IPN80R3K3P7		
4500				IPD80R4K5P7	IPU80R4K5P7		IPN80R4K5P7		

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800 V	CoolMOS™ CE	ACTIVE				
$\begin{array}{c} R_{\text{DS(on)}} \\ [m\Omega] \end{array}$	TO-220	TO-220 FullPAK	TO-247	TO-252 (DPAK)	TO-251 (IPAK)	TO-251 (IPAK Short Lead)
310		IPA80R310CE				
460		IPA80R460CE				
650		IPA80R650CE				
1000		IPA80R1K0CE		IPD80R1K0CE	IPU80R1K0CE	
1400		IPA80R1K4CE		IPD80R1K4CE		
2800				IPD80R2K8CE		

800 V	CoolMOS™ C3	ACTIVE			Adapter	
$R_{DS(on)}$ [m Ω]	TO-220	TO-262 (I²PAK)	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	TO-252 (DPAK)
85					SPW55N80C3	
290	SPP17N80C3		SPB17N80C3	SPA17N80C3	SPW17N80C3	
450	SPP11N80C3			SPA11N80C3	SPW11N80C3	
650	SPP08N80C3			SPA08N80C3		
900	SPP06N80C3			SPA06N80C3		SPD06N80C3
1300	SPP04N80C3			SPA04N80C3		SPD04N80C3
2700				SPA02N80C3		SPD02N80C3

-	700 V	CoolMO	Ѕ™ Р7 астій	E & PREFERRED				Charger		Audio
	$\begin{array}{c} R_{_{DS(on)}} \\ [m\Omega] \end{array}$	TO -220	TO – 262 (I²PAK)	TO-251 (IPAK Short Lead)	TO-220 FullPAK	ThinPAK 5x6	TO-252 (DPAK)	TO-220 FullPAK narrow lead	TO-251 (IPAK Short Lead w/ ISO Standoff)	SOT-223
	360			IPS70R360P7S	IPA70R360P7S		IPD70R360P7S	IPAN70R360P7S	IPSA70R360P7S	IPN70R360P7S
	450				IPA70R450P7S			IPAN70R450P7S	IPSA70R450P7S	IPN70R450P7S
	600			IPS70R600P7S	IPA70R600P7S	IPLK70R600P7	IPD70R600P7S	IPAN70R600P7S	IPSA70R600P7S	IPN70R600P7S
	750				IPA70R750P7S	IPLK70R750P7		IPAN70R750P7S	IPSA70R750P7S	IPN70R750P7S
	900			IPS70R900P7S	IPA70R900P7S	IPLK70R900P7	IPD70R900P7S	IPAN70R900P7S	IPSA70R900P7S	IPN70R900P7S
	1200					IPLK70R1K2P7			IPSA70R1K2P7S	IPN70R1K2P7S

IPS70R1K4P7S

700 V	CoolMOS™	CE ACTIVE					Adapt	
$R_{DS(on)}$ [m Ω]	TO-220	TO-220 FullPAK Wide Creepage	TO-262 (I²PAK)	TO-251 (IPAK Short Lead with ISO Standoff)	TO-252 (DPAK)	TO-251 (IPAK)	TO-251 (IPAK Short Lead)	SOT-223
600		IPAW70R600CE		IPSA70R600CE	IPD70R600CE			
950		IPAW70R950CE	IPI70R950CE	IPSA70R950CE	IPD70R950CE		IPS70R950CE	
1000								IPN70R1K0CE
1400				IPSA70R1K4CE	IPD70R1K4CE		IPS70R1K4CE	
1500								IPN70R1K5CE
2000				IPSA70R2K0CE	IPD70R2K0CE		IPS70R2K0CE	
2100								IPN70R2K1CE

IPLK70R1K4P7

IPLK70R2K0P7

IPD70R1K4P7S

IPSA70R1K4P7S

IPSA70R2K0P7S

IPN70R1K4P7S

IPN70R2K0P7S

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* Coming soon

1400

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

650 V C	CoolMOS™ C7 (Gold (G-series)	ACTIVE & PREFERRED			
$R_{DS(on)}$ [m Ω]	TO -220	TO-Leadless (TOLL)	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	TO -252 (DPAK)
33		IPT65R033G7				
105		IPT65R105G7				
195		IPT65R195G7				

650 V (CoolMOS™ C7	ACTIVE & PREFERRE	D			Solar FC Power Solar	
$\begin{array}{c} R_{\text{DS(on)}} \\ [m\Omega] \end{array}$	TO-220	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin	TO-252 (DPAK)	ThinPAK 8x8
19				IPW65R019C7	IPZ65R019C7		
45	IPP65R045C7	IPB65R045C7	IPA65R045C7	IPW65R045C7	IPZ65R045C7		
65	IPP65R065C7	IPB65R065C7	IPA65R065C7	IPW65R065C7	IPZ65R065C7		
70							IPL65R070C7
95	IPP65R095C7	IPB65R095C7	IPA65R095C7	IPW65R095C7	IPZ65R095C7		
99							IPL65R099C7
125	IPP65R125C7	IPB65R125C7	IPA65R125C7	IPW65R125C7			
130							IPL65R130C7
190	IPP65R190C7	IPB65R190C7	IPA65R190C7	IPW65R190C7		IPD65R190C7	
195							IPL65R195C7
225	IPP65R225C7	IPB65R225C7	IPA65R225C7			IPD65R225C7	
230							IPL65R230C7

LCD TV	LED	Consumer	Adapter	Charger
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50 V	Coo	IMOS	™ CE	ACTIVE	

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$R_{DS(on)}$ [m Ω]	TO-220	TO-220 FullPAK	TO-247	TO-252 (DPAK)	TO-251 (IPAK)	TO-251 (IPAK Short Lead)	SOT-223	TO-220 FullPAK Narrow Lead
400		IPA65R400CE		IPD65R400CE		IPS65R400CE		
650		IPA65R650CE		IPD65R650CE		IPS65R650CE		IPAN65R650CE
1000		IPA65R1K0CE		IPD65R1K0CE		IPS65R1K0CE		
1500		IPA65R1K5CE		IPD65R1K5CE			IPN65R1K5CE	

650 V	CoolMOS™ C	FD2 ACTIVE			Server		eNobility
$R_{DS(on)}$ [m Ω]	TO-220	TO-262 (I²PAK)	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	TO-252 (DPAK)	ThinPAK 8x8
41					IPW65R041CFD		
80					IPW65R080CFD		
110	IPP65R110CFD		IPB65R110CFD	IPA65R110CFD	IPW65R110CFD		
150	IPP65R150CFD		IPB65R150CFD	IPA65R150CFD	IPW65R150CFD		
165							IPL65R165CFD
190	IPP65R190CFD	IPI65R190CFD	IPB65R190CFD	IPA65R190CFD	IPW65R190CFD		
210							IPL65R210CFD
310	IPP65R310CFD		IPB65R310CFD	IPA65R310CFD			
340							IPL65R340CFD
420	IPP65R420CFD			IPA65R420CFD	IPW65R420CFD	IPD65R420CFD	
660				IPA65R660CFD		IPD65R660CFD	
950						IPD65R950CFD	

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IPD65R1K4CFD



Charger Adapter Lighting

	rial grade					l		
$\begin{array}{c} R_{\text{DS(on)}} \\ [m\Omega] \end{array}$	TO -220	TO-220 FullPAK	TO-247	TO-247 4-pin asymmetric leads	TO-252 (DPAK)	TO-220 FullPAK Wide Creepage	ThinPAK 8x8	D²PAK
24			IPW60R024P7	IPZA60R024P7				
37			IPW60R037P7	IPZA60R037P7				
45			IPW60R045P7	IPZA60R045P7				IPB60R045P7
60	IPP60R060P7	IPA60R060P7	IPW60R060P7	IPZA60R060P7				IPB60R060P7
65							IPL60R065P7	
80	IPP60R080P7	IPA60R080P7	IPW60R080P7	IPZA60R080P7			IPL60R085P7	IPB60R080P7
99	IPP60R099P7	IPA60R099P7	IPW60R099P7	IPZA60R099P7				IPB60R099P7
105							IPL60R105P7	
120	IPP60R120P7	IPA60R120P7	IPW60R120P7	IPZA60R120P7				IPB60R120P7
125							IPL60R125P7	
160	IPP60R160P7	IPA60R160P7						
180	IPP60R180P7	IPA60R180P7	IPW60R180P7	IPZA60R180P7	IPD60R180P7			IPB60R180P7
185							IPL60R185P7	
280	IPP60R280P7	IPA60R280P7			IPD60R280P7			IPB60R280P7
285							IPL60R285P7	
360	IPP60R360P7	IPA60R360P7			IPD60R360P7			IPB60R360P7
365							IPL60R365P7	
600	IPP60R600P7	IPA60R600P7			IPD60R600P7			

600 V CoolMOS[™] P7 ACTIVE & PREFERRED Standard grade

600 V CoolMOS[™] P7 ACTIVE & PREFERRED

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$\begin{array}{c} R_{\text{DS(on)}} \\ [m\Omega] \end{array}$	TO -220	TO-220 FullPAK	TO-220 FullPAK Narrow lead	TO-247 4-pin	TO-252 (DPAK)	TO-220 FullPAK Wide Creepage	ThinPAK 8x8	SOT-223
180		IPA60R180P7S	IPAN60R180P7S		IPD60R180P7S	IPAW60R180P7S		
280		IPA60R280P7S	IPAN60R280P7S		IPD60R280P7S	IPAW60R280P7S		
360		IPA60R360P7S	IPAN60R360P7S		IPD60R360P7S	IPAW60R360P7S		IPN60R360P7S
600		IPA60R600P7S	IPAN60R600P7S		IPD60R600P7S	IPAW60R600P7S		IPN60R600P7S

600 V CoolMOS[™] CFD7 ACTIVE & PREFERRED

$\begin{array}{c} R_{\scriptscriptstyle DS(on)} \\ [m\Omega] \end{array}$	TO-220	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin	TO-252 (DPAK)	ThinPAK 8x8
18				IPW60R018CFD7			
24				IPW60R024CFD7*			
31				IPW60R31CFD7			
40		IPB60R040CFD7*		IPW60R40CFD7			
55		IPB60R055CFD7*		IPW60R55CFD7			
60							IPL60R060CFD7
70	IPP60R70CFD7	IPB60R070CFD7*		IPW60R70CFD7			
75							IPL60R75CFD7
90/95	IPP60R90CFD7	IPB60R090CFD7*		IPW60R90CFD7			IPL60R095CFD7
105/115	IPP60R105CFD7	IPB60R105CFD7*		IPW60R105CFD7			IPL60R115CFD7
125/140	IPP60R125CFD7	IPB60R125CFD7*	IPA60R125CFD7	IPW60R125CFD7			IPL60R140CFD7
145/160	IPP60R145CFD7	IPB60R145CFD7*	IPA60R145CFD7	IPW60R145CFD7		IPD60R145CFD7	IPL60R160CFD7
170	IPP60R170CFD7	IPB60R170CFD7*	IPA60R170CFD7	IPW60R170CFD7		IPD60R170CFD7	
185							IPL60R185CFD7
210/225	IPP60R210CFD7	IPB60R210CFD7*	IPA60R210CFD7			IPD60R210CFD7	IPL60R225CFD7*
280	IPP60R280CFD7	IPB60R280CFD7*	IPA60R280CFD7			IPD60R280CFD7	
360	IPP60R360CFD7*	IPB60R360CFD7*	IPA60R360CFD7*			IPD60R360CFD7*	

600 V CoolMOS[™] C7 Gold (G-series) ACTIVE & PREFERRED

$R_{DS(on)}$ [m Ω]	TO -220	TO-Leadless (TOLL)	TO-220 FullPAK	TO-247	TO-247 4-pin	TO-252 (Double DPAK)	ThinPAK 8x8
28		IPT60R028G7					
50		IPT60R050G7				IPDD60R050G7	
80		IPT60R080G7				IPDD60R080G7	
102		IPT60R102G7				IPDD60R102G7	
125		IPT60R125G7				IPDD60R125G7	
150		IPT60R150G7				IPDD60R150G7	
190						IPDD60R190G7	

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*Coming soon

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Discrete IGBTs

Applications

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

EV charger

Solar PC Power Server Telecom SMPS

500 V	CoolMOS™ C	7 ACTIVE & PREFE	RRED				
$\begin{array}{c} R_{_{DS(on)}} \\ [m\Omega] \end{array}$	TO-220	TO-263 (D²PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin	TO-252 (DPAK)	ThinPAK 8x8
17				IPW60R017C7	IPZ60R017C7		
40	IPP60R040C7	IPB60R040C7		IPW60R040C7	IPZ60R040C7		
60	IPP60R060C7	IPB60R060C7	IPA60R060C7	IPW60R060C7	IPZ60R060C7		
65							IPL60R065C7
99	IPP60R099C7	IPB60R099C7	IPA60R099C7	IPW60R099C7	IPZ60R099C7		
104							IPL60R104C7
120	IPP60R120C7	IPB60R120C7	IPA60R120C7	IPW60R120C7			
125							IPL60R125C7
180	IPP60R180C7	IPB60R180C7	IPA60R180C7	IPW60R180C7		IPD60R180C7	
185							IPL60R185C7

600 V	CoolMOS™ P	6 ACTIVE				Consumer Lighting - - - - - - - - - - - - -	
$R_{DS(on)}$ [m Ω]	TO-220	TO-220 FullPAK	TO-247	TO-247 4-pin	TO-252 (DPAK)	ThinPAK 5x6	ThinPAK 8x8
41			IPW60R041P6				
70			IPW60R070P6	IPZ60R070P6			
99	IPP60R099P6	IPA60R099P6	IPW60R099P6	IPZ60R099P6			
125	IPP60R125P6	IPA60R125P6	IPW60R125P6				
160	IPP60R160P6	IPA60R160P6	IPW60R160P6				
180							IPL60R180P6
190	IPP60R190P6	IPA60R190P6	IPW60R190P6				
210							IPL60R210P6
230		IPA60R230P6					
255							
280	IPP60R280P6	IPA60R280P6	IPW60R280P6				
330/360						IPL60R360P6S	
380		IPA60R380P6			IPD60R380P6		
600		IPA60R600P6			IPD60R600P6		
650						IPL60R650P6S	

20-300 V MOSFETs

Packages

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600 V	CoolMOS™	CE ACTIVE							
R _{DS(on)} [mΩ]	TO-220 FullPAK	TO-220 FullPAK Wide Creepage	TO-247	TO-252 (DPAK)	TO-251 (IPAK)	TO-251 (IPAK Short Lead)	SOT-223	TO-220 FullPAK Narrow Lead	
190		IPAW60R190CE		(DFAR)	(IFAR)	(IFAR SHOT Lead)		Natiow Lead	
280		IPAW60R280CE							
380		IPAW60R380CE							
400	IPA60R400CE			IPD60R400CE		IPS60R400CE			
460	IPA60R460CE			IPD60R460CE		IPS60R460CE			
600		IPAW60R600CE							
650	IPA60R650CE			IPD60R650CE		IPS60R650CE		IPAN60R650CE	
800				IPD60R800CE		IPS60R800CE		IPAN60R800CE	
1000	IPA60R1K0CE			IPD60R1K0CE	IPU60R1K0CE	IPS60R1K0CE	IPN60R1K0CE		
1500	IPA60R1K5CE			IPD60R1K5CE	IPU60R1K5CE	IPS60R1K5CE	IPN60R1K5CE		
2100				IPD60R2K1CE	IPU60R2K1CE	IPS60R2K1CE	IPN60R2K1CE		
3400				IPD60R3K4CE		IPS60R3K4CE	IPN60R3K4CE		

500 V CoolMOS[™] CE ACTIVE & PREFERRED



$\begin{array}{c} R_{\text{DS(on)}} \\ [m\Omega] \end{array}$	TO-220	TO-220 FullPAK	TO-247	TO-252 (DPAK)	TO-251 (IPAK)	TO-251 (IPAK Short Lead)	SOT-223	TO-220 FullPAK Narrow Lead
190	IPP50R190CE	IPA50R190CE						
280	IPP50R280CE	IPA50R280CE		IPD50R280CE				
380	IPP50R380CE	IPA50R380CE		IPD50R380CE				
500		IPA50R500CE		IPD50R500CE				IPAN50R500CE
650				IPD50R650CE			IPN50R650CE	
800		IPA50R800CE		IPD50R800CE			IPN50R800CE	
950		IPA50R950CE		IPD50R950CE			IPN50R950CE	
1400				IPD50R1K4CE			IPN50R1K4CE	
2000				IPD50R2K0CE			IPN50R2K0CE	
3000				IPD50R3K0CE			IPN50R3K0CE	

500-950 V MOSFETs

CoolMOS[™] SJ MOSFET automotive

650 V CoolMOS[™] CFDA ACTIVE & PREFERRED



Product type	$\begin{array}{c} {\sf R}_{{}_{{\sf DS}(on)}}@~{\sf T}_{{}_{{\sf J}}}=25^{\circ}{\sf C} \\ {\sf V}_{{}_{{\sf GS}}}=10~{\sf V} \\ [m\Omega] \end{array}$	I _{D,max.} @ T _J = 25°C [A]	I _{D_puls,max.} [A]	V _{GS(th),minmax.} [V]	Q _{G,typ.} [nC]	R _{thJC,max.} [K/W]	Package
IPD65R420CFDA	420	8.7	27	3.54.5	32	1.5	TO-252
IPD65R660CFDA	660	6	17	3.54.5	20	2	TO-252
IPB65R110CFDA	110	31.2	99.6	3.54.5	11	0.45	TO-263
IPB65R150CFDA	150	22.4	72	3.54.5	86	0.64	TO-263
IPB65R190CFDA	190	17.5	57.2	3.54.5	68	0.83	TO-263
IPB65R310CFDA	310	11.4	34.4	3.54.5	41	1.2	TO-263
IPB65R660CFDA	660	6	17	3.54.5	20	2	TO-263
IPP65R110CFDA	110	31.2	99.6	3.54.5	11	0.45	TO-220
IPP65R150CFDA	150	22.4	72	3.54.5	86	0.64	TO-220
IPP65R190CFDA	190	17.5	57.2	3.54.5	68	0.83	TO-220
IPP65R310CFDA	310	11.4	34.4	3.54.5	41	1.2	TO-220
IPW65R048CFDA	48	63.3	228	3.54.5	27	0.25	TO-247
IPW65R080CFDA	80	43.3	127	3.54.5	16	0.32	TO-247
IPW65R110CFDA	110	31.2	99.6	3.54.5	11	0.45	TO-247
IPW65R150CFDA	150	22.4	72	3.54.5	86	0.64	TO-247
IPW65R190CFDA	190	17.5	57.2	3.54.5	68	0.83	TO-247

600 V CoolMOS[™] CPA ACTIVE

Product type	$ \begin{array}{c} {\sf R}_{{\rm DS}({\rm on})} @~{\rm T_J} = 25^{\circ}{\rm C} \\ {\sf V}_{{\rm GS}} = 10~{\rm V} \\ [{\rm m}\Omega] \end{array} $	I _{D,max.} @ T _J = 25°C [A]	I _{D_puls,max.} [A]	V _{GS(th),min-max.} [V]	Q _{G,typ.} [nC]	R _{thJC,max.} [K/W]	Package
IPB60R099CPA	99	31	93	2.5 3.5	60	0.5	TO-263
IPB60R199CPA	199	16	51	2.5 3.5	32	0.9	TO-263
IPB60R299CPA	299	11	34	2.5 3.5	22	1.3	TO-263
IPP60R099CPA	99	31	93	2.5 3.5	60	0.5	TO-220
IPW60R045CPA	45	60	230	2.5 3.5	150	0.29	TO-247
IPW60R075CPA	75	39	130	2.5 3.5	87	0.4	TO-247
IPW60R099CPA	99	31	93	2.5 3.5	60	0.5	TO-247
IPI60R099CPA	99	31	93	2.5 3.5	60	0.5	TO-262

800 V CoolMOS[™] C3A ACTIVE & PREFERRED

Product type	$\begin{array}{c} {\sf R}_{{\rm DS}(on)} @ \ {\rm T}_{{\rm J}} = 25^{\circ}{\rm C} \\ {\sf V}_{{\rm GS}} = 10 \ {\rm V} \\ [m\Omega] \end{array}$	I _{D,max.} @ T _J = 25°C [A]	I _{D_puls,max.} [A]	V _{GS(th),minmax.} [V]	Q _{G,typ.} [nC]	R _{thJC,max.} [K/W]	Package
IPD80R2K7C3A	2700	2	6	2.1 3.9	12	3	TO-252
IPB80R290C3A	290	17	51	2.1 3.9	91	0.55	TO-263
IPW80R290C3A	290	17	51	2.1 3.9	91	0.55	TO-247

www.infineon.com/coolmos www.infineon.com/coolmos-automotive www.infineon.com/cfda



500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Applications

CoolMOS[™] SJ MOSFETs – packages

SOT-223

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
500	CE								650/800	950/1400	2000/3000
600	P7						360	600			
600	CE									1000/1500	2100/3400
650	CE									1500	
700	P7						360	450/600	700	900/1200/1400	2000
100	CE									1000/1500/2100	
800	P7								650/750	900/1200/1400	2000/2400/ 3300/4500
950	P7									1200	2000/3700

TO-247

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
	P7	24/37/45	60/80	99/120	180						
	C7	17/40	60	99/120	180						
600	P6	41	70	99/125	160/190	280					
	CFD7	31/40/55	70	90/125	170						
	CPA	45	75	99							
	C7	19/45	65	95/125	190						
650	CFD2	41	80	110	150/190			420			
	CFDA	48	80	110	150/190						
200	P7					280	360				
800	C3		85			290		450			
900	С3			120			340	500			

TO-247 4-pin

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
600	C7	17/40	60	99							
600	P6		70	99							
650	C7	19/45	65	95							

TO-247 4-pin asymmetric leads

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
600	P7	24/37/45	60/80	99/120	180						

IPAK										6	
						R _{DS(on}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
600	CE									1000/1500	2100
800	P7							600	750	900/1200/1400	2000/2400 3300/4500
	CE									1000	
950	P7							450	750	1200	2000/3700

ACTIVE & PREFERRED

www.infineon.com/coolmos-latest-packages



IPAK Short Lead

				$R_{DS(on)}[m\Omega]$									
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500		
600	CE						400	460	650/800	1000/1500	2100/3400		
650	CE						400		650	1000			
700	P7						360/600			900/1400			
100	CE									950/1400	2000		
800	P7							600	750	900/1200/1400	2000/2400		



IPAK Short Lead with ISO Standoff

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
700	P7						360	450/600	750	900/1200/1400	2000
700	CE							600		950/1400	2000

51744						2	[0]				1
						R _{DS(on}	[mΩ]	,			
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
500	CE					280	380	500	650/800	950/1400	2000/3000
	P7				180	280	360	600			
	C7				180						
600	CE						400	460	650/800	1000/1500	2100/3400
	P6						380	600			
	CFD7				170	280	360*				
	C7				190	225					
650	CE						400		650	1000/1500	
650	CFD2							420	660	950/1400	
	CFDA							420	660		
700	P7						360	600		900/1400	
100	CE							600		950/1400	2000
	P7					280	360	450/600	750	900/1200/1400	2000/2400
800											3300/4500
800	C3									900/1300	2700
	CE									1000/1400	2800
900	C3									1200	
950	P7							450	750	1200	2000

I ² PAK												
						R _{DS(on}	[mΩ]					
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500	
600	СРА			99								
650	CFD2				199							
700	CE									950		
900	С3						340	500		1200		

500-950 V MOSFETs

Packages

*Coming soon

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

D²PAK

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
	C7	40	60	99/120	180		ĺ			ĺ	ĺ
	P7	45	60/80	99/120	180	280	360				
600	CPA			99	199	299					
	CFD7	40* 55*	70*	20*/105* 125*/145*	170*	210* 280*	360*				
	C7	45	65	95/125	190	225					
650	CFD2			110	150/190		310				
	CFDA			110	150/190		310		660		
800	С3					290					
900	C3						340				

Double DPAK (DDPAK)

				$R_{DS(on)}[m\Omega]$							
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
600	G7	50	80	102/125	150/190						

TO-220 FullPAK

						R _{DS(on}	_] [mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
500	CE		ĺ		190	280	380	500	800	950	
	P7		60/80	99/120	160/180	280	360	600			
	C7		60	99/120	180						
600	CE						400	460	650	1000/1500	
	CFD7			125	170	280	360*				
	P6			99/125	160/190	230/280	380	600			
	C7	45	65	95/125	190	225					
650	CE						400		650	1000/1500	
	CFD2			110	150/190		310	420	660		
700	P7						360	450/600	750	900	
	P7					280	360	450/600	750	900/1200/1400	
800	C3					290		450	650	900/1300	2700
	CE						310	460	650	1000/1400	
900	C3						340	500	800	1000/1200	
950	P7							450	750	1200	

TO-220 FullPAK Narrow Lead

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
500	CE							500			
600	CE								650/800		
600	P7				180	280	360	600			
650	CE								650		
700	P7						360	450/600	750	900	
800	P7					280	360	450			

TO-leadles	SS
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			R _{DS(on)} group [mΩ]										
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500		
600	G7	28/50	80	102/125	150								
650	G7	33		105	195								

*Coming soon

ACTIVE & PREFERRED

Packages

20-300 V MOSFETs

ACTIVE & PREFERRED)
ACTIVE & PREFERREL	,

TO-220

						R _{DS(on)}	[mΩ]				
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
500	CE				190	280	380				
	P7		60/80	99/120	160/180	280	360	600			
	С7	40	60	99/120	180						
600	P6			99/125	160/190	280					
	CFD7		70	90/125	170	280	360*				
	CPA			99							
	С7	45	65	95/125	190	225					
650	CFD2			110	150/190		310	420			
	CFDA			110	150/190		310		660		
000	P7					280	360	450/600	750	900/1200/1400	
800	С3					290		450	650	900/1300	
900	C3						340		800	1000/1200	

TO-220 FullPAK Wide Creepage

$R_{DS(on)}\left[m\Omega ight]$											
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
COO	P7				180	280	360	600			
600	CE				190	280	380	600			
700	CE							600		950	

ThinPAK 5x6

			$R_{pS(on)}\left[m\Omega ight]$								
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500
600	P6						360		650		
700	P7							600	750	900/1200/1400	2000
800	P7							600	750	900/1200/1400	2000

ThinPAK 8x8

			$R_{DS(on)}[m\Omega]$										
Voltage [V]	Series	0-59	60-89	90-149	150-199	200-299	300-400	401-600	601-899	900-1500	>1500		
	P7		65/85	105/125	185	285	365						
600	C7		65	104/125	185								
600	CFD7		75		185	225*							
	P6				180	210							
650	С7		70	99/130	195	230							
050	CFD2				165	210	340						

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*Coming soon

Nomenclature

Power MOSFETs (until 2005)



Power MOSFETs (from October 2015 onwards)



Packages



20-300 V MOSFETs



Infineon support for high voltage MOSFETs

Useful links and helpful information

Further information, datasheets and documents

www.infineon.com/coolmos www.infineon.com/coolmos-latest-packages www.infineon.com/coolmos-automotive

Evaluationboards and simulation models www.infineon.com/coolmos-boards www.infineon.com/powermosfet-simulationmodels

Videos www.infineon.com/mediacenter





Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Wide bandgap semiconductors

Gallium nitride (GaN) and silicon carbide (SiC)

The key to the next essential step towards an energy-efficient world is to use new materials, such as wide bandgap semiconductors that allow for greater power efficiency, smaller size, lighter weight, lower overall cost – or all of these together. Infineon Technologies, with its unique market position of being currently the only company offering silicon (Si), silicon carbide (SiC) and gallium nitride (GaN) devices, is the customer's first choice in all segments.

CoolGaN[™] – ultimate efficiency and reliability

Compared to silicon (Si), the breakdown field of Infineon's CoolGaN™ enhancement mode (e-mode) HEMTs is ten times higher and the electron mobility is double. Both the output charge and gate charge are ten times lower than with Si and the reverse recovery charge is almost zero which is key to high frequency operations. GaN is the best-suited technology in hard switching as well as resonant topologies, and is enabling new approaches in current modulation. Infineon's GaN solution is based on the most robust and performing concept in the market – the enhancement mode concept - offering fast turn-on and turn-off speed. CoolGaN™ products focus on high performance and robustness, and add significant value to a broad variety of systems across many applications such as server, telecom, hyperscale data centers, wireless charging, adapter/charger, and audio. CoolGaN™ switches are easy to design-in with the matching GaN EiceDRIVER[™] gate driver ICs from Infineon.

CoolSiC[™] - revolution to rely on

Silicon carbide (SiC) has a wide bandgap of 3 electronvolt (eV) and a much higher thermal conductivity compared to silicon. SiC-based MOSFETs are best-suited for high-breakdown, high-power applications that operate at higher frequencies compared to traditional IGBTs. CoolSiC[™] MOSFETs come along with a fast internal freewheeling diode, thus making hard switching without additional diode chips possible. Due to its unipolar character, the MOSFETs show very low, temperature-independent switching and low conduction losses, especially under partial load conditions. Based on proven, high quality volume manufacturing, Infineon's CoolSiC[™] solutions combine revolutionary technology with benchmark reliability – for our customers' success today and tomorrow. The offering is completed by selected driver ICs based on Infineon's successful coreless transformer technology.

Packages



CoolGaN™ e-mode HEMTs

Tailor-made for the highest efficiency and power density in switch mode power supplies

In comparison to the next best silicon alternative, CoolGaN[™] enables higher power density and the highest efficiency, especially in the partial load range, through novel topologies such as the CCM totem pole PFC stage. GaN e-mode HEMT performance features low reverse recovery charge and excellent dynamic performance in reverse conduction compared to silicon FET solutions. This enables more efficient operation at established frequencies, and much higher frequency operation which can improve power density by shrinking the size of passive components. CoolGaN[™] enables doubled output power in a given energy storage slot size, freeing up space and realizing higher efficiency at the same time.

Infineon's CoolGaN[™] comes with industry leading reliability. During the quality management process, it is not only the device which is thoroughly tested but also its behavior in the application environment. The performance of CoolGaN[™] goes beyond other GaN products in the market.

Features

- Low output charge and gate charge
- > No reverse recovery charge

Design benefits

- High power density, small and light design
- > High efficiency in resonant circuits> New topologies and current
- modulation
- Fast and (near-)lossless switching

Application

orofile

Advantages

QRP – quality

requirement profile

Qualification plan

Released

product

- Operational expenses (OPEX) and capital expenditure (CAPEX) reduction
- > BOM and overall cost savings

Degradation

nodels

Infineon leverages its unique portfolio of high and low voltage MOSFETs, driver ICs and digital controllers to complement its CoolGaN[™] product line, thus enabling full exploit for GaN benefits.

The highest quality

The qualification of GaN switches requires a dedicated approach, well beyond existing silicon standards

- Infineon qualifies GaN devices well beyond industry standards
- Application profiles are an integral part of the qualification
- Failure models, based on accelerated test conditions, ensure target lifetime and quality are met
- > Infineon sets the next level of wide bandgap quality



CoolGaN[™] e-mode HEMTs overview

www.infineon.com/gan

124

Discrete IGBTs

Rel. investigation at

development phase

CoolGaN[™] 400 V and 600 V e-mode GaN HEMTs – bringing GaN technology to the next level

Infineon's CoolGaN[™] 400 V* and 600 V e-mode HEMTs enable more than 98 percent system efficiency and help customers to make their end products smaller and lighter. Driving enhancement mode devices requires some additional features when choosing the correct gate driver IC, however CoolGaN[™] technology does not require customized ICs. Infineon offers three new members of a single-channel galvanic isolated gate driver IC family. The new components are a perfect fit for e-mode GaN HEMTs with non-isolated gate (diode input characteristic) and low threshold voltage, such as CoolGaN[™].

Complete support of all requirements specific to e-mode GaN HEMTs operation:

- > Low driving impedance (on-resistance 0.85 Ω source, 0.35 Ω sink)
- > Resistor programmable gate current for steady on-state (typically 10 mA)
- > Programmable negative gate voltage to completely avoid spurious turn-on in half-bridges

Block diagram: high-efficiency GaN switched mode power supply (SMPS)



*GaN EiceDRIVER™ ICs are single-channel products

www.infineon.com/gan

* Coming soon

Motor control ICs

CoolGaN[™] 400 V^{*} e-mode GaN HEMTs

Class D output stage offering the best audio experience

CoolGaN[™] 400 V enables smoother switching and more linear class D output stage by offering low/linear C_{oss} zero Q_{rr} , and normally-off switch. Ideal class D audio amplifiers offer 0 percent distortion and 100 percent efficiency. What impairs the linearity and power loss is highly dependent on switching characteristics of the switching device. Infineon's CoolGaN[™] 400 V breaks through the technology barrier by introducing zero reverse recovery charge in the body diode and very small, linear input and output capacitances.

In addition, the e-mode concept offers fast turn-on and turn-off speed. This feature also simplifies pairing CoolGaN™ with the IRS20957S class D controller and therefore enables faster go-to-market.

CoolGaN[™] for class D audio solutions

CoolGaN[™] 400 V is tailored for premium HiFi home audio, professional, and aftermarket car audio systems where end users demand every detail of their high resolution sound tracks. These have been conventionally addressed by bulky linear amplifiers or tube amplifiers. With CoolGaN™ 400 V as the class D output stage, audio designers will be able to deliver the best audio experience to their prospective audio fans.

CoolGaN[™] 400 V devices in PG-DSO-20-87 and PG-TOLL package have been tested in class D audio amplifier applications on 300 W+300 W dual-channel system designs.

Key features

- > Ultralow and linear C_{oss} 400 V power devices
- > Zero Q_{rr}
- > E-mode transistor normally-off switch

Key benefits

- > Clean switching performance
- Narrow dead time for better THD
- > Easy to use: compatible with the IRS20957S class D audio control IC

400 V CoolGaN[™] benefits from the engineering expertise Infineon has made towards challenging applications, such as telecom rectifiers and SMPS servers, where CoolGaN[™] technology proved to be highly reliable. It is the most robust and performing concept in the market. The 400 V CoolGaN™ portfolio is built around class D Audio requirements, with high performing SMD packages to fully exploit the benefits of GaN technology.

Gate driver ICs

Microcontrollers

XENSIVTM sensors

CoolGaN[™] 600 V e-mode GaN HEMTs

The highest efficiency and power density with reduced system costs

The e-mode concept offers fast turn-on and turn-off speed, as well as a better path towards integration. CoolGaN™ 600 V e-mode HEMTs enable simpler and more cost-effective half-bridge topologies. As e-mode based products reach maturity, CoolGaN™ 600 V HEMTs are gaining growing prominence thanks to their potential. The CoolGaN™ 600 V series is manufactured according to a specific, GaN-tailored qualification process which goes far beyond the standards for silicon power devices. CoolGaN™ 600 V is designed for datacom and server SMPS, telecom rectifiers, as well as mobile chargers and can be used as a general switch in many other industrial and consumer applications. It is the most rugged and reliable solution in the market. The CoolGaN™ portfolio is built around high performing SMD packages to fully exploit the benefits of GaN.

CoolGaN[™] for PFC

CoolGaN[™] enables the adoption of simpler half-bridge topologies (including elimination of the lossy input bridge rectifier). The result is record efficiency (>99%) with a potential for BOM savings.

CoolGaN[™] for resonant topologies

- > In resonant applications, ten times lower Q_{oss} and Q_g enables high frequency operations (>1 MHz) at the highest efficiency levels
- > Linear output capacitance leads to 8 to 10 times lower dead time
- > Devices can be easily paralleled
- > Power density can be pushed even further by optimizing the thermal performance
- > CoolGaN[™] enables to push the efficiency forward, thus enabling high power density e.g., in low power chargers



Applications

- > Telecom
- > Server
- Datacom
- Adapter and charger
- > Wireless charging
- > SMPS





Demonstration board 2.5 kW totem pole PFC board: EVAL 2500W PFC GAN A



2 x 70 mΩ CoolGaN™ in DSO-20 BSC > 2 x 33 mΩ CoolMOS™

www.infineon.com/gan

Package

R_{DS(on) max}

 $70\,m\Omega$

CoolGaN[™] 400 V e-mode GaN HEMTs

DSO-20-87

Top-side cooling

up to 500 W

IGOT40R070D1**

D))

HSOF-8-3

(TO-leadless)

up to 200 W

IGT40R070D1**

LSON-8-1

SP number

SP002447622

SP003194020

SP002753980

CoolG	iaN™ 600 V e-mode Gal	N HEMTs		
Package R _{DS(on)}	DSO-20-85 Bottom-side cooling	DSO-20-87 Top-side cooling	HSOF-8-3 TO-leadless	
35 mΩ	IGO60R035D1**	IGOT60R035D1**	IGT60R035D1**	

R _{DS(on)}	Bottom-side cooling	Top-side cooling	TO-leadless	DFN 8x8
35 mΩ	IGO60R035D1**	IGOT60R035D1**	IGT60R035D1**	
70 mΩ	IGO60R070D1	IGOT60R070D1	IGT60R070D1	IGLD60R070D1
190 mΩ			IGT60R190D1S*	IGLD60R190D1**
190 mU			IGT60R190D1**	
340 mΩ				IGLD60R340D1**

Infineon's CoolGaN™ devices, driven by single-channel isolated gate driver ICs from the GaN EiceDRIVER™ family, aim to unlock the full potential of GaN technology.

	GaN Eic	eDRIVER™ f	amily proc			Telecom Server	Adapter Drives		
Product Package			Input to out	put isolation	Propagation	Typ. high level	Typ. low level		
			Isolation class	Rating	Surge testing	Certification	delay accuracy	(sourcing) out- put resistance	(sinking) out- put resitance
	1EDF5673K	LGA, 13-pin, 5x5 mm	functional	V _{IO} = 1.5 kV _{DC}	n.a.	n.a.	-6 ns/+7ns	0.85 Ω	0.35 Ω
	1EDF5673F	DSO, 16-pin, 150 mil	functional	V _{IO} = 1.5 kV _{DC}	n.a.	n.a.	-6 ns/+7ns	0.85 Ω	0.35 Ω

 $V_{ISOM} > 10 \text{ kV}_{pk}$

VDE0884-10

UL1577

-6 ns/+7ns

0.85 Ω

0.35 Ω

 $V_{IOTM} = 8 kV_{pk}$ $V_{ISO} = 5.7 kV_{rm}$

reinforced

128

1EDS5663H

DSO, 16-pin,

300 mil



Nomenclature



Divided by 10 (60x10 = 600 V)

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XENSIVTM sensors

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

Silicon carbide

Improve efficiency and solution costs

Silicon carbide (SiC) devices belong to the so-called wide bandgap semiconductor group, which offers a number of attractive characteristics for high voltage power semiconductors when compared to commonly used silicon (Si). In particular, the much higher breakdown field strength and thermal conductivity of silicon carbide allow developing devices which by far outperform the corresponding silicon-based ones, and enable efficiency levels unattainable otherwise. Infineon's portfolio of SiC devices covers 600 V and 650 V to 1200 V Schottky diodes as well as the revolutionary CoolSiC[™] MOSFET.

CoolSiC[™] Schottky diodes

The differences in material properties between silicon carbide and silicon limit the fabrication of practical silicon unipolar diodes (Schottky diodes) to a range up to 100-150 V, with a relatively high on-state resistance and leakage current. In SiC, Schottky diodes can reach a much higher breakdown voltage. Infineon offers products up to 1200 V in discrete packages and up to 1700 V in modules.

Features

- > No reverse recovery charge
- > Purely capacitive switching
- High operating temperature (T_{j, max} 175°C)
- Advantages
- Low turn-off losses
- > Reduction of CoolMOS™ or IGBT turn-on loss
- > Switching losses independent from load current, switching speed and temperature

Benefits

- System efficiency improvement compared to Si diodes
- Reduced cooling requirements
- > Enabling higher frequency/increased power density
- > Higher system reliability due to lower operating
 - temperature

- Applications > Server
 - Telecom >
 - Solar

>

>

- UPS
- EV charging >
- Energy storage >
- PC power >
- Motor drives >
- Lighting
- > CAV
- Reduced EMI

8 6 Z -10 ••
0.07 0.1 0.13 0.16 0.19 0.22 Time [µs] SiC Schottky diode Si-pin double diode (2*300 V) 95.0 94.5 94.0 Efficiency [%] 93.5 93.0 92.5 92.0 91.5 91.0 -120 180 240 Switchting frequency [kHz]

📕 Infineon SiC 6 A 📕 Comp. 1 6 A 📕 Comp. 2 6 A

Reverse recovery charge of SiC Schottky diodes versus Si-pin diodes The majority of carrier characteristics imply no reverse recovery charge and the only contribution to the switching losses comes from the tiny displacement charge of capacitive nature. In the same voltage range, silicon devices have a bipolar component resulting in much higher switching losses. The graph shows the comparison between various 600 V devices.

Improved system efficiency (PFC in CCM mode operation, full load, low line) The fast switching characteristics of the SiC diodes provide clear efficiency improvements at system level. The performance gap between SiC and high-end silicon devices increases with the operating frequency.

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20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Sate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Infineon is the world's first SiC discrete power supplier. The long market presence and experience enable Infineon to deliver highly reliable, industry-leading SiC performance. With over 10 years pioneering experience in developing and manufacturing SiC diodes, Infineon's latest CoolSiC[™] Schottky diode generation 6 family sets benchmark in quality, efficiency and reliability.

CoolSiC[™] Schottky diodes 650 V CoolSiC[™] Schottky diodes 650 V G6 and G5

The new CoolSiC[™] Schottky diode 650 V G6 product family is built over the strong characteristics of the previous generation G5, fully leveraging technology and process innovation to propose the best efficiency and zero price/ performance products to date.

Foundation technology – CoolSiC[™] Schottky diodes 650 V G5

The established CoolSiC[™] Schottky diodes G5 product family has been optimized after all key aspects including junction structure, substrate and die attach. It represents a well-balanced product family which offers state-of-the-art performance and high surge current capability at competitive cost level.

Innovation: optimized junction, substrate and die attach

Infineon's SiC Schottky diode generation 5 is optimized with regard to all key aspects relevant for high power and high efficiency SMPS applications.



Junction: merged PN structure

On the junction level, it has an optimized merged PN structure. Compared to competitors, Infineon's SiC diode has additional P-doped area, which, together with the N-doped EPI layer, forms a PN junction diode. Thus, it is a combination of Schottky diode and PN junction diode. Under normal conditions it works like a standard Schottky diode. Under abnormal conditions such as lighting, AC line drop-out, it works like a PN junction diode. At high current level, the PN junction diode has significantly lower forward voltage (V_F) than Schottky diode, which leads to less power dissipation, thus significantly improving the surge current capability.

Substrate: thin wafer technology

On the substrate level, Infineon introduced thin wafer technology. At the later stage of our SiC diode production, thin wafer process is used to reduce the wafer thickness by about two-thirds, which significantly reduces the substrate resistance contribution, thus, improving both forward voltage (V_F) and thermal performance.

Die attach: diffusion soldering

On the backside, package level diffusion soldering is introduced, which significantly improves the thermal path between lead frame and the diode, enhancing the thermal performance. With the same chip size and power dissipation, the junction temperature is reduced by 30°C.



R_{thJC}=2.0 K/W

 R_{thJC} =1.5 K/W

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Latest development - CoolSiC™ Schottky diodes 650 V G6

On the top of these technologies, the CoolSiC[™] Schottky diodes G6 product family introduces a novel and proprietary Schottky metal system. This contributes to the reduction of the forward voltage (V_F) to levels which are difficult, determining a measurable decrease of conduction losses.



Infineon's CoolSiCTM Schottky diodes enable optimum efficiency and ruggedness. Lower forward voltage (V_F) means lower conduction loss, and lower capacitive charge (Q_c) means lower switching loss. $Q_c \times V_F$ is the figure of merit for efficiency, and comparison indicates that the latest generation 6 products have the lowest $Q_c \times V_F$ on the market. Infineon's CoolSiCTM Schottky diodes offer a surge current robustness far better than the one offered by the most efficient products. Thus, under abnormal conditions, this surge current capability offers excellent device robustness.



Efficiency comparison

In terms of efficiency, the 8 A G6 device has been tested in CCM PFC. The maximum output power is 3.5 kW. The left figure shows the relative efficiency at 65 kHz, while the right figure shows the relative efficiency at 130 kHz. This shows that Infineon's CoolSiC[™] Schottky diode G6 delivers better efficiency over the full load range, keeping this advantage even at 130 kHz, therefore meeting the needs of designers who want to increase the switching frequencies in their designs to attain more power density.

www.infineon.com/coolsic-g6

Discrete IGBTs

Motor control ICs



The best price performance

CoolSiC[™] Schottky diodes G6 are the outcome of Infineon's continuous technological and process improvements, enabling the design and development of SiC-based products, making them more price-competitive and increasing performance across generations. As a result, G6 is Infineon's best price/performance CoolSiC[™] Schottky diode generation, offering the highest cost-efficiency. In addition, Infineon offers the reliability of collaborating with the industry leader. Customers can leverage Infineon's proven quality and supply chain reliability. They can benefit from "one-stop-shop" advantages and maximize system performance, combining CoolSiC[™] Schottky diodes with the SJ MOSFETs of the CoolMOS[™] 7 family, such as 600 V C7, 650 V C7, 600 V G7, 650 V G7 and 600 V P7.



A comprehensive portfolio

The combined G6 and G5 650 V CoolSiC[™] Schottky diode portfolio offers wide choice of packages and ampere class granularity to allow the best fit to application. G6 comes in double DPAK, the first top-side cooled surface mount package, which allows thermal decoupling of PCB to chip junction and enables higher power dissipation and improved system lifetime thanks to the reduced board temperature.

www.infineon.com/coolsic-g6

Discrete IGBTs

Motor control ICs

Packages

CoolSiC[™] Schottky diodes 1200 V

New level of system efficiency and reliability

By using hybrid Si power switch/SiC diode sets, designers of industrial applications will gain flexibility for system optimization compared to purely silicon-based solutions. System improvements by higher efficiency, higher output power or higher switching frequency are enabled by SiC diodes. Implementing CoolSiC[™] diodes generation 5, for example in Vienna rectifier topology, in combination with Infineon's 650 V TRENCHSTOP[™] IGBTs and 650 V CoolMOS[™] MOSFETs, designers can achieve outstanding system level performance and reliability.

Key features of generation 5

- Low forward voltage (V_F) 1.4 V
- > Mild positive temperature dependency of V_F
- High surge current capability up to fourteen times of the nominal current
- > Up to 40A-rated diode

Key benefits of 1200 V generation 5

- Reduced cooling requirements through lower diode losses and lower case temperatures
- > High system reliability by extended surge current



650 V Si IGBT/Si SJ MOSFET and 1200 V SiC diode/ultrafast Si diode in a Vienna rectifier topology, f_{sw}=48 kHz

Packages

CoolSiC[™] silicon carbide MOSFETs – revolution to rely on Infineon's CoolSiC[™] technology enables radically new product designs

Silicon carbide (SiC) opens up new degrees of freedom for designers to harness never before seen levels of efficiency and system flexibility. In comparison to traditional silicon-based switches like IGBTs and MOSFETs, the SiC MOSFET offers a series of advantages. These include the low switching losses with 1200 V switches, very low reverse recovery losses of the internal commutation proof body diode, temperature independent low switching losses, and threshold-free on-state characteristics. Based on volume experience and compatibility know-how, Infineon introduces the revolutionary SiC technology which enables radically new product designs with high performance and high reliability. CoolSiC[™] MOSFET products are targeted for photovoltaic inverters, battery charging and energy storage.

CoolSiC[™] MOSFET features

- Revolutionary semiconductor material silicon carbide
- Very low switching losses
- > Threshold-free on-state characteristic
- Wide gate-source voltage range
- > Benchmark gate threshold voltage, $V_{GS(th)} = 4.5 V$
- > Fully controllable dV/dt
- Commutation robust body diode, ready for synchronous rectification
- > Temperature independent turn-off switching losses

Benefits

> Best-in-class system performance

CoolSiC[†]

- > Efficiency improvement and reduced cooling effort
- Significant reduction in junction temperature for longer lifetime and higher reliability
- Enables higher frequency operation for reduction in system cost and shrink
- > Allows for increase in power density
- Two-level topologies can replace three-level with same efficiency for lower complexity and cost
- Excellent for hard switching and resonant switching topologies like LLC and ZVS

TO-247 4-pin package contains an additional connection to the source (Kelvin connection) that is used as a reference potential for the gate driving voltage, thereby eliminating the effect of voltage drops over the source inductance. The result is even lower switching losses than for TO-247 3-pin version, especially at higher currents and higher switching frequencies.



CoolSiC™	[™] Schottky diode	es 650 V G6 ACT	IVE & PREFERRED		Server	UPS Lighting
ا _۴ [A]	TO-220 R2L	TO-247 Dual Die	TO-247	Double DPAK	D ² PAK R2L	ThinPAK 8x8
4	IDH04G65C6			IDDD04G65C6		
6	IDH06G65C6			IDDD06G65C6		
8	IDH08G65C6			IDDD08G65C6		
10	IDH10G65C6			IDDD10G65C6		
12	IDH12G65C6			IDDD12G65C6		
16	IDH16G65C6			IDDD16G65C6		
20	IDH20G65C6			IDDD20G65C6		

CoolSiC™	Schottky diodes 6	50 V G5 ACTIVE		Server	star UPS USS Ugbung PC Power USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Ugbung USS Usbung USS Usbung USS Usbung USS Usbung USS Usbung USS Usbung USS Usbung USS Usbung USS Usbung USS USBUNG
І _ғ [А]	TO-220 R2L	TO-247 Dual Die	TO-247	D ² PAK R2L	ThinPAK 8x8
2	IDH02G65C5			IDK02G65C5	IDL02G65C5
3	IDH03G65C5			IDK03G65C5	
4	IDH04G65C5			IDK04G65C5	IDL04G65C5
5	IDH05G65C5			IDK05G65C5	
6	IDH06G65C5			IDK06G65C5	IDL06G65C5
8	IDH08G65C5			IDK08G65C5	IDL08G65C5
9	IDH09G65C5			IDK09G65C5	
10	IDH10G65C5		IDW10G65C5	IDK10G65C5	IDL10G65C5
12	IDH12G65C5		IDW12G65C5	IDK12G65C5	IDL12G65C5
16	IDH16G65C5		IDW16G65C5		
20	IDH20G65C5	IDW20G65C5B	IDW20G65C5		
24		IDW24G65C5B			
30/32		IDW32G65C5B	IDW30G65C5		
40		IDW40G65C5B	IDW40G65C5		

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Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



CoolSiC™	Schottky diodes	650 V G3 ACTIV	E		Server	UPS Lighting
ا _۴ [A]	TO-220 R2L	TO-247 Dual Die	TO-247	DPAK R2L	D²PAK	ThinPAK 8x8
3	IDH03SG60C			IDD03SG60C		
4	IDH04SG60C			IDD04SG60C		
5	IDH05SG60C			IDD05SG60C		
6	IDH06SG60C			IDD06SG60C		
8	IDH08SG60C			IDD08SG60C		
9	IDH09SG60C			IDD09SG60C		
10	IDH10SG60C			IDD10SG60C		
12	IDH12SG60C			IDD12SG60C		

CoolSiC™ S	chottky diodes 1200 V	G5 ACTIVE & PREFERRED	Storage	
۱ _۶ [A]	TO-220 R2L	TO-247 Dual Die	TO-247 R2L	DPAK R2L
2	IDH02G120C5			IDM02G120C5
5	IDH05G120C5			IDM02G120C5
8	IDH08G120C5			IDM08G120C5
10	IDH10G120C5	IDW10G120C5B	IDWD10G120C5	IDM10G120C5
15/16	IDH16G120C5	IDW15G120C5B	IDWD15G120C5	
20	IDH20G120C5	IDW20G120C5B	IDWD20G120C5	
30		IDW30G120C5B	IDWD30G120C5	
40		IDW40G120C5B	IDWD40G120C5	

"B" in product name refers to common-cathode configuration

www.infineon.com/sic

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Nomenclature

CoolSiC[™] Schottky diodes G2 and G3



CoolSiC[™] Schottky diodes G5 and G6



*Generation

CoolSiC™ MOSFET



Silicon power diodes

Filling the gap between SiC diodes and emitter controlled diodes

The Rapid diode family complements Infineon's existing high power 600 V/650 V diode portfolio by filling the gap between SiC diodes and previously released emitter controlled diodes. They offer a perfect cost/performance balance and target high efficiency applications switching between 18 and 100 kHz. Rapid 1 and Rapid 2 diodes are optimized to have excellent compatibility with CoolMOS[™] and high speed IGBTs (insulated gate bipolar transistor) such as the TRENCHSTOP[™] 5 and HighSpeed 3.

Emitter controlled diodes		Rapid 1	Rapid 2	SiC
	0 Hz 18 l	۲ ۲ (Hz 40	kHz 100	kHz >100 kHz

The Rapid 1 diode family

Rapid 1 is forward voltage drop (V_F) optimized to address low switching frequency applications between 18 kHz and 40 kHz, for example air conditioner and welder PFC stages.

- > 1.35 V temperature-stable forward voltage (V_F)
- Lowest peak reverse recovery current (I_{rrm})
- Reverse recovery time (t_{rr}) < 100 ns</p>
- > High softness factor

The Rapid 2 diode family

Rapid 2 is Q_{rr/trr} optimized hyperfast diode to address high speed switching applications between 40 kHz and 100 kHz, typically found in PFCs in high efficiency switch mode power supplies (SMPS) and welding machines.

- > Lowest reverse recovery charge (Q_{rr}): V_F ratio for best-in-class performance
- > Lowest peak reverse recovery current (I_{rrm})
- Reverse recovery t_{rr} < 50 ns</p>
- > High softness factor



www.infineon.com/rapiddiodes www.infineon.com/ultrasoftdiodes S

Packages



Rapid 1 (Arrow Legislary Urd			
Continuous current I @T _c =100°C	TO-220	TO-220 FullPAK	TO-220 common cathode	TO-247	TO-247 common cathode	TO-247 advanced isolation
[A]	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free
8	IDP08E65D1					
15	IDP15E65D1					
20		IDV20E65D1				
30	IDP30E65D1			IDW30E65D1	IDW30C65D1	
40				IDW40E65D1		IDFW40E65D1E
60					IDW60C65D1	IDFW60C65D1
75					IDW75D65D1	
80					IDW80C65D1	

Rapid 2 diodes 650 V product family						
Continuous current I _c @T _c =100°C [A]	TO-220	TO-220 FullPAK Malogen-Free	TO-220 common cathode	TO-247	TO-247 common cathode	
8	IDP08E65D2	IDV08E65D2				
15	IDP15E65D2	IDV15E65D2		IDW15E65D2		
20	IDP20E65D2		IDP20C65D2		IDW20C65D2	
30	IDP30E65D2	IDV30E65D2	IDP30C65D2		IDW30C65D2	
40	IDP40E65D2			IDW40E65D2		
80					IDW80C65D2	

Discrete IGBTs

Packages

		controlled diodes 200 V product families			Harris Viscon Applicators
CI	ntinuous urrent I _c T _c =100°C	ТО-252 (DPAK)	TO-263 (D²PAK)	TO-220 Real 2-pin	TO-247
	[A]	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free
	6	IDD06E60			
	15		IDB15E60	IDP15E60	
_	30		IDB30E60	IDP30E60	IDW30E60
600 V	45			IDP45E60	
	50				IDW50E60
	75				IDW75E60
	100				IDW100E60
>	12			IDP12E120	
1200 V	18			IDP18E120	
	30		IDB30E120	IDP30E120	

Nomenclature

Silicon power diodes





Infineon support for wide bandgap semiconductors Useful links and helpful information

Further information, datasheets and documents

www.infineon.com/wbg www.infineon.com/sic www.infineon.com/rapiddiodes

Videos www.infineon.com/mediacenter www.infineon.com/ultrasoftdiodes www.infineon.com/gan www.infineon.com/gan-eicedriver





Packages

Motor control ICs

Microcontrollers

XENSIVTM sensors

Packages

Resolute to achieve the highest standards in performance and quality, Infineon offers a comprehensive portfolio of application-specific discrete IGBTs.

Market leadership through groundbreaking innovation and application focus

Discrete IGBT overview

Discrete IGBTs

	P-SOT-223-4 SMD SMD, single transistor, small signal	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	TO-220 FullPAK	TO-247	TO-247 4-pin	TO- 247PLUS	TO- 247PLUS 4-pin	TRENCHSTOP™ advanced isolation TO-247
Package options	M	Ņ								
Voltage class	600 V, 650 V, 1100 V,	600 V, 650 V, 1100 V, 1200 V, 1350 V, 1600 V							600 V, 650 V	
Configuration	DuoPack (with diode	e), single IGB1	ſs							Duopack IGBTs (with diode) and diodes
Continuous coll- ector current T _c = 100°C	2-120 A									40-90 A

New best-in-class technologies and applications

Technology	Application
TRENCHSTOP™ 5 H5/F5 650 V	
TRENCHSTOP™ 5 L5 650 V	
Rapid diode 650 V	
RC-H5 650 V/1200 V/1350 V	
RC-E 1200 V	
WR5 650 V	
RC-drives RC-drives fast 600 V	Revergelater Constraints
TRENCHSTOP™ 5 S5 650 V	Sour US Source Wide
TRENCHSTOP™ IGBT6 650 V	Reverged and the second
TRENCHSTOP™ IGBT6 1200 V	

www.infineon.com/igbtdiscretes
650 V TRENCHSTOP™ 5 IGBT

In terms of switching and conduction losses, there is no other IGBT on the market that can match the performance of the TRENCHSTOP[™] 5. Wafer thickness has been reduced by more than 25 percent, which enables a dramatic improvement in both switching and conduction losses, while providing an increased breakthrough voltage of 650 V. Based on TRENCHSTOP[™] 5 IGBT technology, Infineon has developed six different product families optimized for specific applications, allowing designers to optimize for high efficiency, system cost or reliability demands of the market. The quantum leap of efficiency improvement provided by the TRENCHSTOP[™] 5 IGBT families opens up new opportunities for designers to explore.

								TRENCHSTO	P™ 5 F5 (hard :	switching)					
					TRENCH	ISTOP™ 5 H5	0P™ 5 H5 (hard switching)								
TREN	ICHSTOP™ 5 L	5 (hard	d switching)												
	TRENCH	HSTOP™ 5 S	S5 (hard switcl	ning)											
	TRENCHSTOP [™] 5 WR5 (resonant switching)				<u>;</u>)										
								RC-H5 (reson	ant switching))					
0	10	20	30	40	50	60	70	80	90	100	110	120	130	140	150 kHz

TRENCHSTOP™5 L5	$\begin{array}{l} \textbf{Best-in-class IGBT low V_{CE(sat)} IGBT} \\ V_{CE(sat)} IGBT - 1.05 \text{ V} \\ \textbf{Best trade-off V_{CE(sat)} V_{ss} E_{ts} \text{ for frequencies below 20 kHz} \end{array}$	Solar, UPS, welding > Ultralow frequency converters > Three-level inverter type I NPC 1 and NPC 2 > Modified HERIC inverter > AC output (aluminum/magnesium welding)
TRENCHSTOP™ 5 S5	 Best-in-class ease-of-use IGBT Elimination of: Collector-emitter snubber capacitor and gate capacitor in low inductance designs (<100 nH) Softer switching than TRENCHSTOP™ 5 H5 	UPS, battery charger, solar, welding > Medium frequency converters > Multilevel inverter stages > Output stages > PFC
TRENCHSTOP™ 5 H5/F5	 Best-in-class high frequency IGBT > Bridge to SJMOSFET performance > Highest efficiency, especially under light load conditions 	UPS, solar, welding > High frequency converters > Multilevel inverter stages > Output stages > PFC
TRENCHSTOP™ 5 R5	Price/performance optimized application specific IGBT	Induction cooking – RC-H5 Half-bridge topologies in induction cooking appliances and other resonant switching applications
TRENCHSTOP™ 5 WR5	 Price optimized application specific IGBT for zero current switching (ZCS) Optimized full rated hard switching turn-off typically found in welding Excellent R_G controllability Soft recovery plus low reverse recovery charge (Q_n) for diode 	Air conditioning, welding > Medium frequency converters > Zero-voltage switching > PFC

Highest power density in D²PAK footprint

Infineon's ultrathin TRENCHSTOP[™] 5 IGBT technology allows higher power density in a smaller chip size. Infineon is the first on the market able to fit a 40 A 650 V IGBT with 40 A diode in D²PAK – 25 percent higher than any other competitors that are offering maximum 30 A DuoPack IGBT in D²PAK. Now it is possible to upgrade the available SMD designs for higher power output P_{out}.

Key features

- The highest power density 40 A IGBT co-packed with a 40 A diode in D²PAK
- > 25 percent higher current than any other competitor
- > Superior efficiency of leading TRENCHSTOP[™] 5 technology

Key benefits

- > Higher power design with D²PAK package
- Upgrade of the available designs for higher power output
- Less paralleling for improved system reliability and less complexity
- > Smaller PCB, more compact system design, lighter

20-300 V MOSFETs

Motor control ICs

1200 V IGBT families

The 1200 V TRENCHSTOP[™] 2 IGBT is optimized for low conduction losses with the lowest saturation voltage V_{CE(sat)} of 1.75 V. A soft fast recovery emitter controlled diode further minimizes the turn-on losses.

The 1200 V HighSpeed 3 discrete IGBTs provides the lowest losses and the highest reliability for switching above 20 kHz. Transition to fast switching high speed devices allows reduction in the size of the active components (25-70 kHz).

The new 1200 V IGBT generation, TRENCHSTOP[™] IGBT6, is designed to meet requirements of high efficiency, lowest conduction and switching losses in hard switching and resonant topologies, operating at switching frequencies above 15 kHz. The IGBT6 devices can be used as direct replacement for the Highspeed3 H3 series, without any changes of the design. Such plug-and-play replacement of H3 with new S6 IGBT may benefit up to 0.2 percent efficiency improvement.

The RC-H5 family is the latest generation in the RC-H series of reverse conducting IGBT. With a monolithically integrated diode, they offer optimized performance for resonant switching applications such as induction cooking. R5 devices are also available in 1350 V blocking voltage.



RC-H5	World-class TRENCHSTOP [™] RC-H products High performance and low losses	Induction cooking Resonant switching Medium to high frequency converters
RC-E	New TRENCHSTOP™ RC-E Price versus performance leader	Induction cooking Resonant switching Low to medium power cookers
TRENCHSTOP [™] 2	Best-in-class 1200 V IGBT > Outstanding efficiency > Lowest conduction and switching losses > Market proven and recognized quality leader	Motor control, general purpose inverter, solar, UPS Low frequency converters
HighSpeed 3 H3	High speed/high power IGBT First tailless/low loss IGBT on market Market proven and recognized quality leader 	Solar, UPS, welding Medium frequency converters
NEW! TRENCHSTROP™ IGBT6	 New low switching losses and high power IGBTs Optimized for operation at 15 - 40 kHz Best combination of low V_{CE(sat)} of 1.85 V and low switching losses 	UPS, solar, welding Medium frequency converters

Motor control ICs

www.infineon.com/rch5 www.infineon.com/rc-e www.infineon.com/igbt6-1200v

TRENCHSTOP™ IGBT6

650 V trench and field-stop IGBT for low power motor drives

Motor drives up to 1 kW are used in a wide variety of applications from home appliance fans and compressors to commercial sewing machines and pumps. The market for these products demands longer lifetimes, high reliability and high efficiency. Therefore, these compact motors require power electronics with the lowest losses and best thermal performance.

The TRENCHSTOP[™] IGBT6 family of discrete devices has been designed to meet these specific requirements of motor drives. It has been optimized for the lowest switching losses, which is particularly important in systems with higher switching frequencies up to 30 kHz. Additionally, the IGBTs are co-packed with the soft, fast recovery Rapid 1 anti-parallel diodes for the lowest total losses.

With a higher blocking voltage at 650 V, and short circuit rating, TRENCHSTOP™ IGBT6 is a key contributor to robust motor designs.

The devices are offered in TO-220 FullPAK packages for the required isolation, as well as DPAK for a more compact surface mount solution.

- > Optimized for small drives requiring best-in-class efficiency
- > Up to 20 percent reduction in total losses
- > Lowest switching losses for better heat management and easier design-in



Power losses [W]

Key features

- Lowest collector-emitter saturation voltage (V_{CE(sat)}) and forward voltage (V_F)
- > 650 V blocking voltage
- > 3 µsec short-circuit protection capability
- > Optimized for switching frequencies from 8–30 kHz

Key benefits

- Good thermal performance, especially at higher frequencies
- > Low losses to meet energy efficiency requirements
- Increased design margin and reliability
- > Leading price/performance

Discrete IGBTs

Motor control ICs

www.infineon.com/igbt6

TRENCHSTOP™ IGBT6

New generation 1200 V fast speed IGBT

The new 1200 V IGBT generation TRENCHSTOP[™] IGBT6 is designed to meet requirements of high efficiency, lowest conduction and switching losses in hard switching and resonant topologies operating at switching frequencies above 15 kHz.

The TRENCHSTOP[™] IGBT 6 is released in two product families – low conduction losses optimized S6 series and improved switching losses H6 series. The TRENCHSTOP[™] IGBT6 S6 series features low conduction losses of 1.85 V collector-emitter saturation voltage V_{CE(sat)} combined with low switching losses of the HighSpeed 3 H3 series. TRENCHSTOP[™] IGBT6 H6 series is optimized for low switching losses, provides ~15 percent lower total switching losses when compared to predecessor generation H3.

Very soft, fast recovery anti-parallel emitter controlled diode is optimized for fast recovery while still maintaining a high level of softness complementing to an excellent EMI behaviour.

Positive temperature coefficient allows easy and reliable device paralleling. Very good R_G controllability allows adjustment of IGBT switching speed to the requirements of application.



Key features

- Easy, plug and play replacement of predecessor HighSpeed 3 H3 IGBT
- 0.15 percent system efficiency improvement when changing from H3 to S6 in TO-247-3²⁾
- 0.2 percent system efficiency improvement when changing from H3 to S6 in TO-247PLUS 4-pin²⁾

Key benefits

- Best combination of switching and conduction losses for switching frequency 15–40 kHz
- Low conduction losses with 1.85 V V_{CE(sat)} for S6 series
- > High R_G controllability
- > Low EM
- > Full rated, robust freewheeling diode

Discrete IGBTs

TRENCHSTOP™ advanced isolation

Fully isolated TO-247 package with industry leading IGBTs

TRENCHSTOP[™] advanced isolation solution breaks the limits reached by traditional packaging and isolation techniques. This new isolated package enables the highest power density, the best performance and the lowest cooling effort thanks to an effective and reliable thermal path from the IGBT die to the heatsink.

In addition to providing 100 percent electrical isolation, TRENCHSTOP[™] advanced isolation also eliminates the need for thermal grease or thermal interface sheets. The new package delivers at least 35 percent lower thermal resistivity, helping designers to increase power density, as well as lower system complexity and assembling costs. This new package solution allows industrial and home appliance designs to fully utilize the high performance of TRENCHSTOP[™] IGBTs without compromises for isolation and cooling.

Key features

- > 2500 V_{RMS} electrical isolation, 50/60 Hz, t = 1 min
- > 100 percent tested isolated mounting surface
- > Lowest R_{th(j-h)}
- > Low coupling capacitance, 38 pF
- No need for isolation film or thermal interface material

Key benefits

- > Up to 35 percent reduction in assembly time reduces manufacturing cost
- > Increased power density
- > Improved reliability from higher yield and no isolation film misalignment
- > Less EMI filter design effort
- > Decreased heatsink size

Thermal resistivity of package and isolation types



1) Isolation material: standard polyimide based reinforced carrier insulator film with 152 μm thickness, 1.3 W/mK thermal conductivity

500-950 V MOSFETs

Power ICs

Technology	Version and package	Part number	Equivalent current rating @ 65°C [A]	R _{th(j-h)} [K/W]	V _{CEsat} [V] @ T _{vj} = 25°C
		IKFW40N60DH3E	44	1.35	2.30
	Price/performance advanced isolation TO-247 ¹⁾	IKFW50N60DH3E	60	1.15	2.20
TRENCHSTOP™		IKFW60N60DH3E	74	1.06	2.20
HighSpeed 3		IKFW50N60DH3	60	1.03	1.85
	Best-in-class advanced isolation TO-247 ²⁾	IKFW60N60EH3	63	0.91	1.85
		IKFW90N60EH3	95	0.84	1.85
TRENCHSTOP™	Best-in-class	IKFW50N60ET	64	0.91	1.50
TRENCHSTOP	advanced isolation TO-247	IKFW75N60ET	95	0.84	1.50
Technology	Version and package	Part number	Equivalent current rating @ 65°C [A]	R _{th(j-h)} [K/W]	V _f [V]
Rapid 1 diode	Price/performance	IDFW40E65D1E	35	1.92	1.70
Rapid I diode	advanced isolation TO-247	IDFW60C65D1	2 x 30	1.37	1.45

TRENCHSTOP[™] advanced isolation offers a broad portfolio for specific application needs

1) Optimized to replace FullPAK packages or systems including TO-247 with medium performance insulator, standard polyimide based reinforced carrier insulator with 152 µm thickness, 0.9 W/mK thermal conductivity.

2) Optimized to replace systems using TO-247 with high performance insulator, standard polyimide based reinforced carrier insulator with 152 µm thickness, 1.3 W/mK thermal conductivity.

www.infineon.com/advanced-isolation



TRENCHSTOP™ 5 selection tree



www.infineon.com/trenchstop5

Yes





Applications

IGBT selection tree



www.infineon.com/igbtdiscretes

Hard/no diode for IG** parts

Т



20-300 V MOSFETs

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Т

> 18 kHz – 60 kHz 10 kHz – 100 kHz > 18 kHz – 60 kHz 50 Hz – 20 kHz 10 kHz – 40 kHz medium speed high speed high speed high speed low speed Low V_{CE(sat)} TRENCHSTOP[™] 5 (L5) RC TRENCHSTOP[™] 5 Soft turn-off HighSpeed 3 TRENCHSTOP[™] 5 TRENCHSTOP[™] 5 (S5) (H3) H5/F5 (WR5) 650 V 600 V, 1200 V 650 V 650 V 650 V IKpccN65dS5 IKpccN60H3 IKpccN65H5 IKpccN65dR5 IKpccN65dL5 . IKpccN120H3 IKpccN65F5 IGpccN65L5 IGpccN60H3 IGpccN65H5 IGpccN120H3 IGpccN65F5 UPS PFC PFC UPS Three-level NPC1 and Energy storage **Battery charger** Welding inverter NPC2 topology, Full-brigde inner switches **Battery charger** Welding Half-bridge Two transistor forward Solar UPS Welding Three-level NPC1 and NPC2 topology, Solar Inverter Solar inner switches Energy storage Welding AC output SMPS (Al/Mag welding) Air conditioning HVDC (Telecom/data centers)

Т

TRENCHSTOP[™] and RC-drives

Continuous collector current @ T_c=100°C [A] TO-251 (IPAK)

Halogen-Free

IGU04N60T

TO-252 (DPAK)

🖗 Halogen-Free

TO-263 (D²PAK)

Halogen-Free

TO-247PLUS/ Super 247 (TO247AA)

🐼 Halogen-Free

		IGD06N60T		IGP06N60T				
	10		IGB10N60T	IGP10N60T				
Single IGBT	15		IGB15N60T	IGP15N60T				
	30		IGB30N60T				IGW30N60T IGW30N60TP	
S	40						IGW40N60TP	
	50		IGB50N60T	IGP50N60T			IGW50N60T IGW50N60TP	
	75						IGW75N60T	
	3	IKD03N60RF						
	4	IKD04N60RF IKD04N60R		IKP04N60T				
		IKD06N60RF IKD06N60R IKD06N65ET6	IKB06N60T	IKP06N60T		IKA06N60T		
	10	IKD10N60RF IKD10N60R	IKB10N60T	IKP10N60T		IKA10N60T		
IGBT and diode	15	IKD15N60RF IKD15N60R	IKB15N60T	IKP15N60T		IKA15N60T		
Land	20		IKB20N60T	IKP20N60T			IKW20N60T	
IGB'	30						IKW30N60T IKW30N60DTP	
	40						IKW40N60DTP	
	50				IKFW50N60ET		IKW50N60T IKW50N60DTP	
	75				IKFW75N60ET		IKW75N60T	
	100							IKQ100N60T
	120							IKQ120N60T

TO-220

Halogen-Free

TO-247 advanced isolation

Halogen-Free

TO-220 FullPAK

🐼 Halogen-Free

TO-247

Halogen-Free

www.infineon.com/600V-1200V-trenchstop

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		ridge I disc. Appliance I disc. I di
TO-220	ТО-262 (І ² РАК)	TO-220 FullPAK
Halogen-Free	Halogen-Free	Halogen-Free

Continuous ollector current	TO-252 (DPAK)			TO-262 (I ² PAK)	TO-220 FullPAK	
@ T _c =100°C [A]	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	
6	IKD06N65ET6					
8					IKA08N65ET6*	
10					IKA10N65ET6*	
15					IKA15N65ET6*	

	RENCHSTOP™ IGBT6 NEW! 10 V fast speed IGBT product family									
Continuous collector current @ T _c =100°C [A]		tor current (D ² PAK)		TO-262 (I²PAK)	TO-220 FullPAK	TO-247	TO-247PLUS 3-pin	TO-247PLUS 4-pin		
		Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free		Halogen-Free	Halogen-Free		
ck	15					IKW15N120BH6				
DuoPack	40					IKW40N120CS6		IKY40N120CS6		
Du	75						IKQ75N120CS6	IKY75N120CS6		

	NCHSTO V product fa							CAV Drives	
Continuous collector current @ T _c =100°C		TO-252 (DPAK)			TO-262 (I ² PAK)	TO-220 FullPAK	TO	-247	TO-247PLUS 3-pin
		阙 Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free		Hal	Halogen-Free	
	[A]						TRENCHSTOP™	TRENCHSTOP™ 2	TRENCHSTOP™ 2
Single IGBT	8						IGW08T120		
	15						IGW15T120		
	25						IGW25T120		
ing	40						IGW40T120		
0)	60						IGW60T120		
	8						IKW08T120		
	15						IKW15T120	IKW15N120T2	
DuoPack	25						IKW25T120	IKW25N120T2	
ono	40						IKW40T120	IKW40N120T2	IKQ40N120CT2
-	50								IKQ50N120CT2
	75								IKQ75N120CT2

www.infineon.com/igbt6

TRENCHSTOP™ IGBT6

 * Limited by maximum junction temperature. Applicable for TO-220 standard package.

Gate driver ICs

Applications

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

		ooking series 00 V, 1350 V and 1600 V pro	duct families			
Continuous collector current @Tc=100°C				TO-247		
	[A]	650 V	1100 V	1200 V	1350 V	1600 V
	15			IHW15N120E1 NEW!		
	20	IHW20N65R5				
	20			IHW20N120R5	IHW20N135R5	
	25			IHW25N120E1 NEW!		
	30	IHW30N65R5	IHW30N110R3	IHW30N120R5	IHW30N135R5	IHW30N160R2
	40	IHW40N65R5		IHW40N120R5	IHW40N135R5	
	50	IHW50N65R5				

	hSpeed 3 ′ product far							Wilding
colle	ontinuous ctor current	TO-251 (IPAK)	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	TO-247 advanced isolation	TO-220 FullPAK	TO-247
ھ	T _c =100°C [A]		Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free
	20			IGB20N60H3	IGP20N60H3			IGW20N60H3
IGBT	30			IGB30N60H3	IGP30N60H3			IGW30N60H3
	40							IGW40N60H3
	50							IGW50N60H3
	60							IGW60N60H3
	75							IGW75N60H3
	100							IGW100N60H3
	20			IKB20N60H3	IKP20N60H3			IKW20N60H3
	30							IKW30N60H3
	40					IKFW40N60DH3E		IKW40N60H3
DuoPack	50					IKFW50N60DH3E IKFW50N60DH3		IKW50N60H3
Du	60					IKFW60N60DH3E IKFW60N60EH3		IKW60N60H3
	75							IKW75N60H3
	90					IKFW90N60EH3		

	n Speed 3 V product fa						UPS	Solar Witding Witding
colled	ntinuous ctor current	TO-263 (D²PAK)	TO-220	TO-262 (I ² PAK)	TO-220 FullPAK	TO-247	TO-247PLUS 3-pin	TO-247PLUS 4-pin
@	T _c =100°C [A]	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	🐼 Halogen-Free	Halogen-Free	Halogen-Free
	15					IGW15N120H3		
IGBT	25					IGW25N120H3		
-	40					IGW40N120H3		
	15					IKW15N120H3		
ъ	25					IKW25N120H3		
DuoPack	40					IKW40N120H3	IKQ40N120CH3	IKY40N120CH3
D	50						IKQ50N120CH3	IKY50N120CH3
	75						IKQ75N120CH3	IKY75N120CH3

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		ÖP™ 5 F5, H	5 and S5					Solar Welding	arger U Garded power tools U
Co colle	V product f Intinuous ctor current	TO-251 (IPAK)	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	TO-262 (I²PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin
@	T _c =100°C [A]		Halogen-Free	Halogen-Free	阙 Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free
	20			IGB20N65S5	IGP20N65F5/H5				
	30			IGB30N65S5	IGP30N65F5/H5				
	40				IGP40N65F5/H5			IGW40N65F5/H5	
IGBT	50			IGB50N60H5 NEW!				IGW50N65F5/H5	IGZ50N65H5
	50			IGB50N60S5 NEW!					
	75							IGW75N65H5	IGZ75N65H5
	100								IGZ100N65H5
	8				IKP08N65F5/H5		IKA08N65F5/H5		
	15			IKB15N65EH5 NEW	IKP15N65F5/H5		IKA15N65F5/H5		
	20			IKB20N65EH5 NEW	IKP20N65H5/F5				
	28				IKP28N65ES5 NEW!				
	30			IKB30N65EH5 NEW	IKP30N65H5/F5			IKW30N65H5	
-*				IKB30N65ES5 NEW					
DuoPack	39				IKP39N65ES5 NEW!				
Duo				IKB40N65ES5 NEW!	IKP40N65F5/H5			IKW40N65F5/H5	
	40			IKB40N65EH5 NEW!					
				IKB40N65EF5 NEW!					
	50							IKW50N65F5/H5	IKZ50N65EH5
								IKW50N65EH5	IKZ50N65NH5
	75							IKW75N65EH5	IKZ75N65NH5
									IKZ75N65EH5

TRENCHSTOP [™] 5 L5 low V _{CE(sat)} 650 V product family							interest and the second		
collec	ntinuous tor current	TO-251 (IPAK)	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	TO-262 (I ² PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin
@	۲ _c =100°C [A]		Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free
IGBT	30							IGW30N65L5	
DuoPack	30							IKW30N65EL5 IKW30N65NL5	
Du	75							IKW75N65EL5	IKZ75N75EL5

	TRENCHSTOP [™] 5 WR5 650 V product family					Air	weiding		
colle	ntinuous ctor current	TO-251 (IPAK)	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	TO-262 (I ² PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin
@	T _c =100°C [A]		Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	阙 Halogen-Free
Ş	30							IKW30N65WR5	
DuoPack	40							IKW40N65WR5	
D	50							IKW50N65WR5	

	TRENCHSTOP [™] 5 S5 650 V product family						PS Welding		
colle	ntinuous ctor current	TO-251	TO-252 (DPAK)	TO-263 (D²PAK)	TO-220	TO-262 (I ² PAK)	TO-220 FullPAK	TO-247	TO-247 4-pin
@	T _c =100°C [A]		Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free	Halogen-Free
	30							IKW30N65ES5	
DuoPack	40							IKW40N65ES5	
Duo	50							IKW50N65ES5	IKZ50N65ES5
	75							IKW75N65ES5	IKZ50N65ES5

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20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Nomenclature

IGBT (after 03/2013)



N = N-channel

P = P-channel

IGBT (before 03/2013)



Discrete IGBTs

Packages

Infineon support for discrete IGBTs Useful links and helpful information

Further information, datasheets and documents

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Evaluationboards and simulation models www.infineon.com/eval-TO-247-4pin www.infineon.com/igbtdiscrete-simulationmodels

Videos www.infineon.com/mediacenter





Power management ICs

Technology leadership in power supply



Discrete IGBTs

Power factor correction and combo controller

Critical conduction mode PFC ICs



TDA4862G

Power factor controller (PFC) IC for high-power factor and active harmonic filter

- > IC for sinusoidal line current consumption
- > Power factor approaching 1
- > Controls boost converter as an active harmonics filter
- > Internal start-up with low current consumption
- > Zero current detector for discontinuous operation mode
- > High current totem pole gate driver
- > Trimmed ±1.4% internal reference
- > Undervoltage lockout with hysteresis
- > Very low start-up current consumption
- > Pin compatible with world standard
- > Output overvoltage protection
- > Current sense input with internal low pass filter
- > Totem pole output with active shutdown during UVLO
- > Junction temperature range -40°C to +150°C
- > Available in DIP-8 and SO-8 packages

TDA4863G/TDA4863-2G

Power factor controller IC for high-power factor and low THD additional features to TDA4862

- > Reduced tolerance of signal levels
- > Improved light load behavior
- > Open loop protection
- > Current sense input with leading edge blanking LEB
- > Undervoltage protection
- > SO-8 package

IRS25051 PBF

- > Crticial conduction mode PFC control
- > High power factor and ultralow THD
- > Wide load and line range
- > Regulated and programmable DC bus voltage
- > No secondary winding required
- > MOSFET cycle-by-cycle overcurrent protection
- > DC bus overvoltage protection
- > Low EMI gate drive
- > Ultralow start-up current
- > 20.8 V internal Zener clamp on V_{cc}
- > Excellent ESD and latch immunity
- > RoHS compliant
- > 5-pin SOT-23 package

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Sate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Continuous conduction mode PFC ICs



2nd generation continuous conduction mode PFC IC features

- > Fulfills class D requirements of IEC 61000-3-2
- > Lowest count of external components
- > Adjustable and fixed switching frequencies
- > Frequency range from 20 to 250 kHz
- > Versions with brown-out protection available
- > Wide input range supported
- > Enhanced dynamic response during load jumps
- > Cycle by cycle peak current limiting
- > Integrated protections OVP, OCP
- > DIP-8 and DSO-8
- > Lead-free, RoHS compliant

2nd generation continuous conduction mode PFC IC product portfolio

Product	Frequency – f _{sw}	Current drives	Package
ICE2PCS01G	50-250 kHz	2.0 A	
ICE2PCS02G	65 kHz	2.0 A	
ICE2PCS03G	100 kHz	2.0 A	DSO-8
ICE2PCS05G	20-250 kHz	2.0 A	

Packages

3rd generation continuous conduction mode PFC IC features

- > Fulfills class D requirements of IEC 61000-3-2
- > Integrated digital voltage loop compensation
- > Boost follower function
- > Bulk voltage monitoring signals, brown-out
- > Multi protections such as double OVP
- Fast output dynamic response during load jump
- > External synchronization
- > Extra-low peak current limitation threshold
- > SO-8 and SO-14
- > Lead-free, RoHS compliant

3rd generation continuous conduction mode PFC IC product portfolio

Product	Frequency – f _{sw}	Current drives	Features	Package
ICE3PCS01G	Adjustable	0.75 A	OVP+brown-out	SO-14
ICE3PCS02G		0.75 A	OVP	SO-8
ICE3PCS03G		0.75 A	Brown-out	SO-8

PFC CCM IC by feature	ICE2PCS01G ICE2PCS05G	ICE2PCS02G ICE2PCS03G	ICE3PCS03G	ICE3PCS02G	ICE3PCS01G
Digital control voltage loop		-	\checkmark	\checkmark	\checkmark
Variable frequency	✓ –		\checkmark	\checkmark	\checkmark
Synchronous frequency		-	\checkmark	\checkmark	\checkmark
Open loop protection	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Low peak current limit	-1 V -1 V		-0.4 V	-0.4 V	-0.2 V
Brown-out protection	-	\checkmark	\checkmark	-	\checkmark
Overvoltage protection	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Second overvoltage protection		-		\checkmark	\checkmark
PFC enable function			-		\checkmark
Boost follower mode		\checkmark			
5 V regulator			-		\checkmark

Discrete IGBTs

Resonant LLC half-bridge controller IC

LLC resonant (no SR)



- > Novel and simple design (12 components + HB driver)
- > Minimum operating frequency is adjustable externally
- Burst mode operation for output voltage regulation during no load and/or bus overvoltage
- > Multiple protections in case of fault
- > Input voltage sense for brown-out protection
- > Open loop/overload fault detection by FB pin with auto restart and adjustable blanking/restart time
- > Frequency shift for overcurrent protection
- > Lead-free, RoHS compliant package
- > DSO-8 package

Product	Frequency – f _{sw}	Dead time	Current drives	Package
ICE1HS01G-1	30 kHz~600 kHz	380 ns	1.5 A	DSO-8

Resonant LLC half-bridge controller IC with integrated synchronized rectifier control

LLC resonant + SR



- Novel LLC/SR operation mode and controlled by primary side controller
- > Multiple protections for SR operation
- > Tight tolerance control
- > Accurate setting of switching frequency and dead time
- > Simple system design
- > Optimized system efficiency
- > Multiple converter protections: OTP, OLP, OCP, latch-off enable
- > External disable for either SR switching or HB switching
- > Lead-free, RoHS compliant package
- > DSO-20 package

Product	Frequency - f _{sw}	Dead time	Current drives	Package
ICE2HS01G	30 kHz~1 MHz	100~1000 ns	0.3 A	DSO-20

164

Discrete IGBTs

Motor control ICs

Packages



LLC half-bridge controller IC	ICE1HS01G-1	ICE2HS01G	
Package	DSO-8	DSO-20	
Switching frequency range	up to 600 kHz	up to 1 MHz	
LLC soft start	\checkmark	\checkmark	
LLC burst mode	\checkmark	\checkmark	
Adjustable minimum frequency	\checkmark	\checkmark	
Overload/open loop protection	\checkmark	\checkmark	
Mains undervoltage protection with hysteresis	✓	\checkmark	
Overcurrent protection	2-level	3-level	
Drive signal for synchronous rectification	-	\checkmark	
Adjustable dead time	-	\checkmark	
External latch-off and OTP	-	\checkmark	
Target application	LCD-TV, audio, etc.	Server, PC, LCD-TV, etc.	

Discrete IGBTs

Power ICs

Gate driver ICs

Climate saver systems

Climate saver 80 PLUS® and 80 PLUS® Bronze



Climate	saver	80	PLUS®	Silver
Cumate	Saver	00	LOJ	JILVUI

ICE5GR1680AG ICE3AR1080JG ICE5AR0680AG

Standby block FF CoolSET™



Power ICs

Motor control ICs

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Packages

Climate saver 80 PLUS® Gold Clima

Climate saver 80 PLUS® Platinum

Certification for Infineon's PC power reference design



80 PLUS® Gold

	ICE3PCS01G
PFC block	ICE3PCS02G
	ICE3PCS03G
PWM block	ICE2HS01G
	ICE5GR4780AG
Standby block	ICE5GR2280AG
FF CoolSET™	ICE5GR1680AG
	ICE3AR1080JG
	ICE5AR0680AG

80 PLUS® Platinum

Certification for Infineon's PC power reference design

PFC block	ICE3PCS01G
	ICE3PCS02G
	ICE3PCS03G
PWM block	ICE2HS01G
	ICE5QR4780AZ
	ICE2QR4780G
Standby block	ICE5QR2280AZ
QR CoolSET™	ICE2QR2280G-1
	ICE5QR1680AG
	ICE2QR1080G
	ICE5QR0680AG

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Isolated AC-DC

5th generation quasi-resonant PWM IC and CoolSET[™] features



- > Integrated CoolMOS[™] in both 700 V and 800 V MOSFET with cascode configuration
- > Digital frequency reduction with reducing load
- Novel quasi-resonant to minimize > the spread of switching frequency between low and high line AC input

5th generation quasi-resonant CoolSET™

15 W

14 W~15 W

5.44 Ω ~ 5.18 Ω

ICE2QR4765Z

ICE2QR4765

ICE2QR4765G

ICE2QR4780G

ICE5QR4770AZ

ICE5QR4770AG

ICE5QR4780AZ

2nd generation quasi-resonant CoolSET™

- Selectable active burst mode 5 entry/exit profile
- > Auto restart mode for line overvoltage protection

DSO-12

DIP-7

DSO-12

Output power 85 V_{AC}~300 V_{AC}

T_=50°C

Output power 85 V_{AC}~300 V_{AC} T_a=50°C

R_{DS(0} , max

650 V

800 V

700 V

800 V

- > Auto restart mode for brown-out protection
- > Auto restart mode for V_{cc} under-/ overvoltage protection
- > Auto restart mode for open-loop and output overload protection
- > Auto restart mode for overtemperature protection with hysteresis
- > Auto restart mode for output overvoltage

ICE5QR1680AG

ICE2QR1765Z

ICE2QR1765

ICE2QR1765G

23 W~26 W

22 W

2.35 Ω

20 W~21 W

2.62 Ω

ICE2QR2280Z

ICE2QR2280G

ICE2QR2280G-1

ICE5QR2270AZ

ICE5QR2280AZ

- > Auto restart mode for CS pin short-to-ground protection
- > Limited charging current during V_{cc} pin short-to-ground protection
- > Peak power limitation with input voltage compensation
- > Minimum switching frequency limitation (no audible noise on power units on/off)
- > DSO package (controller) and DIP-7/DSO-12 (CoolSET[™])

32 W

1.25 Ω

31 W

1.11 Ω

ICE2QR1080G

ICE5QR1070AZ



41 W~42 W

38 W~42 W

0.75 Ω~0.71 Ω

ICE5QR0680AZ

ICE5QR0680AG

ICE2QR0665Z

ICE2QR0665

ICE2QR0665G

ICE2QR0680Z

www.	infineon.com	/coolset
vv vv vv.	minicon.com	/0001301

DIP-8

DSO-12

DSO-12

1) Calculated maximum output power in an open frame design at T_a=50°C, T_j=125°C and without copper area as heat sink

Packages

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs



5th generation fixed frequency PWM IC and CoolSET[™] features

- > Integrated CoolMOS[™] in both 700 V and 800 V MOSFET
- Cascode configuration for brown-in protection, fast and robust start-up
- Available in both 100 kHz and 125 kHz fixed switching frequency
- Frequency reduction in tandem with load reduction to increase efficiency

Output powei 85 V_{AC}~300 V_A T_A=50°C

Output power

85 V_{AC}~300 V_{AC} T_a=50°C

700 V

800 V

650 V

800 V

max DIP-7

DSO-12

DIP-7

DIP-8 DSO-12

DIP-7

DSO-12

5th generation fixed frequency CoolSET™

ICE5AR4770BZS

ICE5AR4770AG

ICE5AR4780BZS

ICE5GR4780AG

10~15 W

11.1~5.44 Ω

ICE3RBR4765JZ

ICE3RBR4765JG

ICE3AR4780JZ

ICE3AR4780VJZ

ICE3AR4780CJZ

ICE3AR10080CJZ

ICE3AR4780JG

ICE3BR4765J

3rd generation fixed frequency CoolSET™

15 W

- Selectable active burst mode entry/ exit profile to optimize standby power and ability to disable
- Support CCM flyback operation with in-build slope compensation
- Integrated error amplifier for direct feedback (e.g. non-isolated flyback)
- Adjustable line input overvoltage protection (only ICE5xRxxxAG)

23 W

2.35 Ω

ICE5GR2280AG

19~21 W

3.42~2.62 Ω

ICE3A1065ELJ

ICE3AR2280JZ

ICE3BR2280JZ

ICE3AR2280VJZ

ICE3AR2280CJZ

- V_{cc} and CS pin short-to-ground protection
- Auto restart protection mode to minimize interruption to operation
- > DSO-8 package (standalone controller), DIP-7 and DSO-12 package for CoolSET[™]

27 W

ICE5GR1680AG

23~26 W

1.96~1.71 Ω

ICE3RBR1765JZ

ICE3RBR1765JG

ICE3AR1580VJZ

ICE3BR1765J



40 W

0.80 Ω

0.75~0.71 Ω

ICE3RBR0665JZ

ICE3RBR0665JG

ICE3AR0680JZ

ICE3BR0680JZ

ICE3AR0680VJZ

ICE3BR0665J

ICE5AR0680BZS

ICE5AR0680AG

30~34 W

1.11~1.05 Ω

ICE3A2065ELJ

ICE3AR1080VJZ

ICE3AR1080JG

XENSIV[™] sensors

ICE3AR2280JG

www.infineon.com/coolset

1) Calculated DCM maximum output power in an open-frame design based on T_a=50° C and T_j=125°C without copper area as heatsink

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Fixed frequency PWM IC

	5 th generation		3rd gene	eration
FF PWM IC	ICE5ASAG	ICE5GSAG	ICE3AS03LJG	ICE3BS03LJG
Package	DSG	D-8	DS	0-8
Switching frequency	100 kHz	125 kHz	100 kHz	65 kHz
Operating temperature	-40°C~	-129°C	-25°C	~130°C
Start-up cell	Case	code		/
V _{cc} on/off threshold	16 V/	/10 V	18 V/	10.5 V
Soft start time	12	ms	10 ms	20 ms
Frequency jittering	v	/		/
Modulated gate drive	√			/
Active burst mode	√ (3 level selectable)		\checkmark	
Slope compensation for CCM	\checkmark		-	
Frequency reduction	\checkmark			-
Integrated error amplifier for direct feedback	√			-
Adjustable line Input overvoltage protection	√ with au	to restart		-
Adjustable brown-in protection	√ with auto restart			-
CS pin short-to-ground protection	√ with auto restart			-
$V_{cc}pinshort\text{-to-ground}protection$	√ (no start–up)			-
V _{cc} undervoltage protection	√ with auto restart		√ with au	ito restart
V _{cc} overvoltage protection	√ with auto restart		√ with l	atch–up
Overload /open loop protection	√ with auto restart		√ with aι	ito restart
Overtemperature protection	√ with auto resta	irt and hysteresis	√ with l	atch–up
External blanking time extension	-	-	√ with au	ito restart
External protection enable pin	-	-	√ with l	atch–up

Quasi-resonant PWM IC

Feature	ICE5QSAG	ICE2QS02G	ICE2QS03G
Package	DSO-8	DSO-8	DSO-8
Switching scheme	Novel QR with 10 zero crossing counters	QR with 7 zero crossing counters	QR with 7 zero crossing counters
Operating temperature	-40°C~129°C	-25°C~130°C	-25°C~130°C
Startup cell	Cascode	-	\checkmark
V _{cc} on/off	16 V/10 V	12 V/11 V	18 V/10.5 V
Power saving during standby	√ active burst mode in QR switching 2-level selectable burst mode entry/exit level	-	√ active burst mode 52 kHz
Digital frequency reduction for high average efficiency	✓	\checkmark	\checkmark
OLP blanking time	Fixed	Adjustable	Fixed
Auto restart timer	Through V _{cc} charging/discharging	Setting with external components	Through V _{cc} charging/discharging
Maximum input power limitation	V _{in} pin voltage dependent	Adjustable through ZC resistor	Adjustable through ZC resistor
V _{cc} undervoltage protection	√ with auto restart	√ with latch	√ with auto restart
Adjustable output overvoltage protection	√ with auto restart	√ with latch	√ with latch
Adjustable line input overvoltage protection	\checkmark	_	-
Brown-out feature	✓	\checkmark	-
V_{cc} and CS pin short to ground protection	✓	-	-
Target application	Home appliances, set-top-box, AUX SMPS	AUX power supply to V _{cc} eg. LCD TV multi/main, audio main, PDP TV multi/address	Self-power supply to V _{cc} eg. smart meter, industrial applications

www.infineon.com/acdc

Applications

Packages



Quasi-resonant CoolSET™

	2 nd generation ICE2QRxxxxZ/G	2 nd generation ICE2QRxx80G-1	5 th generation ICE5QRxxxxAZ/G
Switching scheme	QR with 7 zero o	rossing counters	Novel QR with 10 zero crossing counters
Integrated MOSFET	650 V and 800 V	800 V	700 V and 800 V
High voltage start-up cell		/	Cascode
Power saving during standby	Active burst mode f _{sw} @ 52 kHz		2 level selectable active burst mode quasi-resonant
V _{cc} on/off threshold (typ.)	18 V/10.5 V	18 V/9.85 V	16 V/10 V
Adjustable output overvoltage protection	√ with latch		√ with auto restart
V _{cc} over/undervoltage protection	√ with auto restart		√ with auto restart
Overload/open loop protection	√ with auto restart		√ with auto restart
Overtemperature protection	√ with auto restart		\checkmark (Auto restart with hysteresis)
Adjustable line input overvoltage protection	-		√ with auto restart
Brown-out		√ with auto restart	
CS pin short to ground	-		√ with auto restart
V _{cc} pin short to ground	_		√ (No start-up)
Package	DIP-7 DIP-8 DSO-12	DIP-7 DSO-12	DIP-7 DSO-12

Packages



Fixed frequency CoolSET™

	700 V CoolSET™		650 V CoolSET™	
	Gen5 ICE5ARxx70AG(BZS)	Gen3 ICE3Axx65ELJ	Gen3R ICE3BRxx65J	Gen3R ICE3RBRxx65JZ(G)
Package	DIP-7, DSO-12	DI	P-8	DIP-7, DSO-12
Output power range	15 W	19 W~34 W	15 W~41 W	14 W~39 W
Operating temperature range	-40°C~129°C	-25°C	~130°C	-40°C~130°C
Switching frequency	100 kHz	100 kHz	65 kHz	65 kHz
Frequency reduction	\checkmark		-	
Integrated error amplifier	\checkmark		-	
Slope compensation for CCM mode	\checkmark		-	
V _{cc} on/off threshold	16 V/10 V	18 V/10.5 V		
Soft start time	12 ms	20 ms		
Active burst mode selection	3 level	1 level		
CS pin short-to-ground protection	Auto restart	-		
$V_{\rm cc}$ pin short-to-ground protection	No start-up	-		
V_{cc} overvoltage protection	Auto restart	Latch Auto restart		restart
Overtemperature protection	Auto restart with hysteresis	Latch Auto restart		restart
External protection enable pin	-	Latch	Auto	restart
Adjustable brown-in/-out protection	Brown-in only		-	
Adjustable line input overvoltage protection	Only ICE5ARxx70AG		_	
Fast AC reset			-	
Product available	ICE5AR4770AG ICE5AR4770BZS	ICE3A1065ELJ ICE3A2065ELJ	ICE3BR4765J ICE3BR1765J ICE3BR0665J	ICE3RBR4765JZ ICE3RBR1765JZ ICE3RBR0665JZ ICE3RBR4765JG ICE3RBR1765JG ICE3RBR1665JG

Microcontrollers

Power ICs

Gate driver ICs

Motor control ICs

www.infineon.com/coolset

1) Calculated 85 V_{AC}~300 V_{AC} DCM maximum output power in an open-frame design based on T_a=50°C and T_j=125°C without copper area as heatsink



		800 V C	CoolSET™		
Gen3R ICE3A(B)Rxx80JZ	Gen3R ICE3ARxx80CJZ	Gen3R ICE3ARxx80JG	Gen3R ICE3ARxx80VJZ	Gen5 ICE5ARxx80AG(BZS)	Gen5 ICE5GRxx80AG
DI	P_7	DSO-12	DIP-7	DIP-7, DSO-12	DSO-12
10 W~40 W	11 W~23 W	14 W~30 W	15 W~39 W	15 W~40 W	15 W~27 W
–25°C	~130°C	-40°0	C~130°C	-40°C~	129°C
100 kHz/65 kHz	100 kHz	10	0 kHz	100 kHz	125 kHz
		-		√	
		-		√	
-	\checkmark		-	√	
	17 V/	10.5 V		16 V/	10 V
	10	ms	12 ms		ns
4 level	3 level	4	4 level 3 level		vel
-		Auto re	estart		
		-		No sta	rt–up
			restart		
		Auto restart	with hysteresis		
Auto restart	Latch	Auto restart		-	
	Auto restart		-	Brown-i	in only
	-		Auto restart	Only ICE5ARxx80AG	Auto restart
-	\checkmark			-	
ICE3AR10080JZ ICE3AR4780JZ ICE3AR2280JZ ICE3AR0680JZ ICE3BR2280JZ ICE3BR0680JZ	ICE3AR10080CJZ ICE3AR4780CJZ ICE3AR2280CJZ	ICE3AR4780JG ICE3AR2280JG ICE3AR1080JG	ICE3AR4780VJZ ICE3AR2280VJZ ICE3AR1580VJZ ICE3AR1080VJZ ICE3AR0680VJZ	ICE5AR0680AG ICE5AR4780BZS ICE5AR0680BZS	ICE5GR4780AG ICE5GR2280AG ICE5GR1680AG

Packages

500-950 V MOSFETs 20-300 V MOSFETs

XDP™ SMPS

IDP2308 and IDP2303A – digital multi-mode PFC+LLC combo controller

The IDP2303 and IDP2303A are high performance digital combo controllers with integrated drivers and 600 V depletion cell designed for boost PFC and half-bridge LLC targeting switched mode power supplies (SMPS) from 75 W to 300 W.

- > Support non-AUX operation with the lowest standby performance and start-up cell
- > Support multi-mode PFC operation for optimized efficiency curve
- > Configurable frequency setting for LLC soft-start and normal operation
- > Synchronous PFC and LLC burst mode control with soft-start to prevent acoustic noise
- > Excellent dynamic response by adaptive LLC burst mode
- > Configurable and comprehensive protections for PFC/LLC/IC temp
- > IEC62368-1 certified active X-cap discharge function
- Flexible IC parameter setting with digital UART interface supports
 PSU platform approach

Key benefits

- > Low BOM count due to high integration of digital control
- > No auxiliary power supply needed
- > Easy design of system schematic and PCB layout
- > Small form factor design
- > Higher system reliability
- > Shorter development cycles and higher design and production flexibility

Product	Target application	Major difference	Package
IDP2308	TV embedded PSU	2 nd redundant PFC output overvoltage protection	DSO-14 (with enhanced HV creepage distance)
IDP2303A	Adapter, general SMPS	Constant output voltage	DSO-16

IDP2303A – power adapter











Target applications

- > LCD TV power supply
- > General SMPS
- > Power adapter

Packages

Microcontrollers

Power ICs

Gate driver ICs

Motor control ICs

Non-isolated DC-DC - integrated power stage

60 A and 70 A with integrated current sense

Infineon's integrated power stage family contains a synchronous buck gate driver IC which is co-packed with control and synchronous MOSFETs and a Schottky diode to further improve efficiency. The package is optimized for PCB layout, heat transfer, driver/MOSFET control timing and minimal switch node ringing when layout guidelines are followed. The paired gate driver and MOSFET combination enables higher efficiency at lower output voltages required by cutting edge CPU, GPU, ASIC and DDR memory designs. The TDA21472 integrated power stages internal MOSFET current sense algorithm, with integrated temperature compensation, achieves superior current sense accuracy versus best-in-class controller based inductor DCR sense methods. Up to 1.0 MHz switching frequency enables high performance transient response, allowing miniaturization of output inductors, as well as input and output capacitors, while maintaining industry-leading efficiency. The TDA21472 is optimized for CPU core power delivery in server applications. The ability to meet the stringent requirements of the server market also makes the TDA21472 ideally suited for powering GPU, ASIC, DDR memory, and other high current designs.

Features

- > Integrated driver, Schottky diode, control MOSFET and synchronous MOSFET
- > 5 mV/A on-chip MOSFET current sensing with temperature compensated reporting
- > Input voltage (V_{in}) range of 4.5 to 15 V
- > V_{cc} and V_{DRV} supply of 4.5 to 7 V
- > Output voltage range from 0.25 up to 5.5 V
- > Output current capability of 70 A
- > Operation up to 1.0 MHz
- > V_{cc} undervoltage lockout (UVLO)
- > 8 mV/°C temperature analog output and thermal flag pull-up to 3.3 V
- > Overtemperature protection (OTP)
- > Cycle-by-cycle self-preservation overcurrent protection (OCP)
- > MOSFET phase fault detection and flag
- > Preliminary overvoltage protection (pre-OVP)
- > Compatible with 3.3 V tri-state PWM input
- > Body-Braking[™] load transient support through PWM tri-state
- > Diode emulation mode (DEM) for improved light load efficiency
- > Efficient dual-sided cooling
- > Small 5.0 x 6.0 x 0.9 mm PQFN package

Applications

- > High frequency, high current, low profile DC-DC converters
- > Voltage regulators for CPUs, GPUs, ASICs, and DDR memory arrays

Part type	l _{out} [A]	Package
TDA21472	70	5 x 6 x 0.9 mm PQFN
TDA21462	60	5 x 6 x 0.9 mm PQFN

Motor control ICs

www.infineon.com/integrated-powerstages

70 A with exposed top for improved thermal performance

Infineon's TDA21475 exposed-top power stage contains a low quiescent-current synchronous buck gatedriver IC co-packaged with high-side and low-side MOSFETs. The package is optimized for PCB layout, heat transfer, driver/ MOSFET control timing, and minimal switch node ringing when layout guidelines are followed. The gate driver and MOSFET combination enables higher efficiency at the lower output voltages required by cutting edge CPU, GPU and DDR memory designs.

The TDA21475 internal MOSFET current sense algorithm with temperature compensation achieves superior current sense accuracy versus best-in-class controller-based inductor DCR sense methods. Protection includes cycle-by-cycle over current protection with programmable threshold, V_{cc}/V_{DRV} UVLO protection, bootstrap capacitor undervoltage protection, phase fault detection, IC temperature reporting and thermal shutdown. The TDA21475 also features auto replenishment of the bootstrap capacitor to prevent overdischarging. The TDA21475 features a deep-sleep power saving mode, which greatly reduces the power consumption when the multiphase system enters PS3/PS4 mode. Operation at switching frequency as high as 1.5 MHz enables high performance transient response, allowing reduction of output inductance and output capacitance while maintaining industry-leading efficiency. The TDA21475 is optimized for CPU core power delivery in server applications. The ability to meet the stringent requirements of the server market also makes the TDA21475 ideally suited for powering GPU and DDR memory designs.

Features

- > Co-packaged driver, high-side and low-side MOSFETs
- > 5 mV/A on-chip MOSFET current sensing with temperature compensated reporting
- > Input voltage (V_{IN}) range of 4.25 to 16 V
- > V_{cc} and V_{DRV} supply of 4.25 to 5.5 V
- > Output voltage range from 0.25 up to 5.5 V
- > Output current capability of 70 A
- > Operation up to 1.5 MHz
- > V_{cc}/V_{DRV} undervoltage lockout (UVLO)
- > Bootstrap capacitor undervoltage protection
- > 8 mV/°C temperature analog output
- > Thermal shutdown and fault flag
- > Cycle-by-cycle over current protection with programmable threshold and fault flag
- > MOSFET phase fault detection and flag
- > Auto replenishment of bootstrap capacitor
- > Deep-sleep mode for power saving
- > Compatible with 3.3 V tri-state PWM input
- > Body-Braking[™] load transient support
- > Small 5 x 6 x 0.65 mm PQFN package
- > Lead-free RoHS compliant package
- > Integrated driver, Schottky diode, control MOSFET and synchronous MOSFET

Part type	l _{out} [A]	Package
TDA21475	70	5 x 6 x 0.6 mm PQFN

177

Discrete IGBTs

Motor control ICs

XENSIVTM sensors

20 A with integrated current sense

Infineon's IR35401 integrated power stage contains a synchronous buck gate driver IC, which is co-packaged with control and synchronous MOSFETs and Schottky diode to further improve efficiency. The package is optimized for PCB layout, heat transfer, driver/MOSFET control timing, and minimal switch node ringing when layout guidelines are followed. The paired gatedriver and MOSFET combination enables higher efficiency at lower output voltages required by cutting edge CPU, GPU and DDR memory designs.

The IR35401 power stage features an integrated current sense amplifier to achieve superior current-sense accuracy against best-in-class controller-based inductor DCR sense methods while delivering the clean and accurate current report information. The protection features inside IR35401 include V_{cc} UVLO and thermal flag. IR35401 also features an auto replenishment of bootstrap capacitor to prevent the bootstrap capacitor from overdischarging. The IR35401 supports deep-sleep mode and consumes <100 µA V_{cc} bias current when the EN pin is pulled low. Up to 1.5 MHz switching frequency enables high performance transient response, allowing miniaturization of output inductors, as well as input and output capacitors while maintaining industry-leading efficiency. When combined with Infineon's digital controllers, the IR35401 incorporates the Body-Braking[™] feature through PWM tri-state which enables reduction of output capacitors. The IR35401 is optimized for low current CPU rails in server applications. The ability to meet the stringent requirements of the server market also makes the IR35401 ideally suited for powering GPU and DDR memory rails.

Features

- > Integrated driver, control MOSFET and synchronous MOSFET
- > Integrated bootstrap synchronous PFET
- > Inductor DCR current sensing with temperature compensation
- > Input voltage (V_{IN}) range from 4.25 to 16 V
- > V_{cc} supply of 4.25 to 5.5 V
- > Output voltage range from 0.5 to 3 V or up to 5.5 V if the internal current sense amplifier is not used
- > Local lossless inductor current sensing with improved noise immunity and accuracy
- > Single reference based current reporting output
- > Output current capability of 20 A
- > Operation up to 1.5 MHz
- > V_{cc} undervoltage lockout
- > Over-temperature and V_{cc} UVLO fault communication to controller via T_{out} pin
- > Compatible with 3.3 V tri-state PWM Input
- > Body-Braking[™] load transient support through PWM tri-state
- > Auto-replenishment on BOOST pin
- > Low operating quiescent current and <100 μA when disabled
- > Small 4 x 5 x 0.9 mm PQFN package
- > Lead-free RoHS compliant package

Applications

178

- > General purpose POL DC-DC converters
- > Voltage regulators for CPUs, GPUs, ASICs, and DDR memory arrays

Part type	I _{out} [A]	Package
IR35401	20	4 x 5 x 0.9 mm PQFN

www.infineon.com/integrated-powerstages

Application

20-300 V MOSFETs

500-950 V MOSFETs

25 A, 35 A, 40 A power stages

Infineon's TDA21240 powerstage is a multichip module that incorporates Infineon's premier MOSFET technology for a single high-side and a single low-side MOSFET coupled with a robust, high performance, high switching frequency gate driver in a single PG-IQFN-30-2 package. The optimized gate timing allows for significant light load efficiency improvements over discrete solutions. When combined with Infineon's family of digital multi-phase controllers, the TDA21240 forms a complete core voltage regulator solution for advanced micro and graphics processors as well as point-of-load applications.

Features

- > For synchronous buck converter step down voltage applications
- > Maximum average current of 40 A
- > Input voltage range +4.5 V to +16 V
- > Power MOSFETs rated 25 V
- > Fast switching technology for improved performance at high switching frequencies (> 500 kHz)
- > Remote driver disable function
- > Includes bootstrap diode
- > Undervoltage lockout
- > Shoot through protection
- > +5 V high side and low side MOSFETs driving voltage
- > Compatible to standard +3.3 V PWM controller integrated circuits
- > Tri-state PWM input functionality
- > Small package: PG-IQFN-30-2 (4 x 4 x 1 mm)
- > RoHS compliant
- > Thermal warning

Applications

- > Desktop and server VR buck converter
- > Single Phase and multiphase POL
- > CPU/GPU regulation in notebook, desktop graphics cards, DDR memory, graphic memory
- > High power density voltage regulator modules (VRM)
- > Qualified for DC-DC industrial applications based on JEDEC (JESD47, JESD22, J-STD20)
- > General purpose POL DC-DC converters

Part type	I _{out} [A]	Package		
TDA21242	25	4 x 4 x 1 mm PQFN		
TDA21241	35	4 x 4 x 1 mm PQFN		
TDA21240	40	4 x 4 x 1 mm PQFN		

Discrete IGBTs

Motor control ICs

Digital controllers Point-of-load power management

Infineon's digital multiphase and multirail controllers provide power for today's medium and high current POL applications used in telecom/datacom, server, and storage environments. Infineon's digital controller family enables OEMs and ODMs to improve efficiency and total cost of ownership, while increasing power density and optimizing the total system footprint of the voltage regulator. The products highlighted in the table below represent our fifth generation digital controller family and support up to two rails with 1-6 phases on individual rails. The I²C/PMBus[™] interface connects the digital controllers to the application system and provides real time telemetry information, monitoring and control capabilities. The digital controllers are fully configurable through our PowerCode[™] and PowerClient[™] graphical user interfaces that allows for easy to use and simplified design optimization.

Feature		Controller family								
Configurable output rails		Dual rail	Dual rail	Dual/single rail	Dual/single rail	Dual rail	Dual/single rail	Dual/single rail	Dual rail	
Part number	PMBus™	PXE1610C	IR35212	XDPE10280B	XDPE10281B	IR35204	IR35201	IR35223	XDPE132G5C	
Phase configuration	Main	7 ph	7 ph	8 ph	8 ph	4 ph	8 ph	10 ph	16 ph	
	Subconfigurations	6+1	6+1	8+0, 6+2, 4+4	8+0, 6+2, 4+4	3+1	8+0, 7+1, 6+2	10+0, 5+5	8+8	
V _{out_max}		2.5 V	3.3 V	3.04 V	3.04 V	3.3 V	3.3 V	3.3 V	3.3 V	
Switching frequency		Up to 2 MHz	Up to 2 MHz	Up to 2 MHz	Up to 2 MHz	Up to 2 MHz	Up to 2 MHz	Up to 2 MHz	Up to 2 MHz	
Operating temperature range		- 5°C to 85°C	- 40°C to 85°C	- 40°C to 85°C	- 40°C to 85°C	- 40°C to 85°C	- 40°C to 85°C	- 40°C to 85°C	- 40°C to 120°C	
VQFN package		48-lead (6x6) 0.4 mm pitch	48-lead (6x6) 0.4 mm pitch	56-lead (7x7) 0.4 mm pitch	56-lead (7x7) 0.4 mm pitch	40-lead (5x5) 0.4 mm pitch	56-lead (7x7) 0.4 mm pitch	48-lead (6x6) 0.4 mm pitch	56-lead (7x7) 0.4 mm pitch	
Typical application		Intel server, high end desktop	Intel server, workstation, high end desktop	Intel server, workstation, high end desktop	AMD server, workstation, high end desktop	AMD server, memory and SOC	AMD server, CPU	Phase redundant based server systems	AMD server, GPU, ASIC, networking ASSP	

Multi-phase configurations are supported for best power optimization

Advantages of a digital controller

Protection features include a set of sophisticated overvoltage, undervoltage, overtemperature, and overcurrent protections. Each of the controllers in the table above also detect and protect against an open circuit on the remote sensing inputs. These attributes provide a complete and advanced protection feature set for microprocessor, DSP, FPGA or ASIC power systems. Accurate current sense telemetry is achieved through internal calibration that measures and corrects current sense offset error sources upon start-up. Programmable temperature compensation provides accurate current sense information even when using DCR current sense.
\bullet 12 V

12 V

12 V

V_CPU_L1

٤1

L2

+ CVIN3

L3

L4

12 \

V_CPU_L2

LOA

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Cboost

cv

CVD

Chor

cvc

cv

c

cvcc CVD

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TDA21472

TDA21472

TDA21472



SM_DIO SM_CLK

SM_ALERT#/ /INSEN2/PSI#1

SV_ALERT# SV_DIO SV_CLK

VRHOT_ICRIT#

EN_L2/INMODE/ CAT_FLT

SV_ADDR

RCSP_L2

RCSM_L2

VSEN_L2

VRTN_L2

ccs

PWM3

ISEN3

IRTN3

PWM4

ISEN4

IRTN4

PWM1_L2

ISEN1_L2

TSEN

ADDR_PROT

GND Ť

I2C Bus

R

From > System >

+ ş

I2C Bus - -

3.3V

for SM_ALERT VIN_2

CPU Serial Bus

Typical multiphase application circuit

LED driver ICs for general lighting

Professional lighting

Infineon's innovative multi-mode LED driver ICs deliver high efficiency, high power factor and low harmonics to LED lighting applications, while supporting dimming levels down to one percent. The high level of integration simplifies designs by reducing the need for external components. The XDP™ digital power technology supports quick design and simplifies logistics handling, hence saving effort and cost.

ICL5101– resonant controller with PFC for LED driver

The ICL5101 integrates a half-bridge controller with a PFC stage in a single package. The high level of integration assures a low count of external components, enabling small form factor designs and making them ideal for compact power supplies in lighting applications, such as LED driver. All operation parameters of the IC are adjustable by simple resistors, which makes them a perfect choice for affordable and reliable configuration. A comprehensive set of protection features including an adjustable external overtemperature protection and capacitive load protection, ensures the detection of fault conditions to increase the system safety.

Features and benefits

- Secondary-side constant voltage or constant current control > Allows secondary-side IC dimming down to 1 percent
- > PFC in CrCM mode during nominal load and DCM mode >> PFC/LLC combo IC allows the best matching of PFC in low-load condition down to 0.1 percent for operation without audible noise
- > High-power quality with PF > 0.96, THD < 10 percent
- > Highest efficiency of up to 95 percent due to resonant topology

- stage and LLC stage timing control
- > Supports a wide input voltage range from 90-305 V
- > Ultrafast time to light < 200 ms
- > Complete set of protection features including external thermal protection



Typical application schematic

Order information for ICL5101

Туре	Description	Ordering code
ICL5101	Resonant controller with PFC	SP001213622
EVALLEDICL5101E1	PFC/LLC evaluation board 110 W	SP001296078

www.infineon.com/icl5101

20-300 V MOSFETs

Microcontrollers

XENSIVTM sensors

Gate driver ICs

ICL5102 - High performance PFC + resonant controller for LCC and LLC

Features and benefits

> Small form factor LED driver and low BOM

The high level of integration assures a low count of external components, enabling small form factor designs and making them ideal for compact and slimline power supplies for lighting, such as LED driver for indoor and outdoor applications

> High performance, digital PFC and advanced HB driver

The high performance digital PFC stage achieves power factor of 99 percent, through operation in CrCM and DCM mode, in a frequency range of 22 to 500 kHz. This supports stable operation even at low-load conditions down to 0.1 percent of the nominal power without audible noise

> Fast time-to-light and low standby

With start-up current of less than 100 µA the controller provides very fast time-to-light within less than 300 ms, while standby the controller changes into active burst mode which reduces power consumption to less than 300 mW

> Safety first

The controller has a comprehensive set of protection features built in to increase the system safety. It monitors in the run mode the complete system regarding bus over- and undervoltage, open loop, overcurrent of PFC and/or inverter, output overvoltage, overtemperature and capacitive load operation



Typical application schematic

Order information for ICL5102

Туре	Description	Ordering code
ICL5102	PFC and resonant controller for LCC and LLC	SP002224374
EVAL-ICL5102-U130W-CC	PFC/LLC-CC constant current evaluation board 130 W LED driver	SP001667160

20-300 V MOSFETs

Motor control ICs

XDP™ LED

The IC family XDP[™] is the first all-in-one package solutions combining a digital controller with key power peripherals. Such integration provides exceptional flexibility and performance. The XDP[™] family addresses essential features for advanced LED driver.

XDPL8105 – digital flyback controller IC for LED driver

The XDPL8105 is a digital, single-stage flyback controller with high power factor for constant current LED driver. The device offers versatile functions for different indoor and outdoor lighting applications. The IC is available in a DSO-8 package and it provides a wide feature set, requiring a minimum of external components. The advanced control algorithms in the digital core of the XDPL8105 provide multimode operation for high efficiency. Configurable parameters allow last minute changes, shorten the product development and reduce hardware variants. The extensive set of configurable standard and sophisticated protection mechanisms ensure safe, reliable and robust LED driver device for diverse use cases.

Features and benefits

- > Constant current with primary side regulation
- > Supports AC and DC input
- Nominal input voltage range 90-305 V_{AC} or 120-350 V_{DC}
- > Integrated 600 V start-up cell
- Power factor > 0.9 and THD < 15 percent over wide load range >
 Highly accurate primary side control output current typ.
- ± 3 percent
- > Reference board efficiency > 90 percent
- Internal temperature guard with adaptive thermal management

- > Multimode operation
 - QRM (quasi-resonant mode)
 - DCM (discontinuous conduction mode)
 - ABM (active burst mode)
- > Digital parameters
- > Relevant error conditions are monitored and protected
 - Undervoltage
 - Overvoltage
 - Open load
 - Output shorted



Typical application schematic

Order information for XDPL8105

Туре		Description	Ordering code
XDPL8105		Digital flyback controller IC	SP001639446
REF-XDPL8	3105-CDM10V	40 W reference design with CDM10V isolated 0 V-10 V dimming interface	SP001649474

www.infineon.com/xdpl8105

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

XDPL8210 – digital flyback constant current controller IC for LED driver with 1 percent dimming

The XDPL8210 is a digital, single-stage, quasi-resonant flyback controller with high power factor and high precision primary side controlled constant current output. The IC is available in a DSO-8 package and it provides a wide feature set, which requires only a small number of external components. Sophisticated algorithms provide flicker-free dimming below one percent. The driver fully supports IEC61000-3-2 class C designs. The limited power mode improves functional safety, while configurable parameters allow last minute changes, shorten the product development and reduce hardware variants. The extensive set of configurable standard and sophisticated protection mechanisms ensure safe, reliable and robust LED driver for a large set of use cases.

Features and benefits

- > Constant current with primary side regulation
- > Supports AC and DC input
- Nominal input voltage range 90-305 V_{AC} > or 90-430 V_{DC}
- > Reference board efficiency > 90 percent
- Power factor > 0.9 and THD < 15 percent over wide load range > Relevant error conditions are monitored and protected >
- Standby power < 100 mW >
- Internal temperature guard with adaptive thermal management

- > Multimode operation
 - QRM (quasi-resonant mode)
 - DCM (discontinuous conduction mode)
 - ABM (active burst mode)
- > Digital parameters
- - Undervoltage
 - Overvoltage
 - Open load
 - Output shorted



Typical application schematic

Order information for XDPL8210

Туре	Description	Ordering code
XDPL81210*	Digital flyback constant current controller IC	SP001643692
REF-XDPL8210-U35W	35 W reference design with CDM10V isolated 0 V-10 V dimming interface	SP001886070

www.infineon.com/xdpl8210

185

Discrete IGBTs

Motor control ICs

XDPL8218 – high power factor constant voltage flyback IC with secondary side regulation

The XDPL8218 is a digital, highly integrated, future-proof device combining a constant voltage quasi-resonant flyback controller with algorithms for high power factor and low THD. The main application field for XDPL8218 are dual stage designs with a DC-DC stage at secondary side and XDPL8218 as primary side. The device manages wide load ranges and reacts fast and stable to dynamic load changes. The digital core of the XDPL8218 enables high efficiency over full output power range, multimode operation with quasi-resonant switching at high power, discontinuous conduction mode frequency reduction at medium power and active burst mode at low power. The XDPL8218 is available in a DSO-8 package.

Wide input voltage range

- > Constant voltage with secondary side regulation
- > Supports AC and DC input
- > Nominal input voltage range 100-305 $V_{\mbox{\tiny AC}}$ or 90-430 $V_{\mbox{\tiny DC}}$
- > Reference board efficiency > 90 percent
- > Power factor > 0.9 and THD < 15 percent over wide load range
- > Standby power < 100 mW
- Internal temperature guard with adaptive thermal management
- Brown-out and brown-in protections

- > Embedded digital filters
- > Multimode operation
 - QRM (quasi-resonant mode)
 - DCM (discontinuous conduction mode)
 - ABM (active burst mode)
- > Digital parameters
- > Relevant error conditions are monitored and protected
 - Undervoltage
 - Overvoltage
 - Open load
 - Output shorted



Order information for XDPL8218*

Туре	Description	Ordering code
XDPL8218*	Digital flyback CV-output controller IC	SP001707258
REF-XDPL8218-U40W	40 W reference board with replaceable feedback circuit	SP001710980

www.infineon.com/xdpl8218

* coming Q1/2019

WBG semiconductors

Application

20-300 V MOSFETs

500-950 V MOSFETs

XENSIVTM sensors

XDPL8220 - digital dual stage multi-mode flyback controller for CC, CV, LP with primary side regulation

The XDPL8220 simplifies for the lighting industry to realize essential features for smart lighting and increases the benefits to the end user and the luminaire manufacturers. The XDPL8220 is a digital, highly integrated, future-proof device combining a quasi-resonant PFC plus a quasi-resonant flyback digital controller with primary side regulation. The multi control features - constant voltage, constant current, and limited power - enable a highly versatile LED driver (e.g. window LED driver). The main application field of the XDPL8220 is advanced dual stage LED driver for indoor or outdoor lighting. The IC is available in a DSO-16 package.

Features and benefits

- Constant current, constant voltage, limited power with primary side regulation
- PWM dimming input controls respective analog output current
- > Reference board efficiency > 90 percent
- Power factor > 0.9 and THD < 15 percent over wide load range
- Nominal input voltage range 100-305 V_{AC} or 90-430 V_{DC}
- > Standby power < 100 mW
- Internal temperature guard with adaptive thermal management

- > Multimode operation
 - QRM (quasi-resonant mode)
 - DCM (discontinuous conduction mode)
 - ABM (active burst mode)
- > Digital parameters
- > Relevant error conditions are monitored and protected
 - Undervoltage
 - Overvoltage
 - Open load



Typical application schematic

Order information for XDPL8220

Туре	Description	Ordering code
XDPL8220	Digital dual stage multimode flyback Controller for CC, CV, LP	SP001398160
REF-XDPL8220-U30W	30 W reference board with CDM10V isolated 0 V-10 V dimming interface	SP001630060
REF-XDPL8220-U50W	50 W reference board with CDM10V isolated 0 V-10 V dimming interface	SP001630066
REF-XDPL8220-U100W	100 W reference board with CDM10V isolated 0 V-10 V dimming interface	SP001630068

www.infineon.com/xdpl8220

20-300 V MOSFETs

Discrete IGBTs

Motor control ICs

XENSIVTM sensors

XDPL8221 - digital dual stage multi-mode flyback controller for CC, CV, LP with 1 percent dimming and serial interface

The XDPL8221 is a digital, highly integrated, future-proof device combining a quasi-resonant PFC with a quasi-resonant flyback controller with primary side regulation. A serial communication interface supports direct communication with an external microcontroller unit (MCU). The XDPL8221 is especially designed for advanced LED driver in smart lighting or IoT applications, featuring flicker-free dimming down to 1 percent of nominal current. The device enables customizable LED driver and simplifies the generation and maintenance of different variants without increasing the number of stock keeping units. The IC is available in a DSO-16 package.

Features and benefits

- > Nominal input voltage range 100-305 V_{AC} or 90-430 V_{DC}
- > Reference board efficiency > 90 percent
- > Power factor > 0.9 and THD < 15 percent over wide load range
- > UART Interface for control and real-time monitoring
- Constant current, constant voltage, limited power with primary side regulation
- > 1 percent dimming
- > Dim-to-off with low standby power < 100 mW
- > Internal temperature guard with adaptive thermal management

- The UART interface and the command set enable to control the function of the XDPL8221 or inquire status information
- > Multimode operation
 - QRM (quasi-resonant mode)
 - DCM (discontinuous conduction mode)
 - ABM (active burst mode)
- > Digital parameters
- Relevant error conditions are monitored and protected
 - Undervoltage
 - Overvoltage
 - Open load
 - Output shorted



Order information for XDPL8221*

Туре	Description	Orderable part number
XDPL8221*	Digital dual stage multimode flyback Controller for CC, CV, LP with 1 percent dimming	XDPL8221XUMA1
REF-XDPL8221-U50W	50 W reference board with CDM10V isolated 0 V-10 V dimming interface	REFXDPL8221U50WTOBO1
REF-XDPL8221-U100W	100 W reference board with CDM10V isolated 0 V-10 V dimming interface	REFXDPL8221U100WTOBO1

Typical application schematic

www.infineon.com/xdpl8221

* coming Q1/2019

Linear current regulators

60 V linear LED controller IC with voltage feedback loop to primary side

The BCR601 is a linear LED controller IC regulating the LED current with an external driver transistor. The device supports either NPN bipolar transistors or N-channel MOSFETs to cover a wide LED current and power range up to several hundred milliamperes. The BCR601 provides feedback to the primary side via an optocoupler to control the output voltage of the primary side converter, e.g. a flyback. The control loop minimizes the voltage overhead and power dissipation of the external driver transistor. The voltage overhead can be adjusted by external configuration according to applications needs.

Features and benefits

- > Supports an optocoupler feedback loop to primary side minimizing power losses
- > Suppresses the voltage ripple of the power supply driving a constant LED current for hight light quality
- > The embedded hot plug protection allows plug in and plug out of any LED load during operation without damaging the LEDs
- > Supports wide current range depending on external driver transistor
- > Supply voltage range up to 60 V
- > Gate driver current 10 mA

Typical application schematic

- > LED current can be adjusted by R_{set} functionality
- > Overtemperature protection and adjustable overvoltage protection





Order information for BCR601

Туре	Description	Ordering code
BCR601	60 V linear LED controller IC with voltage feedback to primary side	SP001681722
DEMO_BCR601_60V_IVCTRL	Demonstration board BCR601 current and voltage control, 500 mA	SP002798056

www.infineon.com/bcr601

Application

500-950 V MOSFETs

Packages

60 V linear LED controller IC for dimmable LED applications

The BCR602 is a linear LED controller IC regulating the LED current with an external driver transistor. The BCR602 supports either NPN bipolar transistor or N-channel MOSFETs to cover a wide LED current and power range up to several amperes. The LED current is fully scalable by dimensioning an external current sense resistor.

Features and benefits

- > Suppresses the voltage ripple of the power supply dring a constant LED current for high light quality
- > The LED current can be dimmed by resistors as well as analog or digital PWM voltages connected to the multifunction input-output (MFIO) pin
- > The embedded hot plug protection allows plug in and plug out of any LED load during operation without damaging the LEDs
- > Supports wide current range depending on external driver transistor
- > Supply voltage range up to 60 V makes it ideal for 48 V designs
- > Gate driver current 10 mA
- > LED current can be adjusted by Rset functionality
- > Overtemperature protection



Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Typical application schematic



Order information for BCR602

Туре	Description	Ordering code
BCR602	60 V linear LED controller IC	SP001681730
DEMO_BCR602_60V_IVCTRL	Demonstration board BCR602U current control, 200 mA	SP002798054

www.infineon.com/bcr602

BCR40x linear LED Driver ICs for low power LEDs

The BCR40x family is the smallest size and lowest cost series of LED drivers. These products are perfectly suited for driving low power LEDs in general lighting applications. Thanks to AEC-Q101 qualification, it may also be used in automotive applications such as brake lights or interior.

The advantage over resistor biasing is:

- > Long lifetime of LEDs due to constant current in each LED string
- Homogenous LED light output independent of LED forward voltage binning, temperature increase and supply voltage variations

The advantage versus discrete semiconductors is:

- > Reduced part count and assembly effort
- > Pretested output current
- > Defined negative temperature co-efficient protection

Needing more details on replacing resistors?



Take a look at the application note "Driving low power LEDs from 10 to 65 mA LED driver ICs with BCR401W and BCR402W family"

Features and benefits:

- > Output current from 10 to 100 mA (adjustable by external resistor)
- > Supply voltage up to 18 V (BCR401W, BCR402W) and up to 40 V (BCR401U, BCR402U, BCR405U, BCR430U)
- > Reduction of output current at high temperature, contributing to long lifetime LED systems
- > Ease of use
- > Very small form factor packages with up to 750 mW max. power handling capability

Low-power LED driver ICs (5-100 mA)

Туре	Group	Topology	V _s (min.) [V]	V _s (max.) [V]	l _{out} (typ.) [mA]	l _{out} (max.) [mA]	Dimming	Package	P _{tot} (max.) [mW]
BCR401U	LED drivers for low-power LEDs	Linear	1.4	40	10.0	65	PWM by ext. transistor	SC74	750
BCR401W	LED drivers for low-power LEDs	Linear	1.2	18	10.0	60	PWM by ext. transistor	SOT343	500
BCR402U	LED drivers for low-power LEDs	Linear	1.4	40	20.0	65	PWM by ext. transistor	SC74	750
BCR402W	LED drivers for low-power LEDs	Linear	1.4	18	20.0	60	PWM by ext. transistor	SOT343	500
BCR405U	LED drivers for low-power LEDs	Linear	1.4	40	50.0	65	PWM by ext. transistor	SC74	750
BCR430U NEW	LED driver for low-power LEDs	Linear	6	42	Defined by $R_{\scriptscriptstyle{\text{set}}}$	100	PWM by ext. transistor	SOT23	600

NEW: Ultralow voltage drop version BCR430U with only 135 mV at 50 mA

LED current versus voltage drop ($V_s = 24 V$)



The voltage drop at the integrated LED driver stage can go down to 135 mV at 50 mA and less improving the overall system efficiency and providing extra voltage headroom to compensate for tolerances of LED forward voltage or supply voltage. With the BCR430U, additional LEDs can be added to lighting designs without changing the supply voltage. Applications

Discrete IGBTs

Motor control ICs

www.infineon.com/bcr

Packages

BCR32x/BCR42x/BCR450/BCR601/BCR602 linear LED driver and controller ICs for medium and high power LEDs

The BCR32x and BCR42x LED drivers are dedicated linear regulators for 0.5 W LEDs with a maximum output current of 250 mA. They are optimized in terms of cost, size and feature set for medium power LEDs in general lighting applications. Thanks to AEC-Q101 qualification, it may also be used in automotive applications such as brake lights or interior.

Features and benefits

- > Output current from 10 mA up to 300 mA for BCR32x (200 mA for BCR42xU), adjustable by external resistor
- > Supply voltage up to 40 V for BCR42x (24 V for BCR32x)
- > Direct microcontroller interface for PWM dimming with BCR321U/BCR421U
- > Reduction of output current at high temperature, contributing to long lifetime LED systems
- > Ease of use
- > Very small form factor packages with up to 1000 mW max. power handling capability

Medium- and high-power LED driver ICs

Туре	Group	Topology	V _s (min.) [V]	V _s (max.) [V]	l _{out} (typ.) [mA]	l _{out} (max.) [mA]	Dimming	Package	P _{tot} (max.) [mW]
BCR320U	LED drivers for mid-power LEDs	Linear	1.4	24	250	300	No	SC74	1000
BCR321U	LED drivers for mid-power LEDs	Linear	1.4	24	250	300	Digital input	SC74	1000
BCR420U	LED drivers for mid-power LEDs	Linear	1.4	40	150	200	No	SC74	1000
BCR421U	LED drivers for mid-power LEDs	Linear	1.4	40	150	200	Digital input	SC74	1000
BCR450	LED controller	Linear	3.0	27	70	Ext. switch	Digital input	SC74	500
BCR601	LED controller	Linear	8.0	60	Ext. switch	Ext. switch	Analog	PG-DSO-8	360
BCR602	LED controller	Linear	8.0	60	Ext. switch	Ext. switch	Analog/PWM	PG-SOT23-6	360



DC-DC switch mode LED driver ICs

ILD8150/ILD8150E^{*} – 80 V DC-DC buck LED driver IC for high-power LEDs and high-performance hybrid dimming

The ILD8150 is 80 V DC-DC converter IC, designed to be used in LED applications to drive high power LEDs. For applications operating close to safe extra low voltage (SELV) limits, it provides a high safety voltage margin. The buck LED driver IC is tailored for LEDs in general lighting applications with average currents up to 1.5 A using a high-side integrated switch. Several performance and protection features provide the right fit for professional LED lighting.

The hysteretic current control provides an extremely fast regulation and stable LED current combined with good EMI performance. The efficiency of the LED driver IC is remarkably high, reaching more than 95 percent efficiency over a wide range. A PWM input signal between 250 Hz and 20 kHz controls dimming of the LEDs current in analog mode from 100 to 12.5 percent and 12.5 to 0.5 percent in PWM mode with flicker-free modulation frequency of 3.4 kHz.

Digital PWM dimming detection with high resolution makes ILD8150/E the perfect LED driver IC for the use together with microcontrollers. Precise output current accuracy from device to device under all loads and input voltages conditions makes it perfect for tunable white and flat panel designs where current must be identical string to string.

Features and benefits

- > Wide input voltage ranging from 8–80 V_{DC}
- > Up to 1.5 A average output current, adjustable via shunt resistor
- > Efficiency > 95 percent
- > Up to 2 MHz switching frequency
- > Soft-start
- PWM dimming input, with 250 Hz to 20 kHz PWM dimming frequency

- > Hybrid dimming for flicker free light down to 0.5 percent
 - Analog dimming 100 percent 12.5 percent
 - PWM dimming 12.5 percent 0.5 percent with 3.4 kHz flicker-free modulation, dim-to-off
- > Typical 3 percent output current accuracy
- > Overtemperature protection
- > Pull-down transistor to avoid LED glowing in dim-to-off
- > DSO-8 package to enable wave soldering
- DSO-8 with exposed pad for higher thermal performance (ILD8150E)





Туре	Description	Ordering code	Package
ILD8150	80 V DC-DC buck LED driver IC	SP001805682	DSO-8
ILD8150E	80 V DC-DC buck LED driver IC	SP001805686	DSO-8 exposed pad
REF_ILD8150_DC_1.5A	Reference design board 1.5 A	SP002798058	Board with ILD8150E

www.infineon.com/lowcostleddriver

* coming Q2/2019

Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

DC-DC switch mode LED driver ICs

ILD series DC-DC switch mode LED driver ICs

The ILD series are switch mode LED driver ICs for high power LEDs. They combine protection features that contribute to the lifetime of LEDs with the flexibility in output current range up to multiple amperes. The new ILD series include LED driver ICs with integrated power stage, as well as with external MOSFET achieving up to 98 percent driver efficiency across a wide range of general lighting applications.

Features and benefits

- > Wide input voltage range up to 80 V
- Scalability in output current from 90 mA up to multiple amperes
- > Alternative dimming concepts: digital or analog
- Hybrid dimming: analog and digital output combined for flicker free light down to 0.5 percent realized with ILD8150
- Superior adjustable overtemperature protection for ILD6150 and ILD6070 contributing to longer LED lifetime
- > Overvoltage and overcurrent protection
- ILD1151 supports boost, buck-boost and SEPIC topologies

Туре	V _s (min.) [V]	V _s (max). [V]	l _{out} (typ.) [mA]	I _{out} (max.) [mA]	Package	Dimming	Topology	f _{sw}	Features
ILD1151	4.5	45	90	3.000	SSOP-14	Analog/digital	Boost, buckboost SEPIC	Adjustable 100 kHz-500 kHz	Multi topology controller, constant current or constant voltage mode, overvoltage, overcurrent, short on GND protection
ILD6070	4.5	60	Selectable by resistor	700	DSO-8 exposed pad	Digital output	Hysteretic buck	1 MHz	Integrated switch rated up to 700 mA, PWM or analog dimming input, adjustable overtemperature protection, overcurrent protection
ILD6150	4.5	60	Selectable by resistor	1.500	DSO-8 exposed pad	Digital output	Hysteretic buck	1 MHz	Integrated switch rated up to 1.500 mA, PWM or analog dimming input, adjustable overtemperature protection, overcurrent protection
ILD8150*	8	80	Selectable by resistor	1.500	DSO-8	Hybrid (analog down to 12% and PWM down to 0,5%)dimming output	Hysteretic buck	2 MHz	Integrated 80 V switch rated up to 1.500 mA with low $R_{DS(on)}$, hybrid dimming down to 0.5%, UVLO, thermal protection, digital soft-start, flicker-free operation
ILD8150E*	8	80	Selectable by resistor	1.500	DSO-8 exposed pad	Hybrid (analog down to 12% and PWM down to 0,5%) dimming output	Hysteretic buck	2 MHz	Integrated 80 V switch rated up to 1.500 mA with low $R_{DS(on)}$, hybrid dimming down to 0.5%, UVLO, thermal protection, digital soft-start, flicker-free operation



www.infineon.com/ild

* coming Q2/2019

Application

20-300 V MOSFETs

Discrete IGBTs

Motor control ICs



CDM10V and CDM10VD – most flexible dimming interface ICs for 0–10 V

Infineon's fully integrated dimming solutions

Infineon's CDM10V and CDM10VD are the industry's first single-chip lighting interface ICs. They are capable of transforming an analog 0–10 V input into a PWM or dimming input signal, required by a lighting controller IC. CDM10V and CDM10VD devices are dedicated for commercial and industrial LED lighting applications. The compact and highly integrated devices allow designers to replace up to 25 discrete components, used in conventional 0–10 V dimming schemes, with a single device. Supplied in an ultra-miniature 6-pin SOT package, the CDM10Vx and CDM10VDx perfectly match small PCBs with high component densities.

Key features

- > Active dimming (0–10 V) and passive dimming (resistor)
- > Embedded digital signal processing which maintains
- > minimum variations from device to device
- > PWM input
- One-time configurable device: CDM10V and preconfigured devices with various feature sets

Key benefits

- > Single-device solution leading to low BOM and PCB savings
- > Dimming ICs in small SOT-23 package for high power density designs
- > Granular portfolio for highest flexibility and easy design-in
- > Wide input V_{cc} range 11–25 V, extended range down to 6 V for CDM10V
- > Attractive pricing and faster time to market

l _{out} [mA]	Min. duty cycle [%]	PWM output frequency [kHz]	Dimmer/resistor bias current [µA]	Dimm-to-Off	OPN	SP number
5	1/2/5/10	0.2/0.5/ 1 /2	50/100/ 200 /500	Disabled/enabled	CDM10VXTSA1	SP001424754
5	n.a.	1	200	Enabled	CDM10V2XTSA1	SP001684884
5	1	1	200	Disabled	CDM10V3XTSA1	SP001715882
5	n.a.	2	100	Enabled	CDM10V4XTSA1	SP001727960
5	5	1	120	Enabled	CDM10VDXTSA1	SP001619792
5	10	1	120	Enabled	CDM10V2DXTSA1	SP001619794
1	5	1	120	Enabled	CDM10V3DXTSA1	SP001619796
1	10	1	120	Enabled	CDM10V4DXTSA1	SP001630006
	[mA] 5 5 5 5 5 5 5	[mA] [%] 5 1/2/5/10 5 n.a. 5 1 5 1 5 5 5 5 5 10 1 5	[%] frequency [kHz] 5 1/2/5/10 0.2/0.5/1/2 5 n.a. 1 5 1 1 5 1.2 2 5 5 1 5 1.2 2 5 5 1 5 1.0 1 1 5 1	[mA] [%] frequency [kHz] bias current [μA] 5 1/2/5/10 0.2/0.5/1/2 50/100/200/500 5 n.a. 1 200 5 1 1 200 5 1 1 200 5 1 1 200 5 1 11 200 5 1.3 2.0 100 5 5 1 120 5 10 1 120 1 5 1 120 1 5 1 120	[mA] [%] frequency [kHz] bias current [μA] 5 1/2/5/10 0.2/0.5/1/2 50/100/200/500 Disabled/enabled 5 n.a. 1 200 Enabled 5 1.a. 1 200 Disabled/enabled 5 n.a. 2 100 Enabled 5 n.a. 2 100 Enabled 5 5 1 120 Enabled 5 1.0 1 120 Enabled 1 5 10 1 120 Enabled 1 5 10 1 120 Enabled	[mA] [%] frequency [kHz] bias current [μA] bias current [μA] 5 1/2/5/10 0.2/0.5/1/2 50/100/200/500 Disabled/enabled CDM10VXTSA1 5 n.a. 1 200 Enabled CDM10VXTSA1 5 1.1 1 200 Disabled/enabled CDM10V2XTSA1 5 1.1 1 200 Disabled CDM10V2XTSA1 5 1.0 1 100 Enabled CDM10V2XTSA1 5 1.0.1 120 Enabled CDM10V2XTSA1 5 1.0 1 120 Enabled CDM10V2XTSA1 5 1.0 1 120 Enabled CDM10V2XTSA1 5 1.0 1 120 Enabled CDM10V2DXTSA1 1 5 1 120 Enabled CDM10V2DXTSA1

Board name	Description	SP number
COOLDIM_PRG_BOARD	Configuration board for CDM10V only	SP001493166
REF-XDPL8220-U30W	30 W two stage PFC FB digital power, efficient and flicker free reference design with CDM10V	SP001630060
REF-XDPL8105-CDM10V	40 W single stage PFC FB digital power reference design with CDM10V	SP001649474

Typical application schematic using CDM10V







Application

Ballast control ICs

Infineon's solutions for fluorescent lamps

Ballast control ICs from Infineon integrate all functions required to operate FL lamps such as preheat, ignition and run-mode and protection features.

- > Integrated high performance PFC stage
- > Intelligent digital/mixed signal power control
- > Integrated high voltage half-bridge driver
- > All parameters set using only resistors
- > Highly accurate timing and frequency control over a wide temperature range
- > Different types for single, series and parallel lamps

Features

- > Able to handle lamp chokes with higher saturation behavior
- Separate adjustable levels of lamp overload and rectifier effect detection
- > Adjustment of the preheat time
- No high voltage capacitor required for detection of lamp removal (capacitive mode operation)
- Automatically restarts by surge and inverter overcurrent events
- Self-adapting dead time adjustment of the half-bridge driver

Benefits

- > Optimized lamp choke size
- Dramatically reduced time for key tests such as end of life detection, preheat/ignition timeout and pre-run operation modes
- > Suitable for dimming and multi-power ballasts
- > Enables ballast compatibility with a wider range of lamp types
- Flexible support of both current and voltage mode preheating
- > Reduced BOM costs
- Intelligent distinguishing between surge and half-bridge overcurrent events
- Meets standards for emergency lighting (according to DIN VDE 0108)
- > Eases design of multi-power ballasts and reduces EMI
- > Enhanced reliability of ballasts

Function	ICB2FL03G	ICB2FL02G	ICB2FL01G
Capacitive load protection	Activated	Deactivated	Activated
Suitable for dimming	\checkmark	\checkmark	\checkmark
Max. adjustable run frequency	140 kHz	140 kHz	120 kHz
Package	SO-16 small body	SO-19 wide body	SO-19 wide body
Driver capability	650 V	900 V	900 V
Lamp connection	Single and series	Single, series and parallel	Single, series and parallel



Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Integrated point-of-load converters

Digital interface IPOL voltage regulators

The digital interface IPOL devices are easy-to-use, fully integrated and highly efficient DC-DC regulator offering I₂C/PMBus[™], parallel VID, Intel SVID. The on-board PWM controller and MOSFETs make the family a space-efficient solution, providing accurate power delivery for low output voltage and high current applications.

The IR3806x family of PMBus[™] enabled IR MOSFET[™] IPOL based SupIRBuck[™] voltage regulators offers:

- > Compactness of integrated controller, driver and MOSFETs
- > High performance analog voltage mode engine
- > Flexibility of a rich PMBus™ interface

The IR381(2/3)6x family features OptiMOS[™] 5 for the highest efficiency and adds Intel SVID support (IR381(/3)6x) for Intel based systems or parallel VID (IR3826x) for voltage scaling or 8 programmable output voltages booting options to avoid programming at start up. Pin compatible options with and without PMBus[™] are available to allow the flexibility of using PMBus[™] only during evaluation or easily upgrade a system to PMBus[™] without re-layout.

Main features

- > PMBus[™] revision 1.2 compliant
- > ≥ 66 PMBus[™] commands
- Wide input voltage range and single
 5 V 16 V input operations
- > Differential remote sense
- > Ultralow jitter voltage mode eingine
- > Operation temp: -40° to 125° C

Main benefits

- > Only single chip solution with extensive PMBus™, parallel VID, Intel SVID support allows 50 percent space saving versus external power competition
- > Intel SVID support for Intel-based systems
- > Parallel VID or PMBus™ for voltage setting and margining
- > Telemetry status via digital bus
- Remote monitoring and update
- > Parameter changes by register
- > Flexible sequencing
- > High accuracy low ripple
- Integrated sequencing, margin, current and voltage monitoring

Analog IPOL voltage regulators

High efficiency and accuracy: Our point-of-load converters integrate a PWM controller, driver and MOSFETs into a small PQFN package for ease-of-use. The patented PWM modulation scheme allows greater than 1 MHz switching frequencies to deliver ultra compact layouts and smallest bill-of-materials. It features wide operating temperature ranging from operating temperature from -40° to 125°C.

Main benefits

- Enhanced voltage mode PWM devices offer high accuracy, ultralow ripple and noise and higher control bandwidth for less capacitors
- > Scalable solutions from 3 to 35 A
- For designs requiring high density, low cost and easy design, the family includes a 3 A device with enhanced stability constant-on-time engine that does not require external compensation enabling easy designs and fast time to market

Integrated POL portfolio



Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

DC-DC IPOL portfolio

Digital interface IPOL

	I ² C PMBus [™] , telemetry, margin, faults, SVID PVID Digital control/configuration, telemetry and diagnostic								
Part num- ber	Max. cur- rent [A]	Package size [mm]	Max. V _{in}	Max. f _{sw}	Distinctive features				
IR38064	35	5 x 7	21 V	1500 KHz					
IR38063	25	5 x 7	21 V	1500 KHz	DMDTH				
IR38062	15	5 x 7	21 V	1500 KHz	PMBus™				
IR38060	6	5 x 6	16 V	1500 KHz					
IR38163	30	5 x 7	16 V	1500 KHz	OptiMOS™ 5, SVID + PMBus™				
IR38165	30	5 x 7	16 V	1500 KHz	OptiMOS™ 5, SVID				
IR38363	15	5 x 7	16 V	1500 KHz	OptiMOS™ 5, SVID + PMBus™				
IR38365	15	5 x 7	16 V	1500 KHz	OptiMOS™ 5, SVID				
IR38263	30	5 x 7	16 V	1500 KHz	OptiMOS™ 5, PVID + PMBus™				
IR38265	30	5 x 7	16 V	1500 KHz	OptiMOS™ 5, PVID				
IR38164	30	5 x 7	16 V	1500 KHz	OptiMOS [™] 5, SVID + PMBus [™] , enhanced Imon				
IRPS5401	4+4+2+2+0.5	7 x 7	14 V	1500 KHz	5 output PMIC, PMBus™				

Analog interface IPOL

	"Pe Ultralow jitte	erformace" vol r and noise, hi	tage moc gh accura	le PWM icy and low	ripple
Part num- ber	Max. cur- rent [A]	Package size [mm]	Max. V _{in}	Max. f _{sw}	Distinctive features
IR3883	3	3 x 3	14 V	800 KHz	Constant-on-time
IR3823	3	3.5 x 3.5	21 V	1500 KHz	3 soft start
IR3897	4	4 x 5	21 V	1500 KHz	
IR3898	6	4 x 5	21 V	1500 KHz	DDR tracking and analog voltage margin/AVSO
IR3899	9	4 x 5	21 V	1500 KHz	
IR3894	12	5 x 6	21 V	1500 KHz	
IR3895	16	5 x 6	21 V	1500 KHz	
IR3826	23	5 x 6	17 V	1500 KHz	OptiMOS™ 5, 3-level OCP
IR3826A	16	5 x 6	17 V	1500 KHz	OptiMOS™ 5, 3-level OCP
IR3448	16	5 x 6	21 V	1500 KHz	
IR3847	25	5 x 6	21 V	1500 KHz	remote sensing for accuracy and ther-
IR3846	35	5 x 7	21 V	1500 KHz	mally enhanced Cu clip package
IR3891	4+4	5 x 6	21 V	1500 KHz	Dual output for
IR3892	6+6	5 x 6	21 V	1500 KHz	density and out-of-phase for less input capacitor

Point-of-load products - how to choose



Comms, data, temps

Status

www.infineon.com/analog-ipol

20-300 V MOSFETs

CAN transceivers

Proven quality for power management applications

Our CAN transceivers provide proven quality, reliable track records and high robustness in automation applications. They feature excellent electromagnetic performance and low levels of electromagnetic interference (EMI), and are designed for ISO compliance. While our IFX1050G, IFX1050GVIO and IFX1040SJ devices are optimized for high-speed CAN communication, the new IFX1051 transceiver family addresses the upcoming CAN FD (flexible data rate) markets beyond 1 Mbit/s.

Key features

- > Transmission rates up to 2 Mbit/s ISO11898 compliant
- > Low-power modes
- > Receive-only mode
- > Standby/sleep mode
- > Bus wake-up
- > Thermal protection
- > CAN FD compliance

Key benefits

- > Low current consumption
- > Thermal protection
- Low power modes
- > Excellent EMI performance and EMI robustness
- Standby/sleep mode
- > Pin-to-pin replacements for industry-standard parts

Product portfolio

Product number	Package	Transceiver type	ISO compliance	Transmission rate (max.)
IFX1050G	PG-DSO-8	High-speed CAN	ISO11898-2	1 Mbps
IFX1050GVIO	PG-DSO-8	High-speed CAN	ISO11898-2	1 Mbps
IFX1040SJ	PG-DSO-8	High-speed CAN	ISO11898-2, ISO11898-5	1 Mbps
IFX1051SJ	PG-DSO-8	CAN FD	ISO 11898-2	2 Mbps
IFX1051LE	PG-TSON-8	CAN FD	ISO 11898-2	2 Mbps

CAN FD transceiver

In addition to the classic CAN transceiver portfolio, Infineon is also offering a CAN FD transceiver. By using two reserved bits in the protocol, CAN FD will boost the baudrate of CAN systems. The so-called "bit-rate-switch" (BRS) bit increases the bit rate within the CAN data field from 1 to 2 Mbit/s whereas the so-called "extended-data-length" (EDL) bit increased "payload" from 8 bytes to 64 bytes resulting in higher bandwith.

The Infineon CAN FD transceiver IFX1051, designed for HS CAN networks in industrial applications, acts as an interface between the physical bus layer and the CAN protocol controller - it drives the signals to the bus and protects the microcontroller against interferences generated within the network. Based on the high symmetry of the CANH and CANL signals, the IFX1051 provides a very low level of electromagnetic emission (EME) within a wide frequency range.

20-300 V MOSFETs

IFX1051 key features

- > Fully compatible to ISO 11898-2
- > Wide common mode range for EMI
- > Very low EME
- > Excellent ESD robustness
- Guaranteed loop delay symmetry to support CAN FD data frames up to 2 Mbit/s
- VIO input for voltage adaption to the microcontroller supply
- > Extended supply range on V_{cc} and VIO supply
- > CAN short-circuit proof to ground, battery and V_{cc}
- > TxD time-out function with very long TxD timeout timing
- > Low CAN bus leakage current in power-down state
- > Overtemperature protection
- > Protected against transients
- > Receive-only mode
- > Green product (RoHS compliant)
- Two package options: tiny package PG-TSON-8 or standard package PG-DSO-8

IFX1051 key benefits

- Cost efficient replacement to industry market standard device *1051
- > High-speed communication up to 2 Mbit/s
- > Wide temperature range





CAN FD IFX1051 block diagram

Discrete IGBTs

Packages

www.infineon.com/industrial-transceivers

Voltage regulators Energy-efficient voltage regulators and trackers

Our linear voltage regulators and trackers help to reduce energy consumption, extending operating time and minimizing operating costs across all kinds of systems. The wide supply voltage range, low quiescent current, rich protective feature set and choice of packages make our devices the perfect fit across a broad application spectrum, apart from automation systems as well for heath care, traffic, power tools, lighting and many other multi-market systems. Our trackers are ideal as additional supplies for off-board loads to increase system reliability.

Key features

- > Input voltage up to 60 V
- > Output current up to 1.5 A
- > Output voltage adjustable or fixed to specific values
- > Quiescent current down to 5 μ A
- Overload, overtemperature, short circuit and reverse-polarity protection
- > Low current consumption
- > Extended temperature range -40°C ... +125°C

Key benefits

- Pin-to-pin compatibility with industry-standard parts
- > Very low dropout voltage
- Trackers for optimized heat distribution and external protection
- > Trackers for maximum system cost reduction
- Small robust packages

Infineon's microcontroller families and industrial voltage regulators

Microcontroller family	Input voltage [V]	Input current (max.) [mA]	Voltage regulator
XMC1000 family	1.8 5.5	<100	IFX54211/IFX2931/IFX4949/IFX25001/IFX544xx/ IFX30081
XMC4000 family	3.3	<500/300	IFX1763/IFX544xx/IFX1117/IFX30081
XC8xx	3.3 5.0	200	IFX20001/IFX30081/IFX21401/IFX4949/IFX544xx
XE166/XC2000	1.5 and 3.3 or 5.0	100	IFX25401/IFX24401/IFX2931/IFX4949/IFX1763/IFX54441
TriCore™	1.5 3.3	>400	IFX27001/IFX8117/IFX91041/IFX80471/IFX25001/IFX1117

Industrial linear voltage regulator (selection tree)



www.infineon.com/industrial-voltage-regulators

Discrete IGBTs

Packages

DC-DC converters

Robust range of converters for the widest application spectrum

Our high-efficiency switching regulators and controllers help to reduce energy consumption. In addition to extending the operating time of battery powered systems, they also significantly improve the thermal budget of the application. Overall, this translates into minimal operating costs. For your design flexibility, they are available as adjustable voltage variants as well as with dedicated fixed output voltage values.

Key features

- > Input voltage up to 60 V
- > Output currents going from 500 mA up to 10 A
- > Switching frequencies ranging from 100 kHz to 2.2 MHz
- > Shutdown quiescent current down to below 2 μ A
- > Current limitation and overtemperature protection

Key benefits

- > High-efficiency regulation
- > Only a few external components needed for stable regulation
- Perfectly suited for regulation in pre-/post-regulation power supply architectures

> Enable feature

DC-DC converters

Part number	V _Q (multiple)	Output current type	Output current [A]	Product features	Package
IFX81481ELV	Adjustable	Buck controller	10.0	10 A synchronous DC-DC adjustable step down controller; f = 100 kHz-700 kHz, N	PG-SSOP-14
IFX90121EL V50	5.0 V	Buck converter	0.5	$V_{\mbox{\tiny in}}$ up to 45 V, 2.2 MHz step-down regulator with low quiescent current	PG-SSOP-14
IFX80471SK V	Adjustable	Buck controller	2.3	$V_{_{in}}$ up to 60 V; $V_{\scriptscriptstyle Q}$ adjustable from 1.25 V up to 15 V; external MOSFET	PG-DSO-14
IFX80471SK V50	5.0 V	Buck controller	2.3	V _{in} up to 60 V; external MOSFET	PG-DSO-14
IFX91041EJV	Adjustable	Buck converter	1.8	$V_{\rm Q}$ adjustable from 0.6 V up to 16 V; tolerance 2% up to 1000 mA	PG-DSO-8
IFX91041EJ V33	3.3 V	Buck converter	1.8	$V_{\rm Q}$ fixed to 3.3 V; tolerance 2% up to 1000 mA	PG-DSO-8
IFX91041EJ V50	5.0 V	Buck converter	1.8	$V_{\rm Q}$ fixed to 5.0 V; tolerance 2% up to 1000 mA	PG-DSO-8





Industrial DC-DC buck regulators (selection tree)



Discrete IGBTs

www.infineon.com/industrial-dcdc-converters

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Galvanic isolated high-side switches and input ICs

Our ISOFACE[™] product family provides robust and intelligent galvanic isolation for industrial control applications such as programmable logic controllers, sensor input modules, control panels and general control equipment. The output switches are compact in design, enabling robust and reliable operation at low system cost. Ideal for high-speed applications, input ICs are equally robust, reliable and compact – also offering superior EMI robustness and diagnostics.

Isolated output switches



Key features

- > Integrated galvanic isolation (500 V)
- > Eight channels (0.6 or 1.2 A, each)
- > Inductive load switching
- Diagnostic feedback (overtemperature, overload)
- > Serial and parallel MCU interface

Key benefits

- > Robust and reliable
- > Compact system solution
- > Lower system cost
- > System status feedback
- Directly interfacing with all MPUs and MCUs

Isolated output switch block diagram



	Product overview	ISO1H801G	ISO1H811G	ISO1H812G	ISO1H815G	ISO1H816G
	$V_{\mbox{\tiny bb}}$ operational range: 11 V to 35 V	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Custal	Max. continuous load current per channel	0.6 A	0.6 A	0.6 A	1.2 A	1.2 A
Switch	Load current increase by using outputs in parallel	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Switch Switch Switch Safety features Safety features Diagnostics feedback Safety DSO-36 (16	Inductive clamping energy per channel: 1 Joule	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Microcontroller	Туре	Parallel	Parallel	Serial	Parallel	Serial
interface	Nominal voltages	5 V	3.3 V/5 V	3.3 V/5 V	3.3 V/5 V	3.3 V/5 V
	Isolation voltage: V _{iso} = 500 V UL508 and EN 61131-2 certified	\checkmark	√	√	√	✓
Safety features	Active current limitation	\checkmark	\checkmark	\checkmark	\checkmark	✓
	Thermal shutdown	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
	Common output disable pin	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Diagnostics	Overtemperature		\checkmark	\checkmark	\checkmark	\checkmark
feedback	V _{bb} undervoltage		\checkmark	\checkmark	\checkmark	\checkmark
Package DSO-36 (16x14 mm)	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Infineon ordering	code	SP000722122	SP000413798	SP000413800	SP000555576	SP000555578

www.infineon.com/isoface

Microcontrollers

Discrete IGBTs

Isolated digital input ICs



Digital input switch block diagram

Key features

- > Integrated galvanic isolation (500 V)
- > Eight channels (IEC type 1/2/3)
- > Up to 500 kHz sampling speed
- > Programmable input filters
- Channel-specific diagnostics (wire-break, undervoltage)

Key benefits

- > Robust and reliable
- > Compact system solution
- > High-speed applications
- > Superior EMI robustness
- > System status feedback
- > Valuable maintenance support



XMC4800 automation board V2



Ordering code: SP001632038

The automation board utilizes Infineon's industry-leading XMC[™] ARM[®] Cortex[®]-M4 microcontroller in combination with Infineon supply, interface, communication and safety products.

- > Complete automation kit gateway
- > Combined MCU with EtherCAT[®] slave application
- > Isolated interfaces w/ diagnose
- > Ethernet connectivity with software examples available
- > 24 V supply
- > CAN connectivity
- > Full software DAVE[™] examples

Proc	duct overview	ISO1I811T	ISO1I813T
Input characteristics	IEC type: I, II, III	\checkmark	\checkmark
	Input status LED	\checkmark	\checkmark
	Max. sampling frequency	125 kHz	500 kHz
	Deglitching filter setting	Hard wired	Software, individual per channel
	Synchronous data acquisition	-	✓
μC interface	3.3 V/5 V	\checkmark	✓
	Serial and parallel	\checkmark	√
Safety features	500 V isolation voltage	\checkmark	√
	Wire break, channel-specific	-	√
	V _{bb} undervoltage	_	✓
Support for external V	_{bb} supply	-	\checkmark
Package TSSOP-48 (8x	12.5 mm)	\checkmark	\checkmark
Infineon ordering code	e	SP000876494	SP000876504

www.infineon.com/isoface

Industrial PROFET™

Protected high-side switches

The well-established high-side switch Industrial PROFET[™] products were designed for targeting a variety of industrial applications which include all types of resistive, inductive and capacitive loads. Due to their outstanding energy robustness, they are perfectly suitable for switching even higher inductive loads and driving relays. Their main application areas include high-voltage applications (VBAT up to 60 V), high-speed PWM applications (up to 1 kHz) and they are most notably capable of switching higher inductances smoothly. Industrial PROFET[™] can be applied to drive any kind of sensor units, indicators, displays, LEDs, relays, valves and magnetic actuators or replace electromechanical relays, fuses and discrete circuits. Industrial PROFET[™] are also the perfect match for applications with long wiring or any other kind of inductive loads or applications with space constraints.

Key applications

- > Industrial automation
- > Programmable logic controller (PLC)
- > Digital I/O modules
- > Robotics
- > Building and home automation
- > Set Home

- > Solar applications
- > Wind energy systems
- > Smart grid
- Medical
- E-bikes and LEVs (light electric vehicles)
- Motor control and drives
- Power supplies



Industrial automation system diagram

System benefits

- Right fit for digital output switches, motor or robot control, protected switching of decentralized loads like sensors or auxiliary supply
- Suitable for all types of complex loads including high inductances (high EAS)
- Outstanding robustness and reliability as required by industrial mission profiles
- Thermally optimized products with low R_{DS(on)} to deal with the high ambient temperatures and limited or even no cooling
- > Diagnosis and protection for safe system operation
- Small and compact design for higher integration and applications with space constraints

20-300 V MOSFETs

PLC – programmable logic controller digital output modules



System benefits

- Suitable for all types of complex loads including high inductances (EAS) as PLC manufacturers cannot predict how the end customer will use the digital outputs
- > Outstanding robustness and reliability as required by industrial mission profiles
- Thermally optimized products with low R_{DS(on)} to deal with the high ambient temperatures within I/O modules with limited or even no cooling
- > Diagnosis and protection for safe system operation
- > Small and compact design for higher integration
- Addressing the I/O modules quasi standard currents
 2 A & 0.5 A, but also lower currents as within micro-PLCs

Product	Number of	$R_{DS(on)}$	Nominal load	E _{AS}	Recommended	I _{L(SC)} (typ)	Diagnosis	Package
	channels	(typ)	current		operating voltage range			
		[mΩ]	[A]	[mJ]	[V]	[A]		
ITS4060S-SJ-N	1	50	3.10	900 @ 1.50 A	5.00 34.00	17.0	n/a	DSO-8
ISP772T	1	50	2.60	900 @ 1.50 A	5.00 34.00	17.0	n/a	DSO-8
ITS428L2	1	60	7.00	190 @ 7.00 A	4.75 41.00	22.0	Digital	TO252-5
ITS4100S-SJ-N	1	70	2.40	870 @ 1.00 A	5.00 34.00	10.0	n/a	PG-DSO-8
ISP762T	1	70	2.00	870 @ 1.00 A	5.00 34.00	10.0	n/a	DSO-8
ITS4200S-ME-O	1	150	1.10	700 @ 0.50 A	11.00 45.00	1.4	n/a	SOT-223-4
ITS4141N	1	150	1.10	700 @ 0.50 A	12.00 45.00	1.4	n/a	SOT-223-4
ITS4141D	1	150	1.10	12,000 @ 0.50 A	12.00 45.00	1.4	n/a	TO-252-5
ITS4200S-ME-P	1	150	2.20	160 @ 1.00 A	11.00 45.00	3.0	n/a	SOT-223-4
ITS4142N	1	150	2.20	160 @ 1.00 A	12.00 45.00	3.0	n/a	SOT-223-4
ITS4200S-ME-N	1	160	1.20	500 @ 0.50 A	5.00 34.00	1.5	n/a	DSO-8
ISP452	1	160	1.20	500 @ 0.50 A	5.00 34.00	1.5	n/a	SOT-223-4
ITS4200S-SJ-D	1	150	1.70	125 @ 1.00 A	6.00 52.00	6.5	Digital	DSO-8
ISP752R	1	200	1.70	125 @ 1.00 A	6.00 52.00	6.5	Digital	DSO-8
ISP752T	1	200	1.70	125 @ 1.00 A	6.00 52.00	6.5	n/a	DSO-8
ITS4300S-SJ-D	1	250	0.80	800 @ 0.30 A	5.00 34.00	1.2	Digital	DSO-8
ISP742RI	1	350	0.80	800 @ 0.30 A	5.00 34.00	1.2	Digital, inverted	DSO-8
ITS41K0S-ME-N	1	1000	0.55	1000 @ 0.15 A	4.90 60.00	0.9	n/a	SOT-223-4
ITS4140N	1	1000	0.55	1000 @ 0.15 A	4.90 60.00	0.9	n/a	SOT-223-4
ITS4040D-EP-D	2	40	2 x 2.00	185*	5.00 45.00	4.1	Digital	TSDSO-14
ITS5215L	2	90	2 x 2.00	178 @ 3.50 A	5.50 40.00	15.0	Digital	DSO-12
ITS42K5D-LD-F	2	2500	2 x 0.25	Freewheeling	4.50 45.00	0.6	Digital	TSON-10
ITS4075Q-EP-D	4	75	4 x 2.00	60*	5.00 45.00	4.1	Digital	TSDSO-14
ITS4090Q-EP-D	4	100	4 x 0.50	410*	5.00 45.00	1.5	Digital	TSDSO-14
ITS724G	4	90	4 x 2.00	120 @ 3.30 A	5.50 40.00	15.0	Digital	DSO-20
ITS4130Q-EP-D	4	130	4 x 0.50	380*	5.00 45.00	1.25	Digital	TSDSO-14
ITS716G	4	140	4 x 1.00	76 @ 2.30 A	5.50 40.00	9.0	Digital	DSO-20
ITS711L1	4	200	4 x 1.00	150 @ 1.90 A	5.00 35.00	7.5	Digital	DSO-20
ITS42008-SB-D	8	200	8 x 0.60	10,000 @ 625 mA	11.00 45.00	3.0	Digital	DSO-36
ITS4880R	8	200	8 x 0.60	10,000 @ 625 mA	11.00 45.00	3.0	Digital	DSO-36

Industrial PROFET[™] evaluation board plus samples:

> ITS4060S-SJ-N, ITS4100S-SJ-N, ITS4200S-SJ-D, ITS4300S-SJ-D, ITS4200S-ME-N, ITS4200S-ME-O, ITS4200S-ME-P, ITS41K0S-ME-N order: INDPROFETEVALBOARDTOB01

Additional evaluation boards:

- > ITS42008, order: DEMOBOARDITS42008TOBO1
- > ITS42K5D-LD-F, order: DEMOBOARDITS42K5DTOBO1
- > ITS 4040D-EP-D, order: DEMO BOARD ITS 4040DTOB01
 > ITS 4075Q-EP-D, order: DEMO BOARD ITS 4075QTOB01
- > ITS 4090Q-EP-O, order: DEMO BOARD ITS 4090QTOB01
- > ITS 4130Q-EP-D, order: DEMO BOARD ITS 4130QTOB01

www.infineon.com/industrial-profet
*Per one channel

Application

HITFETTM

Protected low-side switches

HITFET[™] stands for highly-integrated temperature-protected MOSFET. These well-established low-side switches offer a compelling feature set with protection against overtemperature, short circuit and overload conditions as well as ESD robustness. The HITFET[™]+ family is the new generation based on a new technology, enabling a significant shrink compared to the existing HITFET[™] portfolio (up to 50 percent shrink). This new generation consists of standard and fully-featured protected low-side switches (35 to 125 mΩ) in the TO-252-3 DPAK/TO-252-5 DPAK and TDSO-8 packages. HITFET[™] and HITFET[™]+ devices address a wide range of applications including resistive, inductive and resistive loads.

Key features

- > Low-side switches with integrated protection features
- > Scalable in $R_{DS(on)}$ ranges from 490 m Ω down to 11 m Ω
- > Adjustable slew rate control (BTFxxx)
- > Thermal shutdown with auto restart or latch behavior
- > Status feedback via
 - Increased input current (HITFET[™] 2nd gen.)
 - Digital read out via SRP (BTF3050TE)
 - Via status pin (BTF3xxxEJ)

Key applications

- > Industrial automation*
- > Programmable logic controller (PLC)**
- > Digital I/O modules
- > Building and home management
- > All kind of solenoid or valve driving
- > Power modules
- > Solar power inverters

Key benefits

- > High design flexibility with scalable R_{DS(on)} and package
- > Driving applications with high switching speed requirements up to 25 kHz (e.g. valve, solenoid)
- > Easy to design-in
- > Choice of packages to match individual application needs

Application diagramm example for HITFET™



C_{SRP}-GND < 100 pF - maximum permittet parasitic capacitance at the SRP-pin
 Filter capacitor on supply, recommended 100 nF

www.infineon.com/hitfet

*See block diagram on page 204 ** See block diagram on page 205 20-300 V MOSFETs

Discrete IGBTs

Motor control ICs

Product type	Product family	Channels	R _{DS(on)} @ 25°C [mW]	Nominal load current [A]	EAS [mJ]	Operating voltage range [V]	IL _(SD) (typ) [A]	I _{L(lim)} (typ) [A]	I _{L(lim)_TRIGGER} (typ) [A]	Diagnosis	Package
BTS3011TE NEW!	HITFET™+	1	10.7	[A] 10	300 @ 5 A	up to 28	[A] -	[A] 35	[A] 70	Status pin	TO-252-5 (DPAK 5-leg)
BTS3035EJ	HITFET™+	1	28	5.00	105@5A	up to 31	-	20.00	-	Status pin	TDSO-8
BTS3035TF	HITFET™+	1	30	5.00	106@5A	up to 31	-	20.00	-	-	TO-252-3 (DPAK 3-leg)
BTF3035EJ* NEW!	HITFET™+	1	28	5.00	95@5A	up to 32	-	14.00	41.00	Status pin	TDSO-8
BTF3050TE	HITFET™+	1	40	3.00	120@3A	up to 28	-	8.00	30.00	Through SRP pin	TO-252-5 (DPAK 5-leg)
BTS3050EJ	HITFET™+	1	40	4.00	62@3A	up to 31	-	15.00	-	Status pin	TDSO-8
BTS3050TF	HITFET™+	1	44	4.00	64@4A	up to 31	-	15.00	-	-	TO-252-3 (DPAK 3-leg)
BTF3050EJ* NEW!	HITFET™+	1	40	4.00	62@4A	up to 32	-	10.00	29.00	Status pin	TDSO-8
BTS3060TF	HITFET™+	1	50	3.00	55@3A	up to 35	-	10.50	-	-	TO-252-3 (DPAK 3-leg)
BTS3080EJ	HITFET™+	1	64	3.00	35@3A	up to 31	-	10.00	-	Status pin	TDSO-8
BTS3080TF	HITFET™+	1	69	3.00	38@3A	up to 31	-	10.00	-	-	TO-252-3 (DPAK 3-leg)
BTF3080EJ* NEW!	HITFET™+	1	64	3.00	33 @ 3 A	up to 32	-	7.00	18.00	Status pin	TDSO-8
BTS3125EJ	HITFET™+	1	100	2.00	30 @ 2 A	up to 31	-	7.00	-	Status pin	TDSO-8
BTS3125TF	HITFET™+	1	108	2.00	24 @ 2 A	up to 31	-	7.00	-	-	TO-252-3 (DPAK 3-leg)
BTF3125EJ* NEW!	HITFET™+	1	100	2.00	23@2A	up to 32	-	5.00	12.00	Status pin	TDSO-8
BTS3018TC	HITFET™	1	14	6.00	1900	up to 36	-	30.00	-	Through input pin	TO-263-3-2 (TO-220-3 (SMD))
BTS141TC	HITFET™	1	25	5.10	4000	up to 36	-	25.00	-	Through input pin	TO-263-3-2 (TO-220-3 (SMD))
BTS3028SDL	HITFET™	1	28	5.00	350	up to 36	-	18.00	-	Through input pin	TO-252-3 (DPAK 3-leg)
BTS3028SDR	HITFET™	1	28	5.00	350	up to 36	-	18.00	-	Through input pin	TO-252-3 (DPAK 3-leg)
BTS133TC	HITFET™	1	40	3.80	2000	up to 36	-	21.00	-	Through input pin	TO-263-3-2 (TO-220-3 (SMD))
BTS3046SDL	HITFET™	1	46	3.60	140	up to 36	-	10.00	-	Through input pin	TO-252-3 (DPAK 3-leg)
BTS3046SDR	HITFET™	1	46	3.60	140	up to 36	-	10.00	-	Through input pin	TO-252-3 (DPAK 3-leg)
BTS117TC	HITFET™	1	80	3.50	1000	up to 36	-	7.00	-	Through input pin	TO-263-3-2 (TO-220-3 (SMD))
BTS3104SDL	HITFET™	1	104	2.00	50	up to 36	-	6.00	-	Through input pin	TO-252-3 (DPAK 3-leg)
BTS3104SDR	HITFET™	1	104	2.00	50	up to 36	-	6.00	-	Through input pin	TO-252-3 (DPAK 3-leg)
AUIPS2041L	HITFET™	1	100	1.40	-	up to 35	5.00	-	-	-	SOT-223
AUIPS2051L	HITFET™	1	250	0.90	-	up to 35	1.80	-	-	-	SOT-223
AUIPS2052G	HITFET™	2	250	0.90	-	up to 35	1.80	-	-	-	SO-8 (DSO-8)
BTS3408G	HITFET™	2	480	0.55	800	up to 36	-	1.00	-	Through input pin	DSO-8
BSP75N	HITFET™	1	490	0.70	550	up to 36	-	1.00	-	Through input pin	SOT-223

Low-side switch shield with BTF3050TE

The low-side switch shield from Infineon consists out of three BTF3050TE low-side switches of the HITFET^{™+} family providing three independent power channels that can be controlled via the input pins. The shield is compatible with microcontroller boards using the Arduino form factor, for example the corresponding ARM[®] powered XMC[™] microcontroller kits from Infineon and supports fast and easy prototyping of applications with BTF3050TE.

Key features

- > PWM up to 14 kHz (10 percent duty cycle)
- > Driver circuit with logic level inputs
- > Fault feedback
- Protection e.g. against overtemperature and overcurrent
- > Able to switch all kinds of resistive, inductive and capacitive loads

Operating conditions

- > Nominal voltage range 8 V 18 V
- > Nominal current 3 A (typ.) DC



Motor control ICs

www.infineon.com/hitfet www.infineon.com/shields-for-arduino * Available in Q2 2018

Half- and H-bridges

Motor control design made easy

Half-bridges

The NovalithIC[™] provides a complete, low-ohmic protected half-bridge in a single package (typ. path resistance at 25°C down to 10 mΩ). It can also be combined with an additional NovalithIC[™] to create a H-bridge or three-phase bridge. The NovalithIC[™] family has the capability to switch high-frequency PWM while providing overcurrent, overvoltage and overtemperature protection. The NovalithIC[™] family offers cost-optimized, scalable solutions for protected high-current PWM motor drives with very restrictive board space. Due to the P-channel high-side switch the need for a charge pump is eliminated thus minimizing EMI. The latest addition to the NovalithIC[™] family is the IFX007T, which is optimized for industrial applications.

Basic features

- > Low quiescent current
- > Capable for high PWM frequency
- > Logic level input
- > Adjustable slew rate
- > Cross-current protection
- **Protection features**
- > Overtemperature shutdown
- Overvoltage (lockout or smart clamp)
- > Undervoltage
- > Overcurrent

Diagnostic features

- > Overtemperature
- > Overvoltage
- > Overcurrent
- > Current sense and status

Product number	Operating range [V]	R _{DS(on)} path (typ.) [mΩ]	I _{D(lim)} (typ.) [A]	l _q (typ.) [μΑ]	Switch time (typ.) [µs]	Diagnosis	Protection	Package	Qualification
IFX007T	5.5 40.0	10.0	70	7	0.25	0T, 0C, CS	UV, OT, OC	PG-TO-263-7	JESD471

Application example for high-current PWM motor drives



OT = Overtemperature



Gate driver ICs

www.infineon.com/novalithic

CS = Current sense OC = Overcurrent

210

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Integrated multi-half-bridge driver ICs

The TLE94xyz are protected half-bridge drivers designed for 12 V motion control applications such as small DC motors for heating, ventilation and air conditioning (HVAC), as well as automotive mirror adjustment and fold. The family offers three-, four-, six-, eight-, ten-, and twelve-fold integrated half-bridge driver. All devices can drive DC motor loads up to 0.9 A per output in cascaded or parallel operation. They provide diagnosis of short circuit, open load, power supply failure and overtemperature for each half-bridge to ensure safe operation in HVAC or other systems. The TLE94xyz offers enhanced EMC performance, which in combination with the low quiescent current and a small package makes the product attractive for a wide range of 12 V automotive and industrial applications.

Key features and benefits

- Three-, four-, six-, eight-, ten-, and twelve-fold half-bridges with integrated output stages and PWM
- 16-bit SPI or direct inputs for control and diagnosis
- > Voltage supply range: 5.5–20 V
- Adjustable open load threshold for two outputs
- Variable driving schemes for up to 11 motors
- > OUT 1 and 2 optimized for driving
- > HS loads (e.g. LED)

Key applications

- > 12 V automotive and industrial applications
- > Flap motors in HVAC systems
- > Mirror adjustment and fold
- Small DC motors (≤ 0.9 A/output)
- > Bi-stable relays

Block diagram TLE94112EL



Product name	Configuration	I _{L(NOM)} [А]	I _{L(lim)} [A]	Ι _q [μΑ]	V _{s(OP)} [V]	Protection	Diagnostic interface	Highlights	$V_{CE(sat)}/R_{DS(on)}$	Package
TLE94003EP	3 x half-bridge	3 x 0.30	3 x 0.90	0.6	5.520	OC, OT, VS, UV/OV	Error flag	TLE94xyz family concept + small package	850 mΩ/switch	TSDSO-14-EP
TLE94103EP	3 x half-bridge	3 x 0.30	3 x 0.90	0.6	5.520	OC, OT, OL, VS, UV/OV	16-bit SPI	TLE94xyz family concept + small package	850 mΩ/switch	TSDSO-14-EP
TLE94004EP	4 x half-bridge	4 x 0.30	4 x 0.90	0.6	5.520	OC, OT, VS, UV/OV	Error flag	TLE94xyz family concept + small package	850 mΩ/switch	TSDSO-14-EP
TLE94104EP	4 x half-bridge	4 x 0.30	4 x 0.90	0.6	5.520	OC, OT, OL, VS, UV/OV	16-bit SPI	TLE94xyz family concept + small package	850 mΩ/switch	TSDSO-14-EP
TLE94106EL	6 x half-bridge	6 x 0.30	6 x 0.90	0.6	5.520	OC, OT, OL, VS, UV/OV	16-bit SPI	TLE94xyz family concept + back- wards compatible to TLE84106EL	850 mΩ/switch	SSOP-24
TLE94108EL	8 x half-bridge	8 x 0.30	8 x 0.90	0.6	5.520	OC, OT, OL, VS, UV/OV	16-bit SPI	TLE94xyz family concept	850 mΩ/switch	SSOP-24
TLE94110EL	10 x half-bridge	10 x 0.30	10 x 0.90	0.6	5.520	OC, OT, OL, VS, UV/OV	16-bit SPI	TLE94xyz family concept + back- wards compatible to TLE84106EL	850 mΩ/switch	SSOP-24
TLE94112EL	12 x half-bridge	12 x 0.30	12 x 0.90	0.6	5.520	OC, OT, OL, VS, UV/OV	16-bit SPI	TLE94xyz family concept + 12 outputs in one package	850 mΩ/switch	SSOP-24

www.infineon.com/dc-motor-bridges

Power ICs

Microcontrollers

DC motor control shield with IFX007T for Arduino

The DC motor control shield is capable of driving two uni-directional DC motors (half-bridge configuration) or one bidirectional DC motor (H-bridge configuration). The implemented half-bridge NovalithIC[™] IFX007T can be controlled by a PWM via the IN pin. Interfacing to a microcontroller is made easy by the integrated driver IC which features logic level inputs, diagnosis with current sense, slew rate adjustment, dead time generation and protection against overtemperature, undervoltage, overcurrent and short circuit.

Features

- > Capable of high frequency PWM, e.g. 30 kHz
- Adjustable slew rates for optimized EMI by changing external resistor
- > Driver circuit with logic level inputs
- > Diagnosis with current sense

DC motor control with half-bridge IFX007T

Infineon's shields for Arduino are compatible with microcontroller boards using the Arduino-compatible form factor, e.g. Infineon's XMC[™] microcontroller kits.

Target applications

- > Brushed DC motor control up to 250 W continuous load
- > 24 V nominal input voltage (max. 6 V–40 V)
- Average motor current 30 A restricted due to PCB (IFX007T current limitation @ 55 A min.)



DC motor shield with TLE94112EL for Arduino

The DC motor shield is a small evaluation board equipped with TLE94112EL for use with Arduino. The TLE94112EL is capable to drive up to 6 small DC motors in parallel mode or up to 11 DC motors in cascaded mode. All outputs can drive up to 0.9 A. The outputs can be used stand-alone or combined to increase driving capability up to 3.6 A.

Features

- > Driver with 12 half-bridge outputs to drive DC motors, resistive or inductive loads
- Driver is protected against overtemperature, overcurrent, overvoltage, undervoltage and enables diagnosis of overcurrent, overvoltage, undervoltage
- > SPI interface with zero clock diagnosis
- > Enhanced EMC performance
- Integrated PWM generator with three different frequencies (80 Hz, 100 Hz, 200 Hz)

www.infineon.com/shields-for-arduino www.infineon.com/makers

Target applications

- > Multi-motor applications
- DC motors and voltage controlled bipolar stepper motors
- > Toys
- > HVAC systems

20-300 V MOSFETs

Motor control ICs

Packages

Integrated H-bridges

IFX9201SG and IFX9202ED* are general purpose 6 A H-bridges designed for the control of small DC motors and inductive loads. The outputs can be pulse width modulated at frequencies up to 20 kHz, which enables operation above the human sonic range by means of PWM/DIR control. While the signal at the DIR input defines the direction of the DC motor, the PWM signal controls the duty cycle. For load currents above the current limitation threshold (8 A typically), the H-bridges switch into chopper current limitation mode.

Key features and benefits

- > Up to nominal 36 V supply voltage
- Short circuit, overtemperature protection and undervoltage shutdown
- > Detailed SPI diagnosis or simple error flag
- > Simple design with few external components
- Small and robust DSO-12-17 (IFX9201SG) and DSO-36-72 (IFX9202ED) packages



Product number	Current limit (min.) [A]	Quiescent current (typ.) [µA]	Operating range [V]	R _{DS(on)} (typ./switch) [mΩ]	Package	R _{thJC} (max.) [K/W]
IFX9202SG	2 x 6.0 A	19.0	536	2 x 100	DSO-36	2 x 0.5

Applications examples









www.infineon.com/dc-motor-bridges

Applications

Discrete IGBTs

Motor control ICs

20-300 V MOSFETs

500-950 V MOSFETs

NBG semiconductors

Discrete IGBTs

Power ICs

Sate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

H-bridge Kit 2Go with IFX9201SG

Build your own DC motor control with the H-bridge Kit 2GO, a ready-to-use evaluation kit. It is fully populated with all electronic components equipped with the H-bridge IFX9201 combined with XMC1100 microcontroller based on ARM[®] Cortex[®]-M0 CPU. It is designed for the control of DC motors or other inductive loads up to 6 A or up to 36 V of supply.

Target applications

- > DC motor control for industrial applications
- > Home and building automation
- > Power tools battery management
- Industrial robotic applications
- > Electric toys applications



Stepper motor control shield with IFX9201SG and XMC1300 for Arduino

The stepper motor control shield from Infineon is one of the first high current stepper motor control boards being compatible to Arduino as well as to Infineon's XMC1100 boot kit. The stepper motor control shield is capable to drive the two coils in a stepper motors featuring dual-half bridge configuration. The implemented integrated IFX9201 half-bridges can be controlled by a STEP-signal via the STEP pin. Interfacing to a microcontroller is made easy by the integrated XMC1300 microcontroller that holds the peripherals to allow high-speed current control. Microstepping of the stepper motor can be achieved using the internal comparators, while operational amplifiers are installed to adapt the motor current sense signal to the microcontroller's input levels.

Features

- Compatible with microcontroller boards using the Arduino form factor, e.g. Infineon's XMC[™] microcontroller kits
- > Capable of high frequency PWM, e.g. 30 kHz
- Adjustable slew rates for optimized EMI by changing external resistor
- > Driver circuit with logic level inputs
- > Diagnosis with current sense

Target applications

- > Stepper motors up to 5 A phase current
- > 24 V nominal input voltage for the power stage
- Average motor current 3 A without additional cooling effort, 5 A possible with proper cooling

www.infineon.com/h-bridge-kit-2go www.infineon.com/IFX9201SG-stepper-motor-shield www.infineon.com/makers

Benefits

- Fast and inexpensive prototyping of stepper motor control
- > Simple testing of microstepping algorithms
- Diagnose pin to allow hardware feedback during development
- Overtemperature shutdown with latch behavior and undervoltage shutdown of the power section



Stepper drivers Cost-efficient, durable and reliable

The TLE4726G, TCA3727G and TLE8444SL are designed to drive bipolar stepper motors, DC motors and other inductive loads that operate on a constant current. The TLE4726G and TCA3727G have integrated control logic and power output stages for two bipolar windings.

Key features

- > Full to half-step operation
- > Protected bipolar power stages
- > Implemented current control
- > Error flag for diagnosis
- > Overtemperature protection

Applications

- > ATM
- > Franking machines
- > Vending machine
- > Idle speed control
- > Printer
- > Toys



Product number	I _{L(NOM)}	I _{L(lim)}	Ι _q [μΑ]	$V_{s(op)}$	Step operations	Protection	Diagnostic interface	Highlights	Package
TCA3727G	2x0.75	2x1.5	200	5–50	Full to mini-step	ОТ	-	High operating voltage, low quiescent current with inhibit	PG-DSO-24
TLE4726G	2x0.75	2x1.5	200	5–50	Full to mini-step	ОТ	-	High operating voltage, low quiescent current with inhibit	PG-DSO-24
TLE8444SL	4x0.50	4x0.90	1	1-18	Full to half-step	SC, OT, OV, UV, OL	Status flag	Open-load detection in on-state	SSOP-24-7

CS = Current sense OC = Overcurrent SC = Short circuit

OT = Overtemperature

UV = Undervoltage OL = Open-load

20-300 V MOSFETs

WBG semiconductors 500-950 V MOSFETs

Discrete IGBTs

CIPOS[™] IPM family

Control integrated power system (CIPOS™) intelligent power modules (IPM)

Depending on the level of integration and power to be handled, Infineon offers a variety of IPMs, with different semiconductors in different packages and different voltage and current classes.

CIPOS[™] IPMs are families of highly integrated, compact power modules designed to drive motors in applications ranging from home appliances to fans, pumps, and general purpose drives.

Infineon's energy-efficient IPMs integrate the latest power semiconductor and control IC technology leveraging Infineon's advanced IGBTs, MOSFETs, next-generation gate driver ICs and state-of-the-art thermo-mechanical technology.

CIPOS™ product overview



Key benefits

- > Shorter time-to-market
- > Increased reliability
- > Reduced system design complexity
- > Improved manufacturability
CIPOS[™] Nano

Three-phase or half-bridge driver with MOSFETs

CIPOS[™] Nano is a family of highly integrated, ultracompact IPMs for high efficiency appliance and light industrial applications including rectifiers, converters, inverters in power management circuits and motor drives for hair dryers, air purifiers, ceiling fans, circulation pumps and ventilators. By utilizing an innovative packaging solution, these IPMs delivers a new benchmark in device size, offering up to a 60 percent smaller footprint than existing three-phase motor control power IPMs.

The family is comprised of a series of fully integrated three-phase or half-bridge surface-mount motor control circuit solutions. The new alternative approach utilizes PCB copper traces to dissipate heat from the module, providing cost savings through a smaller package design and even eliminating the need for an external heat sink.

Key features

- > Motor drive-optimized fast recovery FETs
- > Heat sink-less operation
- > Smallest modules on the market
- > Wide range of footprint compatible parts
- > Integrated bootstrap functionality
- > Untervoltage lockout for all channels

Key benefits

- Cost savings from smaller footprint and reduced PCB space
- > Easy implementation of two or three-phase motor drives with half-bridge IPMs
- IPMs distribute heat dissipation and enable elimination of heat sink
- Same PCB footprint to address multiple application markets (100-230 V_{AC})

Package overview



www.infineon.com/ipm

Key applications

- > Small home appliances
- > Hair driers
- > Air purifiers
- > Fans
- Motor drives
- > Battery management
- > Water pumps
- > CPAP

20-300 V MOSFETs

Motor control ICs

Packages

CIPOS™ Micro

Solution for low power motor drive applications

CIPOS[™] Micro is a family of compact IPMs for low power motor drive applications including fans, pumps, air purifiers and refrigerator compressor drives.

These IPMs offer cost-effective power solutions by leveraging industry standard footprints and processes compatible with various PCB substrates. The advanced IPMs feature rugged and efficient high voltage MOSFETs and IGBTs specifically optimized for variable frequency drives with voltage ratings of 250~600 V IGBTs. The IPMs offer DC current ratings ranging up to 6 A to drive motors up to 100 W without heatsink and up to 300 W with heatsink, and are available in both through-hole and surface mount package options.

Key features

IPM

- > Integrated bootstrap functionality
- > Undervoltage lockout for all channels
- Matched propagation delay for all channels
- > Optimized dV/dt for loss and EMI trade-off
- > Advanced input filter with shoot-through protection
- > Separate low-side emitter pins for single- or leg-shunt current sensing
- > 3.3 V logic compatible
- > UL certified NTC thermistor for temperature feedback available
- Various lead forms available including through-hole and surface mounted

Key benefits

- > Ease of design and short time-to-market
- > Compact package with multi lead form options available
- > Wide range of current and voltage ratings in the same package
- Wide range of modules for 110 V_{AC} or 230 V_{AC} applications in the same footprint
- > Lower losses than similar modules in the market

Key applications

- > Fan motors
- Low-power general purpose drives (GPI, servo drives)
- > Pumps
- > Blowers
- Active filter (active power factor correction) for HVAC

Package overview

DIP 29x12	DIP 29x12F	SOP 29x12	SOP 29x12F
29 x 12 x 3.1 mm			

www.infineon.com/ipm

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

CIPOS™ Mini

Broad range of applications from PFC to inverter

CIPOS[™] Mini IPMs integrate various power and control components to increase reliability, and to optimize PCB size and system costs. This simplifies the power design and reduces significantly time-to-market.

The IPMs are designed to control AC motors in variable speed drives for applications from 4 A up to 30 A such as air conditioning, washing machines, refrigerators, vacuum cleaners, compressors, and industrial drives up to 3 kW.

The package concept is specially adapted to power applications that need good thermal conduction and electrical isolation, EMI-safe control, innovative fault indication, and overload protection. The feature of Infineon's reverse conducting IGBTs or TRENCHSTOP™ IGBTs are used with a new optimized Infineon SOI gate driver IC for excellent electrical performance.

Key features

- > Dual-in-line transfer molded package with DCB substrate
- > Current rating from 4 A to 30 A, power rating up to 3 kW
- > Optimized for home appliances and motor drives
- > Rugged SOI gate driver IC technology
- > Advanced protection features
- > UL1577 certified

Key benefits

- High integration (bootstrap circuit, thermistor) for easy design and system space saving
- > Single platform possible from 4 A to 30 A
- > Enhanced robustness of the advanced IGBT and gate driver IC technology
- > High power density
- Two kinds of substrates provide cost efficient solution for home appliances
- > UL-certified thermistor

Key applications

- > Fan motors
- Low-power general purpose drives (GPI, servo drives)
- > Pumps
- > Blowers
- Active filter (active power factor correction) for HVAC

Package overview



www.infineon.com/ipm

XENSIVTM sensors

219

IPM

Solutions for high reliability and performance application

CIPOS[™] Maxi IPMs integrate various power and control components to increase reliability, optimize PCB size and system costs. It is designed to control three-phase AC motors and permanent magnet motors in variable speed drives applications, such as low-power motor drives, pumps, fan drives and active filters for HVAC (heating, ventilation, and air conditioning). The existing portfolio offers 5 A and 10 A in 1200 V class up to 1.8 kW power rating. The smallest package in 1200 V IPM class offers highest power density and best performance in its class.

IM818 is the first 1200 V IPM that integrated an optimized 6-channel SOI gate driver to provide built-in dead time that prevents damage from transients. The product concept is especially adapted to power applications, which require excellent thermal performance and electrical isolation as well as meeting EMI requirements and overload protection.

Key applications

> Low-power general purpose

drives (GPI, servo drives)

Active filter (active power

factor correction) for HVAC

> Fan motors

> Pumps

> Blowers

Key features

- > Fully isolated dual in-line molded module with DCB
- > 1200 V TRENCHSTOP[™] IGBT 4
- > Rugged 1200 V SOI gate driver technology
- > Integrated booststrap functionality
- > Overcurrent shutdown
- > Undervoltage lockout at all channels
- > All of six switches turn-off during protection
- Cross-conduction prevention
- Programmable fault clear timing
- > Allowable negative VS potential up to -11 V for signal transmission at $V_{\scriptscriptstyle BS}$ of 15 V
- > Low side emitter pins accessible for all phase current monitoring (open emitter)

Key benefits

- > The smallest package size in 1200 V IPM class with high power density and best performance
- > Enhanced robustness of gate driver technology for excellent protection
- > Adapted to high switching application with lower power loss
- > Simplified design and manufacturing

Package overview



www.infineon.com/ipm

20-300 V MOSFETs

Motor control ICs



Packages

CIPOS™ IPM product portfolio

			MOSFET ba	sed CIPOS™ IPI	Ms
Product family	Voltage [V]	Configuration	$R_{DS(on)}$ max. [Ω]	Package	Product name
CIPOS [™] Nano	40	Half-bridge	0.05	QFN 7x8	IRSM005-800MH
	100	Half-bridge	0.02	QFN 7x8	IRSM005-301MH
	250	Half-bridge	0.15	QFN 8x9	IRSM808-204MH
		3-phase inverter	0.45. ~ 2.20	QFN 12x12	IRSM836-084MA/IRSM836-044MA IRSM836-024MA
	500	Half-bridge	0.80/1.70	QFN 8x9	IRSM807-105MH/IRSM808-105MH IRSM807-045MH
		3-phase inverter	1.70 ~ 6.00	QFN 12x12	IRSM836-045MA/IRSM836-035MA/IRSM836-035MB IRSM836-025MA/IRSM836-015MA
CIPOS [™] Micro	250	3-phase inverter	0.45. ~ 2.20	DIP 29x12F	IRSM5y5-084DA/IRSM5y5-044DA ¹⁾ IRSM5y5-024DA ¹⁾
			0.45. ~ 2.20	SOP 29x12F	IRSM5y5-084PA/IRSM5y5-044DPA ¹⁾ IRSM5y5-024PA ¹⁾
	500		1.30 ~ 6.00	DIP 29x12F	IRSM5y5-065DA/IRSM5y5-055DA ¹⁾ IRSM5y5-035DA/IRSM5y5-025DA ¹⁾ IRSM5y5-015DA ¹⁾
			1.30 ~ 6.00	SOP 29x12F	IRSM5y5-065PA/IRSM5y5-055PA ¹⁾ IRSM5y5-035PA/IRSM5y5-025PA ¹⁾ IRSM5y5-015PA ¹⁾
CIPOS [™] Mini	600	2/3-phase inverter	0.33	DIP 36x21	IM512-L6A/IM513-L6A

			IGBT based	CIPOS™ IPMs	
Product family	Voltage [V]	Configuration	Rated current [A]	Package	Product name
CIPOS [™] Micro	600	3-phase inverter	3.0/4.0	DIP 29x12F	IM240-S6Y1B/IM240-S6Y2B IM240-M6Y1B/IM240-M6Y2B/IRSM5y6-076DA ¹⁾
			4.0/6.0	DIP 29x12	IM231-M6T2B/IM231-L6T2B
			3.0/4.0	SOP 29x12F	IM240-S6Z1B IM240-M6Z1B/IRSM5y6-076PA ¹⁾
			4.0/6.0	SOP 29x12	IM231-M6S1B/IM231-L6S1B
CIPOS™ Mini	600	PFC integrated	10.0/15.0	DIP 36x21D	IFCM10S60GD/IFCM10P60GD IFCM15S60GD/IFCM15P60GD
		3-phase inverter	4.0 ~ 30.0	DIP 36x21	IGCM04F60yA/IGCM04G60yA ²¹ IGCM06F60yA/IGCM06G60yA ²¹ IGCM10F60yA/IKCM10H60yA/IKCM10L60yA ²³ IGCM15F60yA/ICM15L60yA/IKCM15F60yA/IKCM15H60yA ²³ IGCM20F60yA/IKCM20L60yA ²³ IKCM30F60yA ²¹
			15.0 ~ 30.0	DIP 36x21D	IKCM15L60yD/IKCM20L60yD/IKCM30F60yA ²⁾
	650	3-phase interleaved PFC	20	DIP 36x21D	IFCM20T65GD/IFCM20U65GD
		2-phase interleaved PFC	30	DIP 36x21D	IFC30T65GD/IFCM30U65GD
CIPOS [™] Maxi	1200	3-phase inverter	5.0/10.0	DIP 36x23D	IM818-SCC/IM818-MCC

1) y = 0 (with NTC), y = 1 (without NTC) 2) y = G (with NTC), y = H (without NTC)

www.infineon.com/ipm



Infineon support for power ICs Useful links and helpful information

Further information, datasheets and documents

www.infineon.com/acdc www.infineon.com/coolset www.infineon.com/integrated-powerstages www.infineon.com/digital-controller www.infineon.com/lighting-ics www.infineon.com/isoface www.infineon.com/eicedriver www.infineon.com/eicedriver www.infineon.com/industrial-transceivers www.infineon.com/industrial-voltage-regulators www.infineon.com/industrial-dcdc-converters

Videos and eLearnings www.infineon.com/mediacenter www.infineon.com/industrial-profet www.infineon.com/novalithic www.infineon.com/dc-motor-bridges www.infineon.com/shields-for-arduino www.infineon.com/ipol www.infineon.com/analog-ipol www.infineon.com/xdp www.infineon.com/ipm www.infineon.com/madk





Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Industrial and general purpose gate driver ICs

The expert's choice

Leveraging the application expertise and advanced technologies of Infineon, the industrial and general purpose gate driver ICs are well suited for many applications such as industrial motor drives, solar inverters, UPS, switch mode power supplies, lighting and major home appliances. Infineon offers a comprehensive portfolio of industrial and general purpose gate driver ICs with a variety of configurations, voltage classes, isolation levels, protection features, and package options. These flexible gate driver ICs are complementary to Infineon IGBTs, MOSFETs, SiC MOSFET, GaN HEMTs and other power switches in discrete gate drive applications, or as a part of integrated power modules.

EiceDRIVER™ 1EDN family

Rugged, cool and fast, single-channel low-side 4/8 A gate driver ICs

EiceDRIVER™ 1EDN family

Single-channel MOSFET gate driver ICs are the crucial link between control ICs and powerful MOSFET and GaN switching devices. Gate driver ICs enable high system level efficiencies, excellent power density and consistent system robustness.

EiceDRIVER™ 1EDN family: fast, precise, strong and compatible

- > Highly efficient SMPS enabled by 5 ns short slew rates and ± 5 ns propagation delay precision for fast MOSFET and GaN switching
- > Separate source and sink outputs simplify the application design
- > Industry standard packages and pinout ease system design upgrades

EiceDRIVER™ 1EDN family: the new reference in ruggedness and low power dissipation

- > -10 V robustness of control and enable inputs provides crucial safety margin when driving pulse transformers
- > 5 A reverse output current robustness eliminates the need for Schottky switching diodes when driving MOSFETs in TO-220 and TO-247 packages
- > Cool driver ICs thanks to true rail-to-rail low impedance output stages
- > 4 V and 8 V UVLO (undervoltage lockout) options for instant MOSFET protection during start-up and under abnormal conditions

Applications

> PFC

224

- > Synchronous rectification
- > DC-DC converters
- > Telecom bricks
- Power tools
- Industrial SMPS
- > Motor control
- > Wireless charging



Discrete IGBTs

Motor control ICs

XENSIVTM sensors

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors



Application overview: 800 W switched mode power supply



Packa	ige	UVLO	Product name	Orderable part number	Pinout
		4 V	1EDN7511B	1EDN7511BXUSA1	VDD 1 6 IN+
	SOT-23 6-pin	8 V	1EDN8511B	1EDN8511BXUSA1	OUT_SRC 2 1EDN 5 IN- OUT_SNK 3 4 GND
	SOT-23 5-pin	4 V	1EDN7512B	1EDN7512BXTSA1	VDD 1 5 OUT GND 2 1EDN IN+ 3 4 IN-
	WSON 6-pin	4 V	1EDN7512G	1EDN7512GXTMA1	IN- 1 6 IN+ GND 2 1EDN 5 OUT GND 3 4 VDD

www.infineon.com/1edn

EiceDRIVER™ 1EDN7550 and 1EDN8550

Single-channel low-side gate driver family with truly differential inputs prevents false triggering of power MOSFETs

Overview

The input signal levels of conventional low-side gate driver ICs are referenced to the ground potential of the gate driver IC. If in the application, the ground potential of the gate driver IC shifts excessively false triggering of the gate driver IC can occur.

The 1EDN7550/1EDN8550 gate driver ICs have truly differential inputs. Their control signal inputs are largely independent from the ground potential. Only the voltage difference between its input contacts is relevant. This prevents false triggering of power MOSFETs.

Applications

- > Server
- > Telecom
- > DC-DC converters
- > Telecom bricks

> Power tools

- > Industrial SMPS
- > Wireless charging
- Solar micro inverter

Product features

Truly differential inputs

- > 4 A source current
- > 8 A sink current
- Separate source/sink outputsLow-ohmic output stage
- > 29 ns input minimum pulse width
- > 7 ns propagation delay accuracy
- > 5 A reverse current robustness
- of the outputs > 4 V and 8 V UVLO versions
- > SOT-23 package, 6 pins

- Control inputs independent from gate driver GND
 Fast Miller plateau transition
- Fast shut-off
- No diode voltage drop → near zero
- gate voltage at turn-off > Low power dissipation within gate driver IC
- > Up to 15 MHz switching speed
 > Precise
- No Schottky clamping diodes required
 Fast and reliable MOSFET turn-off
- > Small

Application benefits

- Robust against ground shifts from power MOSFET switching
- Low MOSFET switching losses
- Robust against false MOSFET triggering
 Highest effective MOSFET
- driving power

> Efficiency gains

- Increased power density and BOM savings
 Instant MOSFET protection under abnormal operation
- > High power density

Pinout



20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers



1EDN7550 driving CoolMOS[™] SJ MOSFET on single-layer PCB

1EDN8550 driving Kelvin source CoolMOS™ SJ MOSFET in boost PFC



Turne	Ground shif	t robustness	UVLO	Deskere	Orderable part number	
Туре	dynamic	static		Package		
1EDN7550B	+/- 150 V	+/- 70 V	4 V	SOT-23 6-pin	1EDN7550BXTSA1	
1EDN8550B	+/- 150 V	+/- 70 V	8 V	SOT-23 6-pin	1EDN8550BXTSA1	

EiceDRIVER™ 2EDN family

Rugged, cool and fast, dual-channel low-side 4 A/5 A driver IC

EiceDRIVER[™] 2EDN family overview

Dual-channel driver ICs are the crucial link between digital control ICs and powerful MOSFET and GaN switching devices. Driver ICs enable high system level efficiencies, excellent power density and consistent system robustness.

EiceDRIVER[™] 2EDN family: fast, precise, strong and compatible

- > Highly efficient SMPS enabled by 5 ns short slew rates and 10 ns propagation delay precision for fast MOSFET and GaN switching
- > Numerous deployment options due to two 4 A/5 A channels. 1 ns channel-to-channel accuracy to use two channels in parallel
- > Industry standard packages and pinout ease system design upgrades

EiceDRIVER™ 2EDN family: the new reference in ruggedness and low power dissipation

- > 4 V and 8 V UVLO (undervoltage lockout) options for instant MOSFET protection under abnormal conditions
- -10 V robustness of control and enable inputs provides crucial safety margin when driving pulse transformers or driving MOSFETs in TO-220 and TO-247 packages
- > 5 A reverse output current robustness eliminates the need for Schottky switching diodes and reduces bill-of-material
- > Cool driver ICs from true rail-to-rail low impedance output stages

Applications

- > Server
- > Telecom
- > DC-DC converters
- > Bricks

Package overview



Product features

- > 5 A souce/sink current
- 5 ns rise/fall times
 <10 ns propagation delay precision
- True rail-to-rail low impedance output stages
- 4 V and 8 V UVLO options
 19 ns propagation delay for both control and
- enable inputs
- > -10 V robustness of control and enable inputs
- > 5 A reverse output current robustness

> 2 independent channels

- > Excellent 1 ns channel-to-channel accuracy
- Industry standard pinout and packages
- www.infineon.com/2edn

Product benefits

- Fast Miller plateau transition
 Precise timing
- > Low power dissipation in driver IC
- Fast and reliable MOSFET turn-off, independent of control IC
- > Increased GND-bounce robustness
- Saves switching diodes
- Option to increase drive current by truly concurrent switching of 2 channels
- > Straight forward design upgrades

Application benefits

- > High power efficiency
- in hard switching PFC with SiC diode
 in half-bridges and synchronous rectifications
- Cooler driver IC operation
 Higher MOSFET drive capability
- Instant MOSFET protection under abnormal
- > Crucial safety margin to drive pulse transformer
- Increases power density
- > BOM savings
- One IC covering many applications
- > Short time to market

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Sate driver ICs

Motor control ICs

Microcontrollers

> Power tools

- Industrial SMPS
- Motor control
- > Solar
- All lating



Application overview 800 W 130 kHz switched mode power supply

Pack	age	UVLO	Inputs	Product name	Orderable part number	Current	
			Direct	2EDN7524F	2EDN7524FXTMA1	5 A	
And a		4 V	Inverted	2EDN7523F	2EDN7523FXTMA1	5 A	
1999	DSO 8-pin		Direct	2EDN7424F	2EDN7424FXTMA1	4 A	
		8 V	Direct	2EDN8524F	2EDN8524FXTMA1		
		ov	Inverted	2EDN8523F	2EDN8523FXTMA1	5 A	
		4 V	Direct	2EDN7524R	2EDN7524RXUMA1		
Acros Allen			Inverted	2EDN7523R	2EDN7523RXUMA1		
	TSSOP 8-pin		Direct	2EDN7424R	2EDN7424RXUMA1	4 A	
- 11 m		8 V	Direct	2EDN8524R	2EDN8524RXUMA1		
		0 V	Inverted	2EDN8523R	2EDN8523RXUMA1	5 A	
A Mary	WSON 8-pin	4 V	Direct	2EDN7524G	2EDN7524GXTMA1	JA	
	w30w8-pin	- T V	Inverted	2EDN7523G	2EDN7523GXTMA1		

Industry standard pinout configuration



Discrete IGBTs

EiceDRIVER™ 2EDi product family

Fast, robust, dual-channel, functional and reinforced isolated MOSFET gate drivers with accurate and stable timing

2EDi family overview

The EiceDRIVER[™] 2EDi product family is designed for use in high-performance power conversion applications. Very strong 4 A/8 A source/sink dual-channel gate drivers increase efficiency in CoolMOS[™] and OptiMOS[™] MOSFET half-bridges. The low propagation delay of 37 ns, combined with highly accurate and stable timing overtemperature and production, enables further efficiency gains within and across galvanically isolated power stages or in multi-phase/ multi-level topologies. The availability of functional and reinforced isolated drivers in different packages makes these a perfect fit for both primary side and (safe) secondary side control. Gate driver outputs come with a high 5 A reverse current capability and 150 V/ns CMTI robustness for high dv/dt power loops. For slower switching or driving smaller MOSFETs, 1 A/2 A peak current product variants are available as well.



Device overview



EiceDRIVER[™] 2EDi product familiy device diagram







Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Motor control ICs

www.infineon.com/2edi

System application diagram

Packages



	Orderable part	rable part	PWM	Driver source/ Gate				Dead-time		
Part number	number (OPN)	Package	Input type	Sink current	driver UVLO	Isolation class	Rating	Surge testing	Safety certification	control
2EDF7275F	2EDF7275FXUMA1	NB-DSO16	6	4 A/8 A						
2EDF7175F	2EDF7175FXUMA1	10 x 6 mm		1 A/2 A	A 4 V	Functional	V _{IO} =1.5 kV _{DC}	n.a.	n.a.	no
2EDF7275K	2EDF7275KXUMA1	LGA13	Dual Mode							
2EDF7235K	2EDF7235KXUMA1	5.0 x 5.0 mm	(IN_A, IN_B)							yes
2EDS8265H	2EDS8265HXUMA1	WB-DSO16			8 V	Reinforced	V _{IOTM} = 8 kV _{peak} (VDE0884-1x)	V _{IOSM} = 10 kV _{peak}	VDE0884-10 UL1577 IEC60950	no
2EDS8165H	2EDS8165HXUMA1	10.3 x 10.3 mm		1 A/2 A	οv	Remoted	V _{ISO} = 5.7 kV _{rms} (UL1577)	(IEC60065)	IEC60950 IEC62368 CQC	10

For further latest device information, configurations and application notes visit www.infineon.com/2EDi

GaN EiceDRIVER™ family

Single-channel isolated gate driver ICs for high voltage GaN switches

CoolGaN[™] e-mode HEMTs are best driven by Infineon's EiceDRIVER[™] ICs, the 1EDF5673K, 1EDF5673F and 1EDS5663H. They ensure robust and highly efficient high voltage GaN switch operation whilst concurrently minimizing R&D efforts and shortening time-to-market.

Key advantages of designing with the GaN EiceDRIVER™ family

Positive and negative gate drive currents:

> Fast turn-on/turn-off GaN switch slew-rates

Firmly hold gate voltage at zero, during off-phase:

- > Avoids spurious GaN switch turn-on
- > Up to 50% lower dead time losses

Configurable and constant GaN switching slew-rates, across wide range of switching frequency and duty-cycle:

- > Robust and energy efficient SMPS designs
- > Short time to market

Integrated galvanic isolation:

- > Robust operation in hard-switching applications
- > Safe isolation where needed

Key use cases

- > Totem pole PFCs
- > Vienna rectifiers
- > Multilevel topologies
- > Resonant LLC

Key applications



Key features

Low ohmic outputs:

- Source: 0.85 Ω
- > Sink: 0.35 Ω
- > Single-channel galvanic isolation:

Functional:

V_{IO}= 1500 V_{DC} V_{IOWM} = 510 V_{rms} (DSO 16-pin) V_{IOWM} = 460 V_{rms} (LGA 5x5)

Reinforced:

- V_{IOTM} = 8000 V_{pk} (VDE 0884-10 pending)
 V_{IOWM} = 1420 V_{DC}
- > CMTI min: 200 V/ns

Timing:

- > Minimum output pulse width: 18 ns
- > Propagation delay accuracy: 13 ns

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

GaN EiceDRIVER™ ICs evaluation environment

High frequency (1 MHz) half-bridge evaluation board EVAL_1EDF_G1_HB_GAN

Key components:

GaN switches: 2x CoolGaN[™] 600 V e-mode HEMTs (IGOT60R070D1) GaN drivers: 2x GaN EiceDRIVER[™] (1EDF5673K)

Order code: EVAL_1EDF_G1_HB_GAN

High power SMPS application example





*GaN EiceDRIVER[™] ICs are single-channel products

Package	LGA 13-pin 5x5 mm	DSO 16-pin 150 mil	DSO 16-pin 300 mil
Product	1EDF5673K	1EDF5673F	1EDS5663H
OPN	1EDF5673KXUMA1	1EDF5673FXUMA1	1EDS5663HXUMA1
Isolation (input to output)	VI _o = 1500 V _{DC}	$V_{10} = 1500 V_{DC}$	V_{IOTM} = 8000 V_{pk} (VDE0884-10 pending)
Source/sink output resistance	0.85 Ω/0.35 Ω	0.85 Ω/0.35 Ω	0.85 Ω/0.35 Ω
UVLO	4.5 V / 5.0 V	4.5 V / 5.0 V	4.5 V / 5.0 V

Level-shift silicon-on-insulator (SOI) gate driver ICs

2ED2304S06F - 650 V half-bridge gate driver with integrated bootstrap diode (BSD)

The 2ED2304S06F is a 650-V half-bridge gate driver. Its Infineon thin-film-SOI technology provides excellent ruggedness and noise immunity. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration which operates up to 650 V. Additionally, the offline clamping function provides an inherent protection of the parasitic turn-on by floating gate conditions when IC is not supplied.



Typical application diagram



Product features

- > Infineon thin-film SOI technology
- > Fully operational to +650 V
- > Floating channel designed for bootstrap operation
- > Output source/sink current capability +0.36 A/-0.7 A
- $\boldsymbol{\boldsymbol{\mathsf{>}}}$ Integrated ultrafast, low $\boldsymbol{\mathsf{R}}_{\scriptscriptstyle{\mathsf{DS}(\mathsf{ON})}}$ bootstrap diode
- Tolerant to negative transient voltage up to -50 V (pulse width is up 500 ns) given by SOI technology
- > 10 ns typ., 60 ns max. propagation delay matching
- > dV/dt immune ±50 V
- > Gate drive supply range from 10 to 20 V
- > Undervoltage lockout for both channels
- > 3.3 V, 5 V and 15 V input logic compatible
- > RoHS compliant

Potential applications

- > Motor drives, general purpose inverters
- > Refrigeration compressors
- Half-bridge and full-bridge converters in offline AC-DC power supplies for telecom and lighting

Power dissipation of Infineon SOI



DC = 300 V; CoolMOS[™] P7 in D-Pak; 300 kHz switching frequency

500-950 V MOSFETs 20-300 V MOSFETs

Motor control ICs

6ED2230S12T - 1200 V three-phase gate driver with overcurrent protection and integrated bootstrap diode (BSD)*

The 6ED2230S12T is a 1200 V three-phase SOI gate driver with an integrated bootstrap diode and overcurrent protection, with typical 0.35 A source and 0.65 A sink currents in a DSO-24 package (DSO-28 with 4 pins removed) for driving IGBTs. Proprietary HVIC and latch-immune CMOS technologies enable a robust monolithic design. A current-trip function which terminates all six outputs can also be derived from this resistor. An open-drain FAULT signal is provided to indicate that an overcurrent or undervoltage shutdown has occurred. Fault conditions are cleared automatically after a delay programmed externally via an RC network. The output drivers feature a high-pulse current buffer stage designed for minimum driver cross conduction. Propagation delays are matched to simplify the HVIC's use in high-frequency applications.

Product features

- > Infineon thin-film SOI technology
- > Fully operational to +1200 V
- > Floating channel designed for bootstrap operation
- > Output source/sink current capability +0.35 A/-0.65 A
- > Integrated ultrafast, low R_{DS(ON)} bootstrap diode
- Tolerant to negative transient voltage up to -100 V (pulse width is up 700 ns) given by SOI technology
- > Undervoltage lockout for both channels
- > 3.3 V, 5 V, and 15 V input logic compatible
- > Overcurrent protection (ITRIP ±5% reference)
- > Fault reporting, automatic fault clear and enable function on the same pin (RFE)
- > Matched propagation delay for all channels
- > Integrated 460 ns dead time protection
- > Shoot-through (cross-conduction) protection
- > 2.5kV HBM ESD protection

Evaluation board available:

EVAL-M1-6ED2230-B1

Typical application diagram

DC BUS+



DC BUS-

Typical applications

- > Industrial drives, motor control, general purpose inverters
- > Commercial air-conditioning (CAC)

Negative V_s transient robustness of Infineon SOI





Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

* Coming soon

Level-shift junction isolation (JI) gate driver ICs

New IRS200 x 200 V half-bridge, high and low-side gate driver family with V_{cc} and V_{BS} UVLO

Infineon offers 200 V ICs tailored for low-voltage (24 V, 36 V, and 48 V) and mid-voltage (60 V, 80 V, and 100 V) motor drive applications. These MOSFET drivers provide full driver capability with extremely fast switching speeds, designed-in ruggedness and low power dissipation. The 200 V driver ICs are offered in standard packages and pinout configurations with various logic input options for high design flexibility and fast time-to-market. Low side supply voltage (V_{cc}) and floating channel supply (V_{BS}) undervoltage lockout (UVLO) ensures reliable start-up operation.

Product portfolio

Part num- ber	Voltage class [V]	Configuration	Channels	Source/sink current typ. [mA]	Deadtime typ. [ns]	Typ. propagation delay [ns]		Control inputs	UVLO typ. [V]	Package	MSL
						on	off				
IRS2008S	200	Half-bridge	2	290/600	520	680	150	IN, SD	+8.9/-8.2	8-lead SOIC	2
IRS2007S	200	Half-bridge	2	290/600	520	160	150	HIN, LIN	+8.9/-8.2	8-lead SOIC	2
IRS2005S	200	High- and low-side	2	290/600	-	160	150	HIN, LIN	+8.9/-8.2	8-lead SOIC	2
IRS2005M	200	High- and low-side	2	290/600	-	160	150	HIN, LIN	+8.9/-8.2	14-lead 4x4 MLPQ	2

IRS2005 replaces IRS2001 (IRS2001 is not recommended for new designs) / IRS2007 can replace IRS2003 / IRS2008 can replace IRS2004

Simplified application diagram





New 600 V half-bridge gate driver with overcurrent protection (OCP)

The new IRS2890DS half-bridge gate driver provides typical 0.22 A source and 0.48 A sink currents in a 14-lead SOIC package for IGBT and MOSFETs. The IRS2890DS integrates overcurrent protection, fault reporting and bootstrap FET.



- › Advanced input filter
- > Deadtime and cross-conduction prevention logic
- Fully operational to +600 V offset voltage
- Logic operational for V_s* of -8 V
- Operational for transient negative VS -50 V with a 50 ns pulse width
- Integrated bootstrap FET
- > Integrated comparator (with 0.5 V ± 5 % reference) for overcurrent protection
- Fault and enable multifunction pin

- Reliable switching Protection under abnormal operation
- Improved reliability
- High power capability
- Easy-to-use, straight-forward design
- Fast time-to-market









*High-side floating well supply offset voltage

WBG semiconductors

Application

20-300 V MOSFETs

500-950 V MOSFETs

Motor control ICs

Non-isolated low-side gate driver ICs

1ED44176N01F - 25 V low-side gate driver with integrated overcurrent protection and fault/enable function

The 1ED44176N01F is a low-voltage, non-inverting gate driver designed for ground-referenced applications such as digitally controlled power-factor correction (PFC) circuits requiring overcurrent protection (OCP). OCP is typically implemented using a current measurement circuit with a comparator such as LM293 and a network of resistors and capacitors. 1ED44176N01F provides up to 20% cost and 50% space savings by integrating the OCP comparator, which features an accurate current-sensing threshold tolerance of ±5%. 1ED44176N01F also integrates fault-output reporting to the controller and driver enable functionality on the same pin. The driver IC also has separate logic and power ground pins for operational robustness.

Product features

- > Overcurrent detection with positive voltage input
- > +0.8 A/-1.75 A output source/sink current capability
- > +0.5 V overcurrent threshold with ±5% tolerance
- > Single pin for fault output and enable function
- > Programmable fault clear time
- > CMOS Schmitt-triggered inputs
- > 3.3 V, 5 V and 15 V input logic-compatible
- > Output in phase with input
- > Separate logic and power ground
- > 2 kV ESD HBM

Potential applications

- General purpose low-side gate driver for single-ended topologies (e.g. digitally controlled PFC or digital power supplies)
- > Residential and commercial air conditioners
- > Home appliances
- Industrial applications



Application note, PSPICE or SiMetrix models, and evaluation board, **EVAL-1ED44176N01F** are available at www.Infineon.com/1ED44176

Key features

- Integrated overcurrent protection comparator with accurate OCP threshold
- > Single pin for fault output and enable function

> Programmable fault clear time

> Low quiescent supply current

> Separate logic ground and gate driver return

> Undervoltage lockout (UVLO) protection

www.Infineon.com/1ED44176

Key specifications

- 0.5 V overcurrent threshold with accurate ±5 percent tolerance
- Internal Schmitt trigger comparator for the enable function
- > External capacitor (C_{FLTC}) sets the length of the fault clear time
- Max I_{QCC}: 750 μA

V_{ss} and COM pins

Specific UVLO level for IGBTs (typ. on/off = 11.9 V / 11.4 V)

System benefit

- Potential space savings up to 50 percent and cost savings up to 20 percent compared to the discrete solution
- Flexible fault clear time set-up for different microcontroller processing speeds
- Minimizes power consumption
- Avoids noise coupling from output to input which improves noise immunity
- Eliminates switching loss at low V_{cc} supply voltage

Simplified application diagram





Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Sate driver ICs

Motor control ICs

EiceDRIVER™ Enhanced gate driver IC family

1200 V galvanically isolated enhanced gate driver ICs



The EiceDRIVER[™] 1ED Enhanced gate driver ICs are galvanic isolated singlechannel IGBT and SiC MOSFET drivers in DSO-16 package that provide output current capabilities of typically 2 A. The precision DESAT function for IGBT is also an excellent solution for SiC MOSFET short-circuit protection. All logic pins are 5 V CMOS compatible. 2ED020I12-F2 is the dual-channel version of 1ED020I12-F2 in DSO-36 package. 2ED020I12-FI is a high voltage, high speed power MOSFET and IGBT driver with interlocking high and low side referenced outputs.

Product features

- Available in wide body package with 8 mm creepage distance
- Suitable for operation at high ambient temperature
- > Active miller clamp
- Short circuit clamping and active shutdown
- > $\geq 100 \text{ kV}/\mu \text{s CMTI}$
- > Precision DESAT protection

EiceDRIVE	R™ Enhanced	1ED020I12-F2	2ED020I12-F2	1ED020I12-FT	1ED020I12-B2	1ED020I12-BT	2ED020I12-FI
Configura	tion	Single	Dual	Single	Single	Single	Half Bridge
Package (all 300 mil)	DSO-16	DSO-36	DSO-16	DSO-16	DSO-16	DSO-18
		A STATE	A CONTRACTOR OF	P. L.	THE STATE	P. C. S.	Continuent Continuent Continuent Continuent
Galvanic i	solation	Functional	Functional	Functional	Basic (VDE 0884-10)	Basic (VDE 0884-10)	Functional on high side
Protectio	n function	DESAT, UVLO	DESAT, UVLO	DESAT, UVLO, two-level turn-off	DESAT, UVLO	DESAT, UVLO, two-level turn-off	UVLO, OPAMP, comparator
UVLO	Input [V]	4.1/3.8	4.1/3.8	4.1/3.8	4.1/3.8	4.1/3.8	12/11
	Output [V]	12/11	12/11	12/11	12/11	12/11	12/11
DESAT ch	arge current [µA]	500	500	500	500	500	-
Bipolar o	itput supply	√	\checkmark	√	√	\checkmark	-
Active mil	ler clamp	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	-
Inverting inputs	and non-inverting	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	-
	ble enable/shutdown feedback signals	√	\checkmark	\checkmark	\checkmark	\checkmark	-
TLSET		-	-	\checkmark	-	\checkmark	-
Typical pr	opagation delay [ns]	170	170	170 + TLTOff	170	170 + TLTOff	85
				Isolation	definitions		
Functiona	lisolation	Isolation between conduc	ctive parts which is necessa	ary only for the proper func	tioning of the equipment		
Basic isol	ation (VDE 0884-10)	Isolation applied to live p	arts to provide basic prote	ction against electric shock	(



www.infineon.com/gatedriver www.infineon.com/gdisolated



s Application

Discrete IGBTs

EiceDRIVER™ 1ED Compact gate driver IC family

1200 V galvanically isolated single-channel gate driver ICs

Infineon's new EiceDRIVER[™] 1EDC Compact 300 mil family is recognized under UL 1577 with an insulation test voltage of V_{ISO} = 2500 V(rms) for 1 min. The functional isolated EiceDRIVER[™] 1EDI Compact 150 mil and 300 mil families are also available. The EiceDRIVER[™] 1ED Compact family is the perfect driver for superjunction MOSFETs such as CoolMOS[™], IGBTs, silicon carbide (SiC) MOSFETs such as CoolSiC[™], and IGBT modules.

Product features

- > Provide DSO-8 300 mil wide body package with 8 mm creepage distance
- > Up to 10 A typical peak rail-to-rail output
- > Suitable for operation at high ambient temperature
- > Separate source and sink outputs or active miller clamp
- > More than 100 kV/µs CMTI
- > Optimized pinout for low inductance power supply



Compact

1EDI Comp	act 150 mil	1EDI60I12AF	1EDI40I12AF	1EDI20I12AF	1EDI05I12AF	1EDI60N12AF	1EDI20N12AF	1EDI30I12MF	1EDI20I12MF	1EDI10I12MF
1EDI Comp	act 300 mil	1EDI60I12AH	1EDI40I12AH	1EDI20I12AH	1EDI05I12AH	1EDI60H12AH	1EDI20H12AH	1EDI30I12MH	1EDI20I12MH	1EDI10I12MH
1EDC Com	pact 300 mil	1EDC60I12AH	1EDC40I12AH	1EDC20I12AH	1EDC05I12AH	1EDC60H12AH	1EDC20H12AH	1EDC30I12MH	1EDC20I12MH	1EDC10I12MH
Typ. outpu	t current [A]	10/-9.4	7.5/-6.8	4/-3.5	1.3/-0.9	10/-9.4	4/-3.5	5.9/-6.2	4.4/-4.1	2.2/-2.3
Output cor	nfiguration	Separate sink/ source outputs	Active Miller clamp	Active Miller clamp	Active Miller clamp					
Typ. propag	gation delay [ns]	300	300	300	300	125	125	300	300	300
UVLO	Input [V]	2.85/2.75	2.85/2.75	2.85/2.75	2.85/2.75	2.85/2.75	2.85/2.75	2.85/2.75	2.85/2.75	2.85/2.75

Simplified application diagram

Separate sink/source outputs



Active Miller clamp





www.infineon.com/gatedriver www.infineon.com/1EDcompact

1200 V single-channel slew-rate control (SRC) gate driver family with reinforced isolation

The new SRC EiceDRIVER[™] family, which includes 1EDS20112SV, 1EDU20112SV, and 1EDI20112SV, is addressing the latest generation of highly efficient low-EMI electric drive systems, with lower EMI and improved efficiency. Based on the Infineon's coreless transformer technology, it is the first high voltage isolated gate driver on the market with dynamic slew-rate control (SRC), which allows on-the-fly dV/dt control of electric drives through precise gate current control, providing the best trade-off between minimum power dissipation and minimum EMI depending on operating conditions.

To turn on the IGBT, the driver works as an adjustable current source in conjunction with an external PMOS transistor and a sense resistor. To turn off the IGBT, the driver uses a 2 A MOSFET output stage. Several important and advanced protection functions are integrated. The driver includes desaturation protection for IGBTs and overcurrent protection for sense IGBTs via the fault status output pin. Two ready-state output pins indicate proper driver power supply level and normal driver operation. Two-level turn-off with adjustable timing and voltage protects against excessive overvoltage in case of the IGBT operating at overcurrent or a short circuit.

The 1EDx20I12SV family is tailored for industrial drive applications such as those using 1200 V power modules for current up to 900 A like the EconoDUAL[™] 3. The driver meets today's long-term stability requirements for industrial applications. It is offered in a DSO-36 package with a package width of 300 mil. It is RoHS compliant, green, and halogen-free.

Product features

- > Real-time adjustable gate current control
- > DESAT
- > Overcurrent protection
- Soft turn-off shut down
- > Two-level turn-off
- > Drive power modules up to 900 A
- > Drive 1200 V single-channel IGBT driver
- Unique: NPC1 short circuit protection for three-level inverters
- Low EMI during low load conditions and high efficiency during high load conditions
- > Reduction or elimination of dV/dt filter

Potential applications

- > AC and brushless DC motor drives
- > High-voltage DC-DC converters
- > UPS systems, servo drives



Part Number	Isolation rating
1EDS20I12SV	Reinforced isolation according VDE 0884-10 (V _{IORM} = 1420 V) and UL 1577 certified with V _{ISO} = 5 kV (rms) for 1 min
1EDU20I12SV	UL 1577 certified with V _{iso} = 5 kV (rms) for 1 min
1EDI20I12SV	Functional isolation

Evaluation board available: EVAL-1EDS20I12SV www.infineon.com/SRC

Motor control ICs

Simplified application diagram



1EDS-SRC driver board with EconoDUAL[™] 3 power module







Evaluation board available: EVAL-1EDS20I12SV www.infineon.com/SRC



I_c [A]

Effect – gate turn-on tunable across a very large dV/dt range:

Discrete IGBTs

Microcontrollers

Packages

Industrial and general purpose gate driver ICs

Infineon's gate driver IC solutions are the expert's choice. With more than 500 reliable and efficient gate driver solutions, we provide a comprehensive portfolio for virtually any application. Addressing various application requirements, Infineon delivers solutions with an assortment of gate driver topologies, voltage classes, drive capability, features and package options to optimize performance, minimize size and reduce cost. Some discrete gate driver ICs are also available in bare die. The table below shows additional gate driver IC features available in the current portfolio.

Features	Abbreviation	Benefits
Active Miller clamp	M-CLAMP	Protection against inadvertent dynamic turn-on because of parasitic Miller effects
Active shutdown	SD-ACT	Ensures a safe IGBT off-state in case the output chip is not connected to the power supply or an undervoltage lockout is in effect
Brake chopper	BRAKE	Integrated brake IGBT driver with protection
Comparator	CMP	General purpose comparator included
Current sense	CS	Senses the motor phase current through an external shunt resistor, converts from analog to digital signal, and transfers the signal to the low side
Dedicated JFET control	JFETDRIVE	Optimized to drive SiC JFET
Desaturation protection	DESAT	Protects the IGBT at short circuit
Enable	EN	Dedicated pin terminates all outputs
Fault reporting	FAULT-RPT	Indicates an overcurrent or undervoltage shutdown has occurred
Fault reset	FAULT-RST	Dedicated pin resets the DESAT-FAULT-state of the chip
High-voltage start-up	HVSTART	Provides easy and fast circuit start-up while enabling low circuit standby losses
Integrated bootstrap diode	BSD	Integrated bootstrap reduces BOM
Operational amplifier	OPAMP	An independent op-amp for current measurement or overcurrent detection
Self-oscillating (oscillator)	OSC	Integrated front end oscillator
Overcurrent protection (ITRIP)	OCP	Ensures safe application operation in case of overcurrent
Overtemperature shutdown	SD-OT	Internal overtemperature protection circuit protects the IC against excessive power loss and overheating
Programmable dead time	DT-PROG	Dead time is programmable with external resistor for flexible design
Programmable fault clear time	FLTC	The length of the fault clear time period (t _{ruc}) is programmed by external capacitor which connected between FLTC and VSS (C _{ruc}).
Programmable shutdown	SD-PROG	A shutdown feature has been designed into a pin
Separate pin for logic ground	SEP-GND	Dedicated pin or logic ground for improved noise immunity
Separate sink/source outputs	SEP-OUT	Simplifies gate resistor selection, reduces BOM, and improves dV/dt control
Shoot-through protection	STP	Additional shoot-through protection logic such as interlock
Short-circuit clamping	SC-CLAMP	During short circuit the IGBT's gate voltage tends to rise because of the feedback via the Miller capacitance. An additional protection circuit
		connected to OUT+ limits this voltage to a value slightly higher than the supply voltage.
Shutdown	SD	Dedicated pin disables the IC outputs
Soft overcurrent shutdown	SD-SOFT	Dedicated pin turns off the desaturated transistor, preventing overvoltages
Truly differential inputs	TDI	$\pm 70V_{bc}$ and $\pm 150V_{Ac}$ ground-shift robustness of low-side gate driver ICs
Two-level turn-off	TLTO	Lowers VCE overshoots at turn-off during short circuits or overcurrent events
UL 1577	UL	Double galvanic isolation certification
Undervoltage lockout	UVLO	Ensures safe application operation by avoiding unexpected driver behavior at low voltages
VDE 0884-10 or VDE 0884-11	VDE	Reinforced galvanic isolation certifications for non-optical couplers

Infineon's industrial and general purpose gate driver ICs utilize the following technologies:

- > (1) Coreless transformer technology (CT)
- > (2) Level-shifting silicon-on-insulator technology (SOI)
- > (3) Level-shifting junction-isolation technology (JI)
 - > (4) Non-isolated technology (N-ISO)

Infineon gate driver IC technologies



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XENSIVTM sensors

Product overview

To ease the selection process, this overview is structured along the configurations of the gate driver ICs, as opposed to by application topology.

	cation top	ology.				_								_		_		_		_			_		_		_	
Half-b	ridge gat	te driver l	ICs										Aircon		tome Appli				Drive			introl 5	Power	Tools	s, III	l#		2COM
Voltage class [V]	ام،/ _{انه} . typ. [mA]	UVLO on/off typ. [V]	Prop delay off/on typ. [ns]	Base PN	Technology	Comparator	Operational amplifier	Desaturation protection	Enable	Fault reporting			Programmable dead time		Self-oscillating (oscillator)	Schoot through protection	Shutdown	Soft overcurrent shutdown	DSO-8	DS0-14	DSO-16		Pac		6 DIP-14	VDSON-8	VQFN-14	CHIP1
_	1500/2500	12.2/11.2	85/85	2ED020I12-FI	⊢ CT	√	1										′ 🗸	1					\checkmark					
1200	2000/3000	10.2/9.3	440/440	IR2214	JI	V	v	\checkmark		\checkmark								\checkmark					v		V	'		
650	2500/2500	9.1/8.2	200/200	2ED2182S06* 2ED21824S06* 2ED2183S06* 2ED21834S06* 2ED2184S06* 2ED2184S06* 2ED2184S06*	SOI SOI SOI SOI SOI SOI SOI SOI								√ √ √		\ \				√ √ √ √	√ √ √								✓ ✓ ✓ ✓ ✓ ✓ ✓ ✓
650	290/700	9.1/8.3	300/310	2ED2108S06* 2ED21084S06* 2ED2109S06* 2ED21094S06* 2ED21091S06* 2ED2304S06F NEW	SOI SOI SOI SOI SOI								√ √ √			 <	/ \ / \ / \ / \		√ √ √ √	✓ ✓ ✓								 ✓
	1500/2500	12.2/11.2	85/85	2ED020I06-FI	СТ											V	′ √						\checkmark					
	78/169	8.9/8.2	220/220	IR2304	JI											√			\checkmark				,	/		_	_	
	180/260	8.9/8.2 9/8 9/8 9/8 11/9	N.A.	IR25601 IR21531 IR21531D IR25603 IRS2153(1)D	JI JI JI JI JI						√ √ √			√ · √ ·			′√ ′√		✓ ✓ ✓ ✓				,					✓
	200/350	8.9/8.2	200/220	IR2108 IR21084 IR2308 IR25606 IR2109 IR21091 IR21091 IR21094	 														√ √ √ √	√ √ 1			,					
		4.1/3.8		IR2302	JI							-	V		·				\checkmark	\checkmark		-	+			+-	-	
	210/360	8.9/8.2 8.9/8.2 8.9/8.2	150/680	IR2103 IR2104 IR25602	JI JI JI					_							/ / _/ / _/		✓ ✓ ✓				,					
	220/480 250/500	8.9/7.7 8.6/8.2	500/500 150/750	IRS2890D NEW IR2111	JI					\checkmark	√ ·	\checkmark							\checkmark	\checkmark				/				
600		8.9/8.2	150/150	IRS2304	JI											V			\checkmark					/				\checkmark
600		8.9/8.2 8.9/8.2 8.6/8.2	150/680 150/750	IRS2103 IRS2104 IRS2111	JI JI JI												′ √ ′		√ √ √				\ \ \					✓ ✓ ✓
	290/600	8.9/8.2 8.9/8.2 8.9/8.2 8.9/8.2	200/220	IRS2(1,3)08 IRS21084 IRS2109 IRS21091	JI JI JI JI								√ √		\ \		′ ′√		✓ ✓ ✓	√			,		/			✓ ✓
		8.9/8.2	,	IRS21094	JI								√				′ √			\checkmark					/			
	360/700	9.1/8.3 12.5/11.6 8.9/8.2	300/310 400/420	2EDL05N06P 2EDL05I06P IRS2183	SOI SOI JI						√ √					v v	/ /		√ √ √	√ √								✓
	1900/2300	8.9/8.2 8.9/8.2 8.9/8.2 8.9/8.2 8.9/8.2	220/180	IR2183 IR(S)21834 IRS2184 IR2184	JI JI JI JI								✓		\ \		/ / / / /		✓ ✓ ✓	✓ ✓			,	/	/			✓ ✓
	2000/3000	8.9/8.2 8.9/8.2 10.2/9.3	440/440	IR21844 IRS21844 IR2114	JI JI JI			√		√			√ √		\ \					✓ ✓			-		/ / /	/	√	
	2300/2800	9.1/8.3	300/310	2EDL23N06P	SOI						\checkmark					/ /	'			\checkmark								
200	290/600	12.5/11.6 8.9/8.2	400/420 150/160	2EDL23I06P IRS2007 NEW	SOI JI				√	✓	√ _	✓					'		\checkmark	√ 			+			+	✓ ✓	
120	2000/6000 3000/6000 4000/6000	7/6.5	150/680 47/47	IRS2008 NEW 2EDL8112* 2EDL8113* 2EDL8114*	JI JI JI JI						√ √ √						·		✓ 							√ √ √	·	

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20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

Three-	phase gate	driver ICs							Aircon		tome Appl	liance		tion		ives		Control	Por			Solar		Teleco	
Voltage class [V]	l _{o-//o-} typ. [mA]	UVLO on/off typ. [V]	Prop delay off/on typ. [ns]	Base PN	Technology	Brake chopper	Operaltional amplifier	Desaturation protection	Enable	Fault reporting	Integrated bootstrap diode	Overcurrent protection	Programmable dead time	Separate pin tor logic ground	Shoot-through protection	Shutdown	DSO-20 WB DSO-24	DSO-28 WB		LCC-32		_	VQFN-28	VQFN-34	CHIP1
					Tech					Fea	ture	es								Pac	kag	ge			
	350/650	11.4/10.4	600/600	6ED2230S12*	SOI				\checkmark	\checkmark	\checkmark	\checkmark	\checkmark		\checkmark		\checkmark								
1200	250/500	8.6/8.2	700/750	IR2233	JI		\checkmark			\checkmark		\checkmark		\checkmark	\ \	1		\checkmark	\checkmark	\checkmark					\checkmark
1200	230/300	10.4/9.4	100/150	IR2235	JI		\checkmark			\checkmark		\checkmark		/	\	/		\checkmark	\checkmark	\checkmark					
	350/540	11.2/10.2	550/550	IR2238	JI	\checkmark		\checkmark		\checkmark		\checkmark		\checkmark	, N	1					\checkmark				
		11.7/9.8	490/530	6ED003L06-F2	SOI				\checkmark	\checkmark		\checkmark		\checkmark				\checkmark							\checkmark
	165/375	11.7/9.8	490/330	6EDL04I06(N,P)	SOI				\checkmark	\checkmark	\checkmark	\checkmark		\checkmark				\checkmark							\checkmark
		9/8.1	530/530	6EDL04N06P	SOI				\checkmark	\checkmark	\checkmark	\checkmark		\checkmark				\checkmark							\checkmark
		8.9/8.2		IR2136	JI				\checkmark	\checkmark		\checkmark		\checkmark				\checkmark	\checkmark	\checkmark					\checkmark
		11.1/10.9	400/425	IR21363	JI				\checkmark	\checkmark		\checkmark		\checkmark				\checkmark		\checkmark					\checkmark
		11.1/10.9	400/425	IR21365	JI				\checkmark	\checkmark		\checkmark		\checkmark				\checkmark							
		8.9/8.2		IR21368	JI				\checkmark	\checkmark		\checkmark		\checkmark				\checkmark							\checkmark
	200/250	10.4/9.4	530/500	IR21364	JI				\checkmark	\checkmark		\checkmark		1				\checkmark							\checkmark
600	200/350	11.1/10.9		IRS2334	JI												/						\checkmark		
		8.9/8.2		IRS2336	JI				\checkmark	\checkmark		\checkmark		/				\checkmark		\checkmark					
		8.9/8.2	530/530	IRS2336D	JI				\checkmark	\checkmark	\checkmark	\checkmark		/				\checkmark		\checkmark			\checkmark		\checkmark
		8.9/8.2		IRS23364D	JI				\checkmark	\checkmark	\checkmark	\checkmark		1				\checkmark		\checkmark					\checkmark
		8.9/8.2		IRS23365D	JI				\checkmark	\checkmark	\checkmark	\checkmark		/										\checkmark	
		9/8.7	425/675	IR213(0,2)	JI		\checkmark			\checkmark		\checkmark		1				\checkmark	\checkmark	\checkmark					\checkmark
	050/500	8.7/8.3	600/1300	IR2131	JI					\checkmark		\checkmark	_	/	,	1		1	\checkmark	\checkmark					
	250/500	8.6/8.2	700/756	IR2133	JI		\checkmark			\checkmark		\checkmark		/	,	1		\checkmark	\checkmark	\checkmark					
		10.4/9.4	700/750	IR2135	JI		\checkmark			\checkmark	_	\checkmark	_	/		1		√		\checkmark					\checkmark
200	1.05/075	11.7/9.8	490/530	6ED003L02-F2	SOI				\checkmark	\checkmark		\checkmark		1								\checkmark			
200	165/375	9/8.1	530/530	6EDL04N02P	SOI				\checkmark	\checkmark	\checkmark	\checkmark		/								\checkmark			

Packages

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* Coming soon

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Single	high-sid	e gate dri	ver ICs							Ajrcon			ation	-	Drives		گ	ntrol	E	Solar		Teleco	m •• ••) 1		telding	
Voltage class [V]	l _{ο+/io-} typ. [mA]	UVLO on/off typ. [V]	Prop delay off/on typ. [ns]	Base PN	Technology	Active Miller clamp	Dedicated control for JFET	Desaturation protection	Enable	Fault reporting	Fault reset	Overcurrent protection	Separate pin for logic ground	Separate sink/source outputs	Soft overcurrent shutdown	I wo-level turn-off	UL 1577	VDE 0884-10	DSO-8	DSO-8 300mil	DSO-16	DSO-16 WB	DSO-19	DSO-36	DIP-8	SOT23-6 TELGA-12	LI LUGA-13	CUIP-
					Techr						Fea	atur	es									P	Pack	age	•			
	1300/900	12/11.1	300/300	1EDI05I12A	СТ								-	√					\checkmark	√ ,						\square	T	
				1EDC05I12AH NEW	-			,			/		\checkmark	\checkmark		-	\checkmark			\checkmark		/			-	+	+	-
			165/170	1ED020I12-F2 1ED020I12-B2	CT CT	√ √		✓ ✓		√ √	\checkmark	-	\checkmark				√ ·	\checkmark				√ √				+	+	_
	2000/2000	12/11		1ED020112-B2	CT	√ √	-	✓ ✓		√ √	✓ ✓	_	√ √			/	V .	V				✓ ✓				+	+	-
			1750/1750	1ED020I12-PT	СТ	√	-	√		√	√		√		_	-	√ ·	\checkmark				√						
				1EDI10I12M	СТ	√		V		v	V	_	v √		,	/	V	v	\checkmark	\checkmark		v				-	-	-
	2200/2300	12/11.1	300/300	1EDC10I12M	_	√							√				\checkmark			√								
		9.1/8.5	120/115	1EDI20N12A	СТ	, ·	-							\checkmark			•		\checkmark	-						-	-	-
				1EDI20H12A	СТ									\checkmark						\checkmark								
	4000/3500		125/120	1EDC20H12A NEW	_								_	\checkmark			\checkmark			\checkmark						T	T	
				1EDI20I12A	СТ								\checkmark	\checkmark					\checkmark	\checkmark								
		12/11.1	200/200	1EDC20I12A NEW	СТ									\checkmark			\checkmark			\checkmark								
1200	4400/4100		300/300	1EDI20I12M	СТ	\checkmark							\checkmark						\checkmark	\checkmark								
	4400/4100			1EDC20I12M NEW	СТ	\checkmark							\checkmark				\checkmark			\checkmark								
	4000/4000	16.9/16.4	80/80	1EDI30J12C	CT		\checkmark		\checkmark														\checkmark					
	5900/6200			1EDI30I12M	СТ	\checkmark							\checkmark						\checkmark	\checkmark								
	3900/0200	12/11.1	300/300	1EDC30I12M NEW	СТ	\checkmark							\checkmark				\checkmark			\checkmark								
	7500/6800	12/11.1	300/300	1EDI40I12A	СТ								\checkmark	\checkmark					\checkmark	\checkmark								
	1500/0800			1EDC40I12A NEW									\checkmark	\checkmark			\checkmark			\checkmark								
	SRC/2000	11.9/11	460/460	1EDI20I12SV NEW				\checkmark	\checkmark	\checkmark			\checkmark	_		/								\checkmark				
	SRC/2000	11.9/11	460/460	1EDU20I12SV NEW	СТ			\checkmark	\checkmark	\checkmark			\checkmark			1	\checkmark							\checkmark				
	SRC/2000	11.9/11	460/460	1EDS20I12SV NEW				\checkmark	\checkmark	\checkmark		\checkmark	\checkmark	-	√ \	/	√ ·	\checkmark						\checkmark				
			125/120	1EDI60H12A	СТ								_	\checkmark					\checkmark	\checkmark								
	10000/9400	12/11.1	120/120	1EDC60H12A NEW	_					_	_		-	\checkmark			\checkmark							_		_		
		,	300/300	1EDI60I12A	СТ								\checkmark	\checkmark					\checkmark	\checkmark						_	-	
	100/040	0.12		1EDC60I12A NEW	_								\checkmark	\checkmark			√			\checkmark						,	-	_
	160/240	9/8	215/140	IRS25752	JI											-			,						_		+	
		8.6/8.2	105/125	IR2117	JI														√ /					_	√ ∕		√	-
	250/500	10.2/0		IR2118	JI							,				-			√					_	✓ ✓	_	-	,
600		10.3/9	150/200	IR212(7,8)	JI	_	-			\checkmark	_		_	_	_	-	-	-	√ /			_	_		√ /		√	-
		7.2/6.8		IR21271 IRS211(7,8)	JI		-			\checkmark		\checkmark	-	-		+	-	-	✓ ✓			-	-	_	✓ ✓	+	+	/
	290/600	8.6/8.2	105/125	IRS211(7,8) IRS2127	JI					\checkmark		\checkmark						-	√ √					-	√ √	+	√ √	_
	250/600	10.3/9 7.2/6.8	150/150	IRS2127	JI			✓		√ √	_	✓ ✓				+			✓ ✓					_	√ √	+		-
500	1600/3300	9.2/8.3	200/170	IR2125	JI			V		√	-	✓							v			\checkmark		-	√ √		-	
200	1000/3300		200/170	IRS20752	JI	-	-			v		v	-	-	-	+		-				V	-	-			-	-
100	160/240	9/8	215/140	IRS10752	JI																					v V		-
100	4000/8000	4.5/5.0	41/37	1EDS5663H NEW								-				+	√ ·	\checkmark				\checkmark			-	-	-	-
650	4000/8000	4.5/5.0	41/37	1EDF5673F NEW	-												v .	v			\checkmark	v				+		-
250	4000/8000	4.5/5.0	41/37	1EDF5673K NEW																						- v	-	
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20-300 V MOSFETs

500-950 V MOSFETs

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Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

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SRC=Turn on slew rate control 1) Please contact sales team for additional information

Dual high	n-side/h	alf-bridge					Aircor		Driv				E	Solar		Telecor			
Voltage class [V]	l₀./ı₀. typ. [mA]	UVLO on/off typ. [V]	Prop delay off/on typ. [ns]	Base PN		Technology	Active Miller clamp	Deadtime control	Desaturation protection	Disable	Fault reporting	Fault reset	Separate pin for logic ground	UL 1577	VDE 0884-10	DSO-16	DSO-16 WB	DSO-36 (w/o 4 pins)	TFLGA-13
						Tech				Fe	atu	res					Pack	kage	
1200	2000/2000	12/11	165/170	2ED020I12-F2		СТ	\checkmark		\checkmark		\checkmark	\checkmark	\checkmark					\checkmark	
	4000/8000	4.2/3.9		2EDF7275F	NEW	СТ				\checkmark						\checkmark			
650	1000/2000	4.2/3.9		2EDF7175F	NEW	СТ				\checkmark						\checkmark			
050	4000/8000	8/7	37 / 37	2EDS8265H	NEW	СТ				\checkmark				\checkmark	\checkmark		\checkmark		
	1000/2000	0/1	31/31	2EDS8165H	NEW	СТ				\checkmark				\checkmark	\checkmark		\checkmark		
250	4000/8000	4.2/3.9		2EDF7235K	NEW	СТ				\checkmark									\checkmark
250	4000/8000	4.2/3.9		2EDF7275K	NEW	СТ		\checkmark		\checkmark							ιT		\checkmark

| Single low-side gate driver ICs | | | | | | |
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| | typ. | off/on typ. | Base PN | | ology | Automatic minimum on time protection | Enable
 | Fault reporting

 | Overcurrent protection
 | Programmable fault clear time | Programmable minimum on time

 | Separate sink/source outputs | Synchronous rectification
 | Truly differential inputs | DSO-8 | DIP-8 | SOT23-5
 | SOT23-6 |
| | | | | | Techn | |
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 | atur | es

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 | e |
| 1000/4000 | 10.55/9 | 50/60 | IR11662 | | N-ISO | \checkmark | \checkmark
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| 2000/7000 | 10.55/9 | 50/60 | IR11672A | | N-ISO | \checkmark | \checkmark
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| 1000/2500 | 4.5/4.4 | 50/50 | IR1161 | | N-ISO | \checkmark |
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| 4000/8000 | 4.2/3.9 | 45 / 45 | 1EDN7550 | NEW | N-ISO | |
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| 1000/0000 | 8/7 | 45 / 45 | 1EDN8550 | NEW | N-ISO | |
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 | \checkmark |
| 800/1750 | 11.9/11.4 | 50/50 | 1ED44176N01F | NEW | N-ISO | | \checkmark
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| 1500/1500 | 10.2/9.2 | 50/50 | IRS44273 | | | |
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| 300/550 | 5/4.15 | 50/50 | IR44252 | | N-ISO | |
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| 1700/1500 | 5/4.15 | 50/50 | IR44272 | | N-ISO | | \checkmark
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300/550 | 1000/4000 10.55/9 2000/7000 10.55/9 1000/2500 4.5/4.4 4000/8000 8/7 800/1750 11.9/11.4 1500/1500 10.2/9.2 300/550 5/4.15 1700/1500 5/4.15 | 1000/4000 10.55/9 50/60 2000/7000 10.55/9 50/60 1000/2500 4.5/4.4 50/50 4000/8000 4.2/3.9 45/45 800/1750 11.9/11.4 50/50 1500/1500 10.2/9.2 50/50 300/550 5/4.15 50/50 1700/1500 5/4.15 50/50 | 1000/4000 10.55/9 50/60 IR11662 2000/7000 10.55/9 50/60 IR11672A 1000/2500 4.5/4.4 50/50 IR1161 4000/8000 4.2/3.9 45/45 1EDN7550 800/1750 11.9/11.4 50/50 IR1461 1500/1500 10.2/9.2 50/50 IR14273 300/550 5/4.15 50/50 IR44273 1700/1500 5/4.15 50/50 IR44273 | 1000/400010.55/950/60IR116622000/700010.55/950/60IR11672A1000/25004.5/4.450/50IR11614000/80004.2/3.945/45IEDN7550800/175011.9/11.450/50IEDN7550800/175011.9/11.450/50IEDN8550800/175010.2/9.250/50IR34273300/5505/4.1550/50IR442521700/15005/4.1550/50IR442721700/15005/4.1550/50IR44273 | 1000/400010.55/950/60IR11662N-ISO1000/400010.55/950/60IR11672AN-ISO2000/700010.55/950/60IR11672AN-ISO1000/25004.5/4.450/50IR1161N-ISO4000/80004.2/3.945/45IEDN7550NISO800/175011.9/11.450/50IEDN4550N-ISO800/175011.9/11.450/50IEDN4550N-ISO1500/150010.2/9.250/50IR44273N-ISO300/5505/4.1550/50IR44273N-ISO1700/15005/4.1530/50IR44272N-ISO1700/15005/4.1530/50IR44273N-ISO1700/15005/4.1530/50IR44273N-ISO1700/15005/4.1530/50IR44273N-ISO1700/15005/4.1530/50IR44273N-ISO1700/15005/4.1530/50IR44273N-ISO | Interface Interface <thinterface< th=""> <thinterface< th=""> <thi< td=""><td>Interface Interface <t< td=""><td>Interface Interface <t< td=""><td>International system International system Internati</td><td>Interface Interface <t< td=""><td>Index Solution Relation Solution <t< td=""><td>$\frac{1}{1000/4000} = \frac{1}{10.55/9} = \frac{50/60}{50/60} = \frac{1}{11672A} + \frac{1}{160} + \frac{1}{160$</td><td>Index Relation <t< td=""><td>IndexImage: Partial problemImage: Partial problemImage: Partial 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20-300 V MOSFETs

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ltage class [V]	l _{o-//o-} typ. [mA]	UVLO on/off typ. [V]	Prop delay off/on typ. [ns]	Base PN	ology	Integrated bootstrap diode	Separate pin for logic ground	Shutdown	DSO-8	DSO-14	DSO-16 WB	DIP-8	DIP-14	VQFN-14
					Technology	F	eatur	es			Ра	ckag	je	
1200	2000/2500	10.2/9.3	225/280	IR2213	JI		\checkmark	\checkmark			\checkmark		\checkmark	
	290/700			2ED2106S06*	SOI	\checkmark			\checkmark					
650	250/100	91/92	200/200	2ED21064S06*	SOI	\checkmark				\checkmark				
050	2500/2500	5.1/0.2	200/200	2ED2181S06*	SOI	\checkmark			\checkmark					
650 9.1/8.2 200/200 2ED2181S06* 2500/2500 8.9/8.2 2ED21814S06* 200/350 8.9/8.2 IR21064 200/350 4.1/3.8 200/200 IR2301 200/200 8.9/8.2 IR2301 IR25604 210/360 8.9/8.2 150/160 IR2101 1R2102 150/160 IR2101 IR2102	SOI	\checkmark				\checkmark								
			JI				\checkmark			\checkmark				
		8.9/8.2			JI		\checkmark			\checkmark			\checkmark	
	200/350	4.1/3.8	200/220	IR2301	JI				\checkmark			\checkmark		
		8.9/8.2		IR25604	JI				\checkmark					
		4.1/3.8		IRS2301	JI				\checkmark					
210/360 8.9/8.2 150/160 IR2102 250/500 8.6/8.2 105/125 IR2112 8.6/8.2 130/135 IRS2112		IR2101	JI				\checkmark			\checkmark				
	210/300	0.5/0.2	150/100	IR2102	JI				\checkmark			\checkmark		
	250/500	8.6/8.2	105/125	IR2112	JI			\checkmark			\checkmark		\checkmark	
		8.6/8.2	130/135	IRS2112	JI		\checkmark	\checkmark			\checkmark		\checkmark	
	200/600	8.9/8.2	150/160	IRS2101	JI				\checkmark			\checkmark		
600	290/600	8.9/8.2	200/220	IRS2106	JI				\checkmark			\checkmark		
		8.9/8.2	200/220	IRS21064	JI		\checkmark			\checkmark			\checkmark	
	360/700	12.5/11.6	400/420	2EDL05I06BF	SOI	\checkmark			\checkmark					
		8.9/8.2		IRS2181	JI				\checkmark			\checkmark		
8.9/8.2 150/160 IRS2101 600 8.9/8.2 200/220 IRS2106 360/700 12.5/11.6 400/420 2EDL05106BF	220/180	IR2181	JI				\checkmark			\checkmark				
	JI		\checkmark			\checkmark			\checkmark					
		8.9/8.2		IRS21814	JI		\checkmark			\checkmark			\checkmark	\checkmark
		8.6/8.2	94/120	IR2113	JI		\checkmark	\checkmark			\checkmark		\checkmark	
	2500/2500	8.6/8.2	54/120	IR25607	JI		\checkmark	\checkmark			\checkmark			
		8.5/8.2	120/130	IRS2113	JI		\checkmark	\checkmark			\checkmark		√ v	\checkmark
		8.9/8.2		IRS2186	JI				\checkmark			\checkmark		
	4000/4000	8.9/8.2	170/170	IRS21864	JI		\checkmark			\checkmark			\checkmark	
		6/5.5		IRS21867	JI				\checkmark					
500	2500/2500	8.6/8.2	94/120	IR2110	JI		\checkmark	\checkmark			\checkmark		\checkmark	
500	2500/2500	8.5/8.2	120/130	IRS2110	JI		\checkmark	\checkmark			\checkmark		\checkmark	
	290/600	8.9/8.2	150/160	IRS2005 NEW	JI				\checkmark				,	\checkmark
200	1000/1000	9/8.2	60/60	IRS2011	JI				\checkmark			\checkmark		
200	1000/1000	9/8.2	75/80	IR2011	JI				\checkmark			\checkmark		
	3000/3000	8.6/8.2	65/95	IR2010	JI		\checkmark	\checkmark			\checkmark		\checkmark	

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Gate driver ICs

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Microcontrollers

Packages



													_
ltage class [V]	l _{or} / _{lo.} typ. [mA]	UVLO on/off typ. [V]	Prop delay off/on typ. [ns]	Base PN	Technology	Automatic minimum on time protection	Enable	Programmable minimum on time	Synchronous rectification	DSO-8	DIP-8	WSON-8	
							Feat	tures			Pac	kage	•
	1000/4000	8.1/7.6	70/60	IR1168	N-ISO	\checkmark			\checkmark	\checkmark			_
200	1000/4000	8.1/7.6	80/100	IR11682	N-ISO	\checkmark			\checkmark	\checkmark			4
	1000/4000	4.55/4.35	60/250	IR11688	N-ISO	\checkmark		\checkmark	\checkmark	√			+
		10.2/9.2		IRS44262	N-ISO					\checkmark			4
			50/50	IRS4426	N-ISO					\checkmark			+
25	2300/3300	N.A.		IRS4427	N-ISO					\checkmark	\checkmark	<u> </u>	4
			65/85	IR25600	N-ISO					\checkmark	\checkmark		+
				IR442(6,7)	N-ISO					\checkmark	\checkmark	_	4
20	5000/5000	4.2/3.9 8/7	19/19	2EDN752(3,4) 2EDN852(3,4)	N-ISO N-ISO		\checkmark			\checkmark		\checkmark	+

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Gate driver selection tool

To simplify the gate driver selection process, Infineon offers an online easy-to-use gate driver selection tool. By selecting a few key parameters, the tool quickly guides you in finding the right driver for your application.

Scan to find the right driver



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For recommended gate drivers by application, visit www.infineon.com/gdapplication to download the PDF version of the gate driver application matrix.



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XENSIVTM sensors



20-300 V MOSFETs 500-950 V MOSFETs

imotion™

Flexible and scalable platform for motor control solutions

iMOTION™ products are highly integrated devices used to control variable speed drives. By integrating both the required hardware and algorithms to perform control of permanent magnet synchronous motors (PMSM), they provide the shortest time to market for inverterized motor systems at the lowest system and development cost.

Key features

- > Ready-to-use and field-proven motor control solution
- > Various integration levels from motor controller to SmartIPM
- > Multiple integrated protection features
- > Functional safety acc. IEC/UL 60335-1 supported

Key benefits

- > Easy to use no motor control coding required
- > High performance and energy optimized solution
- > Reduced cost of ownership due to R&D and BOM savings
- > Fastest time to market

iMOTION™ product offering

Our markets

- > Air conditioners
- › Home appliances
- Fans >
- > Pumps
- > Cooling compressors
- > Motor control



iMOTION[™] ecosystem

PC tools and evaluation kits available to configure, test and fine-tune the drive inverter.

MCEWizard

SW tool to generate initial drive control parameters

MCEDesigner

SW tool to test, monitor and fine-tune the motor drive - including trace features for live monitoring the drive status

www.infineon.com/iMOTION www.infineon.com/iMOTION-software

iMOTION[™] Link

Isolated debug interface to iMOTION[™] devices

iMOTION[™] MADK Platform

Modular and scalable application kit platform for variable speed drives

Tools and software

Get the necessary software here:


iMOTION™ Modular Application Design Kit

Infineon's motor control evaluation platform

The iMOTION[™] modular application design kit (MADK) evaluation platform covers motor drive applications up to 2 kW. The platform offers a modular and scalable system solution with different control board options and a wide range of power boards. While the M1 platform provides control of a permanent magnet synchronous motor (PMSM), the M3 platform also integrates the power factor correction (PFC) implemented as a boost or totem pole PFC.

Using the iMOTION[™] MADK standardized platform interface, different control and power boards can be combined in a system that perfectly matches the requirements of the application. This modular approach allows developers the maximum flexibility and scalability during evaluation and development phase at affordable cost.

Get a motor running in less than an hour!

	Motor con	itrol boards		Wide range of	power boards
	EVAL-M1-101T IMC101T-T038 Control card			EVAL-M1-36-84A CIPOS™ Nano-power board IRSM836-084MA ~110 V/80 W	
	EVAL-M1-099M IRMCK099 Control card			EVAL-M1-05F310 CIPOS™ Nano-power board IRSM005-310MH -100 V/300 W	
ΠM	EVAL-M1-183 IRMCF183 Control card		M1	EVAL-M1-IM818-A CIPOS™-Maxi power board IM818-MCC -1200 V/2600 W	
	EVAL-M1-101TH IMC101T-F048 Control card				
	Motor + PFC	control boards		Power boar	ds with PFC
	EVAL-M3-102T IMC102T-F064 Control card		3	EVAL-M3-CM615PN CIPOS™ mini with boost PFC IFCM15S60GD ~220 V/800 W	
M3	EVAL-M3-302 IMC302A-F064 Control card		M3	EVAL-M3-CM615TN CIPOS™ mini with totem pole PFC IKCM15H60GA ~220 V/800 W	

www.infineon.com/iMOTION www.infineon.com/MADK



Application

Packages

ХМС™

One microcontroller platform - countless solutions

Infineon's XMCTM 32-bit industrial microcontroller portfolio is designed for efficiency and demanding industrial applications.

XMC[™] MCU portfolio

- > RAM: 8 kB up to 352 kB
- > Flash: 16 kB up to 2 MB
- Accurate analog mixed-signal > peripherals
- > Fast timer/PMW peripherals
- **Rich communication interfaces** >

> 16-pin to 196-pin count packages

XMC1000 family

- > ARM[®] Cortex[®]-M0 up to 48 MHz
- Peripherals up to 96 MHz >
- One-time event request unit (ERU) >
- > V_{DD}: 1.8 to 5.5 V
- > T_{Ambient}: -40°C to 105°C

XMC4000 family

- > ARM[®] Cortex[®]-M4 up to 144 MHz
- Built-in DSP, SFPU >
- Peripherals up to 144 MHz >
- > Event request unit (ERU)
- > T_{Ambient}: -40°C to 125°C



XMC1400

SMPS control,

connectivity VQFN-40/64

LQFP-64

XMC1300

SMPS control,

connectivity, TSSOP-16/38

VQFN-24/40

Digital power

XMC1400

Flicker-free,

4-Ch LED, SMPS

connectivity

VQFN-40/64

LQFP-64

XMC1200, XMC1300

Flicker-free,

4-Ch LED, SMPS,

connectivity TSSOP-16/28/38

VOFN-24, -40

LED lighting

LFBGA-144

XMC1400 Hall and encoder I/F, MATH co-processor, CAN VQFN-40/64 LQFP-64

XMC1300 Hall and encoder I/F, MATH co-processor, TSSOP-16/38 . VQFN-24/40

Motor control

Industrial I/O

XMC1400

Multi CAN - 2 nodes

VQFN-48/64 LQFP-64

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

www.infineon.com/xmc

XMC1000

ARM[®] Cortex[®]-M0

up to 48 MHz core/ 96 MHz peripheral 8-200 KB flash

up to 105°C

. 1.8-5.5 V

XMC1100

Basic control and

connectivity TSSOP-16/38

VQFN-24/40

XMC[™] entry

S

Motor control

Microcontrollers

Power ICs

20-300 V MOSFETs

Packages



XMC[™] ecosystem, enablement and partners

A comprehensive set of tools, products, components, and services are available for fast and efficient design with XMC™ microcontrollers.

Infineon enablement for XMC[™] MCUs

- > DAVE[™] www.infineon.com/dave
 Professional and free-of-charge development platform —
- > XMC[™] library for Embedded Coder[®] www.infineon.com/matlab Model-based design from MATLAB[®] and Simulink[®] environment, download free of charge
- > IEC60730 class B library for XMC[™] www.infineon.com/iec60730 Available for XMC[™] industrial microcontrollers free of charge
- > Microcontroller/Probe[™] XMC[™] www.infineon.com/ucprobexmc Free-of-charge version of microcontroller/Probe[™] for XMC[™] MCUs to build user interfaces for visualizing, observing, and control of the internals of XMC[™] MCUs
- XMC[™] link www.infineon.com/xmclink Functional isolated debug probe, based on SEGGER J-Link technology

In addition to a rich third party ecosystem and enablement landscape, which support the entire development cycle from evaluation to production.

For more www.infineon.com/xmc-ecosystem





Infineon's XMC[™] 32-bit industrial microcontroller portfolio is designed for system cost and efficiency for demanding industrial applications. It comes with the most advanced peripheral set in the industry. Fast and largely autonomous peripherals can be configured to support individual needs.

Highlights include analog mixed-signal, timer/PWM and communication peripherals powered by either an ARM[®] Cortex[®]-M0 core (XMC1000 family) or a Cortex[®]-M4 core with a floating point unit (XMC4000 family).

		Clo	ocks	Me	mory		Analog	ç.		Time	/PWM		Conne	ectivity	Package
ARM® Cortex®-M0	Co-processor	Frequency	Peripherals			ADC1 2-bit/S&H	Number of channels	Analog comparators	CCU4 (4 ch)	CCU8 (4 ch)	POS IF	BCCU	US IC	CAN 2.0B	
XMC11x	IC11x - 32		64	Flash RAM			Up to 12	-	lx	-	-	-	2x	-	VQFN 24/40 TSSOP 16/38
XMC12x	-	32	64	Flash RAM	16-200 kB 16 kB	1/2	Up to 12	Up to 3	lx	-	-	1x	2x	-	VQFN 24/40 TSSOP 16/28/38
XMC13x	đ	32	64	Flash RAM	8-200 kB 16 kB	1/2	Up to 12	Up to 3	lx	1x	1x	1x	2x	-	VQFN 24/40 TSSOP 16/38
XMC14x	Ø	48	96	Flash RAM	32-200 kB 16 kB	1/2	Up to 12	Up to 4	2x	2x	2x	1x	4x	Up to 2	VQFN 40/48/64 LQFP 64
						Suppl	y voltage	range 1.8	-5.5 V						
					Te	mperatu	ire range	-40°C 8	5°C/105	°C					

		Ме	mory		Analog			Tir	mer/PV	٧М			Conn	ectivity	/		Package				
ARM® Cortex®-M0	Frequency [MHz]							ADC1 2-bit/S&H	Number of channels	DAC1 2-bit	CCU4 (4 ch)	CCU8 (4 ch)	HRPWM (150 ps)	POSIF	Σ Demodulator	US IC	CAN 2.0B	USB	Ethernet	EtherCAT®	
XMC41x	80	Flash	64-128 kB	2/2	Up to 9	2 ch	2x	1x	1x	1x	_	4x	Up to 2	-	_	_	VQFN 48				
		RAM	20 kB	2/2	00103	2 011	27	17	17	17		47	00102	_	_	_	TQFP 64				
XMC42x	80	Flash	2		256 kB 2/2		Up to 9	2 ch	2x	1x	4 ch	1x		4x	2x	1x	-		VQFN 48		
	80	RAM	40 kB	2/2	00109	2 011	28	17	4 01	17	-	47	24	14		-	TQFP 64				
XMC43x	144	Flash	256 kB	2/2	Up to 14	2 ch	2x	1x				4.4	2x	1x	1.,	1.	LQFP 100				
	144	RAM	128 kB	2/2	Up to 14	2 Ch	ZX	IX	-	-	-	4x	ZX	IX	1x	1x	LQFP 100				
XMC44x	120	Flash	256-512 kB	4/4	Up to 18	2 ch	4x	2x	4 ch	2x	4ch	4x	2x	1x	1		TQFP 64				
	120	RAM	80 kB	4/4		2 01	4X	ZX	4 Ch	28	400	1 4X	2X	IX	1x	-	LQFP 100				
XMC45x	100	Flash	512 MB		11	2.1				-			11-1-2				LQFP 100/144				
	120	RAM	128-160 kB	4/4	Up to 26	2 ch	4x	2x	-	2x	4 ch	4x	Up to 3	1x	1x	-	LFBGA 144				
XMC47x		Flash	1.5-2 MB					_									LQFP 100/144				
	144	RAM	276-352 kB	4/4	Up to 26	2 ch	4x	2x	-	2x	4 ch	6x	6x	1x	1x	-	LFBGA 196				
XMC48x		Flash	1-2 MB							_							LQFP 100/144				
144 RAM 200-352 kB		4/4	Up to 26	2 ch	4x	2x	-	2x	4 ch	6x	6x	1x	1x	1x	LFBGA 196						
					:	Supply	voltag	e range	e 3.1-3.	6 V											
					Temp	peratur	e range	e -40°C	85°	C/125°	с										

www.infineon.com/xmc www.infineon.com/dave 20-300 V MOSFETs

WBG semiconductors 500-950 V MOSFETs

Discrete IGBTs

Motor control ICs

Microcontrollers



XMC[™] digital power explorer kit

The new digital power explorer kit is designed with the particular goal of making it easy for engineers to take the first steps into digital power control with XMC[™] microcontrollers. It showcases both XMC[™] families Cortex[®]-M microcontrollers: XMC4000 and XMC1000, 30 V dual N-channel OptiMOS[™] MOSFETs and IRS2011S gate drivers. The kit includes two different control card options, XMC1300 control card (ARM[®] Cortex[®]-M0) and XMC4200 control card (ARM[®] Cortex[®]-M4F), which allow designers to evaluate both XMC[™] microcontroller families and make the right price/performance choice for their application.

Key features

- Synchronous buck converter evaluation kit controlled with XMC4200 or XMC1300 ARM[®] Cortex[®]-M MCUs
- > Onboard resistive load banks
- ➤ Featuring BSC0924NDI dual N-channel OptiMOSTM and IRS2011S high- and low-side gate driver
- > Different control schemes possible
 - Voltage mode control
 - Peak current mode control (with slope compensation)

Customer benefits

- > Easy entry in digital power control applications
- > Understand the details of voltage/peak current control and how to extract the maximum of XMC[™] devices
- > DAVE[™] v4 APPs for buck converter and many more examples

XMC™ digital power explorer kit	Specification		Infineon components				
and a	V _{in}	12 V _{DC}	мси	XMC4200 or XMC1300			
Contraction of the second	V _{out_nom}	3.3 V _{DC}	MOSFETs	OptiMOS™ BSC0924NDI			
	I _{out}	2 A	MOSFET half-bridge driver	IRS2011S			
	P _{out}	6 W					

www.infineon.com/xmc

Gate driver ICs

Microcontrollers

High power density 800 W 130 kHz platinum server design with XMC1300

The 800 W PFC CCM evaluation board demonstrates the design and practical results of an 800 W 130 kHz platinum server PFC evaluation board based on Infineon devices, in terms of power semiconductors, non-isolated gate drivers, analog and digital controllers for the PFC converter, as well as flyback controller for the auxiliary supply. This evaluation board verifies the performance of the latest 600 V CoolMOS[™] C7 superjunction MOSFET technology working at 130 kHz in a PFC CCM boost converter along with EiceDRIVER[™] ICs and CoolSiC[™] Schottky diode 650 V G5 using digital control.

Key features

- Classic PFC boost stage digitally controlled with XMC1302 including voltage and current loops
- Protections, including cycle-by-cycle current protection
- > Run time debug with isolated UART to PC interface and PC software

Customer benefits

- > High efficient PFC stage with a complete system solution from Infineon
- > HW and SW available
- > Higher switching frequency permits higher power density

800 W PFC CCM with XMC1300	Specification		Infineon components				
	V _{in}	90-265 V _{AC}	мси	XMC1302 (TSSOP38)			
	V _{out_nom}	380 V _{DC}	MOSFET	600 V CoolMOS™ C7			
	I _{out}	2 A	MOSFET driver	EiceDRIVER™ 2EDN7524F non-isolated			
	PWM frequency	130 kHz	Diode	CoolSiC [™] Schottky diode 650 V G5			
	THD	<10%	Auxiliary PSU	ICE2QR4780Z			
	Power factor	>0.9 from 20% load					
	Efficiency	97% (peak)					

600 W half-bridge LLC evaluation board with 600 V CoolMOS[™] C7 SJ MOSFET with digital control

The 600 W LLC digital control evaluation board shows how to design the half-bridge LLC stage of a server SMPS with the target to meet 80+ Titanium standard efficiency requirements. For this purpose, the latest CoolMOS[™] technologies, 600 V CoolMOS[™] C7 or P6 superjunction MOSFETs have been used on the primary side, and OptiMOS[™] low voltage power MOSFET in SuperSO8, BSC010N04LS, in the synchronous rectification secondary stage in combination with QR CoolSET[™] ICE2QR2280Z, high- and low-side driver 2EDL05N06PF, low-side gate driver 2EDN7524F and a XMC4200 microcontroller.

Key features:

- > 600 W LLC half-bridge stage with synchronous rectification (SR)
- > All controlled with XMC4200 including:
- Start up (PWM to PFM) and burst-mode algorithms
- Adaptive dead time and capacitive-mode detection
- No hard commutation at any condition

Customer benefits

- > Learn LLC topology with a complete system solution from Infineon
 - HW and SW available
- > Close to customer solution
 - High efficiency \rightarrow 97.8%
 - Reliability and power density

600 W LLC digital control	Specification		Infineon components				
	V _{in}	350-410 V _{DC}	MCU	XMC4200 (VQFN48)			
	V _{out_nom}	12 V _{DC}	MOSFET SR	BSC010N04LS			
A REAL PROPERTY AND A REAL	I _{out}	50 A	HB driver	2EDL05N06PF			
	P _{out}	600 W	LLC HB MOSFET	CoolMOS™ IPP60R190P6			
	f _{res}	157 kHz	Auxiliary PSU	ICE2QR2280Z			

www.infineon.com/xmc

www.infineon.com/800w-pfc-eval

Application

Motor control ICs

Packages

Microcontrollers

3 kW dual-phase LLC converter using XMC4400

The 3 kW dual-phase LLC demonstration board is an example of a high efficiency isolated DC-DC converter using the state-of-the-art Infineon components, both power devices and controller/driver ICs. The use of an advanced digital control using the XMC4400 microcontroller, together with the latest generation of CoolMOS™ and OptiMOS™ devices, allows achieving a very flat efficiency curve in the entire load range. The demonstration board is targeting the high voltage DC-DC stage of high-end telecom rectifiers.

Key features

- > Full digital control by XMC4400 on the secondary side
- > Digital current sharing with phase shedding
- > Accurate algorithm able to prevent hard commutation and capacitive load mode in LLC operation

Customer benefits

- > Full digital control by XMC4400 on the secondary side
- > Efficiency peak 98.5% and more than 97.2% in the entire load range
- > Easy monitoring and parameter setting via a graphic user interface

3 kW dual-phase LLC converter using XMC4400	Specification		Infineon components					
	V _{in}	350-410 V _{DC}	МСО	XMC4400 (LQFP64)				
	V _{out_nom}	54.3 V _{DC}	SR MOSFET	OptiMOS™ BSC093N15NS5				
	I _{out_max}	55 A	Drivers	1EDI60N12AF 2EDN7524R				
	P _{out}	3000 W	LLC Half-bridge MOSFET	CoolMOS™ P6 IPW60R041P6				
	f _{range}	90-200 kHz	Auxiliary PSU	ICE2QR2280Z				
	Peak efficiency	>98.4%						

RGB LED lighting shield with XMC1202 for Arduino

The RGB LED lighting shield with XMC1202 for Arduino uses a DC-DC buck topology and is able to drive up to three LED channels with constant current. The shield itself is powered by a programmable XMC[™] 32-bit ARM[®] MCU with embedded brightness color control unit (BCCU, XMC1200 MCU series), for flicker-free LED dimming and color control.

Features

- > Compatible with Arduino Uno R3 and XMC1100 boot kit from Infineon
- > Easily configurable for various light engines and any input voltage (within operating conditions)
- > Wide DC input voltage range
- > Simple I²C interface

Operating conditions

- > Nominal: 12-48 V input voltage (max. 6-60 V)
- > Average LED current up to 700 mA (max. peak current 1 A)

The Infineon shields mentioned above are hardware compatible with Arduino and Infineon's XMC[™] boot and relax kits.



Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

^oower ICs

Gate driver ICs

3 kW dual-phase LLC converter

XMC4800 automation board V2 – explore XMC4800 microcontroller based on ARM® Cortex®-M4

The XMC4800 automation board V2 uses Infineon's industry leading XMC[™] ARM[®] Cortex[®]-M4 microcontroller in combination with Infineon's supply, interface, communication and safety products. The XMC4800 automation board V2 is designed to evaluate the capabilities of the XMC4800 microcontroller especially in EtherCAT[®] slave applications and can be used with a wide range of development tools including Infineon's free-of-charge Eclipse based IDE, DAVE[™].

Key features

- > XMC4800-E196 MCU based on ARM[®] Cortex[®]-M4 at 144 MHz
- > EtherCAT[®] slave controller, 2 MB flash and 352 kB RAM
- > OPTIGA[™] Trust E embedded security solution (CC EAL6+)
- > Real time clock crystal
- > SPI FRAM (64 kB non-volatile memory)
- > EtherCAT[®] slave node (2 EtherCAT[®] PHY and RJ45 Jacks)
- > 24 V ISOFACE[™] 8-channel inputs and 8-channel outputs CAN transceiver
- > CAN transceiver

Customer benefits

- > Complete automation kit gateway
- > Combined MCU with EtherCAT slave application
- > Isolated interfaces with diagnose
- > Ethernet connectivity with software examples available
- > 24 V supply
- > CAN connectivity
- > Full software DAVE[™] examples

XMC4800 automation board V2	Туре	Description	OPN
	KIT_XMC48_AUT_BASE_V2	The XMC4800 automation board V2 utilizes Infineon's industry leading XMC ARM® Cortex®-M4 microcontroller in combination with Infineon's supply, interface/communication and safety products.	KITXMC48AUTBASEV2TOBO1
Channel Comp martin	XMC4800-E196K2048	ARM® Cortex®-M4 microcontroller	XMC4800E196K2048AAXQMA1
	ISO2H823V2.5	24 V 8-channel isolated output	ISO2H823V25XUMA1
	ISO1I813T	24 V 8-channel isolated input	ISO1I813TXUMA1
and the second s	SLS 32AIA020A4 USON10	OPTIGA™ Trust E – embedded security solution	SLS32AIA020A4USON10XTMA2
Condition of the of the second	TLE6250GV33	Infineon CAN transceiver	TLE6250GV33XUMA1
	IFX54441LDV	Infineon voltage regulator	IFX54441LDVXUMA1

XMC[™] wireless power controller – enabling wireless charging transmitter applications

Infineon's XMC[™] wireless power controller, based on the ARM[®] Cortex[®]-M0 core, provides a powerful and cost-effective platform for high performance, smart and safe wireless charging applications. The XMC[™] wireless power controller helps the next-generation wireless charging systems to meet strict safety, environmental and regulatory requirements, while still enabling industry-leading charging performance and efficiency. This controller works seamlessly with Infineon's power devices in a scalable architecture to provide a complete charging solution for everything from a fast-charge smartphone, to a 20 W robot, or a 60 W drone and beyond.

Key features

- > Supports inductive and resonant charging methods
- > Power levels up to 60 W
- > Multiple industry standard and custom charging profiles using the same hardware architecture
- > Single- and multi-coil transmitters
- > Half- and full-bridge support
- > Variable and fixed frequency transmitter types
- > Buck and boost topologies
- > Integrated flash for parameter storage
- > Voltage supply 1.8-5.5 V
- > Space saving VQFN-40 package

Customer benefits

- > Supports 15 W charging and existing standards, including fast charging of smartphones
- > Full power 15 W without exotic thermal management
- > Achieves charging rates equivalent to wired charging
- > Supports custom-charging profiles and industry standards on the same hardware
- > Foreign object detection (FOD) with improved accuracy quality-factor monitoring
- > Foreign object detection capability can be extended beyond existing standards to improve detection
- > Supports custom coils, and greater than three coils

For a detailed overview of Infineon's wireless charging solutions, check pages 60 to 64.

Packages

XMC[™] peripherals IEC60730 class B library for XMC[™]

Supporting the XMC1xxx and XMC4xxx families

In collaboration with the consultancy Hitex, Infineon developed the IEC60730 – class B software library for XMC[™] industrial microcontrollers for household electrical appliances. This is a dedicated software library for XMC[™] MCUs with routines for internal supervisory functions and for self-diagnostics.

Extended documentation and pre-certified software libraries to XMC[™] Cortex[®] ARM[®] based controllers are free of charge. For more information, please check: www.hitex.com/classb

Documentation	Consultancy
 > Safety application note > Failure mode report > FMEDA tool 	EMBEDDED TOOLS & SOLUTIONS
by Infineon, revised in workshops by TÜV Süd	Implementation support by Hitex

Embedded security for XMC[™] MCUs

Infineon and its partners provide solutions which support support with data protection, allowing authentication and encryption and securing firmware file updates to prevent cloning and downtimes.

Security solutions		
Software		Hardware
Secure bootloader by Infineon, XMC1000		IGA™ family by Infineon re-based security solutions
CodeMeter μEmbedded by WIBU, XMC4000 exclusive	OPTIGA™ Trust family	OPTIGA™ TPM family
KMS/CycurKEYS by ESCRYPT, XMC4000	S where I I	Continent
emSecure by SEGGER	Turnkey and programmable security so	olutions Standardized certified turnkey solution

AURIX[™]–32-bit microcontrollers

32-bit multicore TriCore[™] – safety joins performance

AURIX™ is Infineon's family of microcontrollers serving the needs of industrial applications in terms of performance and safety. Its innovative multicore architecture, based on up to six independent 32-bit TriCore™ CPUs at 300 MHz, has been designed to meet the highest safety standards while increasing the performance at the same time. Using the AURIX[™] scalable platform, developers will be able to implement applications such as motor control and drives, PLC or any other automation application. Developments using AURIX™ require less effort to achieve the SIL/ IEC61508 standard based on its innovative safety concept and multiple HW safety features. Furthermore, AURIX™ has enhanced communication capabilities to support communication between CAN, LIN, FlexRay and Ethernet buses.

Key features

- > TriCore[™] with DSP functionality
- Best-in-class real-time performance: up to six TriCore™ > with up to 300 MHz per core
- > Supporting floating point and fix point with all cores
- Up to 6.9 MB of internal RAM, up to 16 MB of flash >
- Innovative single supply 5 V or 3.3 V >
- > IEC61508 conformance to support safety requirements up to SIL 3
- Embedded EEPROM >
- Advanced communication peripherals: CAN FD, LIN, SPI, > FlexRay, Ethernet

Key benefits

- > High scalability gives the best cost-performance fit
- > High integration leads to significant cost savings
- High integration leads to reduced complexity
- > Innovative supply concept leads to best-in-class power consumption



Upgrade/downgrade with pin-compatible packages

www.infineon.com/aurix

AURIX[™] family package scalability

Motor control ICs

Packages

Applications

Packages

AURIX™ TC2xx portfolio

Product type	Max. clock frequency [MHz]	Program memory [kB]	SRAM (incl. cache) [kB]	Co-processor ¹⁾	Cores/lockstep	Timed I/O	Number of ADC channels	External bus interface	CAN nodes	Communication interfaces ²⁰	Temperature ranges ³	Packages	Additional features/remarks ⁴⁾
TC299TX	300	8000	2728	FPU	3/1	263	84/10 DS	yes	6	4xASCLIN, 6xQSPI, 3xMSC, 2xI ² C, 15xSENT, HSSL, 5xPSI5, 2xFlexRay, Ethernet, CAN FD	к	LFBGA-516	EVR, STBU, HSM
TC299TP	300	8000	728	FPU	3/1	263	84/10 DS	yes	6	4xASCLIN, 6xQSPI, 3xMSC, 2xI ² C, 15xSENT, HSSL, 5xPSI5, 2xFlexRay, Ethernet, CAN FD	к	LFBGA-516	EVR, STBU, HSM
TC298TP	300	8000	728	FPU	3/1	232	60/10 DS	yes	6	4xASCLIN, 6xQSPI, 3xMSC, 2xI ² C, 15xSENT, HSSL, 5xPSI5, 2xFlexRay, Ethernet, CAN FD	к	LBGA-416	EVR, STBU, HSM
TC297TA	300	8000	2728	FPU, FFT, CIF	3/1	169	60/10 DS	no	6	4xASCLIN, 4xQSPI, 3xMSC, 2xI ² C, 15xSENT, HSSL, 5xPSI5, 2xFlexRay, Ethernet, CAN FD	к	LFBGA-292	EVR, STBU, HSM
TC297TX	300	8000	2728	FPU	3/1	263	60/10 DS	no	6	4xASCLIN, 4xQSPI, 3xMSC, 2xI ² C, 15xSENT, HSSL, 5xPSI5, 2xFlexRay, Ethernet, CAN FD	к	LFBGA-292	EVR, STBU, HSM
TC297TP	300	8000	728	FPU	3/1	169	60/10 DS	no	6	4xASCLIN, 4xQSPI, 3xMSC, 2xI ² C, 15xSENT, HSSL, 5xPSI5, 2xFlexRay, Ethernet, CAN FD	к	LFBGA-292	EVR, STBU, HSM
TC277TP	200	4000	472	FPU	3/2	169	60/6 DS	no	4	4xASCLIN, 4xQSPI, 2xMSC, HSSL, 2xI ² C, 10xSENT, 3xPSI5, FlexRay, Ethernet, CAN FD	к	LFBGA-292	EVR, WUT, HSM
TC275TP	200	4000	472	FPU	3/2	112	60/6 DS	no	4	4xASCLIN, 4xQSPI, 2xMSC, HSSL, 2xI ² C, 10xSENT, 3xPSI5, FlexRay, Ethernet, CAN FD	к	LQFP-176	EVR, WUT, HSM
TC267D	200	2500	240	FPU	2/1	169	50/3 DS	no	5	4xASCLIN, 4xQSPI, 2xMSC, 2xI ² C, 10xSENT, 3xPSI5, HSSL, FlexRay, Ethernet, CAN FD	к	LFBGA-292	EVR, STBU
TC265D	200	2500	240	FPU	2/1	112	50/3 DS	no	5	4xASCLIN, 4xQSPI, 2xMSC, 2xI ² C, 10xSENT, HSSL, 3xPSI5, FlexRay, Ethernet, CAN FD	к	LQFP-176	EVR, STBU
TC264DA	200	2500	752	FPU, FFT, CIF	2/1	88	40/3 DS	no	5	4xASCLIN, 4xQSPI, 2xMSC, 2xI ² C, 10xSENT, HSSL, 3xPSI5, FlexRay, Ethernet, CAN FD	к	LQFP-144	EVR, STBU
TC264D	200	2500	240	FPU	2/1	88	40/3 DS	no	5	4xASCLIN, 4xQSPI, 2xMSC, 2xI ² C, 10xSENT, HSSL, 3xPSI5, FlexRay, Ethernet, CAN FD	к	LQFP-144	EVR, STBU
TC237LP	200	2000	192	FPU	1/1	120	24	no	6	2xASCLIN, 4xQSPI, 4xSENT, FlexRay, CAN FD	к	LFBGA-292	EVR, WUT, HSM
TC234LA	200	2000	704	FPU, FFT	1/1	120	24	no	6	2xASCLIN, 4xQSPI, 4xSENT, FlexRay, Ethernet	к	TQFP-144	EVR, WUT, HSM
TC234LX	200	2000	704	FPU	1/1	120	24	no	6	2xASCLIN, 4xQSPI, 4xSENT, FlexRay, Ethernet	к	TQFP-144	EVR, WUT, HSM
TC234LP	200	2000	192	FPU	1/1	120	24	no	6	2xASCLIN, 4xQSPI, 4xSENT, FlexRay, CAN FD	к	TQFP-144	EVR, WUT, HSM
TC233LP	200	2000	192	FPU	1/1	78	24	no	6	2xASCLIN, 4xQSPI, 4xSENT, FlexRay, CAN FD	к	TQFP-100	EVR, WUT, HSM
TC224L	133	1000	96	FPU	1/1	120	24	no	3	2xASCLIN, 4xQSPI, 4xSENT, CAN FD	к	TQFP-144	EVR, WUT
TC223L	133	1000	96	FPU	1/1	78	24	no	3	2xASCLIN, 4xQSPI, 4xSENT, CAN FD	к	TQFP-100	EVR, WUT
TC222L	133	1000	96	FPU	1/1	59	24	no	3	2xASCLIN, 4xQSPI, 4xSENT, CAN FD	к	TQFP-80	EVR, WUT
TC214L	133	500	96	FPU	1/1	120	14	no	3	2xASCLIN, 4xQSPI, 4xSENT, CAN FD	к	TQFP-144	EVR, WUT
TC213L	133	500	96	FPU	1/1	78	24	no	3	2xASCLIN, 4xQSPI, 4xSENT, CAN FD	к	TQFP-100	EVR, WUT
TC212L	133	500	96	FPU	1/1	59	24	no	3	2xASCLIN, 4xQSPI, 4xSENT, CAN FD	к	TQFP-80	EVR, WUT

¹¹ CIF = camera and external ADC Interface, FFT = fast fourier transform accelerator, FPU = floating point unit, PCP = peripheral control processor ²¹ ASC = asynchronous serial channel, ASCLIN = asyn/synchronous local interconnect network, HSSL= high-speed serial link, I²C = inter-integrated circuit, LIN = local interconnect network, MLI = micro link interface, MSC = micro second channel, PSI5 = peripheral sensor interface 5, QSPI = queued serial peripheral interface,

SENT = single edge nibble transmission, SSC = synchronous serial channel, CAN FD ISO11898-1:2015 ³⁾ Ambient temperature range: A = -40°C ... 140°C, B = 0°C ... 70°C, F = -40°C ... 85°C, H = -40°C ... 110°C, K = -40°C ... 125°C, L = -40°C ... 150°C, X = -40°C ... 105°C ⁴ EVR = embedded voltage regulator, HSM = hardware security module, STBU = stand-by control unit, WUT = wake-up timer

AURIX[™] 2nd generation – TC3xx

AURIX™ TC3xx architecture evolution from TC2xx to TC3xx



Packages

AURIX™ TC3xx package scalability



> Advanced package technologies deliver the best price/performance ratio

Customers can choose between different devices in the same pin-compatible package >



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500-950 V MOSFETs

WBG semiconductors

Power ICs

Microcontrollers

TriCore™ microcontroller portfolio

Product type	Cores/lockstep	Max clock frequency [MHz]	Program memory [kB]	SRAM (incl. cache) [kB]	Radar accelerator/ radar interface ¹	CAN/CAN FD nodes	Ethernet 100/1000 Mbit	External bus interface ²²	Communication Interfaces	HSM	Temperature ranges	Packages	Additional features/ remarks [»]
AURIX™ TC	3xx fai	mily											
TC399XX	6/4	300	16000	6912	no	12	1	EBU, eMMC, 2x HSSL	6x SPI, 2x FlexRay, 12x LIN, 25x SENT, 4x PSI5, 2x I²C, 4x MSC	EVITA full	K, L	LFBGA-516	5 V/3.3 V EVR, 8-bit SCR
TC399XP	6/4	300	16000	2816	no	12	1	EBU, eMMC, 2x HSSL	6x SPI, 2x FlexRay, 12x LIN, 25x SENT, 4x PSI5, 2x I²C, 4x MSC	EVITA full	K, L	LFBGA-516	5 V/3.3 V EVR, 8-bit SCR
TC397XX	6/4	300	16000	6912	no	12	1	eMMC, 2x HSSL	6x SPI, 2x FlexRay, 12x LIN, 25x SENT, 4x PSI5, 2x I²C, 4x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC397XP	6/4	300	16000	2816	no	12	1	eMMC, 2x HSSL	6x SPI, 2x FlexRay, 12x LIN, 25x SENT, 4x PSI5, 2x I²C, 4x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
ТС397ХА	6/4	300	16000	6912	2x SPU/ 8x 400 Mbit/s LVDS	12	1	2x HSSL	6x SPI, 2x FlexRay, 12x LIN, 25x SENT, 4x PSI5, 2x I²C, 4x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC389QP	4/2	300	10000	1568	no	12	1	HSSL	5x SPI, 2x FlexRay, 24x LIN, 25x SENT, 4x PSI5, 2x I²C, 3x MSC	EVITA full	K, L	LFBGA-516	5 V/3.3 V EVR, 8-bit SCR
TC387QP	4/2	300	10000	1568	no	12	1	HSSL	5x SPI, 2x FlexRay, 24x LIN, 25x SENT, 4x PSI5, 2x I²C, 3x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
ТС377ТХ	3/3	300	6000	4208	no	12	2	eMMC, HSSL	5x SPI, 1x FlexRay, 12x LIN, 15x SENT, 2x PSI5, 1x I²C, 2x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC377TP	3/2	300	6000	1136	no	8	1	HSSL	5x SPI, 1x FlexRay, 12x LIN, 15x SENT, 2x PSI5, 1x I²C, 2x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC375TP	3/2	300	6000	1136	no	8	1	HSSL	5x SPI, 1x FlexRay, 12x LIN, 15x SENT, 2x PSI5, 1x I²C, 2x MSC	EVITA full	K, L	LQFP-176	5 V/3.3 V EVR, 8-bit SCR
TC367DP	2/2	300	4000	672	no	8	1	HSSL	4x SPI, 1x FlexRay, 12x LIN, 10x SENT, 2x PSI5, 1x I²C, 1x MSC	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC366DP	2/2	300	4000	672	no	8	1	HSSL	4x SPI, 1x FlexRay, 12x LIN, 10x SENT, 2x PSI5, 1x I ² C, 1x MSC	EVITA full	K, L	LFBGA-196	5 V/3.3 V EVR, 8-bit SCR
TC365DP	2/2	300	4000	672	no	8	1	HSSL	4x SPI, 1x FlexRay, 12x LIN, 10x SENT, 2x PSI5, 1x I²C, 1x MSC	EVITA full	K, L	LQFP-176	5 V/3.3 V EVR, 8-bit SCR
TC364DP	2/2	300	4000	672	no	8	1	HSSL	4x SPI, 1x FlexRay, 12x LIN, 10x SENT, 2x PSI5, 1x I ² C, 1x MSC	EVITA full	K, L	TQFP-144	5 V/3.3 V EVR, 8-bit SCR
TC364DP	2/2	300	4000	672	no	8	1	HSSL	4x SPI, 1x FlexRay, 12x LIN, 10x SENT, 2x PSI5, 1x I ² C, 1x MSC	EVITA full	K, L	LQFP-144	5 V/3.3 V EVR, 8-bit SCR
TC357TA	3/2	300	4000	3664	2x SPU/ 8x 400 Mbit/s LVDS	8	1	no	4x SPI, 1x FlexRay, 4x LIN	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC356TA	3/2	300	4000	3664	2x SPU/ 8x 400 Mbit/s LVDS	8	1	no	4x SPI, 1x FlexRay, 4x LIN	EVITA full	K, L	LFBGA-196	5 V/3.3 V EVR, 8-bit SCR
TC337DA	2/1	200	2000	1568	1x SPU/ 4x 400 Mbit/s LVDS	8	1	eMMC	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC336DA	2/1	200	2000	1568	1x SPU/ 4x 400 Mbit/s LVDS	8	1	eMMC	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	LFBGA-196	5 V/3.3 V EVR, 8-bit SCR
TC337LP	1/1	200	2000	248	no	8	no	no	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC336LP	1/1	200	2000	248	no	8	no	no	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	LFBGA-196	5 V/3.3 V EVR, 8-bit SCR
TC334LP	1/1	200	2000	248	no	8	no	no	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	TQFP-144	5 V/3.3 V EVR, 8-bit SCR
TC333LP	1/1	200	2000	248	no	8	no	no	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	TQFP-100	5 V/3.3 V EVR, 8-bit SCR
TC332LP	1/1	200	2000	248	no	8	no	no	4x SPI, 1x FlexRay, 12x LIN, 6x SENT	EVITA full	K, L	TQFP-80	5 V/3.3 V EVR, 8-bit SCR
TC327LP	1/1	160	1000	96	no	8	no	no	4x SPI, 6x SENT, 6x LIN	EVITA full	K, L	LFBGA-292	5 V/3.3 V EVR, 8-bit SCR
TC324LP	1/1	160	1000	96	no	8	no	no	4x SPI, 6x SENT, 6x LIN	EVITA full	K, L	TQFP-144	5 V/3.3 V EVR, 8-bit SCR
TC323LP	1/1	160	1000	96	no	8	no	no	4x SPI, 6x SENT, 6x LIN	EVITA full	K, L	TQFP-100	5 V/3.3 V EVR, 8-bit SCR
TC322LP	1/1	160	1000	96	no	8	no	no	4x SPI, 6x SENT, 6x LIN	EVITA full	K, L	TQFP-80	5 V/3.3 V EVR, 8-bit SCR

1) SPU – Signal processing unit

2) HSSL – High-speed serial link

3) 8-bit SCR – Standby controller for low power modes

4) EVR – Embedded voltage regulator

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20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers

AURIX[™] starter and application kits

Infineon starter kits – 32-bit microcontrollers

TriBoards

Infineon TriCore[™] family starter kits are powerful evaluation systems that enable evaluation and development well before the target hardware is available. They offer a solid platform for both hardware and software engineers to evaluate and prototype designs that are closely aligned with their final applications.



Application kits

To simplify the development of your own application, the kit comes with a variety of onboard components, including a highly integrated software development environment that gives you everything you need to compile, debug, and flash your AURIX[™] multicore application, such as radar, Arduino, gateway and safety.



System application kits

The system application kits provide a quick jump-start to typical microcontroller applications, such as motor control, radar etc. These reference design kits enable faster design-in support for end applications by providing a reference board, application software, tooling and documentation.



20-300 V MOSFETs

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Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

ACT– AURIX™ configuration tool

ACT is a powerful tool that helps engineers to jump-start the programming of Infineon microcontrollers.

Key feature

- > Altium TASKING VX TriCore[™] lite version including built-in
 - AURIX[™] pin mapping incl. interactive package view
 - AURIX[™] iLLD (low-level driver)
 - AURIX[™] OSEK

For further information on TriCore[™] tools, visit www.infineon.com/aurix-tools



Free TriCore™ entry tool chain

This free-of-charge entry tool chain provides all the features required to develop and test software for TriCore[™] and AURIX[™]. The tool can be used with all available TriCore[™] and AURIX[™] starter kits and application boards.

Key features

- > Eclipse-based IDE
- Project wizard to easily define the project properties for device and board support
- > High-performance GNU C compiler
- Integrated source-level debugger
- > On-chip flash programming support

For further information on TriCore™ tools, visit www.infineon.com/aurix-tools

AURIX[™] and XMC[™] PDH partners

Preferred Design Houses (PDH) and software resellers

Optimized open market customer support set up for systems using AURIX[™] and XMC[™], including software and other Infineon's products, such as power products, sensor products and modules. Our partners are trained to use AURIX[™] and XMC[™].

Classic (Free of charge)	 > 1st level customer support covering Infineon products/solutions > Technical interface and support to the customer 	 > Driving design at customer > Basic training for design teams at customer > 24 h response time to the customer
Premium (Consultancy mode)	 > Project management and project-specific application support > Specification of general software architecture defining required layers, control and data flow structure etc. 	 Software testing Support for project-specific functional safety engineering Project-specific support for security solution
To be agreed between customers and PDH	 > Specification and implementation of custom device drivers > Optimization of software components with regard to speed/code size 	 > Safety support > Security support > Multicore support

Optimized regional and application-specific presence

									EMEA									
Support capabilities	BLUE	茶 AVL	My HIGHTEC	hitex	(4) SSt	😵 FROBAS	Mixed Mode	RDM GROUP	MecTronik	driveXpert [®]	UULMA	Autogramma	PINTearr	Embedded Office	Ø GRINN	iav	(k)	ф олния
Autosar																		
Motor control																		
Lighting																		
PFC/power conversion																		
AURIX™ general support HW																		
AURIX™ general support SW																		
Safety support IEC61508																		
Safety support ISO26262																		
Security support/SHE+																		
XMC [™] general support HW																		
XMC [™] general support SW																		
Class B certification																		
Capacitive sensing with XMC™																		
Secure boot for XMC TH																		
24 GHz radar																		
77 GHz radar																		



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Basic

Essential principles and elementary know-how to support a customer; provision of basic training for design teams

Advanced

High-level project-specific application support/consulting

Expert

Extensive knowledge and ability to fully support development

20-300 V MOSFETs

500-950 V MOSFETs



Infineon support for industrial microcontrollers

One platform, countless solutions

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Gate driver ICs

Motor control ICs

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Microcontrollers

Infineon XENSIV™ – sensing the world

Infineon XENSIV[™] sensors are exceptionally precise thanks to industry-leading technologies. They are the perfect fit for various customer applications in automotive, industrial and consumer markets.

From the world leader in sensing technology, XENSIV[™] sensors simplify lives by enabling "things" to "see", "hear", "feel" and intuitively "understand" their environment. As a result of proven quality and outstanding reliability, customers can rely on XENSIV[™] for system stability, durability and integrity. Providing high accuracy and best-in-class measurement performance, XENSIV[™] sensors add great value to customer applications. More than 40 years' experience in sensing solutions and a deep-rooted system understanding result in the broadest portfolio of ready-to-use sensor solutions on the market. Ecosystem partners and our customers partner with us for leading technologies, perfect-fit solutions and continuous innovation.

With a proven track record in IoT innovation, we continue to seamlessly and securely connect people and machines. Many IoT trends, such as smart devices and wearables, electromobility and connected cars, smart factories and homes, and energy intelligence are being driven by technologies that develop with XENSIV[™] sensors families as one of their key elements. Today, we are already inspiring the next generation of smart environments, capable of understanding and responding to human communication. Infineon's semiconductors are at the very heart of machine-to-machine (M2M), human-machine interface (HMI), mobile and wireless infrastructure technologies. As the technological boundary between humans and machines gradually disappears, these devices need even more advanced intelligence, enriched with voice assistance capabilities and the latest sensor fusion innovations, not to mention robust security technologies to protect personal data. Infineon's sensors and microphones are already delivering this intelligent functionality and inspiring the next step in mobile connectivity.

XENSIV™ MEMS microphone

Time to debottleneck your audio chain



The popularity of voice user interfaces and the usage of audio recording to share information and experiences are increasing dramatically. However, the performance of microphones often limits the potential of today's cutting edge devices. Not anymore!

Infineon's XENSIV[™] MEMS microphones introduce a new performance class for digital MEMS microphones that overcome existing audio chain limitations. IM69D130 is designed for applications where low self-noise (high SNR), wide dynamic range, low distortions and a high acoustic overload point are required.



Don't miss a single thing! With XENSIV[™] MEMS microphones, you can create a new user experience benchmark in audio recording.



Talk to tomorrow and be heard! With XENSIV[™] MEMS microphones, you can define the benchmark in speech recognition for a new user experience.



Hear nothing but your favorite beats!

With XENSIV[™] MEMS microphones, you can create headsets offering users a benchmark noise cancellation experience.

Features

274

- > 69 dB(A) signal-to-noise ratio (SNR)
- > Below 1 percent distortions at 128 dBSPL (130 dBSPL AOP)
- > Digital (PDM) interface with 6 µs group delay at 1 kHz
- > Tight sensitivity (-36 ±1 dB) and phase (± 2 deg) tolerances
- > 28 Hz low frequency roll-off
- > 4.0 x 3.0 x 1.2 mm package

Benefits

- > High fidelity and far field audio recording
- Matched, noise and distortion free audio signals for advanced audio processing
- > Ultralow group delay for latency-critical applications
- No analog components required

- > High quality audio capturing: e.g. cameras, camcorders, conference systems
- > Voice user interface: e.g. smart speaker, home automation and IoT devices
- > Active noise cancellation: headphones and earphones
- > Audio pattern detection: predictive maintenance, security or safety applications

20-300 V MOSFETs

Motor control ICs

Infineon's dual backplate MEMS technology is based on a miniaturized symmetrical microphone design, similar as utilized in studio condenser microphones, and results in high linearity of the output signal within a dynamic range of 105 dB. The microphone noise floor is at 25 dB[A] (69 dB[A] SNR) and distortion does not exceed 1 percent even at sound pressure levels of 128 dB SPL (AOP 130 dB SPL). The flat frequency response (28 Hz low-frequency roll-off) and tight manufacturing tolerance result in close phase matching of the microphones, which is important for multi-microphone (array) applications.

Maximum noise rejection	Ultralow distorsion (<1% THD)
Ultra precise corner frequency < +/- 7Hz	IM69D130: 128dBSPL IM69D120: 118dBSPL
Phase matched microphones	Class leading dynamic range
+/- 2deg @1kHz	IM69D130: 105dB IM69D120: 95dB

Product portfolio

Product	OPN	Package	Current consumption	Sensitivity	Signal to noise	Supply voltage
IM69D130	IM69D130V01XTSA1	LLGA-5-1	980 µA	-36 dBFS	69 dB	1.62-3.6 V
IM69D120	IM69D120V01XTSA1	LLGA-5-1	980 µA	-26 dBFS	69 dB	1.62-3.6 V



+ Ultraclear voice pickup

Sensitive to softest audio signals

+ Best noise attenuation



www.infineon.com/microphones

Discrete IGBTs

Motor control ICs

Microcontrollers

XENSIV™ digital barometric pressure sensor

For mobile and wearable devices

Infineon's digital barometric pressure sensor family is the best choice for mobile and wearable devices due to its small form factor, high precision and low power consumption. Pressure sensing is based on capacitive technology which guarantees ultrahigh precision (±2/±5 cm) and relative accuracy (±0.6 hPa) over a wide temperature range. The sensor's internal signal processor converts the output from the pressure and temperature sensor elements to 24-bit results. Each pressure sensor has been calibrated individually and contains calibration coefficients. The coefficients are used in the application to convert the measurement results to true pressure and temperature values. All sensors have a FIFO that can store the latest 32 measurements. Since the host processor can remain in a sleep mode for a longer period between readouts, a FIFO can reduce the system power consumption. Sensor measurements and calibration coefficients are available via the serial I2C/SPI interface.

DPS310

Barometric pressure sensor with very low power consumption, recommended for applications where power consumption is critical and highest precision in pressure metering is required.

DPS422

Monolithic chip solution that has an ultrasmall critical area and a very thin package (0.73 mm typ.). Beneath high precision pressure metering, DPS422 offers also highly accurate absolute temperature sensing (±0.4°C), which is required in applications like weather stations, thermostats, etc. It can be used in applications such as weather stations / smart thermostats and offers additional features by pressure sensing (e.g. intruder detection, weather forecast).

DPS368*

DPS368 offers the best-in-class resolution (±2 cm), a very fast read-out speed and a low current consumption. The sensor can be used in harsh environment, as it is robust against water (IPx8 - 50 m under water for 1 hour), dust and humidity. The small package size saves up to 80 percent of the space and makes the DPS368 ideal for mobile applications and wearable devices.

Typical applications

- > Drones: altitude detection and height stability
- > Health and fitness: accurate elevation gain and step counting (e.g. for smart watches)
- > Outdoor navigation: GPS start-up time/accuracy improvement; dead reckoning (e.g. in tunnels)
- > Indoor navigation: floor detection e.g. in shopping malls and parking garages
- > Smart home: micro weather forecasting; room temperature control; intruder detection
- > Air flow control: Smart filter replacement alarm (e.g. in home appliances); predictive maintenance
- > Health care: fall detection; respiratory devices; smart inhalers

Key product features	DPS310	DPS422	DPS368*					
Package size	LGA 8-pin: 2.0 x 2.5 x 1.0 mm	LGA 8-pin: 2.0 x 2.5 x 0.73 mm	LGA 8-pin: 2.0 x 2.5 x 1.1 mm					
Operating pressure range		300 1200 hPa						
Operating temperature range		-40 85°C						
Pressure level precision	± 0.005 hPa	(or ±0.05 m)	± 0.002 hPa (or ±0.02 m)					
Relative accuracy	± 0.06 hPa (or ±0.5 m)							
Absolute accuracy	± 1 hPa (or ±8 m)							
Temperature accuracy	0.5°C	< 0.4°C	0.5°C					
Pressure temperature sensitivity		0.5 Pa/K						
Measurement time	3	3.6 ms (low precision); 27.6 ms (standard mode	2)					
Average current consumption @ 1 Hz sampling rate	1.7 μA pressure measurement, 1.5 μA temp. measurement, standby 0.5 μA	1.7 μA pressure measurement, 2.0 μA temp. measurement, standby < 1 μA	1.7 μA pressure measurement, 1.5 μA temp. measurement, standby 0.5 μA					
Supply voltage		V _{DDIO} : 1.2 - 3.6 V; V _{DD} : 1.7 - 3.6 V						
Operating modes	Com	nmand (manual), background (automatic), star	ndby					
Interface		I2C and SPI, both with optional interrupt						

www.infineon.com/pressuresensor

* Environmentally protected pressure sensor, available Q2 2019

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

^oower ICs

Sate driver ICs

Motor control ICs

Microcontrollers

Functional block diagram





Digital signal

processing

Calibration

Digital core

Digital interface

I²C/SPI

V_{DDIO}



MUX

ADC



Pin configuration (top view)



Pin	Name	Function
1	GND	Ground
2	CSB	Chip select
3	SDI	Serial data in/out
4	SCK	Serial clock
5	SDO	Serial data out
6	V _{DDIO}	Digital interface supply
7	GND	Ground
8	V _{DD}	Analog supply

DPS310 package drawing

DPS368 package drawing

DPS422 package drawing



www.infineon.com/pressuresensor

Absolute pressure sensors (MAP and BAP)

Infineon's pressure sensors are ideal for a wide range of applications in the automotive and industrial sectors. Typical applications in automotive include side airbag, engine control and seat comfort with high quality, highly accurate products adhering to ISO26262 standard. Infineon offers the ideal portfolio for these systems.

The analog and digital interfaces of Infineon's pressure sensors provide customers with a high degree of design flexibility and enable manufacturers to meet evolving market demands.

KP21x/KP22x

Analog manifold air pressure sensor IC family (MAP + turbo MAP)

Features

- Manifold air pressure measurement MAP and turbo MAP
- Excellent accuracy of up to 1.0 kPa over a large temperature range
- Ratiometric analog voltage output proportional to the applied pressure
- Output signal fully compensated over pressure and temperature
- > Pressure range from 10 to 400 kPa
- > Temperature range from -40 to +140°C
- > Output clamping (optional)
- Complete product family available with multiple transfer function
- > Reverse polarity protection
- > Green SMD package

KP23x Analog barometric air pressure (BAP) sensor IC family

Features

- > Absolute air pressure measurement
- Excellent accuracy of 1.0 kPa over a large temperature range
- Ratiometric analog voltage output proportional to the applied pressure
- Output signal fully compensated across pressure and temperature range
- > Pressure range from 40 to 115 kPa
- > Temperature range from -40 to +125°C
- > Serial service interface
- > Open bond detection (OBD) for supply and GND
- > Inverse polarity protection
- > Green SMD package

Sate driver ICs

KP275 Media robust MAP sensor with digital interface

Features

- > Media robustness for current automotive requirements
- > Digital single edge nibble transmission (SENT) interface
- > Excellent accuracy of ±0.77 percent FFS
- > Green SMD package
- > Temperature range -40 to +170°C
- > Integrated NTC temperature sensor functionality

Block diagram



Integrated pressure sensor ICs for manifold and barometric air pressure

Product	Pressure range [kPa]	Max. accuracy [kPa]	Max. operating temperature [°C]	Automotive	Industrial
KP21x	10 150	1.0	140	\checkmark	\checkmark
KP22x	10 400	2.5	140	\checkmark	\checkmark
KP23x	15 115	1.0	125	\checkmark	\checkmark
KP236N6165	60 165	1.0	125	\checkmark	\checkmark
KP253	60 165	1.0	125	\checkmark	\checkmark
KP254	40 115	1.5	125	\checkmark	\checkmark
KP255	10 125	1.4	140	\checkmark	\checkmark
KP256	60 165	1.0	125	\checkmark	\checkmark
KP275	10 400	3.0	170	\checkmark	\checkmark

XENSIV™ 24 GHz radar sensor ICs

Infineon offers a wide portfolio of mmWave radar sensors to address different customer requirements. The BGT24M/L family is the largest and highest integrated 24 GHz radar transceiver family currently on the market, saving ~30 percent board space compared to discrete lineups. Infineon provides a total of four 24 GHz industrial radar chips, providing a range of different transmitter and receiver channel configurations, supporting different application requirements.

Applications

- > Building and smart home (IoT)
- > Indoor/outdoor lighting
- > Security
- > UAV/multicopters
- > Robotics
- > Smart street lighting



Key benefits

- > Direction, proximity and speed detection
- > Hidden mounting capability
- > Maintains operation through harsh weather conditions
- Motion tracking
- > Sensitive enough to capture breathing and heartbeat
- > Target positioning
- > Adaptable to different application requirements

In addition to the BGT24M/L family of MMIC chips, Infineon provides a continuously expanding range of evaluation and demonstration boards to support the testing and development of radar in multiple applications. All boards are provided with base level software to support the ease of use and faster time-to-market integration.

Utilizing our strong network of partners, the radar portfolio is extended to include a range of easy-to-integrate modules. Each of them contains Infineon's 24 GHz MMIC.



www.infineon.com/24GHz

Application

Discrete IGBTs

Microcontrollers

Infineon BGT24M/L family of MMIC chips

Infineon's range of 24 GHz industrial radar chips provides four configurations of transmit and receiver channels, ensuring that there is a chip to support your specific application. From basic applications such as motion detection in security systems, which only requires one transmit and one receive channel, to more complex applications like 3D positioning, which requires two or more receive channels, our range of radar chips supports all of your requirements.

Features	Infineon MMIC	Benefits
 24 GHz ISM band operation for motion, speed, direction move- ment and distance measurements 4 MMIC chips available 	Silver Stranger	 > Long range distance detection of moving objects up to 30 m > Wide range speed detection up to ±100 km/h

> Lower BOM costs

Product	Configuration	Features
BGT24MTR11	1Tx + 1Rx	 Measures not just motion, but also speed, direction, and distance Small form factor
BGT24MR2	2Rx	 > Resistance to moisture, dirt and temperature > Increased area coverage > Discrete design
BGT24MTR12	1Tx + 2Rx	 > Discrete design > Energy savings > Privacy protection
BGT24LTR11	1Tx + 1Rx	 Adaptable to different application requirements Highly integrated chips eliminating costly external components

The BGT24LTR11N16 key features

> 24 GHz transceiver MMIC

> Highly integrated

- > Fully integrated low phase noise V_{co}
- > Built in temperature compensation circuit for V_{co} stabilization, no PLL needed
- Low power consumption

- > Fully ESD protected device
- > Single ended RF and IF terminals
- > 200 GHz bipolar SiGe:C technology B7HF200
- > Single supply voltage 3.3 V
- Divider output for PLL operation
- > Smallest 24 GHz transceiver in the market



www.infineon.com/24GHz

Gate driver ICs

Application

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Microcontrollers

24 GHz evaluation and demonstration boards

Infineon's range of 24 GHz evaluation and demo boards continues to expand to support the needs of our customers and the increasing number of innovative ways radar is being incorporated into new applications.

Features

- > Three system boards available
- > All include 24 GHz radar and XMC[™] microcontroller
- Kit contains user manual, GUI, MATLAB compiler and Gerber files
- > Requires software

Infineon development kit



Demokit with SW, reference design

Benefits

- Capability to detect motion, speed and direction of movement (approaching or retreating) distance and angle of arrival based on hardware
- Firmware/software available for each radar mode

Sense2GOL (BGT24LTR11 + XMC1300)	Distance2Go (BGT24MTR11 + XMC4200)	Position2Go (BGT24MTR12 + XMC4700)
 Capability to detect motion, speed and direction of movement (approaching or retreating) Precise measurement of object detection compared to PIR Operates in harsh environments and detects through non-metallic materials Low power mode for enhanced battery life One of the world's smallest complete radar + MCU development kit BGT24LTR11 – 24 GHz highly integrated RF MMIC XMC1300 ARM® Cortex®-M0 –32-bit industrial microcontroller Debug over Cortex 10 pin debug connector Integrated multiple element patch antennas 	 > Capability to detect distance of multiple targets > Capability to detect motion, speed and direction of movement (approaching or retreating) > Operates in harsh environments and detects through non-metallic materials > BGT24MTR11 - 24 GHz highly integrated RF MMIC > XMC4200 ARM® Cortex®-M4 -32-bit industrial microcontroller > Debug over Cortex 10 pin debug connector > Integrated multiple element patch antennas 	 Capability to detect and track position of multiple targets Capability to detect distance of multiple targets Capability to detect motion, speed and direction of movement (approaching or retreating) Operates in harsh environments and detects through non-metallic materials BGT24MTR12 - 24 GHz highly integrated RF MMIC XMC4700 ARM® Cortex®-M4 -32-bit industrial microcontroller Debug over Cortex 10 pin debug connector Integrated multiple element patch antennas
Main applications > Security > Lighting control > Automatic door opener > Vital sensing	Main applications Drone: soft landing/obstacle avoidance Smart toilets Tank level sensing Intelligent switches	Main applications > Drone/robots: obstacle avoidance > Security > People tracking (IoT, smart home) > Vital sensing
Board dimensions > 25 mm x 25 mm (pictured with the Segger debugger break-off board for reprogram- ming)	Board dimensions > Board 36 mm x 45 mm	Board dimensions > Board 50 mm x 45 mm
Kit contents > User manual > Demonstration board > SW GUI to operate kit > Schematic and bill-of-materials of module	Kit contents > User's manual > Demonstration board > Corner reflector > SW GUI to operate kit > FMCW FW and SW ¹³ > Doppler FW and SW ¹³ > Schematic and bill-of-materials of module	Kit contents > User's manual > Demonstration board > Corner reflector > SW GUI to operate kit > FMCW FW and SW > Doppler FW and SW > Schematic and bill-of-materials of module

20-300 V MOSFETs

1) Usage of the FMCW and/or Doppler FW and SW requires agreeing to Infineon's user's agreement and licensing terms.

24 GHz modules

Partnering with the leading radar solution providers enables Infineon to connect our customers looking for turnkey solutions and design support for a complete range of applications.

Features

 Complete module, including radar MMIC, antenna options, MCU signal processing options, and SW options (Doppler, FSK and FMCW versions available) Partner modules using Infineon chips



Benefits

- > Ease of design
- Turnkey solution, no need for test and certification

Module (RF module; RF module + MCU including SW)

By integrating Infineon's 24GHz MMIC chip into the partners easy-to-use and simple-to-integrate modules the complexity and time to market for a range of applications such as home automation, multicopter, robotics and street lighting, are reduced.



New application or simple PIR replacement? Radar has it covered.

Radar, used in motion detection applications, increases accuracy when compared to passive infrared (PIR) technology, allowing a more precise measurement of object detection, and providing new capabilities such as the detection of speed and the direction of moving objects. Radar is also superior to camera-based systems by allowing detection of the objects while keeping identities anonymous.

Visit the link below to view our network of partners who provide modules and design support for all 24GHz industrial applications: www.infineon.com/24GHzpartners

Applications

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

High-precision current sensor for industrial applications - based on Hall technology

TLI4970: the miniaturization advantage

TLI4970 is a high-precision current sensor for industrial applications, based on our proven Hall technology. The coreless concept significantly reduces footprint compared with existing solutions. Infineon's current sensor is an easy-to-use, fully-digital solution, which does not require external calibration or additional parts such as A/D converters, 0 pAmps or reference voltage. It thus significantly reduces overall implementation effort, as well as PCB space and cost. The differential measurement principle integrated in the TLI4970 sensor suppresses interference caused by external magnetic fields. Accordingly, the sensor achieves an extremely low offset of just 25 mA. With conventional current measurement principles, the measuring accuracy is always governed by the ambient conditions (e.g. the temperature).

TLI4970 is more accurate than existing open-loop and comparable to closed-loop systems. It also provides additional functions such as fast overcurrent detection and programmable filter, yet it has a significantly smaller footprint and lower power consumption.

Infineon's sensor is extremely robust against external magnetic fields thanks to implemented stray field suppression, and is also suitable for fast overcurrent detection at a pre-configurable level. This allows the control unit to switch off independently of the main measurement path and protect power consumers from damage.

Features

- > Fully calibrated digital output
- High accuracy over life time due to on-chip temperature and stress compensation
- Programmable low-pass filter for measuring current (0 to 18 kHz)
- > Fast, configurable overcurrent detector (< 1.8 μs typ.)
- > Inherent magnetic stray field suppression
- > Small package size and weight for SMD mounting

Applications (AC and DC current measurement)

- Photovoltaic and general purpose inverters
- Power supplies (SMPS)
- > Battery chargers
- > Lighting applications
- > Electrical drives



Product	Accuracy ¹⁾	Current range [A]	Bandwidth [kHz]	Resolution [mA/LSB]	Automotive	Industrial	Package
TLI4970-D050T4	±1.6	±50	18	12.5	-	\checkmark	TISON-8
TLI4970-D050T5	±3.5	±50	18	12.5	-	\checkmark	TISON-8
TLI4970-D025T4	±1.6	±25	18	6.25	-	\checkmark	TISON-8
TLI4970-D025T5	±3.5	±25	18	6.25	-	\checkmark	TISON-8

www.infineon.com/current-sensor

1) Total error over lifetime and temperature

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Ι

Hall switches

The energy-saving option with excellent accuracy and robustness

TLE/TLI/TLV4961/64/6: Energy-efficient Hall switch family for up to 32 V

The TLE/TLI/TLV496x-xM/L family of Hall switches saves energy and enables designers to create precise, compact systems. With an operational current consumption of just 1.6 mA, TLE/TLI/TLV496x-xM/L products can cut energy consumption by up to 50 percent compared with similar competitor products. Thanks to its small magnetic hysteresis, the family paves the way for precise switching points in systems. The integrated temperature profile compensates magnetic drifts and enables stable performance over temperature and lifetime.

TLE/TLI/TLV496x-xM products come in the smallest SOT23 package, thus reducing height by 10 percent compared with predecessor products. The sensors also feature an integrated functionality test for better system control.

Features

- > Current consumption of just 1.6 mA
- > 3 to 32 V supply voltage range (over voltage up to 42 V)
- > 7 kV ESD protection (HBM)
- > Overtemperature and overcurrent protection
- > Temperature compensation
- Smallest SOT23 package
- > Dedicated products for industrial applications (TLI496x)
- > AEC-Q100 qualified
- > Electrical drives

Applications

- > Window lifter (index counting)
- > Power closing (index counting)
- > Gear stick (position detection)
- > Seat belt (position detection)
- > BLDC commutation
 - (e.g. wiper seat belt pretentioner, pump, seating)
- > Service robots
- > Power tools
- > White goods

Product	Туре	Operating point BOP	Release point BRP	Hysteresis ΔBHY	Automotive	Industrial	Consumer	Package
TLE4961-1M/L	Latch	2.0	-2.0	4.0	\checkmark	\checkmark	√	SOT23/SSO-3-2
TLE4961-2M	Latch	5.0	-5.0	10.0	\checkmark	\checkmark	√	SOT23
TLE4961-3M/L	Latch	7.5	-7.5	15.0	\checkmark	\checkmark	✓	SOT23/SSO-3-2
TLE4964-1M	Switch	18.0	12.5	5.5	\checkmark	\checkmark	√	SOT23
TLE4964-2M	Switch	28.0	22.5	5.5	\checkmark	\checkmark	✓	SOT23
TLE4964-3M	Switch	12.5	9.5	3.0	\checkmark	\checkmark	√	SOT23
TLE4964-5M	Switch	7.5	5.0	2.5	\checkmark	\checkmark	✓	SOT23
TLE4968-1M/L	Bipolar	1.0	-1.0	2.0	\checkmark	\checkmark	√	SOT23/SSO-3-2
TLE4961-5M	Latch	15.0	-15.0	30.0	\checkmark	\checkmark	√	SOT23
TLE4961-4M	Latch	10.0	-10.0	20.0	\checkmark	\checkmark	√	SOT23
TLE4964-4M	Switch	10.0	8.5	1.5	√	\checkmark	✓	SOT23
TLE4964-6M	Switch	3.5	2.5	1.0	√	\checkmark	√	SOT23
TLV4964-1M	Switch	18.0	12.5	5.5	-	-	✓	SOT23
TLV4964-2M	Switch	28.0	22.5	5.5	-	-	√	SOT23
TLI4961-1M/L	Latch	2.0	-2.0	4.0	-	\checkmark	√	SOT23/SSO-3-2
TLV4961-3M	Latch	7.5	-7.0	15.0	-	-	\checkmark	SOT23

20-300 V MOSFETs

TLE/TLI4963/65-xM 5 V high-precision automotive/industrial Hall-effect sensors

By offering an excellent magnetic behavior Infineon's switches are ideally suited for:

- > Index counting application with a pole wheel
- > Rotor position detection (BLDC motors)
- > Open/close detection

Features

- > 3.0 to 5.5 V operating supply voltage
- > Low current consumption 1.4 mA
- > ESD protection 4 kV HBM
- > Active error compensation (chopped)
- > High stability of magnetic thresholds
- Low jitter (typ. 0.35 μs)

- > Operating temperature range:
- from -40 to +170°C (TLE496x-xM)
- from -40 to +125°C (TLI496x-xM)
- Small SMD package SOT23
- > TLE: AEC-Q100 qualified
- > TLI: JESD47 qualified



Product	Туре	Operating point B _{op}	Release point B _{RP}	Hysteresis ΔB _{HY}	Automotive	Industrial	Package
TLE4963-1M	Latch	2.0	-2.0	4.0	\checkmark	-	SOT23
TLE4963-2M	Latch	5.0	-5.0	10.0	\checkmark	-	SOT23
TLE4965-5M	Unipolar switch	7.5	5.0	2.5	\checkmark	-	SOT23
TLI4963-1M	Latch	2.0	-2.0	4.0	-	\checkmark	SOT23
TLI4963-2M	Latch	5.0	-5.0	10.0	-	\checkmark	SOT23
TLI4965-5M	Unipolar switch	7.5	5.0	2.5	-	\checkmark	SOT23

TLV496x-xTA/B

Precision Hall-effect sensor for consumer applications in leaded package

Features

- > 3.0 to 26 V operating supply voltage
- > Low current consumption 1.6 mA
- > ESD protection 4 kV HBM
- > Operating temperature range from -40 to +125 °C
- Leaded package TO92S

Applications

- BLDC motor commutation for consumer devices (e.g. e-bikes, fans, aircons)
- > Position detection e.g. flaps and
 - control buttons

Product	Туре	Operating point B _{op}	Release point B _{RP}	Hysteresis ΔB _{HY}	Consumer	Industrial	Package
TLV4961-1TA	Latch	2.0	-2.0	4.0	√	TO92S-3-1	T092S-3-1
TLV4961-1TB	Latch	2.0	-2.0	4.0	\checkmark	T092S-3-2	T092S-3-2
TLV4961-3TA	Latch	7.5	-7.5	15.0	\checkmark	T092S-3-1	T092S-3-1
TLV4961-3TB	Latch	7.5	-7.5	15.0	\checkmark	T092S-3-2	T092S-3-2
TLV4964-4TA	Unipolar switch	10.0	8.5	1.5	\checkmark	T092S-3-1	T092S-3-1
TLV4964-4TB	Unipolar switch	10.0	8.5	1.5	\checkmark	T092S-3-2	T092S-3-2
TLV4964-5TA	Unipolar switch	7.5	5.0	2.5	\checkmark	T092S-3-1	T092S-3-1
TLV4964-5TB	Unipolar switch	7.5	5.0	2.5	\checkmark	T092S-3-2	T092S-3-2
TLV4968-1TA	Latch	1.0	-1.0	2.0	\checkmark	T092S-3-1	T092S-3-1
TLV4968-1TB	Latch	1.0	-1.0	2.0	\checkmark	T092S-3-2	T092S-3-2

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Gate driver ICs

Motor control ICs

Microcontrollers



TLE4966

Two-in-one double Hall sensor

Features

- > Two Hall probes
- > Excellent matching between the two Hall probes
- > Hall plate distance of 1.45 mm
- Industry standard
- > Outstanding quality
- > Information on direction and speed
- > TSOP6 package
- > AEC-Q100 qualified

Applications

- > Window lifter
- > Sunroof
- > Automatic tailgate
- Automated doors
- > Sun blinds

Product	Туре	Operating point B _{op}	Release point B _{RP}	Hysteresis ∆B _{нγ}	Automotive	Package
TLE4966K/L	Double Hall, speed and direction output	7.5	-7.5	15	\checkmark	TSOP6/SSO-4-1
TLE4966-2K	Double Hall, two independent outputs	7.5	-7.5	15	\checkmark	TSOP6
TLE4966-3K	Double Hall, speed and direction output	2.5	-2.5	5	\checkmark	TSOP6
TLE4966V-1K	Vertical double Hall, speed and direction output	2.5	-2.5	5	\checkmark	TSOP6

Linear Halls

TLE499x family: programmable analog/digital linear Hall sensor family

Infineon's family of TLE499x linear Hall ICs is tailored to the needs of highly accurate angular and linear position detection and current measurement applications. Each product measures the vertical component of a magnetic field and outputs a signal that is directly proportional to the magnetic field. These programmable linear Hall sensors come with different interface options: TLE4997 features ratiometric analog output, while TLE4998P comes with pulse width modulation (PWM), TLE4998S with single edge nibble transmission (SENT) and TLE4998C with short PWM codes (SPC). These high-precision 12-bit resolution linear Hall sensors feature EEPROM memory for flexible programming across a wide range of parameters.

Thanks to digital signal processing based on a 20-bit DSP architecture plus digital temperature compensation, these sensors deliver outstanding temperature stability compared with similar compensation methods. TLE4998 also includes stress compensation to withstand stress effects from the package, such as moisture, thus ensuring best-in-class accuracy over the device's lifetime.

Features

- Best-in-class accuracy with low drift of output signal temperature range lifetime (including stress compensation in TLE4998)
- Programmable transfer function (gain, offset), clamping, bandwidth and temperature characteristics
- > AEC-Q100 qualified
- Available in various packages including SSO-3-9 with two integrated capacitors to improve ESD and ESC behavior
- > Dual-die SMD package

EEPROM

www.infineon.com/linear-hall

3/4/

Single die SMD 8

> ISO26262 ready

Applications

- Detecting linear and angular position
- Detecting pedal and throttle position
- > Steering torque measurement
- > Headlight leveling
- > High-current sensing
- Seat position and occupant detection
- > Suspension control

5 V +10% (16 V)

- > Detecting gear stick/lever positions
- > Detecting liquid levels in fuel tanks
- > Current sensing e.g. for battery management

Package

TDSO-8

TDSO-8

TDSO-8

SPC

SSO-3-10 TDSO-8

SSO-3-10 SSO-4-1

SSO-3-10 SSO-4-1

SSO-3-10 SSO-4-1

SSO-3-9 (2 capacitors)

SSO-3-9 (2 capacitors)

SSO-3-9 (2 capacitors)

Product Programmable Number of pins Sensitivity Magnetic offse Supply voltage (extended range) Interface TLE4997 EEPROM ±12.5 to ±300 < ±400 µT 5 V ±10% (7 V) Analog 3/ 1 Single die SMD 8 TLE4998P FFPROM 3/4/ 5 V ±10% (16 V) PWM ±0.2 to ±6%/mT < ±400 µT Single die SMD 8 **TLE4998S** EEPROM 3/4/ ±8.2 to ±245 LSB/mT < ±400 µT 5 V ±10% (16 V) SENT Single die SMD 8

< +400 µT

+8.2 to +245 | SB/mT

TLE4998C

500-950 V MOSFETs

Sate driver ICs

Packages


Dual linear Halls

Two sensors in one SMD package



The SMD package (TDSO) includes two independent sensors with separate power supply and separate signal outputs. Due to special mounting technology, Infineon is able to keep dual-sensor package size very small to enable compact PCB layouts and small magnet sizes.

Infineon offers a wide range of Hall sensors in the TDSO package. The combination of two sensors in one package offers sensors redundancy, a feature which is especially interesting for new generation EPS steering systems with increased ISO26262 requirements and other safety critical applications. All sensors are automotive qualified.

Features

- > Two sensors in one package
- > Separate power supply and signal output
- > AEC-Q100 qualified
- > Temperature range from -40 to +125°C
- > Outstanding quality
- > Single-sensor versions available
- > 16-pin and 8-pin versions available
- > ISO26262 ready

- > Steering torque systems
- > Pedal position
- > Any other safety critical application

Product	Interface	Dual-/single-sensor available	Package
TLE4997A8D	Analog	Yes/yes	TDSO-8
TLE4998P8D	PWM	Yes/yes	TDSO-8
TLE4998S8D	SENT	Yes/yes	TDSO-8
TLE4998C8D	SPC	Yes/yes	TDSO-8



Discrete IGBTs

Angle sensors

Compact designs in small outline packages

Highest variety - low end to high end, standardized and specialized in all four magnetic technologies: Hall, GMR, AMR and TMR

Infineon's new magnetic sensor products TLE5501, are fast analogue TMR-based angle sensors dedicated to automotive applications. Their fields of use range from steering angle applications, with the highest functional safety requirements, to motors for wipers, pumps and actuators and electric motors in general. They are also ready to be used in industrial and consumer applications like robotics or gimbal. Angle sensors detect the orientation of an applied magnetic field by measuring sine and cosine angle components with monolithically integrated magneto resistive elements.

Infineon's iGMR sensors are ideal for applications with a wide angle range, such as BLDC motors or steering sensors. They are pre-calibrated and ready-to-use. Different levels of signal processing integration enable designers to optimize system partitioning. The XENSIV[™] iAMR sensors also perfectly fit applications with the highest accuracy requirements, as they offer best performance over temperature, lifetime and magnetic field range.

iGMR, iAMR and iTMR based angle sensors

Product	Technology	Die configuration	ISO26262	Sin/cos output	Angle output	Second interface	Accuracy	Package
TLE5009	GMR	Single die	Ready	Analog sin/cos	-	-	0.9°	DSO-8
TLE5009A16(D)	GMR	Dual die	Ready	Analog sin/cos	-	-	1.0°	TDSO-16
TLE5011	GMR	Single die	Ready	SSC (SPI)	-	-	1.6°	DSO-8
TLI5012B	GMR	Single die	Ready	SSC (SPI)	SSC (SPI)	PWM/IIF/SPC/HSM	1.9°	DSO-8
TLE5012B(D)	GMR	Single and dual die	Ready	SSC (SPI)	SSC (SPI)	PWM/IIF/SPC/HSM	1.0°	DSO-8/ TDSO-16
TLE5014C16(D)	GMR	Single and dual die	Compliant	-	SPC	-	1.0°	TDSO-16
TLE5014P16(D)	GMR	Single and dual die	Compliant	-	PWM	-	1.0°	TDSO-16
TLE5014S16(D)	GMR	Single and dual die	Compliant	-	SENT	-	1.0°	TDSO-16
TLE5014SP16(D)	GMR	Single and dual die	Compliant	-	SPI	-	1.0°	TDSO-16
TLE5109A16(D)	AMR	Single and dual die	Ready	Analog sin/cos	-	-	0.5°	TDSO-16
TLE5309D	AMR + GMR	Dual die	Ready	Analog sin/cos	SSC (SPI)	-	AMR 0.5°, GMR 1.0°	TDSO-16
TLE5501	TMR	Single die	Compliant	Analog sin/cos	-	-	1.0°	DSO-8

Diverse redundant sensor with analog and digital interface

SPI = Serial peripheral interface IIF = Incremental interface PWM = Pulse width modulation 20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Gate driver ICs

Tunneling Magneto Resisitive (iTMR) technology is offering high sensing sensitivity with a high output voltage, reducing the need for an internal amplifier. Thus, the sensor can be connected directly to the microcontroller without any further amplification. In addition, iTMR technology shows a very low temperature drift, reducing external calibration and compensation efforts. The iTMR technology is also well known for its low current consumption.

TLE5501

With the TLE5501 products, Infineon is currently launching the first angle sensor products based on iTMR technology. TLE5501 is available in two versions.

TLE5501 - product versions with different pin out:

 TLE5501 E0001: pin-compatible to TLE5009 automotive qualified acc. AEC-Q100

iTMR based angle sensors

 TLE5001 E0002: decoupled bridges for redundant external angle calculation and highest diagnostic coverage, realizing ISO26262-compliant development ASIL D

Features

- > Large output signals of up to 0.37 V/V for direct microcontroller connection
- > Discrete bridge with differential sine and cosine output
- > Very low supply current: ~2 mA
- > Magnetic field range (20-100 mT)
- > Typ. angle error ~ 1.0 ° (overtemperature and lifetime)
- > DSO-8 package
- > AEC-Q100, grade 0: TA = -40°C to 150°C (ambient temperature)
- > For TLE5501 E0002:
 - Reaching ASIL D with just one single sensor chip
 - ISO26262-compliant development ASIL D

Applications

- > Steering angle sensor
- > BLDC motor commutation (e.g. wipers, pumps and actuators)
- > Angular position sensing for e.g. robotics or gimbal
- > Electric motors
- > Industrial automation
- Safety applications



20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

Power ICs

Sate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

iT MR

TLE5014(D)

Digital iGMR sensor with an easy-to-use plug-and-play concept for highest functional safety applications

All XENSIV™ TLE5014 angle sensors are available as single and dual die products. The products come pre-configured and pre-calibrated as plug-and-play sensors and are easy to use. Customers can choose between the interfaces SENT, PWM, SPC an SPI. On top of those protocol options, the sensors can be adapted to any kind of application setup via their programmable E²PROM interfaces. TLE5014 magnetic angle sensors meet ISO26262 ASIL C for the single die and ISO26262 ASIL D for the dual die versions. All products are ready for applications with the highest functional safety requirements. The sensors show an extremely small angle error of less than 1° across the entire temperature profile and lifetime. This is particularly helpful in applications with the need for very accurate position sensing such as steering angle sensing or motor commutation. Further application areas range from rotor position measurement, electric power steering (EPS), pedal position to any other kind of position measurement.

Features

- > Easy-to-use, plug-and-play sensors, pre-configured and pre-calibrated
- > Offering high flexibility:
 - Available as single and dual die products
 - 12bit digital interface with protocol options PWM, SENT, SPC and SPI
 - E2 PROM and look-up table for customer configuration and calibration
- > High angle accuracy: max. 1.0° over temperature and lifetime
- > High voltage capability up to 26 V
- Development fully compliant with ISO26262
 - Developed acc. ASIL D level
 - Dual die sensors reaching ASIL D, single die sensors ASIL-C metrics
- > Safety manual and safety analysis summary report available on request

Applications

- Steering angle sensing (SAS)
- Motor commutation
- Rotor position measurement
- > Pedal position
- > Safety applications
- > Any other kind of high-accuracy position measurement

TLE5109A16(D)

Analog iAMR sensor with temperature compensation

Features

- > Features a differential or single-ended analog interface for sine and cosine values
- Internal temperature drift compensation for gain and offset
- > Also available as a dual-sensor package
- > ISO26262 ready
- > Typical 0.1" angle error over lifetime and temperature range after compensation (max 0.5")
- > Available as single and dual die product

www.infineon.com/angle-sensors

*Giant Magneto resistance



PRO

SIL







20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

^ower ICs

Sate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

3D magnetic sensors TLV493D-A1B6/TLI493D-A2B6 for consumer and industrial market

The TLV493D-A1B6 sensor realizes an accurate three-dimensional sensing with extremely low power consumption in a small 6-pin package. Capable of detecting the magnetic field in the x, y, and z-direction, the sensor is ideally suited for the measurement of linear, rotation or 3 dimensional movements. Thanks to its small package and low power consumption, the TLx493D-AxB6 can be used in new applications, replacing potentiometer and optical solutions. Featuring contactless position sensing and high temperature stability of the magnetic threshold, the sensor allows systems getting smaller, more accurate and more robust.



Rotation movement

Features

- > 3D magnetic sensing
- Integrated temperature sensing
- > Low current consumption
- 7 nA in power-down mode
- 10 μ A in ultralow power mode
- > 2.8 to 3.5 V operating supply voltage



3D movement



Linear movement

- > Digital output via a 2-wire standard I2C interface
- > Bx, By and Bz linear field measurement up to ±160 mT
 > JESD47 qualified
- > 12-bit data resolution for each measurement direction
- > Various resolution options from 65 μ T/LSB to 130 μ T
- Operating temperature range from -40 to +125°C

Product	Temperature range	Qualification	Linear magnetic range	Resolution	IDD	Update rate	Package	Ordering code
TLV493D-A1B6	-40 125°C	JESD47	±130 mT (typ)	98 μT/LSB	7 nA – 3.7 mA	10 Hz – 3.3 kHz	TSOP6	SP001286056
TLI493D-A2B6	-40 105°C	JESD47	±160 mT (min) ±100 mT (min)	130 μT/LSB (65 μT/LSB) ¹⁾	7 nA – 3.3 mA	10 Hz – 8.4 kHz	TSOP6	SP001689844

1) Half range mode

While the TLV493D-A1B6 just supports a typical value for the linear magnetic range of ± 130 mT, the TLI493D-A2B6 specification includes also a minimum value of ± 160 mT.

With the TLI493D-A2B6,s a broader microcontroller compatibility as well an enhanced feature set is included.

New features

- Sensor address read back
- Short mode range setting, focusing on the half of the magnetic range, ensuring higher accuracy
- Higher update frequency allows for an application field that requires faster update speed
- > Angular mode (for x and y read-out only)

Applications

- > Anti tempering protection in smart meters
- Joysticks e.g. for medical equipment, cranes, CCTV-control, game consoles
- > Control elements e.g. white goods multifunction knobs

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

^oower ICs

Sate driver ICs

Motor control ICs

Microcontrollers

XENSIVTM sensors

3D magnetic sensors

TLE493D-A2B6/W2B6 for automotive low power applications

Infineon's TLE493D-x2B6 enables for all kind of automotive control element applications within the passenger compartment or under the hood with a temperature range of -40 to +125°C, with linear magnetic range requirements up to ±160 mT.



Features

- > 3D magnetic sensing
- Integrated temperature sensing
- > 2.8 to 3.5 V operating supply voltage
- > Low current consumption
 - 0.007 μA in power-down mode
 - 10 μA in ultralow power mode
 - Up to 10 power modes

- > Digital output via a 2-wire standard I2C interface
- > Bx, By and Bz linear field measurement ±160 mT
- > AEC-Q100 qualified
- > 12-bit data resolution for each measurement direction
- Various resolution options from 67 µT/LSB to 134 µT
- > Operating temperature range from -40 to +125°C

Product	Temperature range	Qualification	Linear magnetic range	Resolution	I _{DD}	Update rate	Wake- up	Package	Ordering code
TLE493D-A2B6	-40 125°C	AEC-Q100	±160 mT (min)	130 μT/LSB (65 μT/LSB) ¹⁾	7 nA – 3.3 mA	10 Hz – 8.4 kHz	No	TSOP6	SP001689848
TLE493D-W2B6 A0 TLE493D-W2B6 A1 TLE493D-W2B6 A2 TLE493D-W2B6 A3	-40 125°C	AEC-Q100	±160 mT (min) ±100 mT (min)	130 μT/LSB (65 μT/LSB) ¹⁾	7 nA – 3.3 mA	0.05 Hz – 8.4 kHz	Yes	TSOP6	SP001655334 SP001655340 SP001655344 SP001655348

1) Half range mode

The XENSIV™ sensor TLE493D-A2B6 features include a sensor address read-back feature for additional communication verification, a half range mode focusing to half of the magnetic range, ensuring higher accuracy and an angular mode (for x and y readout only).

With the TLE493D-W2B6 A0-A3, a 3D sensor has been developed, which includes an enhanced dynamic wake up feature. Four pre-programmed address options (A0-A3) will be available, enabling for a fast start-up initialization, when used in I²C bus configurations. It also includes enhanced test options, and a safety documentation is available to enable the usage of this sensor in the context of ASIL B systems.

Applications

> Control elements for infotainment/navigation systems, air conditions, multifunctional steering wheels, seat controls

- > Top column modules e.g. direction indicator, wiper control
- Gear stick position sensing

XENSIVTM sensors

20-300 V MOSFETs

500-950 V MOSFETs

WBG semiconductors

Discrete IGBTs

^oower ICs

Sate driver ICs

Motor control ICs

Microcontrollers



Magnetic speed sensors

Easy-to-use, robust and cost-effective sensors for speed measurement

Infineon's Hall- and GMR-based magnetic speed sensors are designed to measure speed in safety and powertrain applications such as speedometers, ABS, camshafts/crankshafts and automatic transmissions. They are also used in similar applications in the industrial sector. The sensors use a ferromagnetic gear tooth or encoder structure to measure linear or rotational speed and position. Hall sensor measuring rotational speed with a gear tooth and a magnetic encoder wheel. The majority of sensors also feature additional benefits such as integrated capacitors (C-types) for high EMC robustness and the highest levels of ESD protection.

Modern powertrain systems rely on magnetic speed sensors, along with automotive pressure sensors, to achieve the required CO2 targets and smart powertrain solutions. Infineon offers a broad variety of magnetic speed sensors for camshaft, crankshaft and transmission applications.

TLE4922

Highly robust, easy-to-use mono-Hall speed sensor with twist-independent mounting

This sensor is specially designed to provide an easy-to-use, robust and cost-effective solution for vehicle or industrial speed sensing applications. The TLE4922 can, therefore, be back-biased using a simple, low-cost bulk magnet, while providing a good air gap performance and switching accuracy. Its hidden adaptive hysteresis and calibration algorithm enable good accuracy over air gap jumps and immunity to vibration and run-out events.

Features

- > Large operating air gap capability
- > Twist-independent mounting
- > Hidden adaptive hysteresis
- > Low current consumption
- > Reverse magnetic polarity capability
- Advanced protection technology
 - Reverse voltage protection at VS-pin
 - Short-circuit protection
 - Overtemperature protection
- > Wide operating temperature ranges of $-40^{\circ}C \le Tj \le \pm 150^{\circ}C$
- > High ESD robustness up to ±4 kV HBM
- > 3-wire PWM voltage interface

Applications

- > Two-wheeler
- > Automotive vehicle speed



TLE4929

Fully programmable crankshaft sensor

The TLE4929 is an active Hall sensor ideally suited for crankshaft applications and similar industrial applications, such as speedometer or any speed sensor with high accuracy and low jitter capabilities.

Features

- Differential Hall speed sensor to measure speed and position of tooth/pole wheels
- > Switching point in the middle of the tooth enables backward compatibility
- > Robustness over magnetic stray-field due to differential sensing principle
- Digital output signal with programmable output-protocol including diagnosis interface
- > Direction detection and stop-start-algorithm
- > High accuracy and low jitter
- > High sensitivity enable large air gap
- > End-of-line programmable to adapt engine parameters
- > Can be used as a differential camshaft sensor
- Automotive operating temperature range



Product	Automotive	Industrial	Sensor technology	AEC-Q100 qualified	RoHS	HAL free	Product status
TLE4922	\checkmark	\checkmark	Mono-Hall	\checkmark	\checkmark	\checkmark	In production
TLE4929	\checkmark	\checkmark	Differential Hall	\checkmark	\checkmark	\checkmark	In production

Sensor 2GO kits

Infineon's solutions for quick evaluation

Smallest, fully featured sensor 2GO evaluation kits for current, low-cost rotational speed, 3D magnetic sensors and angle sensors with optional joystick adapter, rotation knob, linear slider and out-of-shaft adapter, as well as digital barometric air pressure sensor and XENSIV[™] MEMS microphones.

- > Plug-and-measure evaluation board
- > First measurements possible within minutes
- > Various mechanical adapters for 3D magnetic sensor available for quick evaluation

Infineon's XENSIV[™] sensor 2GO kits are budget-priced evaluation boards that are already equipped with a sensor combined with an ARM[®] Cortex[®]-M0 CPU. The sensor 2GO kits provide a complete set of onboard devices, including an onboard debugger. Build your own application and gadget with the sensor 2GO kits. Our 2GO kits are ready-to-use, plug-and-play boards.



3D magnetic sensor 2GO kit features

- > We offer three different derivatives
 - TLE493D-A2B6 (three dimensional magnetic sensor)
 - TLE493D-W2B6 (three dimensional magnetic sensor)
 - TLV493D-A1B6 (three dimensional magnetic sensor)
- > XMC1100 (ARM[®] Cortex[™]-M0 based)
- Onboard J-Link Lite debugger (realized with XMC4200 microcontroller)
- > Power over USB (micro USB), ESD and reverse current protection
- GUI for free download

Current sensor 2GO kit features

- > TLI4970-D050T4 (current sensor with digital interface)
- > XMC1100 (ARM[®] Cortex[®]-M0 based)
- > Onboard J-link lite debugger (realized with XMC4200 microcontroller)
- > Power over USB (micro USB), ESD and reverse current protection
- > GUI for free download

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Speed sensor 2GO kit features

- > Budget-priced evaluation board for speed sensing
- Complete speed sensor incl. back-bias magnet, fixing and cable
- TLE4922 (active mono cell Hall sensor)
- > XMC1100 (ARM[®] Cortex[™]-M0 based)
- > Onboard J-Link Lite debugger (realized with XMC4200 microcontroller)
- > Power over USB (micro USB), ESD and reverse current protection
- > GUI based tool for real in-application evaluation for free download

20-300 V MOSFETs

Add on components for 3D magnetic sensor 2GO kit

Out of shaft adapter for angle measurements Product information:

- > Easy mounting on all 3D magnetic sensor 2GO kits
- > First angle measurement in out-of-shaft configuration
- > Three different out-of-shaft configurations possible
- > Magnetic rotation bar with ring magnet included

Joystick adapter

Product information:

- > Easy mounting on 3D magnetic sensor 2GO
- > First magnetic joystick measurements within minutes
- The user manual in the download area explains usage, mounting and functionality

Rotate knob

Product information:

- > Rotate and push button control element
- > Simulates rotational and angle sensing movements
- The user manual in the download area precisely explains usage, mounting and functionality and functionality

Linear slider

- > Easy mounting on 3D Magnetic Sensor 2GO
- > First magnetic linear evaluations within minutes
- Flexible setup: adaptable airgaps, two different magnetic strengths/ materials and distance limiters

Enstyle Services - Getting Started Box lot Internet was entranged. The function of the entranged of the function of the entranged of the entra

Getting Started Box IoT

For fast, flexible and easy prototyping - never been easier

A box consists of:

- XENSIV[™] magnetic position sensor TLV493D-A1B6
- Rotate knob add-on component for 3D magnetic Hall sensor
- > Joystick add-on component for 3D magnetic Hall sensor
- > OPTIGA™ Trust E hardware security chip
- > XENSIV[™] pressure sensor DPS310 for consumer
- XMC 1100 Bootkit 32-bit microcontroller based on ARM[®] Cortex[®]-M form factor compatible with Arduino Uno
- XMC2Go (qty 2) 32-bit microcontroller based on ARM[®] Cortex[®]-M in Shield2Go form factor
- XENSIV[™] magnetic current sensor TLI4970-D050T4 with integrated current rail
- > XENSIV[™] MEMS microphone IM69D130
- > ESP32 Wemos form factor including BLE and WIFI functionality
- > Dual-adapter Trust X adapter for Infineon Shield2Go board with Wemos form factor equipped with OPTIGA™ Trust X
- Triple-adapter adapter for Infineon Shield2Go board form factor compatible with Arduino Uno (alternatively: Grove Base_Shield_V2)
- VSB-cable and soldering connectors



MEMS 2GO

The flex evaluation kit allows simple and easy evaluation of XENSIV[™] MEMS microphone IM69D130. The flex board can be easily connected to audio testing setup. The evaluation kit includes five IM69D130 mounted on flex board and one adapter board.

Features

- > Quick and easy evaluation of XENSIV[™] MEMS microphones
- > Flex dimensions: 25 x 4.5 mm
- > Adapter dimensions: 20 x 15 mm

Shield2Go boards and My IoT adapter

Easy evaluation for shorter time to market

Infineon's Shield2Go boards offer a unique customer and evaluation experience. The boards are equipped with a featured Infineon's XENSIV[™] sensor and come with a ready-to-use software library for Arduino. Customers can now develop their own system solutions by combining Shield2Go boards with Infineon My IoT adapter, which serves as a gateway to external hardware solutions and popular IoT evaluation platforms such as Arduino and Raspberry PI. All this enables the fastest evaluation and development of an IoT system on the market.



www.infineon.com/2go www.infineon.com/sensors2go

Applicatior

Microcontrollers

Packages



www.infineon.com/angle-sensors

www.infineon.com/pressuresensor

www.infineon.com/3dmagnetic

www.infineon.com/24GHz

www.infineon.com/pressure

Infineon support for sensors

Useful links and helpful information

Further information, datasheets and documents

www.infineon.com/sensors www.infineon.com/microphones www.infineon.com/magnetic-sensors www.infineon.com/current-sensor www.infineon.com/hall-switches

2GO evaluation kits www.infineon.com/sensors2go

Online simulation tools

www.infineon.com/cms/en/product/sensor/#!simulation





Gate driver ICs

Motor control ICs

Packages

Surface mount device (SMD) technology

Г)PAK (TO-252-2)	DPAK (TO-252)	DPAK 5-pin (TO-252)	нря	OP-10-1		HDSOP-22-1		D ² PAK (TO-263)
2	9.9 x 6.5 x 2.3	3 9.9 x 6.5 x 2.3	5 9.9 x 6.5 x 2.3		.96 x 6.5 x 2.3	22	20.96 x 15.0 x 2.3	3	15.0 x 10.0 x 4.4
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2	15.0 x 10.0 x 4.4	7 15.0 x 10.0 x 4.4	7 15.0 x 10.0 x 4.4	7 15.	.0 x 10.0 x 4.4	7	15.0 x 10.0 x 4.4	8	11.68 x 9.9 x 2.3
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3	3.0 x 2.8 x 1.1	3 2.9 x 2.4 x 1.0	5 2.9 x 1.6 x 1.3	0 2.	.9 x 1.6 x 1.3	3	4.5 x 4.0 x 1.5	4	6.5 x 7.0 x 1.6
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	SOT223-3-1	SOT-323	SOT-363	Т	SOP6		PQFN 2x2		PQFN 2x2 dual
3	6.5 x 7.0 x 1.6	3 2.0 x 2.1 x 0.9	6 2.0 x 2.1 x 0.9	6 2.	.9 x 2.5 x 1.1	6	2.0 x 2.0 x 0.9	6	2.0 x 2.0 x 0.9
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8	3.3 x 3.3 x 1.0	8 5.15 x 6.15 x 1.0	8 5.15 x 6.15 x 1.0	8 5.1	.5 x 6.15 x 1.0	8	5.15 x 6.15 x 1.0	10	3.0 x 3.0 x 0.9
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	TDSON-10-7	TSDSON-8-25 fused leads	TISON-8		ower stage Evel	TICO	N-8-4 (Power Block)		TSON-8-1
10	3.0 x 3.0 x 0.9	8 3.3 x 3.3 x 1.0	8 7.0 x 7.0 x 1.0		.0 x 6.0 x 1.0	8	5.0 x 6.0 x 1.0	8	3.0 x 3.0 x 1.0
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	TSON-8-3	ThinPAK 5x6 (TSON-8)	TSON-10	TSI	NP-6-13	Thi	nPAK 8x8 (VSON-4)		VDSON-8
8	5.0 x 6.0 x 1.0	8 5.0 x 5.0 x 1.0	10 3.3 x 3.3 x 1.0	6 1.	5 x 1 x 0.375	4	8.0 x 8.0 x 1.0	8	4.0 x 4.0 x 0.9
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	WSON-6-1	WSON-8-3	WSON-10		T [™] Small Can	<u> </u>	ctFET [™] Medium Can		ectFET [™] Large Can
6	3 x 3 x 0.75	8 3 x 3 x 0.75	10 4.0 x 4.0 x 0.8	V 4.8	8 x 3.8 x 0.65	V	6.3 x 4.9 x 0.65	V	9.1 x 6.98 x 0.71
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V = V	ariable number of pins limensions in mm						All products are RoHS Co		nt. RoHS

www.infineon.com/packages

20-300 V MOSFETs

Packages



	IQFN-27-2	IQF	FN-30 (DrMOS 4x4)	IQI	N-31 (DrMOS 5x5)		IQFN-36		IQFN-39		IQFN-40
27	3.3 x 6.0 x 0.9	30	4.0 x 4.0 x 1.0	31	5.0 x 5.0 x 0.8	36	7.5 x 6.0 x 0.9	39	5.0 x 6.0 x 0.9	40	6.0 x 6.0 x 0.8
<	0 4 3		C)				(i)		6		
:	SO-8/SO-8 dual		SO-16/12		SO-14		SO-16		SO-18		DSO-12
8	5.0 x 6.0 x 1.75	12	10.0 x 6.0 x 1.75	14	8.75 x 6.0 x 1.75	16	10.0 x 6.0 x 1.75	18	12.8 x 10.3 x 2.65	12	10.3 x 7.8 x 2.6 (max
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DS	0-16-30 (300 mil)		DSO-24		SSOP-24		TDSO-16		SO-19		SO-20
16	10.3 x 7.5 x 2.35	24	10.5 x 15.6 x 2.65 (max)	24	6 x 8.65 x 1.75 (max)	16	5.0 x 6.0 x 1.2	19	12.8 x 10.3 x 2.65	20	12.8 x 10.3 x 2.65
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	DSO-28		SO-36		TSSOP-28		TSSOP-48		LFBGA-516-5		LFBGA-292-6
28	18.1 x 10.3 x 2.65	36	15.9 x 11.0 x 3.5	28	9.7 x 6.4 x 1.2	48	12.5 x 6.1 x 1.1	516	25.3 x 25.3 x 2.8	292	17.3 x 17.3 x 2.35
4		2			C				CI DI		6
	BGA-416-26		TFLGA-13-1		LQFP-176-22		LQFP-144-22		TQFP-144-27		TQFP-100-23
416	27.3 x 27.3 x 3.2	13	5 x 5 x 0.96	176	26.7 x 26.7 x 2.1	144	22.4 x 22.4 x 2.2	144	18.7 x 18.7 x 1.6	100	14.5 x 14.5 x 1.5
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	TQFP-80-7		VQFN-40-13		VQFN-48-60	١	/QFN-48-78 (LTI)		VQFN-56-5/-6	Pac	kage (JEITA-code)
80	12.6 x 12.6 x 1.5	40	5 x 5 x 0.85	48	6 x 6 x 0.85	48	7 x 7 x 0.85	56	7 x 7 x 0.9	X	LxWxH
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All products are RoHS Compliant.



Through-hole device (THD) technology

	IPAK (TO251)	IP	AK SL (TO251 SL)		I ² PAK (TO262)	-	TO220 real 2-pin		TO220 2-pin		TO220 3-pin
3	15.5 x 6.5 x 2.3	3	10.7 x 6.5 x 2.3	3	25.1 x 10 x 4.4	2	29.15 x 10.0 x 4.4	2	29.1 x 9.9 x 4.4	3	29.15 x 10.0 x 4.4
	E		G		G		đ		đ		đ
	TO220 FullPAK	T022	0 FullPAK Narrow Lead	TO220	0 FullPAK Wide Creepage		TO220-6-46		TO220-6-47		TO247
3	29.6 x 10.5 x 4.7	3	29.6 x 10.5 x 4.7	3	28.85 x 11 x 4.7	6	21.7 x 9.9 x 4.4	6	26.1 x 9.9 x 4.4	3	40.15 x 15.9 x 5.0
	đ		-		0		G		0		ġ
	T0247-3-AI		TO247 4-pin		DIP-7		DIP-8		DIP-14		DIP-20
3	41.3 x 10.9 x 5.18	4	40.15 x 15.9 x 5.0	7	9.52 x 8.9 x 4.37	8	9.52 x 8.9 x 4.37	14	19.5 x 8.9 x 4.37	20	24.6 x 9.9 x 4.2
	m								THINK		PPPPPPPP
_	Super220		Super247		SSO-3-9		SSO-3-10		SSO-4-1		T092S-3-1
3	28.25 x 10.5 x 4.5	3	34.6 x 15.6 x 5	3	A: 3.71 x 5.34 x 1 B: 2.68 x 5.34 x 1.2	3	4.06 x 1.5 x 4.05	4	5.34 x 1.0 x 3.71	3	4.0 x 1.52 x 3.15
			A		AB				-		
	T092S-3-2	Pac	kage (JEITA-code)								
3	4.0 x 1.52 x 3.15	X	L x W x H								
		V = V	count ariable number of pins limensions in mm								





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